

INTELLIGENT DISK CONTROLLER (IDC) DISK SYSTEM

Installation and Maintenance Manual



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PREFACE

This manual documents the installation, operation and maintenance of an intelligent disk controller (IDC) disk system. An IDC disk system is a mass storage module (MSM) system or a medium capacity cartridge disk drive (MCCDD) system having as its controller a printed circuit board referred to as the IDC.

Chapters 1 and 2 are directed towards all users, e.g.; sales personnel, instructors, customer engineers, technicians and programmers. Chapter 1 defines what an IDC disk system is. Chapter 2 presents detailed parts lists for possible IDC disk systems and discusses procedures for installing an IDC disk system. Chapters 3 and 4 are directed to customer engineers, technicians and programmers. Chapter 3 describes the operation of the IDC board at the block diagram level. Chapter 4 presents detailed information necessary for the maintenance of an IDC disk system.

This manual is also intended to cover the operation of the high speed intelligent disk controller (HSIDC). All sections are pertinent to the description of operation for the HSIDC with the following exceptions:

- The HSIDC (35-932) is configurable only into systems with the MSM825F disks.
- The HSIDC is designed to operate with shared memory data (SMD) interface devices using up to 15MHz data clocks which allows for disk data transfer rates of up to 1.8MB per second.

Revisions 21 through 23 include text and drawing changes. Schematic and assembly drawings for the HSIDC have been incorporated to accommodate support of the 825MB disk drives.

For information on the contents of all 32-bit manuals, see the 32-Bit Systems User Documentation Summary.

CHAPTER 1 OVERVIEW

1.1 DESCRIPTION OF AN INTELLIGENT DISK CONTROLLER (IDC) DISK SYSTEM

A disk system is the hardware that provides a processor with disk support. It provides a processor with the capability of writing to and reading from disk media. Basically, a disk system consists of these hardware components:

- one or more disk files (a disk file is a disk drive with removable or fixed disk media),
- a controller for interfacing these disk files to the processor, and
- necessary cabling for interconnecting the controller hardware and disk files.

An IDC disk system provides a Series 3200 Processor with support for direct access devices or disk files. Chapter 2 specifies all components of the various IDC disk systems. As shown in Figure 1-1, an IDC disk system consists of:

- one controller board, a printed circuit (PC) board referred to as the IDC,
- one to four disk files with specially formatted disk media, and
- necessary cabling for connecting the IDC and disk files.

Figure 1-2 shows the IDC PC board. This board contains microprocessor logic for directly interfacing disk files with the Series 3200 Processor. Data transfer to and from the processor, via a direct memory access (DMA) port, is through either a Series 3200 selector channel (SELCH) or channel manager (CM). For data recovery from disk read errors, the IDC has the capability of performing strobe offset or track offset sequences. It also has an automatic error correction capability for correcting error bursts of up to 11 bits in length. For detailed programming information on the characteristics of the IDC, see Table 1-1 and the Intelligent Disk Controller (IDC) Programming Manual.

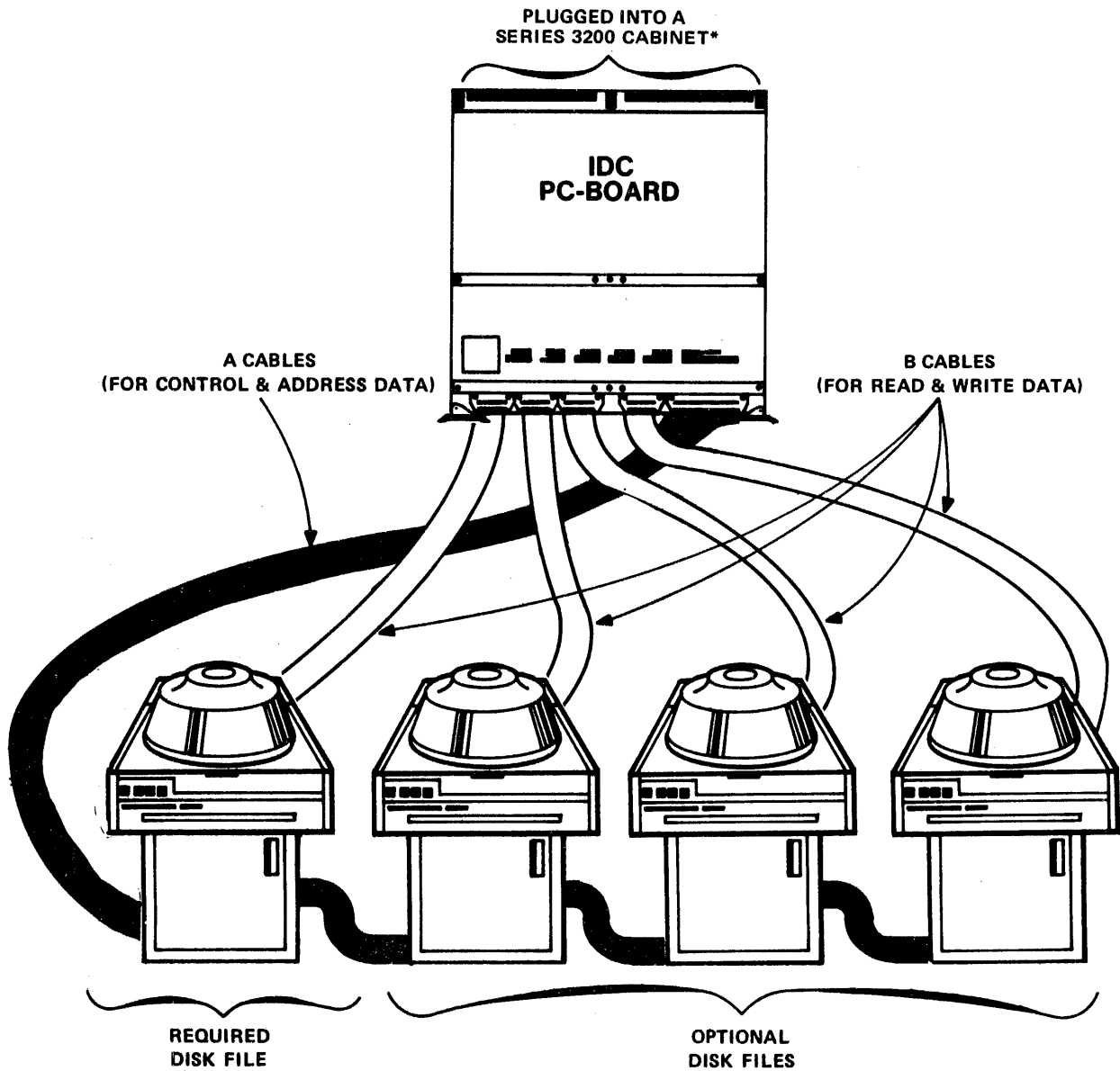
The IDC can interface a maximum of four disk files to the Series 3200 Processor with overlapping seek and restore operations. These can be any combination of disk files, i.e., mass storage modules (MSMs) and/or medium capacity cartridge disk drives (MCCDDs). For example, four interfaced files might be one of the following combinations: 67MB MSM, 256MB MSM, 256MB MSM, and 81MB cartridge disk drive (CDD); or, 256MB MSM, 256MB MSM, 256MB MSM, and 54MB CDD; or, this: 27MB CDD, 54MB CDD, 81MB CDD, and 256MB MSM. The IDC board will also support future disk files. For performance data and other information on the supported disk files, see the vendor manuals listed in Table 1-1.

NOTE

The disk media of an IDC system have a physical format that is different from and incompatible with the format of MSM disk media. For additional information on these differences, see the IDC Programming Manual.

MSM disk drives allow installation of a dual-port option which permits two controllers to share a single disk file; these two controllers can be in the same processor cabinet or in separate processor cabinets. The MCCDD and CDD50 systems are not capable of dual-port operation.

Cabling from the IDC board to the disk files is simple and direct because there is no interface, such as a control panel, between the board and interfaced files.



* For special applications requiring an Input/Output (I/O) bus switch, the IDC is installed in a slot under the I/O bus Switch.

Figure 1-1 Basic IDC Disk System

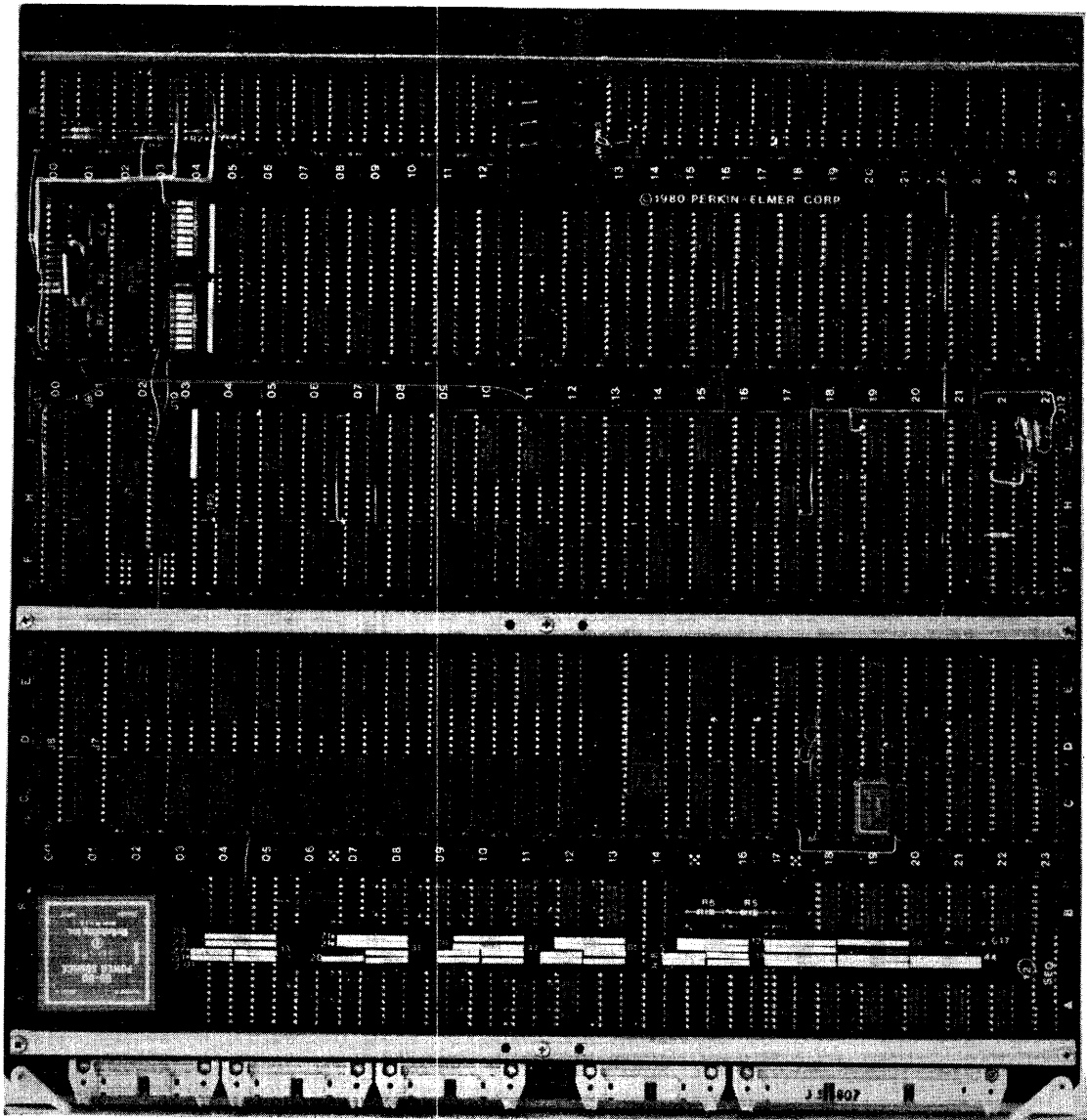


Figure 1-2 IDC PC-Board

1.2 LIST OF RELATED PUBLICATIONS

Table 1-1 lists the manuals related to IDC disk systems.

TABLE 1-1 LIST OF RELATED PUBLICATIONS

RELATED MANUAL
M48-018 Input/Output (I/O) Bus Switch Manual and Control Panel Installation Manual
80MB Maintenance Manual Package (This package contains vendor manuals for the 67MB MSM removable media disk systems.)
300MB Maintenance Manual Package (This package contains vendor manuals for the 256MB MSM removable media disk systems.)
Model 3200 Selector Channel (SELCH) Maintenance Manual
80MB (Fixed) Maintenance Manual Package (This package contains vendor manuals for the 67MB MSM fixed media disk systems.)
Vendor Manual Cartridge Disk Drive (This manual is for the 27MB, 54MB and 81MB MCCDD systems.)
825MB (Fixed) Maintenance Manual Package (This package contains vendor manuals for the 646MB MSM fixed media disk systems).
Channel Manager (CM)
Intelligent Disk Controller (IDC) Programming Reference Manual (includes CDD50 system)
330MB Disk Drive Vendor Manual

CHAPTER 2 INSTALLATION

2.1 INTRODUCTION

This chapter gives detailed parts lists and instructions for installing an intelligent disk controller (IDC) system. Before reading it, you should be familiar with Chapter 1.

2.2 DETAILED PARTS LISTS

Tables 2-1 through 2-20 in this section list the components and give a product-number to part number cross reference for the disk systems supported by the IDC. Corresponding to these tables are the 21 IDC disk systems:

DISK TABLE SYSTEM	DISK SYSTEM	DESCRIPTION
	2-1 1	Removable Media 67MB MSM Disk System, 60Hz
	2-2 2	Removable Media 67MB MSM Disk System, 50Hz
	2-3 3	Fixed Media 67MB MSM Disk System, 60Hz
	2-4 4	Fixed Media 67MB MSM Disk System, 50Hz
	2-5 5	Fixed Media 67MB MSM Disk System, 60Hz, with HPT*
	2-6 6	Fixed Media 67MB MSM Disk System, 50Hz, with HPT*
	2-7 7	Removable Media 256MB MSM Disk System, 60Hz
	2-8 8	Removable Media 256MB MSM Disk System, 50Hz
	2-9 9	27MB MCCDD System, 60Hz
	2-10 10	27MB MCCDD System, 50Hz
	2-11 11	54MB MCCDD System, 60Hz
	2-12 12	54MB MCCDD System, 50Hz
	2-13 13	81MB MCCDD System, 60Hz
	2-14 14	81MB MCCDD System, 50Hz
	2-15 15	Fixed Media 330MB Disk System, 60Hz
	2-16 16	Fixed Media 330MB Disk System, 50Hz
	2-17 17	CDD50 Disk System, 60Hz
	2-18 18	CDD50 Disk System, 50Hz
	2-19 19	Fixed Media 825MB MSM Disk System, 60Hz+
	2-20 20	Fixed Media 825MB MSM Disk System, 220V/50Hz+
	2-20 21	Fixed Media 825MB MSM Disk System, 240V/50Hz+

* HPT refers to the Head Per Track option available with the 67MB fixed media disk.

+ Applies only to systems with HSIDC

See Section 2.2.1 for additional cabling information.

TABLE 2-1 REMOVABLE MEDIA 67MB MSM DISK SYSTEM, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-102	Single Drive System, 60Hz, 115V	02-798F01
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual Package	29-585
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 9.14m (30ft)	17-295F01
1	67MB Disk Drive, 60Hz, and Cable	27-081F04
1	External A- and B-Cable, 9.14m (30ft)	17-685
1	Formatted Disk Pack	24-080F02
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-110	Expansion Drive, 60Hz	02-801F01
1	Vendor Maintenance Manual Package	29-585
1	Ground Strap, 4.57m (15ft)	17-295F03
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External B-Cable, 9.14m (30ft)	17-686
1	67MB Disk Drive, 60Hz, and Cable	27-081F04
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Pack	24-080F02
M60-116	67MB Formatted Disk Pack	24-080F02

TABLE 2-2 REMOVABLE MEDIA 67MB MSM DISK SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-103	Single Drive System, 50Hz, 220V	02-798F02
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual Package	29-585
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 9.14m (30ft)	17-295F01
1	67MB Disk Drive, 50Hz, and Cable	27-081F05
1	External A- and B-Cable, 9.14m (30ft)	17-686
1	Formatted Disk Pack	24-080F02
1	Disk-Drive Terminator	35-636
1	IDC Board	35-807
M60-111	Expansion Drive, 50Hz	02-801F02
1	Vendor Maintenance Manual Package	29-585
1	Ground Strap, 4.57m (15ft)	17-295F03
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External B-Cable, 9.14m (30ft)	17-686
1	67MB Disk Drive, 50Hz, and Cable	27-081F05
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Pack	24-080F02
M60-116	67MB Formatted Disk Pack	24-080F02

TABLE 2-3 FIXED MEDIA 67MB MSM DISK SYSTEM, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-104	MSM 80F, 60Hz, 115V	02-799F01
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual Package	29-729
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, 115V	27-115F05
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 4.57m (15ft)	17-521F01
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-112	MSM 80F Expansion, 60Hz, 115V	02-802F01
1	Vendor Maintenance Manual Package	29-729
1	Chassis Ground Strap, 1.83m (6ft)	17-295F04
1	6MB Fixed Media Disk Drive, 115V	27-115F05
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 2.44m (8ft)	17-521F02
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01

TABLE 2-4 FIXED MEDIA 67MB MSM DISK SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-105	MSM 80F, 50Hz, 220V	02-799F02
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual Package	29-729
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, 220V	27-115F06
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 4.57m (15ft)	17-521F01
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-113	MSM 80F Expansion, 50Hz, 220V	02-802F02
1	Vendor Maintenance Manual Package	29-729
1	Chassis Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, 220V	27-115F06
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 2.44m (8 ft)	17-521F02
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15 ft)	17-520F01

TABLE 2-5 FIXED MEDIA 67MB MSM DISK SYSTEM, 60Hz, WITH HPT

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-106	MSM 80F w/HPT Option, 60Hz, 115V	02-799F03
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual Package	29-729
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, with 1.6MB HPT, 115V	27-115F07
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 4.57m (15ft)	17-521F01
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-114	MSM 80F Expansion with HPT, 60Hz, 115V	02-802F03
1	Vendor Maintenance Manual Package	29-729
1	Chassis Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, with 1.6MB HPT, 115V	27-115F07
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 2.44m (8ft)	17-521F02
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01

TABLE 2-6 FIXED MEDIA 67MB MSM DISK SYSTEM, 50Hz, WITH HPT

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-107	MSM 80F w/HPT Option, 50Hz, 220V	02-799F04
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual Package	29-729
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, with 1.6MB HPT, 220V	27-115F08
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 4.57m (15ft)	17-521F01
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-115	MSM 80F Expansion with HPT, 50Hz, 220V	02-802F04
1	Vendor Maintenance Manual Package	29-729
1	Chassis Ground Strap, 1.83m (6ft)	17-295F04
1	67MB Fixed Media Disk Drive, with 1.6MB HPT, 220V	27-115F08
1	Heavy Duty Shielded MSM A-Cable, 60 pins, 2.44m (8ft)	17-521F02
1	Heavy Duty Shielded MSM B-Cable, 26 pins, 4.57m (15ft)	17-520F01

TABLE 2-7 REMOVABLE MEDIA 256MB MSM DISK SYSTEM, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-100	Single Drive System, 60Hz, 115V	02-797F01
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-586
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 9.14m (30ft)	17-295F01
1	256MB Disk Drive, 60Hz	27-082F04
1	External A- and B-Cable, 9.14m (30ft)	17-685
1	Formatted Disk Pack	24-079F02
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-108	Expansion Drive, 60Hz	02-800F01
1	Vendor Maintenance Manual	29-586
1	Ground Strap, 4.57m (15ft)	17-295F03
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External B-Cable, 9.14m (30ft)	17-686
1	256MB Disk Drive, 60Hz	27-082F04
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Pack	24-079F02
M60-117	256MB Formatted Disk Pack	24-079F02

TABLE 2-8 REMOVABLE MEDIA 256MB MSM DISK SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-101	Single Drive System, 50Hz, 220V	02-797F02
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-586
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 9.14m (30ft)	17-295F01
1	256MB Disk Drive, 50Hz	27-082F05
1	External A- and B-Cable, 9.14m (30ft)	17-685
1	Formatted Disk Pack	24-079F02
1	Disk Drive Terminator	35-636
1	IDC Board	35-807
M60-109	Expansion Drive, 50Hz	02-800F02
1	Vendor Maintenance Manual	29-586
1	Ground Strap, 4.57m (15ft)	17-295F03
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External B-Cable, 9.14m (30ft)	17-686
1	256MB Disk Drive, 50Hz, and Cable	27-082F05
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Pack	24-079F02
M60-117	256MB Formatted Disk Pack	24-079F02

TABLE 2-9 27MB MC-CDD SYSTEM, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M46-770	MCCDD 27, 60Hz, 115V	02-777F03
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-749
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.07m (42in)	17-295F05
1	27MB MCCDD, 60Hz, 115V	27-131F03
1	External A- and B-Cable, 4.57m (15ft)	17-685F01
1	Disk Drive Terminator	35-815
1	IDC Board	35-807
1	Mounting Kit	16-876
M46-732	Expansion Drive, MCCDD 27, 60Hz	02-761F01
1	Vendor Maintenance Manual	29-749
1	Ground Strap, 1.07m (42in)	17-295F05
1	Ground Strap, 1.83m (6ft)	17-295F04
1	External B-Cable, 4.57m (15ft)	17-686F01
1	27MB MCCDD, 60Hz, 115V	27-131F03
1	External A-Cable, 1.07m (42in)	17-411F03M01
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Cartridge, 13.5MB	24-104F02
1	Mounting Kit	16-876
M46-776	13.5MB Formatted Disk Cartridge	24-104F02

TABLE 2-10 27MB MCCDD SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M46-771	MCCDD 27, 50Hz, 220V	02-777F04
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-749
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.07m (42in)	17-295F05
1	27MB MCCDD, 50Hz, 220V	27-131F04
1	External A- and B-Cable, 4.57m (15ft)	17-685F01
1	Disk Drive Terminator	35-815
1	IDC Board	35-807
1	Mounting Kit	16-876
M46-733	Expansion Drive, MCCDD 27, 50Hz	02-761F02
1	Vendor Maintenance Manual	29-749
1	Ground Strap, 1.07m (42in)	17-295F05
1	Ground Strap, 1.83m (6ft)	17-295F04
1	External B-Cable, 4.57m (15ft)	17-686F01
1	27MB MCCDD, 50Hz, 220V	27-131F04
1	External A-Cable, 1.07m (42in)	17-411F03M01
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Cartridge, 13.5MB	24-104F02
1	Mounting Kit	16-876

TABLE 2-11 54MB MCCDD SYSTEM, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M46-772	MCCDD 54, 60Hz, 115V	02-778F03
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-749
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.07m (42in)	17-295F05
1	54MB MCCDD, 60Hz, 115V	27-130F03
1	Exterenal A- and B-Cable, 4.57m (15ft)	17-685F01
1	Disk-Drive Terminator	35-815
1	IDC Board	35-807
1	Mounting Kit	16-876
M46-734	Expansion Drive, MCCDD 54, 60Hz	02-762F01
1	Vendor Maintenance Manual	29-749
1	Ground Strap, 1.07m (42in)	17-295F05
1	Ground Strap, 1.83m (6ft)	17-295F04
1	External B-Cable, 4.57m (15ft)	17-686F01
1	54MB MCCDD, 60Hz, 115V	27-130F03
1	External A-Cable, 1.07m (42in)	17-411F03M01
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Cartridge, 13.5MB	24-104F02
1	Mounting Kit	16-876

TABLE 2-12 54MB MCCDD SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M46-773	MCCDD 54, 50Hz, 220V	02-778F04
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-749
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.07m (42in)	17-295F05
1	54MB MCCDD, 50Hz, 220V	27-130F04
1	External A- and B-Cable, 4.57m (15ft)	17-685F01
1	Disk Drive Terminator	35-815
1	IDC Board	35-807
1	Mounting Kit	16-876
M46-735	Expansion Drive, MCCDD 54, 50Hz	02-762F02
1	Vendor Maintenance Manual	29-749
1	Ground Strap, 1.07m (42in)	17-295F05
1	Ground Strap, 1.83m (6ft)	17-295F04
1	External B-Cable, 4.57m (15ft)	17-686F01
1	54MB MCCDD, 50Hz, 220V	27-130F04
1	External A-Cable, 1.07m (42in)	17-411F03M01
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Cartridge, 13.5MB	24-104F02
1	Mounting Kit	16-876

TABLE 2-13 81MB MCCDD SYSTEM, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M46-774	MCCDD 81, 60Hz, 115V	02-779F03
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-749
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.07m (42in)	17-295F05
1	81MB MCCDD, 60Hz, 115V	27-129F03
1	External A- and B-Cable, 4.57m (15ft)	17-685F01
1	Disk Drive Terminator	35-815
1	IDC Board	35-807
1	Mounting Kit	16-876
M46-736	Expansion Drive, MCCDD 81, 60Hz	02-763F01
1	Vendor Maintenance Manual	29-749
1	Ground Strap, 1.07m (42in)	17-295F05
1	Ground Strap, 1.83m (6ft)	17-295F04
1	External B-Cable, 4.57m (15ft)	17-686F01
1	81MB MCCDD, 60Hz, 115V	27-129F03
1	External A-Cable, 1.07m (42in)	17-411F03M01
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Cartridge, 13.5MB	24-104F02
1	Mounting Kit	16-876

TABLE 2-14 81MB MCCDD SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M46-775	MCCDD81, 50Hz, 220V	02-779F04
1	IDC Installation/Maintenance Manual	47-032
1	Vendor Maintenance Manual	29-749
1	IDC Programming Manual	50-007
1	Test Program	06-267
1	Format Program	06-268
1	Ground Strap, 1.07m (42in)	17-295F05
1	81MB MCCDD, 50Hz, 220V	27-129F04
1	External A- and B-Cable, 4.57m (15ft)	17-658F01
1	Disk-Drive Terminator	35-815
1	IDC Board	35-807
1	Mounting Kit	16-876
M46-737	Expansion Drive, MCCDD81, 50Hz	02-763F02
1	Vendor Maintenance Manual	29-749
1	Ground Strap, 1.07m (42in)	17-295F05
1	Ground Strap, 1.83m (6ft)	17-295F04
1	External B-Cable, 4.57m (15ft)	17-686F01
1	81MB MCCDD, 50Hz, 220V	27-129F04
1	External A-Cable, 1.07m (42in)	17-411F03M01
1	External A-Cable, 4.57m (15ft)	17-687
1	Formatted Disk Cartridge, 13.5MB	24-104F02
1	Mounting Kit	16-876

TABLE 2-15 FIXED MEDIA 330MB DISK SYSTEM 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-120	MSM300F Disk System 115V, 60Hz	02-830F01
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-932
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External A- and B-Cable, 4.57m (15ft)	17-685F01
1	330MB Disk Drive 115V, 60Hz	27-148F01
1	Intelligent Disk Controller	35-807
1	Disk Drive Terminator	35-852
1	Installation/Maintenance Manual	47-032
1	IDC Programming Manual	50-007
1	Vendor Maintenance Manual	51-041
M60-122	MSM300FE Disk Exp. 115V, 60Hz	02-831F01
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-932
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External A-Cable, 2.44m (8ft)	17-687F01
1	External B-Cable, 4.57m (15ft)	17-686F01
1	330MB Disk Drive 115V, 60Hz	27-148F01
1	Vendor Maintenance Manual	51-041

TABLE 2-16 FIXED MEDIA 330MB DISK SYSTEM, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-121	MSM300F Disk System 230V, 50Hz	02-830F02
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-932
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External A- and B-Cable, 4.57m (15ft)	17-658F01
1	330MB Disk Drive 230V, 50Hz	27-148F02
1	Intelligent Disk Controller	35-807
1	Disk Drive Terminator	35-852
1	Installation/Maintenance Manual	47-032
1	IDC Programming Manual	50-007
1	Vendor Maintenance Manual	51-041
M60-123	MSM300FE Disk Exp. 230V, 50Hz	02-831F02
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-932
1	Ground Strap, 9.14m (30ft)	17-295F01
1	External A-Cable, 2.44m (8ft)	17-687F01
1	External B-Cable, 4.57m (15ft)	17-686F01
1	330MB Disk Drive 230V, 50Hz	27-148F02
1	Vendor Maintenance Manual	51-041

TABLE 2-17 CDD50 DISK SYSTEM 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-140	CDD50 Disk System 115V, 60Hz	02-841F01
1	Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-942F01
1	Intelligent Disk Controller	02-734
1	Disk Drive 50MB (115V AC)	27-149F01
1	Cartridge Disk 25MB	24-109
1	Terminator Board	35-876
1	A/B Cable (shielded)	17-663
1	10" Ground Cable	17-584F01
1	24" Ground Cable	17-584F02
1	36" Ground Cable	17-585F02
1	Manual, Installation & Maintenance	47-032
1	Manual, Programming	50-007
1	Manual, Vendor Maintenance	51-054
M60-142	CDD50E Disk System 115V, 60Hz	02-842F01
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-942F02
1	Disk Drive 50MB (115V AC)	27-149F01
1	Cartridge Disk 25MB	24-109F01
1	"A" Cable	17-664
1	"B" Cable	17-665
1	10" Ground Cable	17-584F01
1	24" Ground Cable	17-584F02
1	36" Ground Cable	17-585F02
1	Manual, Vendor Maintenance	51-054

TABLE 2-18 CDD50 DISK SYSTEM 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-141	CDD50 Disk System 230V, 50Hz	02-841F02
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-942F01
1	Intelligent Disk Controller	02-734
1	Disk Drive 50MB (230V AC)	27-149F02
1	Cartridge Disk-25MB	24-109F01
1	Terminator Board	35-876
1	A/B Cable (shielded)	17-663
1	10" Ground Cable	17-584F01
1	24" Ground Cable	17-584F02
1	36" Ground Cable	17-585F02
1	Manual, Installation & Maintenance	47-032
1	Manual, Programming	50-007
1	Manual, Vendor Maintenance	51-054
M60-143	CDD50E Disk System 230V, 50Hz	02-842F02
1	IDC Disk Test Program	06-267
1	IDC Disk Format Program	06-268
1	Installation Kit	16-942F02
1	Disk Drive 50MB (230V AC)	27-149F02
1	Cartridge Disk-25MB	24-109F01
1	"A" Cable	17-664
1	"B" Cable	17-665
1	10" Ground Cable	17-584F01
1	24" Ground Cable	17-584F02
1	36" Ground Cable	17-585F02
1	Manual, Vendor Maintenance	51-054

TABLE 2-19 MSM825F DISK SYSTEM 120V, 60Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-180	MSM825F 60Hz, 120V	02-952 F01
1	IDC Installation/Maintenance Manual	47-032
1	Test Program	06-267*
1	IDC Formatter Program	06-311
1	IDC Programming Manual	50-007
1	Jumper 10G 30.0ft #10 Ring	17-295 F01
1	Cable Shielded "A & B" 15ft	17-685 F01
1	Disk 825MB Single Port DOM	27-178 F01
1	Terminator - I/O	35-852
1	IDC High Speed	35-932
1	Disk 825MB	51-143
1	825MB Disk Vendor's Manual	51-145
1	825MB Disk Vendor's Manual	51-146
1	Kit Inst 825MB Disk	66-117
M60-182	Expansion Drive, 60Hz	02-975 F01
1	Jumper 10G 30.0ft #10 Ring	17-295 F01
1	Cable Shielded "B" 15ft	17-686 F01
1	Cable Shielded "A" 8.3ft	17-687 F01
1	Disk 825MB Single Port DOM	27-178 F01
1	Disk 825MB	51-143
1	Kit inst 825MB Disk	66-117
1	825 MSM Expanded Module Dr. Vol 2	51-145
1	825 MSM Expanded Module Dr. Vol 3	51-146

* Revision R04 or higher supports the MSM825F.

TABLE 2-20 MSM825F DISK SYSTEM 240V, 50Hz

PRODUCT NO (QUANTITY)	DESCRIPTION	PART NUMBER
M60-181	MSM825F 50Hz, 240V	02-952 F02 (*)
1	IDC Installation/Maintenance Manual	47-032
1	Test Program	06-267 **
1	IDC Formatter Program	06-311
1	IDC Programming Manual	50-007
1	Jumper 10G 30.0ft #10 Ring	17-295 F01
1	Cable Shielded "A & B" 15ft	17-685 F01
1	Disk 825MB Single Port DOM	27-178 F01
1	Terminator I/O	35-852
1	IDC High Speed	35-932
1	Disk 825MB	51-143
1	825MB Disk Vendor's Manual	51-145
1	825MB Disk Vendor's Manual	51-146
1	Kit Inst 825MB Disk	66-117
M60-183	Expansion Drive, 50Hz	02-975 F02
1	Jumper 10G 30.0ft #10 Ring	17-295 F01
1	Cable Shielded "B" 15ft	17-686 F01
1	Cable Shielded "A" 8.3ft	17-687 F01
1	Disk 825MB Single Int 240V	27-178 F02 (+)
1	Disk 825MB	51-143
1	Kit inst 825MB Disk	66-117
1	825 MSM Expanded Module Dr. Vol 2	51-145
1	825 MSM Expanded Module Dr. Vol 3	51-146

* Functional variation F03 is a 220V, 50Hz version

** Revision R04 or higher supports the MSM825F.

+ Functional variation F03 uses a single port international 220V (27-178 F03)

2.2.1 Additional Cabling Information

Table 2-21 is a summary of all the cables and straps associated with the IDC disk systems. As listed in the table, those cables and straps having a functional variation with the part number are applicable to your particular system. For example, instead of installing the 15ft A-cable numbered 17-521F01, you can select the 8ft A-cable numbered 17-521F02.

TABLE 2-21 STANDARD CABLING SUPPLIED WITH IDC DISK SYSTEMS

PART NO.	CABLE/STRAP	DESCRIPTION
17-685	External A-Cable and B-Cable	Shielded, 9.14m (30ft), for first drive of all removable media systems.
17-685F01	External A-Cable and B-Cable	Shielded, 4.57m (15ft), for first drive of all MCCDD systems.
17-686	External B-Cable	Shielded, 9.14m (30ft), for second, third, and fourth drives of all removable media disk systems.
17-686F01	External B-Cable	Shielded, 4.57m (15ft), for second, third, and fourth drives of all MCCDD systems.
17-687	External A-Cable	Shielded, 4.57m (15ft), for second, third and fourth drives of all removable media disk systems.
17-520F01	External B-Cable	Heavy duty, shielded, 4.57m (15ft), for all drives of fixed media 67MB systems.
17-521F01	External A-Cable	Heavy duty, shielded, 4.57m (15ft), for first drive of fixed media 67MB systems.
17-521F02	External A-Cable	Heavy duty, shielded, 2.44m (8ft), for second, third and fourth drives of fixed media 67MB systems.
17-411F03 M01	External A-Cable	Heavy duty, shielded, 1.07m (42in), for second, third and fourth drives of MCCDD systems.
17-663	External A-Cable and B-Cable	Shielded, 1.52m (5ft), for first drive of CDD50 systems.
17-664	External A-Cable	Shielded, 1.07m (3.5ft), for all drives of CDD50 systems.
17-665	External B-Cable	Shielded, 1.52m (5ft), for all drives of CDD50 systems.
17-295F01	Ground Strap	9.14m (30ft)
17-295F03	Ground Strap	4.57m (15ft)
17-295F04	Ground Strap	1.83m (6ft)
17-295F05	Ground Strap	1.07m (42in)

2.3 UNPACKING INSTRUCTIONS

For instructions on how to unpack your particular IDC disk system, see the supplied vendor manuals. These manuals are listed in Table 1-1 and in the tables of Section 2.2.

2.4 INSTALLING AN INTELLIGENT DISK CONTROLLER (IDC) DISK SYSTEM

Figure 2-1 is a general illustration of how to install a normal IDC disk system. A normal IDC disk system is one which has the IDC board plugged into the processor cabinet and employs the normal selector channel (SELCH) protocol. IDC (35-807) revision level 10 and above must have its backpanel pin 224-1 wired to its SELCH backpanel pin 224-1. If the IDC board for your system is installed with an input/output (I/O) bus switch, and consequently employs the "new" high-speed SELCH protocol, then your system is not normal. Its installation requires the additional information presented in the M48-018 I/O Bus Switch Manual and Control Panel Installation Manual.

Along with the applicable vendor manuals listed in Table 1-1 and the relevant tables in Section 2.2, Figure 2-1 should enable you to install your particular IDC disk system. However, before plugging in your IDC board and connecting the cables as shown in the figure, you must set two address switches; see Section 2.4.1. For optional IDC board strapping, see Section 2.4.2.

See Section 2.5 if one or more of your disk drives are to be equipped with a dual-port option.

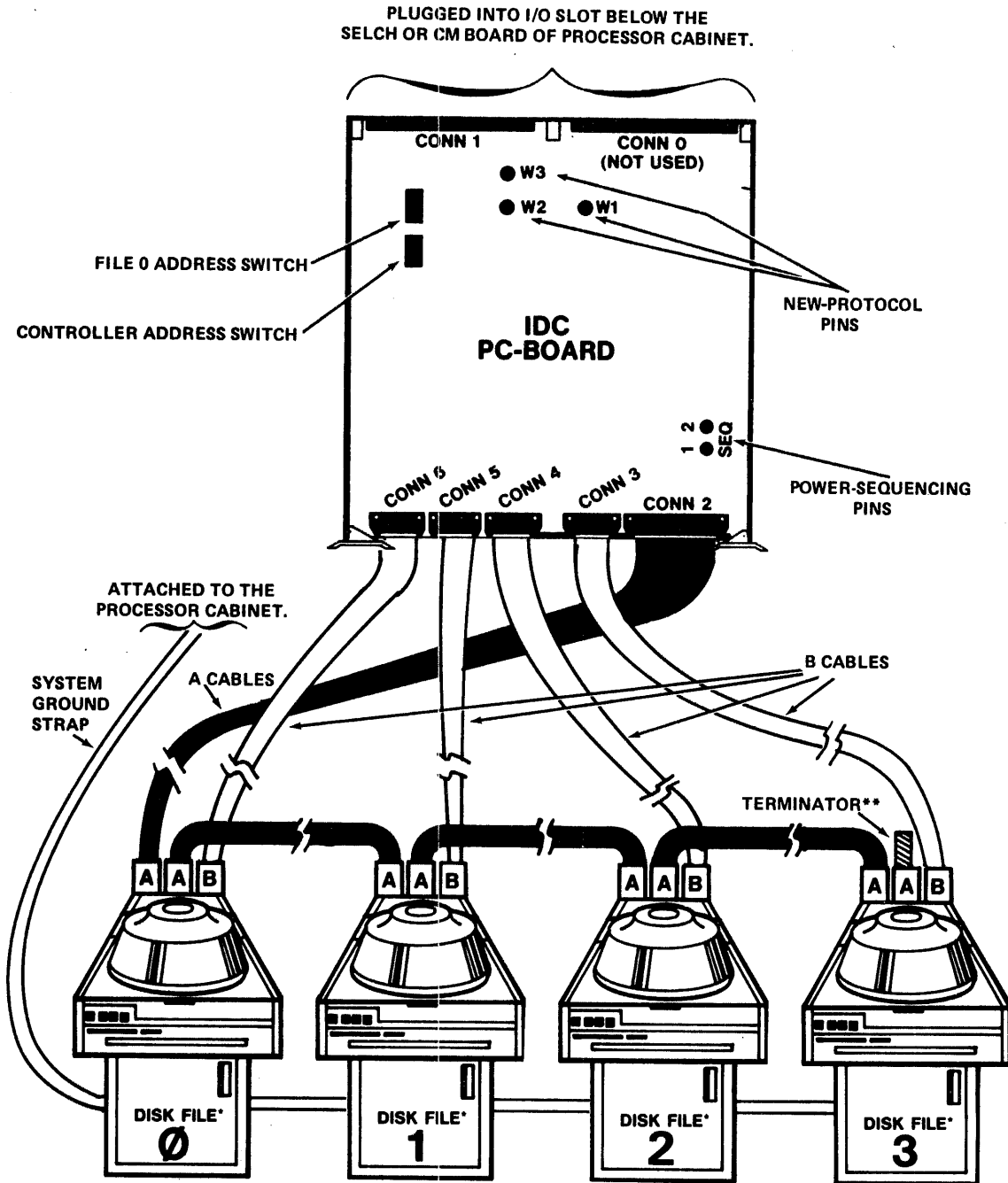
2.4.1 Setting the Address Switches on the Intelligent Disk Control (IDC) Board

As seen from Figures 1-2 and 2-1, the IDC board has two address switches in its upper-left corner:

1. Controller address switch (or device address switch)
2. File 0 address switch

Figures 2-2 and 2-3 present a close up view of these switches. As shown in Figure 2-2, the controller address switch has eight toggles, numbered 1 through 8, each with two possible settings: 0 or 1. Each toggle setting represents a bit in a 1-byte controller address, with toggle 1 being the most significant bit (MSB) and toggle 8 being the least significant bit (LSB). You must set the toggles to the address wanted for your IDC.

As shown in Figure 2-3, the file 0 address switch also has eight toggles, numbered 1 through 8, each with two possible settings: 0 or 1. Toggles 1 through 6 represent six bits in a 1-byte address for your disk file 0, with toggle 1 being the MSB. The other two bits of the 1-byte address are always considered as zero. Toggles 7 and 8, which will be discussed shortly, are for selecting the new high-speed SELCH protocol and for enabling or disabling IDC formatting capability. They are not used for addressing.



* Connector numbers depend on the disk files configured.

** Last disk drive must have a terminator, as shown with the A-cable plug.

Figure 2-1 Installation of an IDC Disk System

032-4

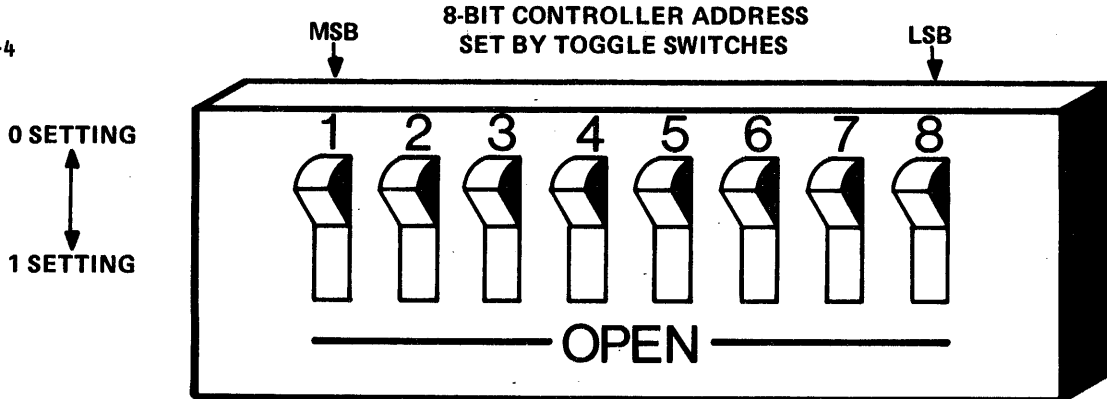


Figure 2-2 Controller Address Switch

032-5

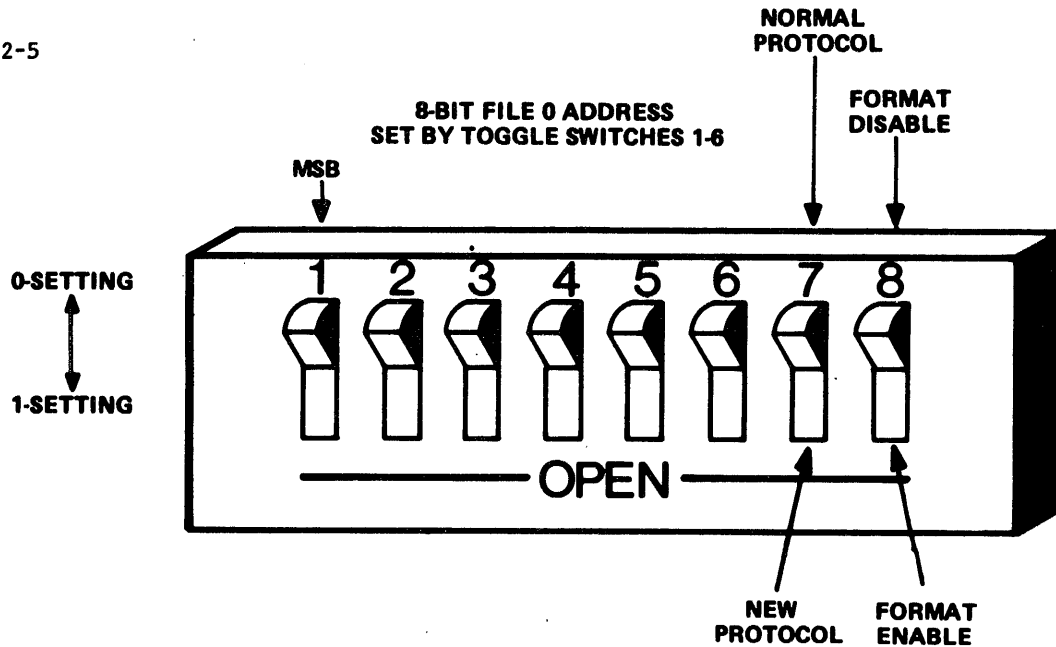


Figure 2-3 File 0 Address Switch

As an example for setting addresses on these switches, suppose you have an IDC system consisting of one IDC board and four disk files. You want the controller address to be X'FB' and the four disk file addresses to be X'FC' through X'FF'. Before installing the IDC board, you would set the controller address switch to the binary value of '11111011' (for X'FB') and the file 0 address switch to '11111100' (for X'FC'). Disk files 1 through 3 are automatically addressed at X'FD', X'FE' and X'FF', respectively.

Now, with the desired addresses set on the two switches, you have the option of setting toggle 7 and/or toggle 8 in the file 0 address switch. If you want to employ the normal SELCH protocol, you push toggle 7 up to the 0 setting. But if your IDC is plugged into the 25ft cable of an I/O Bus Switch, you must push toggle 7 down to the 1 setting, thereby employing the new high-speed SELCH protocol. For additional information on the I/O bus switch, see the M48-018 I/O Bus Switch Manual and Control Panel Installation Manual. (Also, as discussed in Section 2.4.2, the new protocol pins W1 and W3 should be strapped when toggle 7 is at the 1 setting.) In summary, place toggle 7 in the 0 setting when your IDC board is plugged into the processor cabinet; place toggle 7 in the 1 position when your IDC board is plugged into the I/O bus switch.

Toggle 8 of the file 0 address switch is usually left in the 1 setting to enable IDC formatting. That is, if you want the capability of formatting an unformatted disk according to IDC format, leave toggle 8 down. The IDC Programming Manual describes the IDC disk media format in detail. If, for some reason, you want to disable the IDC formatting capability, push toggle 8 up to the 0 position.

2.4.2 Intelligent Disk Controller (IDC) Strapping Information

As shown in Figures 2-1 and 1-2, the IDC board has two sets of pins:

1. Power sequencing (SEQ) pins 1 and 2
2. New protocol pins W1 through W3

Power sequencing refers to the serial application of power to the disk files once the processor is turned on, where: after disk file 0 is powered and comes up to speed, disk file 1 is powered up; after disk file 1 comes up to speed, disk file 2 is powered up; and so forth. When you want your disk files to power up sequentially, do not place a jumper wire across the power sequencing (SEQ) pins 1 and 2. Also ensure that the local/remote switch on each attached disk file is in the remote position. Subsequently, when the processor is turned off, the disk files power down simultaneously. When pins 1 and 2 are strapped, or when the local/remote switch on each attached disk file is in the local position, the disk files can be simultaneously powered up, in parallel, as opposed to serial. Occasionally, simultaneous application of power to the disk files causes an excessive power surge. To determine the advisability of power sequencing to prevent this, see the AC power requirements presented in Section 2.6. The 50MB cartridge disk drive (CDD50), when configured with the IDC, does not use power sequencing, even though it will be passed along to any subsequent drives if enabled on the IDC.

The new protocol pins W1, W2 and W3 apply to the use of the new high-speed SELCH protocol for special applications. The HSIDC board must be strapped for high-speed SELCH protocol with the MSM825F disk drive. When your IDC is installed under an I/O bus switch, and when toggle 7 of the file 0 address switch is down in the 1 setting, you must strap pins W1 and W3. Also, although not recommended, pins W1 and W2 can alternately be strapped for employing the high-speed protocol without the use of an I/O bus switch. This is required when configuring the IDC in a processor which uses the 35-864 CPU board. The MSM825F requires a Series 3200 SELCH. When the IDC board is strapped for high-speed SELCH protocol, backpanel pins 124-1, 224-1 and 225-1 must be wired between the slots containing the IDC and the SELCH.

NOTE

Regardless of the IDC strapping, normal protocol or high-speed, the SELCH used must be strapped for high-speed protocol (see the appropriate SELCH reference manual) and backpanel pin 224-1 of the SELCH slot must be strapped to pin 224-1 of the IDC slot.

2.5 INSTALLING DUAL-PORT OPTIONS

Only the 67MB and 256MB removable media disk systems can be equipped for dual-port operation. Hardware for the dual-port option consists of four items:

1. IDC board
2. Dual-port kit
3. A-cable and B-cable
4. Disk-drive terminator

Sections 2.5.1 through 2.5.4 discuss the installation of these items.

2.5.1 Intelligent Disk Controller (IDC) Board

The additional IDC board supplied with the dual-port option can be plugged into the same processor cabinet with the other controller, or it can be plugged into another processor cabinet. To install the controller in the same cabinet, plug it into the first available backpanel I/O slot below the other controller after removing the RACK0/TACK0 wire from that backpanel. To install the controller into another cabinet, plug it into the first available I/O slot immediately below the SELCH or channel manager (CM) board.

2.5.2 Dual-Port Kit

The dual-port kit consists of these components: driver/receiver printed circuit (PC) boards add-on connectors for the disk file and a dual-port steering card.

After installing the two PC boards and the add-on connectors to the disk drive according to supplied instructions, install the dual-port steering card. First, set three switches on this card according to the operational requirements. Figure 2-4 and Table 2-22 describe and illustrate these switches and associated indicator lights.

2.5.3 A-Cable and B-Cable

A- and B-cable connections depend on whether you are installing just one dual-port option or more than one. Cable connections for a single dual-port disk file are similar to those shown for disk file 0 in Figure 2-1, with one exception: instead of plugging the cables into the plugs labeled A and B in the figure, plug them into the corresponding A and B add-on connectors. On a second, third or fourth dual-ported drive, the A-cable connects to a previously dual-ported drive. With the exception just mentioned, Figure 2-1 also illustrates cable connections for a completely dual-ported IDC disk system.

032-6

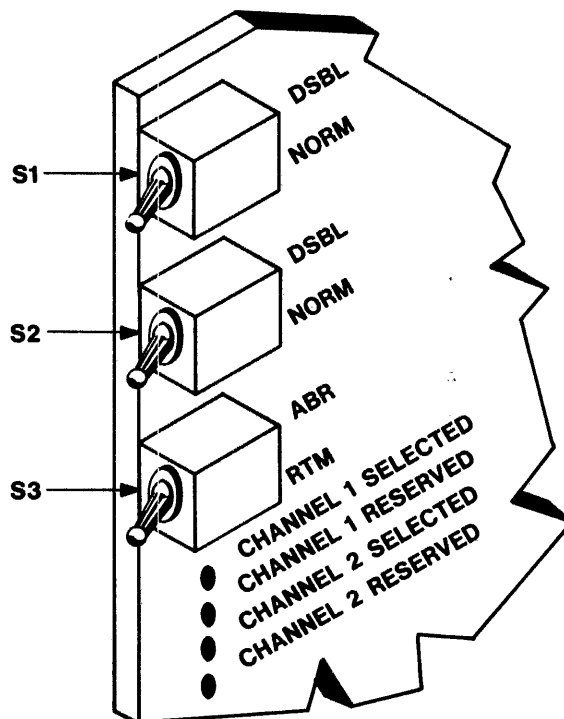


Figure 2-4 Switches and Indicators on Dual-Port Steering Card

TABLE 2-22 SWITCHES AND INDICATORS ON DUAL-PORT STEERING CARD

SWITCHES/INDICATORS	FUNCTION
S1, Maintenance Unit-Disable Switch for Channel 1	<p>This switch has two positions: normal (NORM) and disable (DSBL). It lets you disable channel 1 in the disk drive; i.e., it allows you to disable all transmissions from the disk drive to the controller connected to channel 1.</p> <p>For dual-port operation, S1 should be set to the NORM position, along with S2. During maintenance, S1 should be set to the DSBL position, along with S2.</p>
S2, Maintenance Unit-Disable Switch for Channel 2	<p>This switch has two positions NORM and DSBL. It lets you disable channel 2 in the disk drive; i.e., it allows you to disable all transmissions from the disk drive to the controller connected to channel 2.</p> <p>For dual-port operation, S2 should be set to the NORM position, along with S1. During maintenance, S2 should be set to the DSBL position, along with S1.</p>
S3, Release Timer Select Switch	<p>This switch has two positions: reserve timer (RTM) and absolute reserve (ABR). If you set S3 to RTM, the controller at either channel has about 5 seconds to use the disk file after selecting it. If the controller does not use the file within 5 seconds, it becomes available to the controller at the other channel. If you set the switch to ABR, the controller at either channel has exclusive, uninterruptible use of a disk file; i.e., the controller continues uninterrupted use of that disk file until it issues a release command.</p>
Channel 1 Selected Indicator	<p>Lights to indicate that the channel 1 controller has selected the drive in RTM mode.</p>
Channel 1 Reserved Indicator	<p>Lights to indicate that the channel 1 controller has reserved the drive in ABR mode.</p>
Channel 2 Selected Indicator	<p>Lights to indicate that the channel 2 controller has selected the drive in RTM mode.</p>
Channel 2 Reserved Indicator	<p>Lights to indicate that the channel 2 controller has reserved the drive in ABR mode.</p>

2.5.4 Disk-Drive Terminator

As with single-port disk drives, the last dual-port disk drive attached to the IDC board must have a terminator plugged into the add-on connector of its A-cable plug.

2.6 AC POWER REQUIREMENTS

Table 2-23 lists power requirements for the disk drives supported by IDC.

TABLE 2-23 AC VOLTAGE AND CURRENT REQUIREMENTS FOR DISK FILES*

DISK DRIVES (PART NOS)	INPUT VOLTS	CURRENT REQUIREMENTS	
		STARTING CURRENT	RUNNING CURRENT
27-081F04	115V 60Hz	30A for 15 seconds	8.9A maximum
27-081F05	220V 50Hz	23A for 15 seconds	4.6A maximum
27-115F05	115V 60Hz	23A for 7 seconds	4.7A maximum
27-115F06	220V 50Hz	14A for 7 seconds	2.7A maximum
27-115F07	115V 60Hz	23A for 7 seconds	4.7A maximum
27-115F08	220V 50Hz	14A for 7 seconds	2.7A maximum
27-082F04	115V 60Hz	38A for 10 seconds	8.6A maximum
27-082F05	220V 50Hz	41A for 7 seconds	9.2A maximum
27-131F03	115V 60Hz	23A for 7 seconds	5.0A maximum
27-131F04	220V 50Hz	13A for 7 seconds	2.7A maximum
27-130F03	115V 60Hz	23A for 7 seconds	5.0A maximum
27-130F04	220V 50Hz	13A for 7 seconds	2.7A maximum
27-129F03	115V 60Hz	23A for 7 seconds	5.0A maximum
27-129F04	220V 50Hz	13A for 7 seconds	2.7A maximum
27-148F01	115V 60Hz	20A for 10 seconds	5.0A maximum
27-148F02	230V 50Hz	12A for 10 seconds	3.0A maximum
27-149F01	115V 60Hz	2.1A for 20 seconds	1.2A maximum
27-149F02	230V 50Hz	1.0A for 20 seconds	0.8A maximum
27-178F01+	115V 60Hz	28A for 8 seconds	4.2A maximum
27-178F02+	220V 50Hz	16.5A for 8 seconds	2.1A maximum
27-178F03+	240V 50Hz	15.0A for 8 seconds	2.2A maximum

* See Tables 2-1 through 2-20 in Section 2.2 for more information on these disk files supported by IDC.

+ Applies only to systems with HSIDC

2.7 APPLICATION OF AC POWER

Depending on how you strap the SEQ pins 1 and 2 on the IDC board, you can apply power to the disk drives either simultaneously (in parallel) or sequentially (in serial). Section 2.7.1 describes simultaneous application of power, where the SEQ pins are strapped or the local/remote switch of each disk file is in the local position. Section 2.7.2 describes sequential application of power, also referred to as power sequencing, where the SEQ pins are not strapped and the local/remote switch of each disk file is in the remote position.

2.7.1 Simultaneous Application of Power

To apply power simultaneously to the disk files attached to your controller(s), follow this procedure:

1. Ensure correctness of all AC power-input connections.
2. At the front of each disk file, depress the START/STOP switch so it is unlit, i.e.; so it is in the STOP position. (This step applies only to the removable-media disk systems.)
3. At the rear of each disk file, set the AC input power switch to the OFF position.
4. Apply primary AC power.
5. At disk file 0, the first drive in the IDC system, set the AC input power switch to the ON position. (At this time, a fixed media disk would start up.)
6. Depress the START/STOP switch so it is lit, i.e.; so it is in the START position. This disk file should now start up; the disk media rotation should come up to speed. If the disk file does not start up, make these additional checks:
 - a. Ensure that the remote/local switch in the disk drive is set to the local position.
 - b. Check AC input power.
 - c. Check fuses in the disk drive.
7. Repeat Steps 5 and 6 for remaining disk files. Consequently, the IDC disk files simultaneously come up to speed.

2.7.2 Power Sequencing

To apply power serially to the disk files attached to your controller(s), follow this procedure:

1. Ensure correctness of all AC power input connections.
2. In each disk drive, set the remote/local switch to the remote position.
3. Apply primary AC power.
4. At the rear of each disk file, ensure that the AC input power switch is in the ON position.
5. At the front of each disk file, depress the START/STOP switch to the START position. (This step applies only to removable media disk files.)
6. Power up the processor in which the controller is connected. The disk files now start up sequentially, starting with disk file 0.

2.8 INTELLIGENT DISK CONTROLLER (IDC) TESTING AND FORMATTING

Once your IDC system is installed and powered up, you can run the IDC Test Program to check for proper operation of your system. Follow this procedure:

1. Ensure you have an IDC formatted media on your disk drive. If you do not, your disk must be formatted by loading and running the IDC Format Program. This program and appropriate instructions are supplied with your IDC disk system.
2. Load and run the IDC Test Program. This program and appropriate instructions are supplied with your IDC disk system.

C A U T I O N

OPTIMUM PERFORMANCE OF AN IDC DISK SYSTEM REQUIRES PROPERLY CERTIFIED DISK MEDIA. TO MINIMIZE THE EFFECTS OF LATENT DEFECTS, REMOVABLE DISK MEDIA HAVE BEEN CAREFULLY SCREENED AND CERTIFIED ON A CALIBRATED DISK DRIVE. THIS CERTIFICATION ASSURES TRANSPORTABILITY OF DISK MEDIA AND MINIMIZES THE OCCURRENCE OF DATA ERRORS.

THE 67MB MSM, 256MB MSM AND MEDIUM CAPACITY CARTRIDGE DISK DRIVE (MCCDD) DISK MEDIA (AVAILABLE ONLY FROM PERKIN-ELMER) ARE RECOMMENDED FOR THE HIGH-PERFORMANCE IDC DISK SYSTEMS.

COMPATIBLE DISK MEDIA MAY BE OBTAINED FROM A VENDOR AND CERTIFIED WITH THE IDC FORMAT PROGRAM, WITH ITS PARAMETERS SET UP EXACTLY AS SPECIFIED WITH THE SUPPLIED INSTRUCTIONS. HOWEVER, THE USER IS CAUTIONED THAT THESE MEDIA MAY RESULT IN REDUCED SYSTEM PERFORMANCE. SPECIFICALLY, DATA MAY NOT BE RECOVERABLE FROM THE MEDIA WHEN IT IS TRANSPORTED BETWEEN DRIVES. SUCH IRRECOVERABLE DATA COULD ALSO RESULT IN AN OPERATING SYSTEM CRASH. IN COMPARISON, A DISK DRIVE, DURING CERTIFICATION, CAN FLAG CERTAIN MEDIA DEFECTS THAT WOULD CAUSE A CRASH.

CHAPTER 3 THEORY OF OPERATION

3.1 BLACKBOX OVERVIEW OF INTELLIGENT DISK CONTROLLER (IDC) BOARD

By understanding the flow of external input/output (I/O) signals associated with the IDC board, you will gain a general idea of what the IDC does. With this objective in mind, this section treats the IDC as a blackbox circuit and presents an overview of all the I/O lines to and from the IDC connectors. Later sections discuss the internal operation of the IDC.

Figure 2-1 illustrates the physical connections of an IDC board. Figure 3-1 illustrates the I/O lines associated with the physical connectors, connector 1 (CONN1) through CONN6, of the IDC board. The following sections briefly describe these I/O lines. Section 3.1.1 describes the lines from IDC CONN1 to the selector channel (SELCH) or channel manger (CM) board plugged into the processor. Section 3.1.2 describes the A-cable lines between IDC connector CONN2 and the attached disk files. Section 3.1.3 describes the B-cable lines between IDC connectors CONN3 through CONN6 and the attached disk files.

NOTE

References in this chapter to the SELCH also apply to the CM.

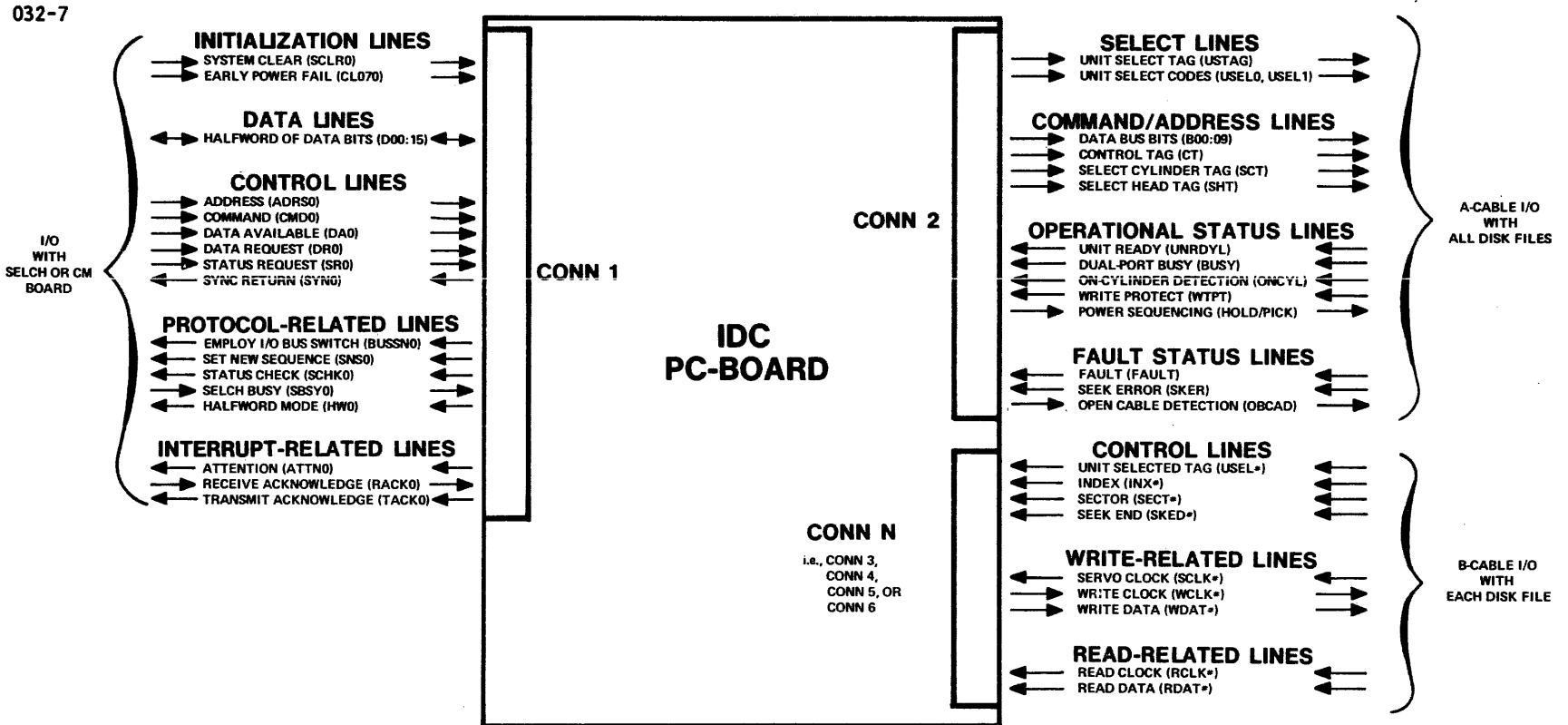


Figure 3-1 Blackbox Diagram of IDC Logic

3.1.1 Input/output (I/O) Lines at Connector 1 (CONN1)

The I/O lines at CONN1 are connected with the SELCH or CM board plugged into the same processor chassis with the IDC or installed under an I/O bus switch (see Figure 3-1). These lines are classified here into five functional groups:

1. Initialization lines
2. Data lines
3. Control lines
4. Protocol-related lines
5. Interrupt-related lines

The following Items, 1 through 5, describe the I/O lines within these groups.

1. Initialization Lines

This group of lines initializes the IDC logic:

a. System Clear (SCLR0)

Input from the processor to initialize IDC logic during a system power up, shutdown or initialization operation.

b. Early Power Fail (EPF) (CL070)

Input from the processor to warn the IDC of an imminent power failure.

2. Data Lines

This group of 16 I/O lines transfers data between the SELCH and the IDC board:

a. Halfword Data Bits (D00:15)

SELCH or processor I/O consisting of a halfword or a byte of data. With halfword I/O, data bits D00:15 transfer the data for a read/write operation or the address for a disk cylinder or head. With byte I/O, D08:15 transfer an IDC or disk file address, a processor command, an IDC or disk file status, a sector address or rotational position sensing (RPS) data.

3. Control Lines

This group consists of these I/O lines:

a. Address (ADRS0)

Input from the processor to inform the IDC that data bits D08:15 contain an IDC address or a disk file address. The addressed device is to be selected for subsequent I/O operation.

b. Command (CMD0)

Input from the processor to inform the IDC that data bits D08:15 contain a command for the selected device, i.e.; the IDC or disk file.

c. Data Available (DA0)

Input from the SELCH or processor to inform the IDC that a halfword of data is available on D00:15 for a write operation to IDC.

d. Data Request (DR0)

Input from the SELCH or processor that requests IDC for a halfword of data on D00:15 for a read operation from IDC.

e. Status Request (SR0)

Input from the SELCH or the processor to request an IDC status or disk file status byte from data bits D08:15.

f. Sync Return (SYN0)

IDC output signaling the SELCH or processor that the IDC has properly accepted and responded to a received control line signal.

4. Protocol-Related Lines

This group of lines relates to the protocol exchanges between the SELCH and the IDC board:

a. Employ I/O Bus Switch (BUSSW0)

IDC output informing the SELCH that the IDC employs the new high-speed SELCH protocol with an I/O bus switch.

b. Set New Sequence (SNS0)

IDC output informing the SELCH that the IDC uses new high-speed SELCH protocol without an I/O bus switch.

c. Status Check (SCHK0)

IDC output informing the SELCH of a bad IDC status. This output applies only when the IDC uses the high-speed SELCH protocol.

d. SELCH Busy (SBSY0)

Input from the SELCH to inform IDC that the SELCH is currently busy with a blockdata transfer.

e. Halfword Mode (HW0)

IDC output informing the SELCH that this controller (IDC) is a halfword-oriented device.

5. Interrupt-Related Lines

This group of lines relates to an interrupt request from the IDC board:

a. Attention (ATN0)

IDC output requesting a processor interrupt, placing the IDC into an interrupt pending state.

b. Receive Acknowledge (RACK0)

Input from the processor to acknowledge an interrupt from an IDC; (see Item a). If the IDC has no interrupt pending, it passes the RACK0 signal out as a TACK0 signal to the next IDC board stacked in the processor.

c. Transmit Acknowledge (TACK0)

IDC output consisting of a RACK0 signal received by an IDC having no interrupt pending.

3.1.2 Input/output (I/O) Lines at Connector 2 (CONN2)

The I/O lines at CONN2 are through the A-cable to the attached disk files (see Figure 3-1). These lines are classified here into four functional groups:

1. Select lines

2. Command/address lines
3. Operational status lines
4. Fault status lines

The following Items, numbered 1 through 4, describe the I/O lines within these groups.

1. Select Lines

This group of lines is involved with the selection of a disk file:

- a. Unit Select Tag (USTAG)

IDC output informing the attached disk files that the two unit select lines (USEL0 and USEL1, described below) are supplying a binary-coded number, 0-3, to select a disk file.

- b. Unit Select Lines (USEL0, USEL1)

IDC output consisting of a binary-coded number, 0 through 3, to select a particular disk file for I/O with the IDC.

2. Command/Address Lines

This group of lines supplies command and address data as control input to a selected disk file:

- a. Data Bus Bits (B00:09)

IDC output consisting of control or address data, e.g.; a driver command, a cylinder address or a head address. The contents of these lines depends on the three tags discussed in Items b, c and d below.

- b. Control Tag (CT)

IDC output indicating that B00:09 are supplying a driver command.

- c. Select-Cylinder Tag (SCT)

IDC output indicating that B00:09 are supplying a cylinder address.

d. Select-Head Tag (SHT)

IDC output indicating that B00:09 are supplying head-select or volume-select data.

3. Operational Status Lines

This group of lines supplies various operational status of a disk file:

a. Unit Ready (UNRDYL)

Disk file output signaling IDC that the selected disk file is ready for I/O with the IDC.

b. Dual-Port Busy (BUSY)

Disk file output applicable only to dual-port operation of a disk file. It informs IDC that the disk file is currently selected by another IDC.

c. On-Cylinder Detection (ONCYL)

Disk file output that signals the IDC once the heads of the selected disk file are positioned over an addressed cylinder.

d. Write Protect (WTPT)

Disk file output informing IDC that the write protect button on the disk file is depressed, i.e.; that the disk file is in the write protect mode.

e. Power Sequencing (HOLD/PICK)

IDC output of a ground signal that picks and holds power sequencing for the attached disk files in the remote mode. (This signal is present when the processor is on and IDC SEQ pins 1 and 2 are not strapped.)

4. Fault Status Lines

This group of lines supplies various fault status of a disk file.

a. Fault (FAULT)

Disk file output informing IDC of a fault condition at a disk file.

b. Seek Error (SKER)

Disk file output informing IDC of a seek error at a disk file.

c. Open Cable Detection (OBCAD)

Disk file output informing IDC of an open cable or a loss of power. This signal prevents IDC from outputting select or control data to the disk file.

3.1.3 Input/Output (I/O) Lines at Connector 3 (CONN3)
Through Connector 6 (CONN6)

The I/O lines on any one of these connectors CONN3, CONN4, CONN5 or CONN6 are through a B-cable to a disk file (see Figure 3-1). These lines are classified here into three functional groups:

1. Control lines
2. Write-related lines
3. Read-related lines

The following Items, numbered 1 through 3, describe the I/O lines within these groups.

1. Control Lines

This group of lines passes various control signals to IDC in order to coordinate the transfer of read/write data. The pound (#) symbol with each mnemonic denotes one of four numbers, 0-3, for one of the four possible disk files.

a. Unit Selected Tag (USEL#)

Disk file output signaling IDC that the disk file is now acquired, i.e.; selected, by the IDC.

b. Index (INX#)

Disk file output consisting of a pulse for every disk revolution. This pulse serves as an index for disk sector 0.

c. Sector (SECT#)

Disk file output consisting of a pulse to mark the beginning of each physical sector of an IDC-formatted disk. (See the IDC Programming Manual for a description of a physical sector.)

d. Seek End (SKED#)

Disk file output signaling the end of a seek operation, either successful or unsuccessful.

2. Write-Related Lines

This group of lines relates to write operations from the IDC to a disk file.

a. Servo Clock (SCLK#)

Disk file output used by the IDC as input for the WCLK# signal; see Item b below.

b. Write Clock (WCLK#)

IDC output that synchronizes data written to the disk file.

c. Write Data (WDAT#)

IDC output consisting of data written to the disk file.

3. Read-Related Lines

This group of lines relates to read operations from the disk file to the IDC:

a. Read Clock (RCLK#)

Disk file output that synchronizes data read from the disk file.

b. Read Data (RDAT#)

Disk file output consisting of data read from the disk file.

3.2 INPUT/OUTPUT (I/O) LINES OF THE INTELLIGENT DISK CONTROLLER (IDC) BOARD

This section presents detailed descriptions of the same external I/O lines discussed in Section 3.1. Figure 3-2 shows the connectors of the IDC board and serves as a reference to other figures that illustrate the I/O lines attached to the connector pins. Sections 3.2.1 through 3.2.3 describe these I/O lines.

NOTE

References in these descriptions to the SELCH also apply to the CM.

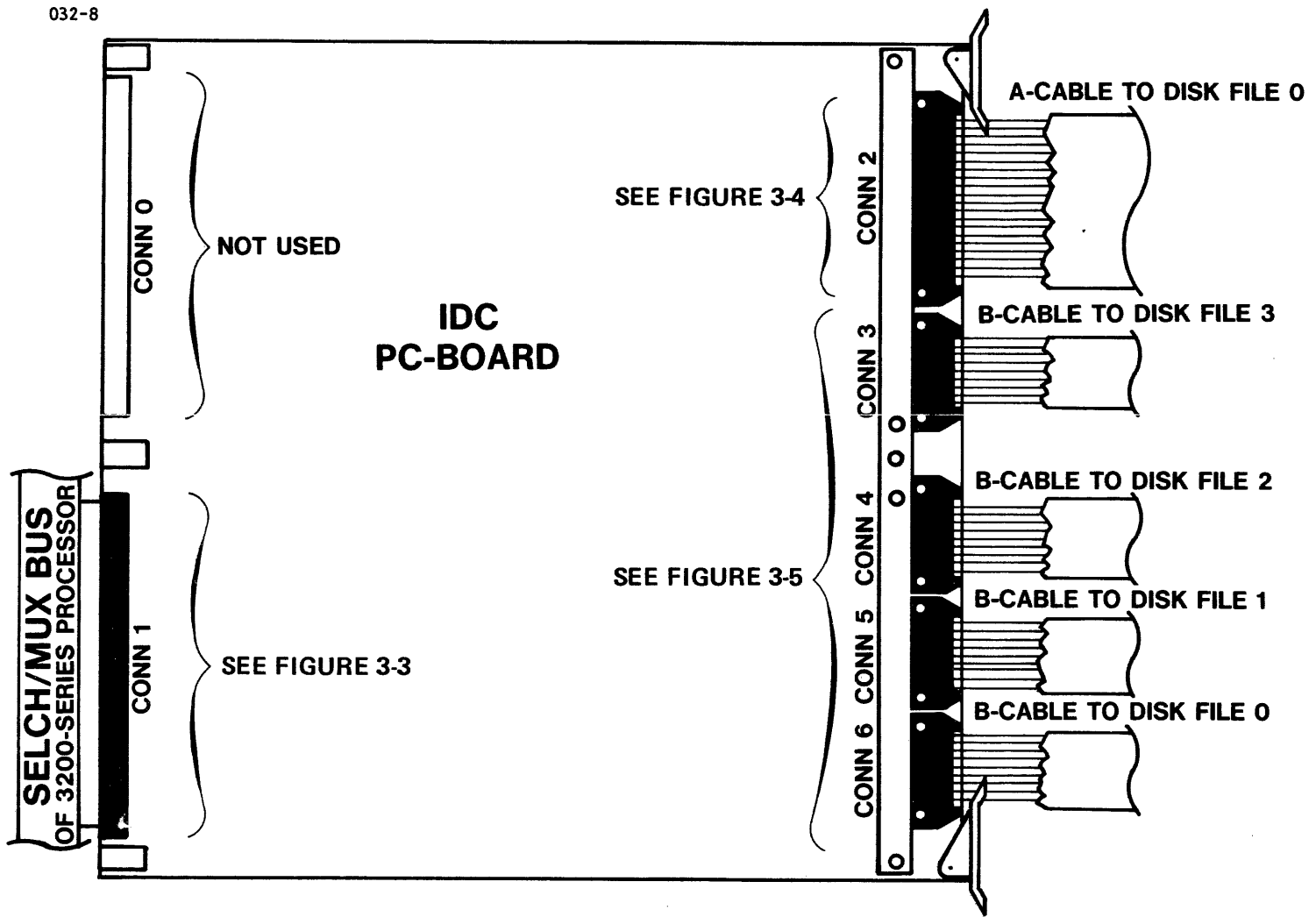


Figure 3-2 Connectors on IDC Board

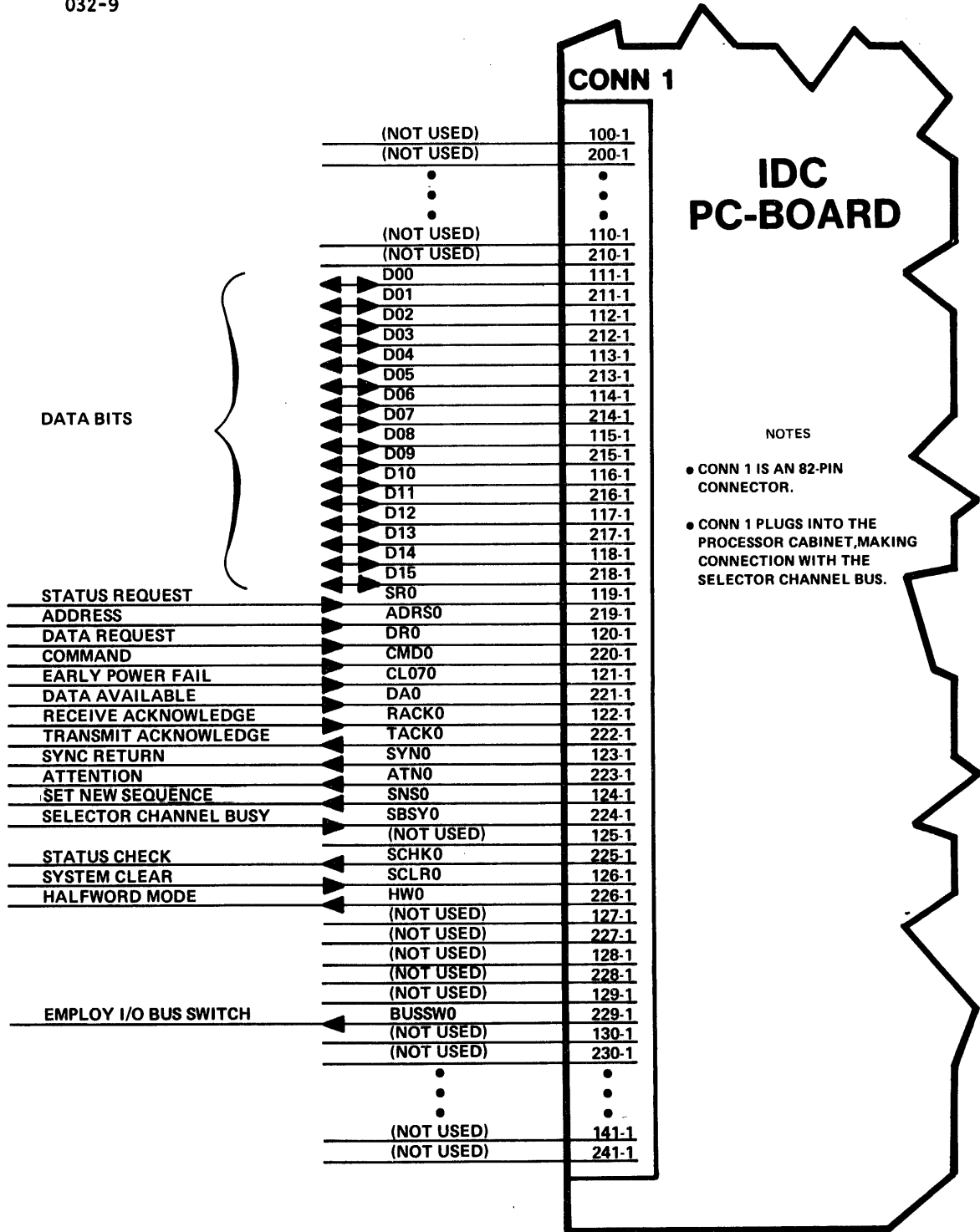


Figure 3-3 IDC CONN1 Connections to SELCH/MUX Bus

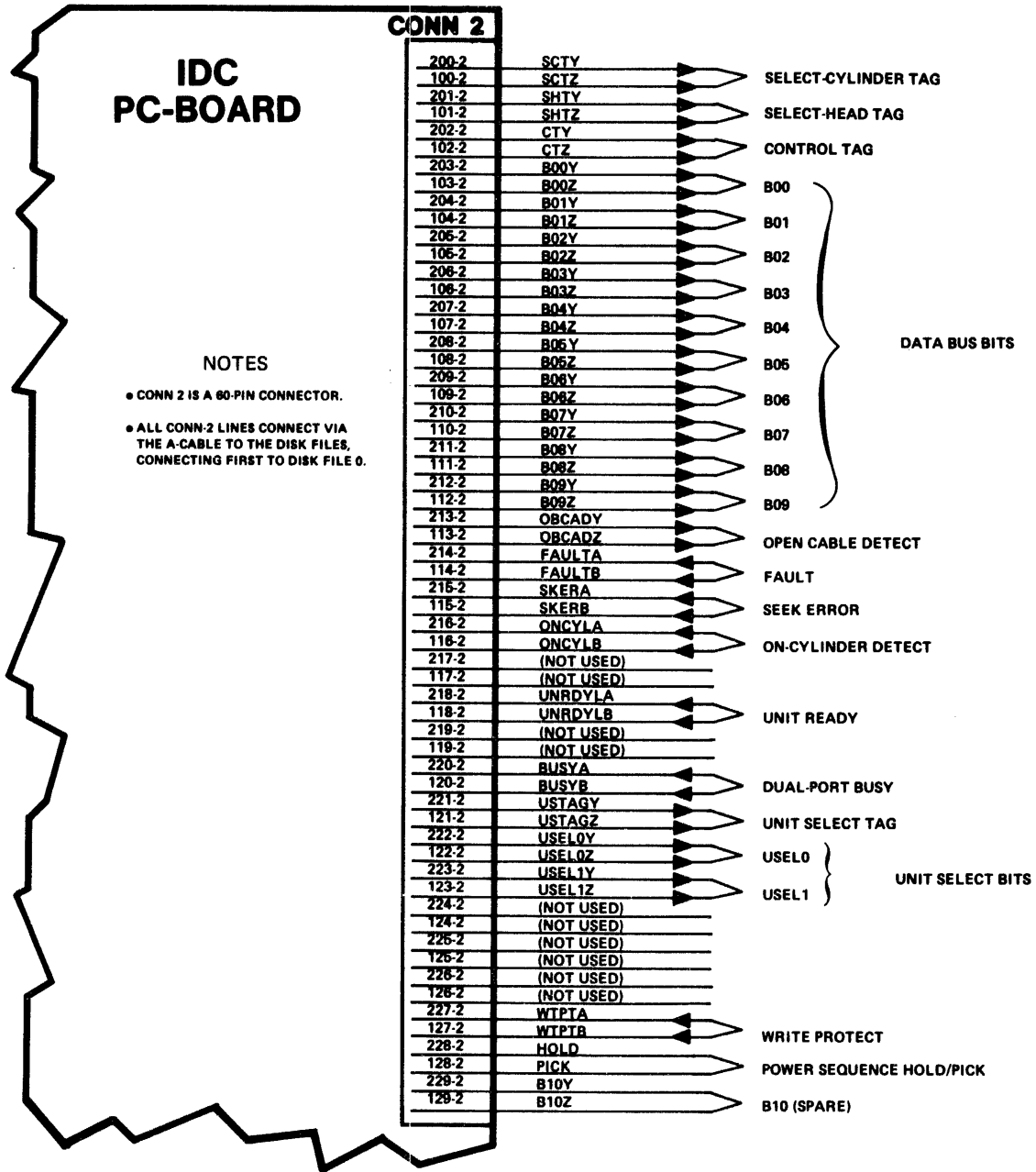


Figure 3-4 IDC CONN2 Connections with A-Cable to Disk Files

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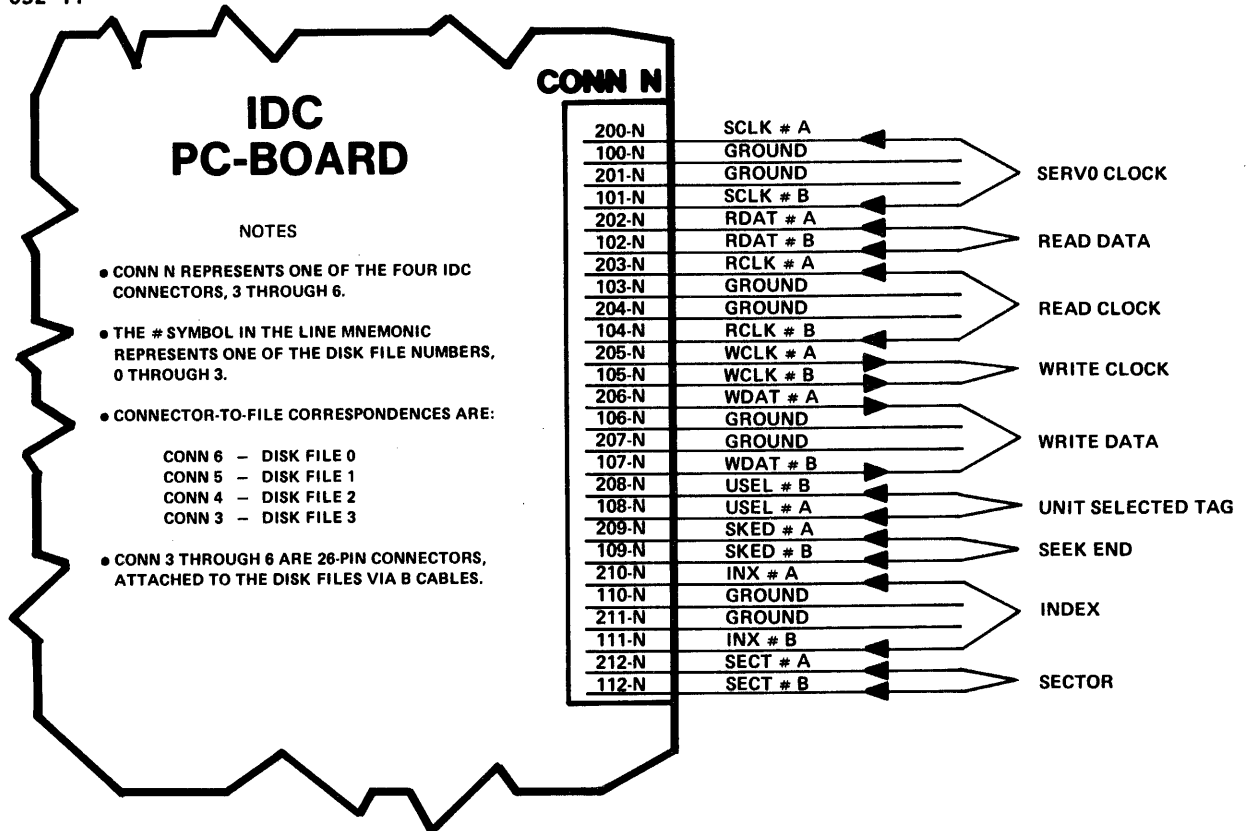


Figure 3-5 IDC CONN3, CONN4, CONN5 and CONN6 Connections with B-Cables to Disk Files

3.2.1 Intelligent Disk Controller (IDC) Connector 1 (CONN1) Pin

Figure 3-3 illustrates and identifies all of the CONN1 pins from the IDC board to the SELCH bus. The following signals, presented alphabetically according to pin mnemonics, describe the inputs and outputs associated with these pins.

a. ADRS0 (Address)

Input from the processor to IDC pin 219-1. When active, this signal informs the IDC that data bits D08 through D15 contain the address of an IDC or a disk file. This address selects a particular device for a subsequent operation, e.g.; a read/write or a status request. ADRS0 must result in device selection before any one of these signals, described below, can have effect: CMD0, DA0, DR0 and SR0.

b. ATN0 (Attention)

Output from IDC pin 223-1 to the processor. When active, this signal indicates that the IDC needs to interrupt the processor. The IDC sends this signal after completing an operation, and consequently has an interrupt pending.

c. BUSSW0 (Employ I/O Bus Switch)

Output from IDC pin 229-1. When active, this signal informs the SELCH that this IDC supports the new high-speed SELCH protocol and employs an I/O bus switch.

NOTE

This signal can be active only if these conditions are met: new-protocol pins W1 and W3 are strapped; toggle 7 of the file 0 address switch is pushed down to the 1 setting; and the IDC is installed under an I/O bus switch.

d. CL070 (EPF)

Input from the processor to IDC pin 121-1. When active, this signal serves as a warning that a power failure is imminent.

e. CMD0 (Command)

Input from the processor to IDC pin 220-1. When active, this signal informs the IDC that data bits D08 through D15 contain a command for the selected IDC or disk file. The IDC Programming Manual discusses these commands.

f. DA0 (Data Available)

Input from the processor or SELCH to IDC pin 221-1. When active, this signal informs the IDC of a write operation to the selected IDC or disk file. Data is available on IDC bits D00 through D15.

g. DR0 (Data Request)

Input from the processor or SELCH to IDC pin 120-1. When active, this signal informs the IDC of a read operation from the selected IDC or disk file to the processor. A halfword of data is read from IDC bits D00 through D15.

h. D00 through D15 (Data Bits 0 through 15)

I/O data on IDC pins 111-1 through 118-1 and 211-1 through 218-1. For halfword I/O, bits D00 through D15 hold read/write data; these bits can also hold a cylinder or head address as input from the processor. For byte I/O, bits D08 through D15 can hold one of the following: processor command, IDC address, IDC status, disk file address, disk file status, sector address and RPS data.

i. HW0 (Halfword Mode)

Output from IDC pin 226-1 to the SELCH. When active, this signal informs the SELCH that this IDC is a halfword-oriented device.

j. RACK0 (Receive Acknowledge)

Input from the processor to IDC pin 122-1. When active, this input indicates an interrupt acknowledgment from the processor. Whenever an IDC sends an ATN0 signal, thereby requesting a processor interrupt, that IDC then has an interrupt pending. The RACK0 input acknowledges this interrupt request. If a RACK0 is received at an IDC having no interrupt pending, that IDC passes this RACK0 as a TACK0 (see its description) to the next IDC in the processor cabinet. That IDC then receives the TACK0 as a RACK0.

In summary, the RACK0 is a daisy-chained interrupt acknowledgment from the processor to an IDC with an interrupt pending.

k. SBSY0 (SELCH Busy)

Input from the SELCH to IDC pin 224-1. When active, this signal indicates that a block data transfer to or from the SELCH is in progress.

l. SCHK0 (Status Check)

Output from IDC pin 225-1 to the SELCH. When active, this signal indicates the occurrence of a bad IDC status: EXAMINE, CONTROLLER IDLE or DATA ERROR. For information on this status, see the IDC Programming Manual. This is applicable only to the high-speed SELCH protocol.

m. SCLR0 (System Clear)

Input from the processor to IDC pin 126-1. When active, this signal causes the initialization of IDC logic. It is active during system power up, shutdown and initialization.

n. SNS0 (Set New Sequence)

Output from IDC pin 124-1 to the SELCH. When active, this signal informs the SELCH that this IDC supports the new high-speed SELCH protocol without an I/O bus switch.

NOTE

This signal can be active only if these conditions are met: the IDC is installed under an I/O bus switch; new protocol pins W1 and W2 are strapped; and toggle 7 of the file 0 address switch is pushed down to the 1 setting. Employing the high-speed protocol by strapping W1 and W2, however, is not a recommended procedure. Standard procedure is to strap W1 and W3 and to employ an I/O bus switch; see Item c above.

o. SR0 (Status Request)

Input signal from the processor or SELCH to IDC pin 119-1. When active, this signal requests the current status of the IDC or an attached disk file. The requested status is passed as one byte of data, bits D08 through D15. The IDC Programming Manual discusses these statuses.

p. SYN0 (Sync Return)

Output from IDC pin 123-1 to the processor or SELCH. When active, this signal informs the processor or SELCH that this IDC has properly accepted and responded to a control line signal.

q. TACK0 (Transmit Acknowledge)

Output from IDC pin 222-1 to the next controller plugged into the I/O slot. This output, consisting of a received RACK0, indicates that this IDC did not have an interrupt pending. See the description above for the RACK0 input.

3.2.2 Intelligent Disk Controller (IDC) Connector 2 (CONN2) Pins

Figure 3-4 illustrates and identifies all of the CONN2 pins and A-cable lines from the IDC board to the disk files. The following items, presented alphabetically according to the line mnemonics, describe the inputs and outputs associated with the A-cable lines.

- a. B00Y (differential data bus bit-0 +) and
B00Z (differential data bus bit-0 -)
B09Y (differential data bus bit-9 +) and
B09Z (differential data bus bit-9 -)

Ten output lines, subsequently referred to as B00 through B09, from IDC pins 203-2 and 103-2 (for B00) through pins 212-2 and 112-2 (for B09) to the disk files. These multipurpose bus lines supply control and address data to the attached disk files. The actual content of B00 through B09 depends on one of three tags:

1. CTY/CTZ (differential control tag +/-)
2. SCTY/SCTZ (differential select-cylinder tag +/-)
3. SHTY/SHTZ (differential select-head tag +/-)

As shown in Table 3-1, B00 through B09 can supply a control function, a cylinder address or a head address depending on which of the three tags is active. For further information on bus line contents, see the subsequent tag descriptions.

TABLE 3-1 BUS LINE CONTENTS CORRESPONDING TO ACTIVE OUTPUT TAG

BUS LINE	CONTROL* FUNCTION	CYLINDER** ADDRESS	HEAD*** ADDRESS
B00	Write Gate	1	1
B01	Read Gate	2	2
B02	Servo Offset +	4	4
B03	Servo Offset -	8	8
B04	Fault Clear	16	16
B05	(Not Applicable)	32	N/A
B06	Return to Zero (RTZ)	64	N/A
B07	Data Strobe Early	128	N/A
B08	Data Strobe Late	256	N/A
B09	Release (Dual-Port Operation)	512	N/A

- * Applies when CTY/CTZ tag is active.
- ** Applies when SCTY/SCTZ tag is active.
- *** Applies when SHTY/SHTZ tag is active.

- b. B10Y (differential data bus bit-10 +) and B10Z (differential data bus bit-10 -)

This is a spare differential data bus line.

- c. BUSYA (differential dual-port busy +) and BUSYB (differential dual-port busy -)

Input from a disk file to IDC pins 220-2 and 120-2, applicable only to dual-port operation of a particular disk file. When active, this line indicates to the IDC that the selected disk file has been acquired by another IDC.

- d. CTY (differential control tag +) and CTZ (differential control tag -)

Output from IDC pins 202-1 and 102-2 to the disk files. When active, this input tag informs the disk files that bus lines B00 through B09 are supplying a binary-coded control function (i.e.; a disk driver command). Table 3-2 lists and describes the control functions corresponding to the settings of these ten bus lines.

TABLE 3-2 CONTROL FUNCTIONS ACTIVATED BY CONTROL TAG CTY/CTZ

BUS* LINE	CONTROL FUNCTION	DESCRIPTION
B00	Write Gate	Informs the selected disk drive (selected by USEL0 and USEL1 on the A-cable) that the IDC will write data over the write data line of the B-cable to the current location of the disk medium.
B01	Read Gate	Informs the selected disk drive that the IDC will read data over the read data line of the B-cable from the current location of the disk medium.
B02	Servo Offset +	Offsets the head of the selected disk file in a positive direction, i.e.; towards the spindle of the disk drive.
B03	Servo Offset -	Offsets the head of the selected disk file in a negative direction, i.e.; away from spindle.
B04	Fault Clear	Clears the fault condition that resulted from a DC power failure, a simultaneously active read gate and write gate, or a selection of a nonexistent head. (See the description for the FAULTA/FAULTB line.)
B05	-----	Not applicable. Must equal zero.
B06	Return to Zero	Restores the selected disk file to cylinder 000.
B07	Data Strobe Early	Causes the disk file to advance the read clock in order to retrieve marginal data.
B08	Data Strobe Late	Causes the disk file to retard the read clock in order to retrieve marginal data.
B09	Release	Releases a dual-port operational disk file so another processor can access it.

* These ten lines are read as a binary number with B00 representing 2 to the 0 power, B01 representing 2 to the first power, B02 representing 2 to the second power, and so forth.

- e. FAULTA (differential fault +) and
FAULTB (differential fault -)

Input from a disk file to IDC pins 214-2 and 114-2. When active, this line indicates a fault condition at a disk file.

- f. HOLD/PICK (power sequence hold/pick)

A power sequencing ground provided by IDC logic from pins 228-2 and 128-2 to attached disk files. If SEQ pins 1 and 2 are not strapped and if attached disk files have their local/remote switch in the remote position, the IDC logic switches a ground onto these lines to permit power sequencing once the processor is turned on. When the processor is turned off, IDC logic removes the ground to power-down disk files. Essentially, these lines pick and hold the power sequencing capability.

- g. OBCADY (differential open cable detection +) and
OBCADZ (differential open cable detection -)

Output from IDC pins 213-2 and 113-2 to a disk file. When active, this line indicates an open A-cable or a loss of IDC power. While this condition exists, no selection or control data will be sent from the IDC.

- h. ONCYLA (differential on-cylinder detection +) and
ONCYLB (differential on-cylinder detection -)

Input status from a disk file to IDC pins 216-2 and 116-2. When active, this line signals the IDC that the heads of the selected disk file are positioned, i.e.; in response to a Seek instruction, they are positioned over a selected track. The on-cylinder status clears with another Seek instruction, and again becomes active once the heads are positioned. A carriage offset results in the loss of the on-cylinder status for 2.75ms (nominal), i.e.; about 2.75ms are required to move the head to a +/- offset.

- i. SCTY (differential select-cylinder tag +) and
SCTZ (differential select-cylinder tag -)

Output from IDC pins 200-2 and 100-2 to the disk files. When active, this output tag informs the disk file that the ten bus lines, B00 through B09, are supplying a binary-coded cylinder address. B00 represents 2 to the 0 power, B01 represents 2 to the first power, etc.

- j. SHTY (differential select-head tag) and
SHTZ (differential select-head tag)

Output from IDC pins 201-2 and 101-2 to the disk files. When active, this output tag informs the disk file that B00 through B09 are supplying head-select or volume-select data.

For a mass storage media (MSM) file, bus lines B00 through B04 supply head-select data, where B00 represents 2 to the 0 power, B01 represents 2 to the first power, etc. See Table 3-1 for further illustration.

For a medium capacity cartridge disk drive (MCCDD) bit-B04 represents a volume select bit; B00 through B03 are nonapplicable. B04, which represents 2 to the fourth power, supplies part of the data for a volume-select address: when reset, it denotes a removable disk; when set, it denotes a fixed disk. The remainder of the volume-select address is supplied by another input, a cylinder address, on B00 through B09. This input is associated with the select-cylinder tag SCTY/SCTZ. In summary, supplying a volume-select address to an MCCDD requires two tag sequences:

1. An active SHTY/SHTZ tag with bus line B04 set or reset.
 2. An active SCTY/SCTZ tag with bus lines B00 through B09 containing a valid cylinder address. (The worst-case switching delay is 4ms.)
- k. SKERA (differential seek error +) and SKERB (differential seek error -)

Input from a disk file to IDC pins 215-2 and 115-2. When active, this line indicates that a seek error occurred at a disk file. A seek error refers to one of these three conditions:

1. The disk drive could not move the head within a specified time interval.
2. The disk drive moved the head to a position outside the recording area of the disk.
3. The disk drive received an illegal track address.

A seek error can be cleared only by an RTZ control function.

1. UNRDYLA (differential unit ready +) and UNDRYLB (differential unit ready -)

Input from a disk file to IDC pins 218-2 and 118-2. When active, this line indicates that the selected disk file is up-to-speed, that the heads are positioned over the recording tracks, and that no fault condition exists within the disk file.

- m. USELOY (differential unit select 0 +),
USELOZ (differential unit select 0 -),
USEL1Y (differential unit select 1 +), and
USEL1Z (differential unit select 1 -)

Two output lines, subsequently referred to as USELO and USEL1, from IDC pins 222-2 and 122-2 (for USELO) and pins 223-2 and 123-2 (for USEL1). These binary-coded lines supply a number, 0 through 3, of the disk file to be selected. USELO represents 2 to the 0 power; USEL1 represents 2 to the first power.

- n. USTAGY (differential unit select tag +) and
USTAGZ (differential unit select tag -)

Output from IDC pins 221-2 and 121-2 to the disk files. When active, this output tag informs the disk files that the two unit-select lines, USELO and USEL1, are supplying a binary-coded number, as mentioned above.

- o. WTPTA (differential write protect +) and
WTPTB (differential write protect -)

Input from a disk file to IDC pins 227-2 and 127-2. When active, this line indicates that the particular disk file is in write-protected mode: a write-protect button on the disk file has been depressed.

3.2.3. Intelligent Disk Controller (IDC) Connector 3 (CONN3) Through Connector 6 (CONN6) Pins

Figure 3-5 illustrates and identifies all of the pins and B-cable lines from these IDC connectors: CONN3, CONN4, CONN5 and CONN6. The following items, presented alphabetically according to line mnemonics, describe the inputs and output associated with the lines. These descriptions, which apply to all four connectors, use the letter N to represent the connector numbers (3, 4, 5 or 6) and the pound (#) symbol to represent the disk file number (0, 1, 2 or 3).

- a. INX#A (differential index +) and
INX#B (differential index -)

Input from disk file # to IDC pins 210-N and 111-N. This line receives a pulse for every disk revolution. The leading edge of the pulse is treated as the leading edge of sector 0. Pulse width is typically 2.5ms.

- b. RCLK#A (differential read clock +) and
RCLK#B (differential read block -)

Input from disk file # to IDC pins 203-N and 104-N. The IDC uses this input to clock-in, or synchronize, data read from disk file #.

- c. RDAT#A (differential read data +) and
RDAT#B (differential read data -)

Input from disk file # to IDC pins 202-N and 102-N. This line carries read data from disk file #. Read data is in NonReturn to zero (NRZ) form.

- d. SCLK#A (differential servo clock +) and
SCLK#B (differential servo clock -)

Input from disk file # to controller pins 200-N and 101-N. The IDC uses this input as the write clock; see WCLK#A/WCLK#B below.

- e. SECT#A (differential sector +) and
SECT#B (differential sector -)

Input from disk file # to IDC pins 212-N and 112-N. This input pulse marks the beginning of each physical sector of the IDC-formatted disk. (There are 33 physical sectors per disk revolution.)

- f. SKED#A (differential seek end +) and
SKED#B (differential seek end -)

Input from disk file # to IDC pins 209-N and 109-N. This input line is a combination of the on-cylinder detect line (ONCYLA/ONCYLB) and the seek error line (SKERA/SKERB). These two lines connect through the A-cable to IDC CONN2. It indicates to the IDC that a seek operation has ended, either successfully or unsuccessfully.

- g. USEL#A (differential unit selected tag +) and
USEL#B (differential unit selected tag -)

Input from disk file # to IDC pins 108-N and 208-N. It indicates that the attached disk file is now acquired by the IDC, i.e.; the disk has been selected.

- h. WCLK#A (differential write clock +) and
WCLK#B (differential write clock -)

Output from IDC pins 205-N and 105-N to disk file #. The IDC uses this output to clock-out, or synchronize, data written to the disk file.

- i. WDAT#A (differential write data +) and
WDAT#B (differential write data -)

Output from IDC pins 206-N and 107-N to disk file #. This line carries write data to be recorded on the disk. Written data is in NRZ form.

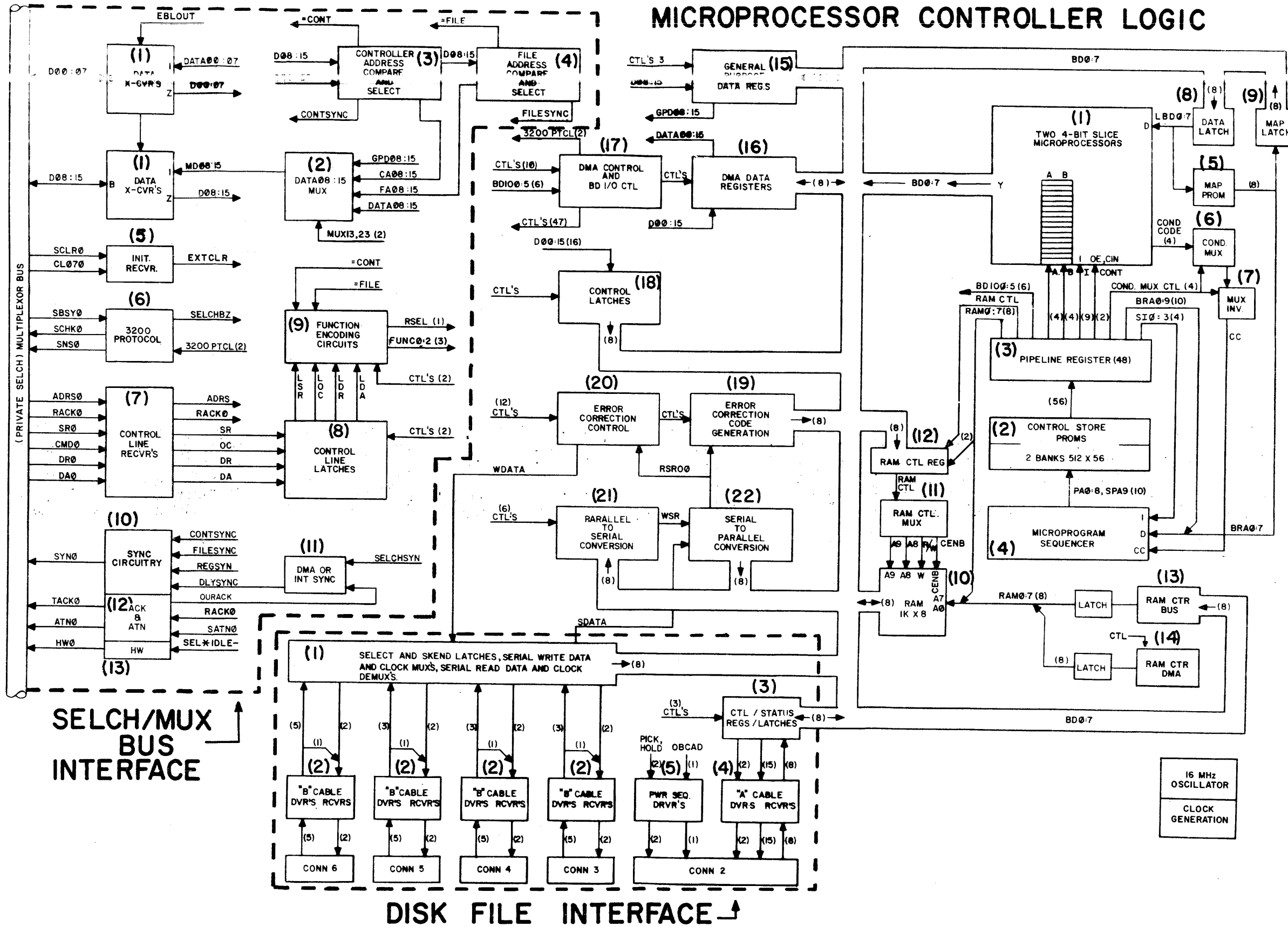


Figure 3-6 Block Diagram of the IDC Logic

3.3 BLOCK DIAGRAM ANALYSIS OF INTELLIGENT DISK CONTROLLER (IDC)

Figure 3-6 is a block diagram of the IDC logic circuitry. As shown, this block diagram has three logical sections:

1. SELCH/MUX bus interface
2. Disk file interface
3. Microprocessor controller logic

Section 3.3.1 describes the constituent blocks for the SELCH/MUX bus interface; Section 3.3.2, the disk file interface; and Section 3.3.3, the microprocessor controller logic.

3.3.1 SELCH/MUX Bus Interface

This portion of the IDC board serves as the interface to the SELCH/MUX bus. It consists of thirteen functional blocks:

1. Data Transceivers
2. Data Multiplexer for Bits 08:15
3. Controller Address Compare-and-Select Circuitry
4. File Address Compare-and-Select Circuitry
5. Initialization Receiver
6. 3200-Protocol Circuitry
7. Control Line Receivers
8. Control Line Latches
9. Function Encoding Circuits
10. Synchronization Circuitry
11. DMA and Interrupt Sync Circuits
12. Acknowledgment and Attention Circuitry
13. Halfword-Mode Circuitry

The following items describe these functional blocks and their associated I/O lines.

1. Data Transceivers

Transmit data to or receive data from the SELCH/MUX bus. I/O lines are:

a. EBL0UT (driver control), input

Signal for setting the transceiver mode to transmit or receive.

b. D00:15 (data bits D00 through D15), I/O

Data to or from the SELCH/MUX bus. See Section 3.2.1 for a more complete description.

- c. DATA00:07 (data bits 00 through 07), input
More significant byte of Direct Memory Access (DMA) data to be transmitted to the SELCH.
- d. MD08:15 (multiplexed data bits 08 through 15), input
One of four multiplexed data sources to be sent to the SELCH or processor.
- e. D00:07 (receive data bits 00 through 07), output
More significant byte of data received from the SELCH/MUX bus, i.e.; from the processor or SELCH.
- f. D08:15 (receive data bits 08 through 15), output
Less significant byte of data received from the SELCH/MUX bus, i.e.; from the processor or SELCH.

2. Data Multiplexer for Bits 08:15

Selects one of four data sources as MD08:15 input to the data transceivers. I/O lines are:

- a. MUX13,23 (multiplexer control bits), input
Binary value for selecting one of the following four data-source inputs.
- b. GPD08:15 (general-purpose data), input
General purpose control data like status, RPS, etc.; to be sent as MD08:15 input to the data transceivers.
- c. CA08:15 (controller-address bits 08 through 15), input
IDC address (of this controller) to be sent as MD08:15 input to the data transceivers.
- d. FA08:15 (file-address bits 08 through 15), input
File address (of a disk file attached to this controller) to be sent as MD08:15 input to the data transceivers.
- e. DATA08:15 (data bits 08 through 15), input
Less significant byte of DMA data to be transmitted, via the data transceivers, to the SELCH.
- f. MD08:15 (multiplexed data bits 08 through 15), output
One of four multiplexed data sources to be sent to the SELCH or processor.

3. Controller Address Compare-and-Select Circuitry

Detects when this IDC is addressed by the processor. More specifically, this circuitry compares a received controller address with the address of this IDC; if the two addresses match, then this IDC is selected for I/O with the processor via the SELCH/MUX bus. (The IDC address is determined by the setting of the controller address switch on the IDC board, discussed in Section 2.4.1.) I/O lines are:

- a. D08:15 (receive data bits 08 through 15), input
Controller address received from the processor.
- b. D06:07 (receive data bits 06 and 07), input
Controller address bits appended to D08:15 for a full 10-bit address selection. These two bits must equal zero for address comparison to occur.
- c. =CONT (equals controller), output
Signal for indicating that the received controller address matches the address of this IDC.
- d. CONTSYNC (controller sync return), output
A sync signal indicating that the IDC has properly accepted and responded to control line signals.
- e. CA08:15 (controller-address bits 08 through 15), output
IDC address (of this controller) to be sent to the processor, along with the sync signal SYN0.

4. File Address Compare-and-Select Circuitry

Detects when an attached disk file is addressed by the processor. More specifically, this circuitry compares a received disk file address with the addresses of the disk files attached to this IDC; if there is a match, then the addressed disk file is selected for I/O with the processor via the SELCH/MUX bus. (Disk file addresses are determined by the setting of the file 0 address switch on the IDC board, discussed in Section 2.4.1.) I/O lines are:

- a. D08:15 (receive data bits 08 through 15), input
Disk file address received from the processor.

- b. =FILE (equals file), output

Signal for indicating that the received file address matches the address of a disk file at this IDC.

- c. FILESYNC (file sync return), output

A sync signal indicating that an attached disk file has properly accepted and responded to control line signals.

- d. FA08:15 (file address bits 08 through 15), output

File address (of the selected disk file) to be sent to the processor, along with the sync signal SYN0.

5. Initialization Receiver

Initializes IDC logic to permit controller communication with the Series-3200 Processor, or to prepare the IDC logic for an imminent power failure. I/O lines are:

- a. SCLR0 (system clear), input

Signal from the processor for initializing IDC circuitry. See Section 3.2.1 for more information.

- b. CL070 (early power fail), input

Signal from the processor as a warning that a power failure is about to occur. See Section 3.2.1.

- c. EXTCLR (external clear), output

Signal for initializing the IDC logic.

6. 3200-Protocol Circuitry

Enables the IDC to employ the new high-speed SELCH protocol. This protocol applies only when the New Protocol pins W1 and W3 or W1 and W2 are strapped. I/O lines are:

- a. SBSY0 (SELCH busy), input

Signal for indicating that the SELCH is currently busy with a block-data transfer. See Section 3.2.1 for further description.

- b. SELCHBZ (SELCH busy), output

Same description as above with SBSY0.

c. 3200 PTCL (3200 protocol), input

Data indicating the occurrence of a bad IDC status, namely: S13, EXAMINE; S14, CONTROLLER IDLE; or S15, DATA ERROR. The indicated status results from bits 13, 14 and 15 of a status register within the Random Access Memory (RAM) circuitry. See the IDC Programming Manual for further description. (Physically, 3200 PTCL represents two lines: STCHK and CTLOPTC. See Appendix A for further description.)

d. SCHK0 (status check), output

Output to SELCH to indicate a bad IDC status associated with the high-speed SELCH protocol. See Item c above. See Section 3.2.1 for more information.

e. SNS0 (set new sequence), output

Signal for indicating that the controller is set-up for the optional new high-speed SELCH protocol. This signal results when toggle 7 of the file 0 address switch is pushed down to the 1 setting, and when the New Protocol pins W1 and W2 are strapped. See Sections 2.4.1 and 2.4.2 for detailed information.

7. Control Line Receivers

Receive control signals from the SELCH/MUX bus. I/O lines are:

a. ADRS0 (address), input

Signal indicating that D08:15 (input lines to the data transceivers) contain the address of an IDC or disk file. This signal must result in device selection at the IDC before any one of these signals, described below, can have effect: SR0, CMD0, DR0 and DA0. See Section 3.2.1 for more information.

b. ADRS (address), output

Same description as above with ADRS0.

c. RACK0 (receive acknowledgment), input

Signal acknowledging that the processor received an ATN0 from an IDC with an interrupt pending, possibly this one. In effect, RACK0 acknowledges an interrupt request signaled by the ATN0 signal. See Section 3.2.1 for a more complete description.

d. RACK0 (receive acknowledgment), output

Same description as above. If the IDC does not have an interrupt pending, RACK0 is passed as TACK0 output to the next IDC in the I/O slot of the processor cabinet. See Item 12 below for further description.

e. SR0 (status request), input

Signal for requesting the status of a selected IDC or disk file. See Section 3.2.1 for further description.

f. SR (status request), output

Same description as above with SR0.

g. CMD0 (command), input

Signal indicating that input lines D08:15 contain a command for this selected IDC or for a selected disk file. See Section 3.2.1 for further description.

h. OC (output command), output

Same description as above with CMD0.

i. DR0 (data request), input

Signal indicating a read operation from output lines D00:15. See Section 3.2.1 for further description.

j. DR (data request), output

Same description as above with DR0.

k. DA0 (data available), input

Signal indicating a write operation from the processor to input lines D00:15. See Section 3.2.1 for further description.

l. DA (data available), output

Same description as above with DA0.

8. Control Line Latches

Temporarily store (i.e.; latch) control inputs for later use by the IDC microprocessor logic. I/O lines are:

a. CTL'S (control lines), input

Binary coded control lines to enable or disable latching of the four control inputs SR, OC, DR and DA.

- b. SR (status request), input
Control input resulting from a received SR0 signal.
- c. LSR (latched status request), output
Latch signal corresponding to the above SR input.
- d. OC (output command), input
Control input resulting from a received CMD0 signal.
- e. LOC (latched output command), output
Latch signal corresponding to the above OC input.
- f. DR (data request), input
Control input resulting from a received DR0 signal.
- g. LDR (latched data request), output
Latch signal corresponding to the above DR input.
- h. DA (data available), input
Control input resulting from a received DA0 signal.
- i. LDA (latched data available), output
Latch signal corresponding to the above DA input.

9. Function Encoding Circuits

Encodes the latched control lines (LSR, LOC, LDR and LDA) into a 3-bit code for a selected IDC or disk file. I/O lines are:

- a. LSR (latched status request), input
Latch signal corresponding to the SR0 input from the SELCH/MUX bus.
- b. LOC (latched output command), input
Latch signal corresponding to the CMD0 input from the SELCH/MUX bus.
- c. LDR (latched data request), input
Latch signal corresponding to the DR0 input from the SELCH/MUX bus.

- d. LDA (latched data available), input
Latch signal corresponding to the DA0 input from the SELCH/MUX bus.
- e. FUNC0:2 (function code), output
Binary coded signal representing one of eight possible functions. This output goes onto the microprocessor bus, BD0:7, when RSEL is also active. See Appendix A for further description.
- f. RSEL (register select), output
Signal indicating that the encoded FUNC0:2 bits are now active.
- g. CTL'S (control lines), input
Control lines to gate the FUNC0:2 bits onto BD0:7.
- h. =CONT (equals controller), input
Signal for indicating that the FUNC0:2 bits apply to this selected IDC.
- i. =FILE (equals file), input
Signal for indicating that the FUNC0:2 bits apply to a selected disk file.

10. Synchronization Circuitry

Receives synchronization signals from the IDC logic and outputs a synchronization signal to the processor or SELCH. I/O lines are:

- a. CONTSYNC (controller sync return), input
Sync signal indicating that this IDC has properly accepted and responded to a control line signal.
- b. FILESYNC (file sync return), input
Sync signal indicating that a selected disk file attached to this IDC has properly accepted and responded to a control line signal.
- c. REGSYN (register sync), input
Sync signal indicating that the IDC received one of the four control functions SR0, CMD0, DR0 or DA0. See Item 7 above for more information.

d. DLYSYNC (delayed sync return), input

Either the DMA sync signal to the SELCH (resulting from SELCHSYN) or the interrupt-acknowledgment sync signal (resulting from OURACK0) to the processor. See Item 11 below for further description.

e. SYN0 (sync return), output

Sync signal informing the processor or SELCH that this IDC or an attached disk file has properly accepted and responded to control line signals. See the corresponding description in Section 3.2.1.

11. DMA and Interrupt Sync Circuits

Outputs a delayed sync signal resulting from either SELCHSYN or OURACK0. I/O lines are:

a. SELCHSYN (SELCH sync return), input

Sync return in response to a DMA transfer with the SELCH. (Physically, SELCHSYN represents two lines: DMASR and XFRSYNCH. See Appendix A for further description.)

b. OURACK0 (our RACK0), input

Signal indicating that a RACK0 signal was received by this IDC, which had an interrupt pending.

c. DLYSYNC (delayed sync return), output

A DMA sync signal (resulting from SELCHSYN) to the SELCH or an interrupt-acknowledgment sync signal (resulting from OURACK0) to the processor.

12. Acknowledgment and Attention Circuitry

Handles controller interrupt requests (ATN0) and interrupt acknowledgments (RACK0/TACK0). I/O lines are:

a. RACK0 (receive acknowledge), input

Signal (resulting from a received RACK0) acknowledging that the processor received an interrupt request (ATN0 signal) from a controller.

b. OURACK0 (our RACK0), output

Signal indicating that the received RACK0 signal was for this IDC, which had an interrupt pending. If this IDC had no interrupt pending, output would be TACK0 instead of OURACK0.

c. TACK0 (transmit acknowledge), output

Signal, consisting of a received RACK0, passed onto the next controller in the processor cabinet. See Section 3.2.1 for further description.

d. SATNO (set attention), input

Signal for activating ATNO output.

e. ATNO (attention), output

Signal indicating that this IDC wants to interrupt the processor, i.e.; that this IDC has an interrupt pending. See Section 3.2.1 for further description.

13. Halfword-Mode Circuitry

Informs the SELCH that this controller is in the halfword-mode of operation via lines D00 through D15. I/O lines are:

a. SEL*IDLE- (selected and not idle), input

Signal indicating that this IDC is selected and is not idle. It activates the HW0 output. (Physically, SEL*IDLE- represents two lines: CONTSEL and IDLE. See Appendix A for further description.)

b. HW0 (halfword-mode), output

Signal informing the SELCH that this IDC is a halfword-oriented device. See Section 3.2.1 for more information.

3.3.2 Disk File Interface

This portion of the IDC board serves as the interface to the disk files. It consists of five functional blocks:

1. Select and Seek-End (SKEND) Latches, serial-write-data and clock multiplexers (MUXs), and serial-read-data and clock demultiplexers (DEMUXs)

2. B-cable drivers/receivers
3. Control and status registers/latches
4. A-cable drivers/receivers
5. Power sequencing drivers

The following Items describe these functional blocks and their associated I/O lines.

1. Select and Seek-End (SKEND) Latches, Serial-write-data and clock multiplexers (MUXs), and Serial-read-data and clock demultiplexers (DEMUXs)

These circuits serve as the interface between the 8-bit microprocessor bus, BD0:7, and the B-cable circuitry to the disk drives. Select latches are available for selecting one of four possible disk drives attached to the IDC; SKEND latches are available for signaling a seek end from the drives. MUXs transmit serial write data and clock signals to the disk drives. And in the other direction, DEMUXs receive serial read data and clock signals from the disk drives. Associated with these MUX and DEMUX operations are write clocks, write data registers, and read clocks. I/O lines are:

- a. WDATA (serial write data), input

Serial data, along with error correction code (ECC), to be written to a disk file.

- b. SDATA (serial read data), output

Serial data, along with ECC, read from a disk file.

- c. BD0:7 (bus data lines 0 through 7), I/O

Various data and control bytes.

NOTE

BD0:7 is the 8-bit microprocessor bus of the IDC -- the main data path among the the functional blocks, or modules, of the IDC.

- d. Driver Lines (not labeled), Output

Serial write data and clock signals to the B-cable drivers.

e. Receiver Lines (not labeled), Input

Serial read data and clock signals from the B-cable receivers.

2. B-Cable Drivers/Receivers

B-cable drivers receive serial write data and clock signals from the MUXs and transfer them to the disk files. B-cable receivers receive serial data and clock signals from the disk files and transfer them to the DEMUXs. For detailed descriptions of all I/O lines connected to the drivers/receivers via these four connectors, CONN3 through CONN6, see Sections 3.1.3 and 3.2.3.

3. Control and Status Registers/Latches

Latch data and controls associated with the A-cable. I/O lines are:

a. BD0:7 (bus data lines 0 through 7), I/O

Various data and controls to and from the registers and latches.

b. CTL'S (control lines), input

Control signals to latch or enable data and controls for BD0:7.

c. Driver/Receiver Lines (not labeled), I/O

See Item 4 below.

4. A-Cable Drivers/Receivers

By means of registers and latches, A-cable drivers receive various data and controls from BD0:7 and transfer them to the disk files. A-cable receivers receive data and controls from the disk files and transfer them to BD0:7 by means of registers and latches. For detailed descriptions of all I/O lines connected to the A-cable drivers/receivers via CONN2, see Sections 3.1.2 and 3.2.2.

5. Power Sequencing Drivers

Control the power sequencing grounds, PICK and HOLD, and the open cable detect signal. I/O lines are:

a. PICK,HOLD (power sequence pick/hold), I/O

Signals for enabling or disabling power sequencing. Both of these signals are active (ground) when IDC SEQ pins 1 and 2 are not strapped and when the processor is turned on. For more details, see Section 3.2.2.

b. OBCAD (open cable detect), I/O

Signal for indicating an open A-cable or loss of IDC power. See Section 3.2.2 for more details.

3.3.3 Microprocessor Controller Logic

This portion of the IDC board interprets and acts on the Series-3200 Processor commands (e.g.; seek, read, write and format), causing the disk drives to perform specific operations or data transfers. It also controls the IDC interface circuitry between the SELCH/MUX bus and the disk files. Microprocessor control logic consists of twenty-two functional blocks:

1. Two 4-bit slice microprocessors
2. Control-store programmable read only memory (PROM) banks
3. Pipeline register
4. Microprogram sequencer
5. Map PROM
6. Condition code MUX
7. MUX inverter
8. Data latch
9. Map latch
10. Random access memory (RAM)
11. RAM control MUX
12. RAM control register
13. RAM-address counter for disk file transfer, and latch
14. RAM-address counter for DMA transfer, and latch
15. General-purpose data registers
16. DMA data registers
17. DMA control and bus data (BD) I/O control
18. Control latches
19. Error correction code (ECC) generation
20. Error correction control
21. Parallel-to-serial conversion
22. Serial-to-parallel conversion

The following Items describe these functional blocks and their associated I/O lines.

1. Two 4-Bit Slice Microprocessors

Serve as the 8-bit arithmetic logic unit (ALU) of the IDC. This ALU includes sixteen 8-bit ALU registers: each register consists of two 4-bit slices, with two address ports labeled A and B. Chapter 4 presents a more thorough description of this functional block. I/O lines are:

- a. BD0:7 (bus data lines 0 through 7), I/O

Various data and controls to and from the microprocessor controller logic.

- b. LBD0:7 (latched bus data Bits 0 through 7), input

Latched data (i.e.; temporarily stored data) from BD0:7. This data is used by the ALU as input.

- c. A (A-register address bits), input

A 4-bit binary-coded value for selecting one of the sixteen ALU registers as the A-register. (Physically, A represents four lines: A0 through A3. See Appendix A for further description.)

- d. B (B-register address bits), input

A 4-bit binary-coded value for selecting one of the sixteen ALU registers as the B-register. (Physically, B represents four lines: B0 through B3. See Appendix A for further description.)

- e. I (ALU instruction bits), input

A 9-bit binary coded field for ALU instruction input. The first 3-bit value of this field yields the source of the ALU input data. The second 3-bit value gives a specific ALU instruction, arithmetic or logical. The third 3-bit value yields the destination for the resulting ALU output data. (Physically, I represents nine lines: I0 through I8. See Appendix A for further description.)

- f. CONT (control), input

Two control bits: one for enabling output onto BD0:7, and one for arithmetic carry-in. (Physically, CONT represents two lines: CIN and POE. See Appendix A for further description.)

g. COND CODE (condition code), output

A 4-bit condition code associated with ALU instruction execution: overflow, sign bit, carry and zero result. (Physically, COND CODE represents four lines: OFLOW, SIGN, CARRY7 and F=0. See Appendix A for further description.)

2. Control Store PROM Banks

Consist of PROM for storing the IDC microcode, the internal IDC program which controls the microprocessor circuitry to provide controller operations. PROM is organized into 1024 (two banks of 512) 56-bit words. Throughout the following descriptions, these 56-bit words are referred to as microinstructions or microcode. I/O lines are:

a. PA0:8, SPA9 (program address lines 0 through 9), input

A 10-bit address from the microprogram sequencer for selecting one of the 1024 microcode locations.

b. 56 Lines (not labeled), output

A 56-bit word containing microcode as output to the pipeline register.

3. Pipeline Register

Provides pipeline storage of the next sequential microinstruction. I/O lines are:

a. 56 Lines (not labeled), input

A 56-bit word, from control store PROM, containing the next sequential microinstruction.

b. RAM0:7 (RAM address bits), output

An 8-bit address of a RAM location.

c. RAM CTL (RAM control), output

Lines for controlling RAM enable, read and write. (Physically, RAM CTL represents five lines: MWE, MCE, AE/OE, PZ and CNT. See Appendix A for further description.)

- d. BDI00:5 (bus data I/O control), output
A 6-bit code for controlling the source and destination of BD0:7 data and for controlling IDC operations like latching and ECC-register shifting. See Appendix A for further description of these controls.
- e. A (A-register address bits), output
A 4-bit binary-coded value for selecting one of the sixteen ALU registers as the A-register. (Physically, A represents four lines: A0 through A3. See Appendix A for further description.)
- f. B (B-register address bits), output
A 4-bit binary coded value for selecting one of the sixteen ALU registers as the B-register. (Physically, B represents four lines: B0 through B3. See Appendix A for further description.)
- g. I (ALU instruction bits), output
A 9-bit binary coded field for ALU instruction input. The first 3-bit value of this field yields the source of the ALU input data. The second 3-bit value gives a specific ALU instruction, arithmetic or logical. The third 3-bit value yields the destination for the resulting ALU output data. (Physically, I represents nine lines: I0 through I8. See Appendix A for further description.)
- h. CONT (control), output
Two control bits: one for enabling output onto BD0:7, and one for arithmetic carry-in. (Physically, CONT represents two lines: CIN and POE. See Appendix A for further description.)
- i. COND MUX CTL (condition code MUX control), output
Four bits three of which select one of eight conditions to be output by the condition code MUX. The fourth bit controls the MUX inverter. (Physically, COND MUX CTL represents four lines: MA, MB, MC and MI. For further description see Appendix A.)
- j. BRA0:9 (branch address bits), output
A 10-bit address serving as a possible microprogram branch address or as a count value for the microprogram sequencer.

k. SI0:3 (sequencer instruction bits), output

A hexadecimal value for one of sixteen sequencer instructions. See Appendix A for further description.

4. Microprogram Sequencer

Calculates the next address within control store PROM. It performs any one of sixteen next address calculations, including sequential, branch conditional and return conditional. I/O lines are:

a. SI0:3 (sequencer instruction bits), input

A hexadecimal value for one of sixteen sequencer instructions. See Appendix A for further description.

b. BRA0:9 (branch address bits), input

A 10-bit microprogram branch address or count value from the pipeline register.

c. BRA0:7 (branch address), input

An alternate 8-bit microprogram branch address or count value from the map PROM.

d. CC (condition code), input

A pass or fail condition code for one of eight possible conditions determined by MA:MC. See Appendix A. The microprogram sequencer uses CC for a next address calculation, e.g.; a conditional branch or conditional return.

e. PA0:8, SPA9 (program address lines 0 through 9), output

A 10-bit address for selecting one of the 1024 microcode locations in control store PROM.

5. Map PROM

Contains constant data used by the microcode program, and contains addresses of routines within control-store PROM. Map PROM is organized into 512 8-bit locations: 256 bytes for the routine addresses and 256 bytes for the constant data. During power-up, the second set of 256 bytes (containing the constant data) is copied into RAM.

Later, the first set of 256 bytes (containing a table of routine addresses) is used for vectoring to a particular microcode routine: on receiving an instruction from the processor, e.g.; read, write or format track, the IDC logic references this table, gets the address of the microroutine for executing that instruction, and vectors to the routine. I/O lines are:

- a. LBD0:7 (latched bus data bits 0 through 7), input

Latched BD0:7 data which will result in the map PROM outputting either constant data or a microroutine address.

- b. BRA0:7 (branch address), output

Either a constant value or a microroutine address. If BRA0:7 contain a constant, it goes to the map latch. If BRA0:7 contain a microroutine address, it goes to the microprogram sequencer.

6. Condition Code MUX

Provides the CC input to the microprogram sequencer. I/O lines are:

- a. COND CODE (condition code), input

A 4-bit condition code associated with an ALU instruction execution: overflow, sign bit, carry and zero result. (Physically, COND CODE represents four lines: OFLOW, SIGN, CARRY7 and F=0. See Appendix A for further description.)

- b. COND MUX CTL (condition code MUX control), input

Three bits for selecting one of eight conditions to be output by the condition code MUX. The selected condition is output as the CC to the microprogram sequencer. (Here, COND MUX CTL represents three lines: MA, MB and MC. See Appendix A for further description.)

- c. CC (condition code), output

Selected condition code sent to the microprogram sequencer, via the MUX inverter.

7. MUX Inverter

Passes the selected condition code to the microprogram sequencer, with or without inversion according to the received MI bit. I/O lines are:

a. MI (MUX inverter bit), input

The fourth bit of the COND MUX CTL output from the pipeline register. If the MI bit is set, the CC output is inverted; otherwise, the CC is passed as received from the condition code MUX.

b. CC (condition code), I/O

As input, CC is the selection of one of eight possible condition codes from the condition code MUX. As output, CC is in either true or complement form according to the MI input.

8. Data Latch

Latches BD0:7 data for input to either the ALU (the two 4-bit slice microprocessors) or the map PROM. I/O lines are:

a. BD0:7 (bus data lines 0 through 7), input

Various microprocessor bus data.

b. LBD0:7 (latch bus data bits 0 through 7), output

Data as input to the ALU or the map PROM.

9. Map Latch

Latches data constants output from the Map PROM and outputs this data onto BD0:7. I/O lines are:

a. BRA0:7 (constant data), input

Data constants from the map PROM. (At power-up, the map PROM must write data constants to the RAM.)

b. BD0:7 (bus data lines 0 through 7), output

Data constants written to the RAM.

10. Random Access Memory (RAM)

Stores data constants and buffers read/write data. RAM consists of 1024 8-bit locations. It is equally divided into four pages: Page 0, consisting of 256 bytes, holds tabularized data constants from the map PROM. Pages 1, 2 and 3 buffer data read from and written to one of the disk files; each of these pages holds one logical sector (256 bytes) for the IDC-formatted disk media. I/O lines are:

a. BD0:7 (bus data lines 0 through 7), I/O

Data bytes to and from various functional blocks throughout the microprocessor control logic.

b. RAM0:7 (RAM address bits), input

An 8-bit address within a page of RAM memory. One of the two RAM-address counters generate this address; see Items 13 and 14 below.

c. RAM0:7 (RAM address bits), input

An 8-bit address within a page of RAM memory. Control store PROM generates this address in order to read a data constant.

d. A8, A9 (RAM page address lines), input

Two binary bits for selecting one of four pages in RAM. (Physically, A8 and A9 represent two lines: PAGE13 and PAGE23. See Appendix A for further description.)

e. R/W (read/write enable), input

Signal for selecting a RAM read operation or a RAM write operation over BD0:7. (Physically, R/W represents one line: WENB. See Appendix A for further description.)

f. CENB (chip enable), input

Signal for enabling RAM output onto BD0:7.

11. RAM Control MUX

Controls the multiplexing of I/O operations at the RAM. (See Item 10 above for a description of RAM organization.)

The RAM control MUX multiplexes simultaneous read operations at the RAM, as follows: During a read operation from a disk file, RAM first reads a logical sector from the disk file into page 1. If this operation is a multisector read, RAM also reads another logical sector into page 2. Once page 1 is filled with a logical sector, and the ECC circuitry validates the ECC, DMA transfer to the SELCH/MUX bus begins. This transfer occurs simultaneously with the filling of page 2, as directed by the RAM control MUX. The filling of pages 2 and 3, and pages 3 and 1, proceed in the same manner.

Likewise, the RAM Control MUX multiplexes simultaneous write operations at the RAM, as follows: During a write operation to a disk file, RAM first writes a logical sector from the SELCH/MUX bus into page 1. Once page 1 is filled with a logical sector, data transfer to the selected disk file may begin. While this transfer is in progress, page 2 is filled with an additional sector of DMA data from the SELCH/MUX bus. The filling of pages 2 and 3, and pages 3 and 1, proceed in the same manner.

In summary, the RAM control MUX directs the multiplexing of RAM operations for DMA and disk file I/O. This multiplexing ensures that these operations are performed simultaneously at their required speeds. I/O lines are:

a. RAM CTL (RAM control), input

Control information required for multiplexing the DMA and disk file I/O. (Physically, RAM CTL represents five lines: MWE, MCE, AE/OE, PZ and CNT. See Appendix A for further description.)

b. A8, A9 (RAM page address lines), output

Two binary bits for selecting one of the three buffering pages: page 1, 2 or 3. (Physically, A8 and A9 represent two lines: PAGE13 and PAGE23. See Appendix A for further description.)

c. R/W (read/write enable), output

Signal for selecting a RAM read or RAM write operation over BD0:7. (Physically, R/W represents one line: WENB. See Appendix A for further description.)

d. CENB (chip enable), output

Signal for enabling RAM output onto BD0:7.

12. RAM Control Register

Holds information necessary for generating the RAM page number, read/write control, and chip enable as described above in Item 11. I/O lines are:

- a. BD0:7 (bus data lines 0 through 7), input

Input data related to the page number and control signals needed for I/O multiplexing at the RAM.

- b. RAM CTL (RAM control), output

Control information required for multiplexing the DMA and disk file I/O. (Physically, RAM CTL represents five lines: MWE, MCE, AE/OE, PZ and CNT. See Appendix A for further description.)

13. RAM-Address Counter for Disk File Transfer, and Latch

Specifies the address of a RAM location written to or read from a disk file. The associated latch controls the counter output to the RAM0:7 lines.

- a. BD0:7 (bus data lines 0 through 7), input

Value for determining the RAM page location from which data transfer shall occur.

- b.2 RAM0:7 (RAM address bits), output

RAM memory location for the disk file transfer.

14. RAM-Address Counter for DMA Transfer, and Latch

Specifies the address of the RAM location written to or read from the SELCH/MUX bus. The DMA transfer is always 256 bytes, i.e.; 128 halfwords. The associated latch controls the counter output to the RAM0:7 lines.

- a. CTL (control line), input

Signal for initializing the counter, which then counts up to 255 for the transfer of 256 bytes.

- b. RAM0:7 (RAM address bits), output

RAM memory location for the DMA transfer.

15. General-Purpose Data Registers

Store various data to be sent to the SELCH/MUX bus, e.g.; status, sector addresses or RPS data. These registers also store various data received from the SELCH/MUX bus for RAM input, e.g.; a cylinder or head address. I/O lines are:

- a. CTL'S (control lines), input

Three controls for determining whether general-register data is to be transmitted to the SELCH/MUX bus, received from the SELCH/MUX bus or enabled for output over BD0:7.

- b. D08:15 (data bits 8 through 15), input

Byte of information from the SELCH/MUX bus.

- c. GPD08:15 (general-purpose data), output

Register data to be sent to the SELCH/MUX bus.

- d. BD0:7 (bus data lines 0 through 7, I/O

General-purpose data sent to and received from the microprocessor controller logic.

16. DMA Data Registers

Hold data received and transmitted between the SELCH/MUX bus and RAM. I/O lines are:

- a. BD0:7 (bus data lines 0 through 7), I/O

DMA data transferred between RAM and the SELCH/MUX bus.

- b. CTL'S (control lines), input

Ten control/timing signals for loading the registers and enabling them to output data to the applicable buses.

- c. D00:15 (receive data bits 00 through 15), input

Halfword of data received from the SELCH/MUX bus, to be output to the RAM.

- d. DATA00:15 (data bits 00 through 15), output

Halfword of data to be sent to the SELCH/MUX bus.

17. DMA Control and Bus Data (BD) I/O Control

Sets up and maintains DMA transfers, via the DMA Data Registers, between the SELCH/MUX bus and the RAM. I/O lines are:

- a. CTL'S (control lines), input

Ten control/timing signals. These are also passed on to the DMA data registers.

- b. BDIO0:5 (bus data I/O and controls), input

A 6-bit code that controls the source and destination for BD0:7 and provides numerous control signals. See Appendix A for further description.

- c. CTL'S (control lines), output

Control for one of the operations selected by the decoding of BDIO0:5 input.

- d. 3200 PTCL (3200 protocol), output

Control signals to the SELCH for the new high-speed SELCH protocol. (Physically, 3200 PTCL represents two lines: STCHK and CTLOPTC. See Appendix A for further description.)

18. Control Latches

Latches halfword data (e.g.; cylinder or head address) from the processor for subsequent input to the RAM. I/O lines are:

- a. D00:15 (data halfword), input

Data halfword received over the SELCH/MUX bus from the processor.

- b. CTL'S (control lines), input

Control/timing functions required for receiving halfword data from the processor.

- c. BD0:7 (bus data lines 0 through 7), output

Halfword data latched from the processor and sent as bytes to the RAM.

19. Error Correction Code (ECC) Generation

Generates a 32-bit ECC for a disk file write or read operation.

With a write operation, ECC Generation receives serial write data from input line RSRO0, as described in Item 21 below. The circuitry then generates an ECC, which error correction control appends to the end of the 256 bytes of data written to the selected disk file.

With a read operation, ECC generation receives serial read data from input line RSRO0, as described in Item 22 below. This input, consisting of 256-bytes of data and a 32-bit ECC, is serially shifted into the ECC generation circuitry. ECC generation then generates a new ECC from the 256 data bytes, and compares it with the read ECC. If the two ECCs match, the ECC is validated.

I/O lines are:

- a. CTL'S (control lines), input

Control/timing signals necessary for generating ECCs.

- b. RSRO0 (read/write serial data), input

Serial data shifted into the ECC circuitry during a read or write operation. During a read operation, this serial input data also includes an ECC.

- c. BD0:7 (bus data lines 0 through 7), output

Error correction information output to the microprocessor logic whenever an ECC is not validated, i.e.; whenever an ECC is found erroneous.

20. Error Correction Control

Provides control circuitry necessary for ECC operations.
I/O lines are:

- a. RSRO0 (read/write serial data), input

Serial data shifted into the ECC circuitry during a write operation to a disk file.

- b. CTL'S (control lines), I/O

Control/timing signals necessary for generating ECCs and for detecting ECC errors.

- c. WDATA (write data), output

Serial data, along with a generated ECC, to be written to a disk file.

21. Parallel-to-Serial Conversion

Converts parallel RAM data from BD0:7 to serial data to be written to a disk file. This conversion circuitry applies only during disk file write operations, where data is written from the SELCH/MUX bus, via the RAM, to a disk file. I/O lines are:

- a. CTL'S (control lines), input

Control/timing signals necessary for synchronizing the resulting serial write data to the disk file.

- b. BD0:7 (bus data lines 0 through 7), input

Parallel data written from the RAM. The RAM originally received this data from the SELCH/MUX bus.

- c. WSR (write serial data), output

Serial data to be written to a disk file. WSR output is passed, via serial-to-parallel conversion, as RSRO0 to Error Correction Control. There, a 32-bit ECC from ECC Generation circuitry is appended to the end of the 256 bytes of write data.

22. Serial-to-Parallel Conversion:

Converts serial disk file data from the SDATA input to parallel data, to be sent to the RAM. This conversion circuitry applies during disk file read operations, where data is read from a disk file, to the RAM, and to the SELCH/MUX bus. Also, during a write operation, this circuitry passes WSR input as RSRO0 output to error correction control and ECC Generation. I/O lines are:

- a. SDATA (serial data), input

Serial data and ECC read from the disk file.

- b. RSRO0 (read/write serial data), output

Same serial data and ECC as above, output to the ECC generation circuitry. More specifically, for a single disk file read operation, RSRO0 contains 256 bytes of data and a trailing 32-bit ECC. This data and ECC are input to ECC Generation circuitry which checks for errors. See Item 19 above.

- c. BD0:7 (bus data lines 0 through 7), output

Parallel data sent to the RAM.

CHAPTER 4 MAINTENANCE

4.1 INTRODUCTION

Along with the table of mnemonics in Appendix A and the intelligent disk controller (IDC) board schematics, Chapter 4 presents detailed information necessary for troubleshooting the IDC board. Before reading this chapter, you should be thoroughly familiar with Chapter 3. For information pertaining to preventive maintenance on IDC disk files, see the list of related publications in Section 1.2.

4.2 MICROPROCESSOR/SEQUENCER CIRCUITRY

The heart of the IDC board is the microprocessor/sequencer circuitry. It provides, sequences, executes and routes the various microinstructions for interfacing a Series-3200 Processor and selector channel (SELCH)/multiplexor (MUX) bus with the IDC disk files. As shown in Figure 3-6, the microprocessor/sequencer circuitry consists of these functional blocks:

- Microprocessor (two 4-Bit microprocessor chips)
- Pipeline register
- Control store PROM
- Microprogram sequencer

Microinstructions are stored as part of the microprogram within the control store programmable read-only memory (PROM). Section 4.2.1 discusses these microinstructions.

The pipeline register latches each microinstruction (output from PROM) for input to the microprocessor and to the various functional blocks of the IDC controller logic.

The microprocessor, alternately referred to as the arithmetic logic unit (ALU), executes ALU instructions which are part of each microinstruction received from the pipeline register. Section 4.2.2 discusses the microprocessor.

The microprogram sequencer gives the IDC the capability of executing its stored microprogram from PROM. This capability classifies the IDC as intelligent. By acting on condition code, sequencer instruction and branch address inputs, the microprogram sequencer controls the execution sequence of the microprogram. Each 10-bit address output from the microprogram sequencer selects one of the 1024 microinstructions as the next instruction to be executed. Section 4.2.3 discusses the microprogram sequencer.

Section 4.2.4 describes the clock signals associated with microprocessor/sequencer operation.

Section 4.2.5 discusses general operation of the microprocessor/sequencer circuitry and presents examples of typical operations.

4.2.1 Microcode Instructions

A microcode instruction, or microinstruction, is a 56-bit output from control store PROM. Corresponding to these 56 bits are 56 output lines. See Figure 3-6, to the right side of the block diagram. As shown, going into the pipeline register from PROM are 56 lines (unlabeled). These same lines, which represent the 56 bits of a stored microinstruction, are output from the top of the pipeline register to these destinations: the random access memory (RAM) circuitry, the bus data Input/Output (I/O) control circuitry, the microprocessor (i.e.; the two 4-bit microprocessor chips), and the microprogram sequencer.

Table 4-1 lists the line mnemonics corresponding to the 56 microinstruction bits. These bits or lines are classified into five functional fields:

1. RAM address/control
2. Bus data I/O control
3. ALU address/control
4. Branch address/control
5. Microprogram sequencer

Sections 4.2.1.1 through 4.2.1.5 discuss the 56 output lines within these five fields.

TABLE 4-1. BIT DEFINITIONS OF THE 56-BIT MICROINSTRUCTION

BIT*	MNEMONIC	NAME	BIT*	MNEMONIC	NAME
55	BRA7	Branch Address Bit 7	26	CIN	Carry-In
54	BRA6	Branch Address Bit 6	25	POE	ALU Output Enable
53	BRA5	Branch Address Bit 5	24	MI	CC MUX Inverter Bit
52	BRA4	Branch Address Bit 4	23	RAM7	RAM Address Bit 7
51	BRA3	Branch Address Bit 3	22	RAM6	RAM Address Bit 6
50	BRA2	Branch Address Bit 2	21	RAM5	RAM Address Bit 5
49	BRA1	Branch Address Bit 1	20	RAM4	RAM Address Bit 4
48	BRA0	Branch Address Bit 0	19	RAM3	RAM Address Bit 3
47	SI3	Sequencer Instruction Bit 3	18	RAM2	RAM Address Bit 2
46	SI2	Sequencer Instruction Bit 2	17	RAM1	RAM Address Bit 1
45	SI1	Sequencer Instruction Bit 1	16	RAM0	RAM Address Bit 0
44	SI0	Sequencer Instruction Bit 0	15	BDIO5	Bus Data I/O Bit 5
43	A3	A-Register Address Bit 3	14	PZ	RAM Page Zero
42	A2	A-Register Address Bit 2	13	AE/OE	RAM Address Enable
41	A1	A-Register Address Bit 1	12	MCE	RAM Chip Enable
40	A0	A-Register Address Bit 0	11	MWE	RAM Write Enable
39	B3	B-Register Address Bit 3	10	CNT	RAM Page Counter Enable
38	B2	B-Register Address Bit 2	09	BRA9	Branch Address Bit 9
37	B1	B-Register Address Bit 1	08	BRA8	Branch Address Bit 8
36	B0	B-Register Address Bit 0	07	MC	CC MUX Selection Bit C
35	I8	ALU Instruction Bit 8	06	MB	CC MUX Selection Bit B
34	I7	ALU Instruction Bit 7	05	MA	CC MUX Selection Bit A
33	I6	ALU Instruction Bit 6	04	BDIO4	Bus Data I/O Bit 4
32	I5	ALU Instruction Bit 5	03	BDIO3	Bus Data I/O Bit 3
31	I4	ALU Instruction Bit 4	02	BDIO2	Bus Data I/O Bit 2
30	I3	ALU Instruction Bit 3	01	BDIO1	Bus Data I/O Bit 1
29	I2	ALU Instruction Bit 2	00	BDIO0	Bus Data I/O Bit 0
28	I1	ALU Instruction Bit 1			
27	I0	ALU Instruction Bit 0			

*MSB is bit 55; LSB is bit 00.

4.2.1.1 Random Access Memory (RAM) Address/Control Field

This field has thirteen bits. As shown in Figure 3-6, two outputs leave the top of the pipeline register and go to the RAM control circuitry: RAM address lines (RAM0:7) and RAM control (RAM CTL). RAM0:7 is an 8-bit address for selecting one of 256 locations within one of the four RAM pages. RAM CTL represents five control lines:

1. RAM address enable (AE/OE).

A high on this line selects RAM0:7 from the pipeline register as the RAM address source. A low selects RAM0:7 from the RAM address counter as the address source.

2. RAM page counter enable (CNT)

When high, this line enables the RAM page counter to increment to the next page.

3. RAM chip enable (MCE)

This line enables the RAM for a read or write operation.

4. RAM write enable (MWE)

This line enables RAM to be written to.

5. Page zero (PZ)

This line selects RAM page zero.

4.2.1.2 Bus Data Input/Output (I/O) Control Field

This field has six bits: Bus data I/O and control bits (BDIO0:5). BDIO0:5 contain a 6-bit code for controlling I/O over the microprocessor bus BD0:7. Table 4-2 lists the BDIO0:5 codes and the corresponding BD0:7 contents. For additional information to interpret this table, see the table of mnemonics in Appendix A.

Notice that the MODE column of Table 4-2 specifies either a read, a write or a strobe. A read denotes BD0:7 source data going into the microprocessor or RAM. A write denotes BD0:7 destination data going out of the microprocessor, RAM or map PROM. A strobe denotes one of the numerous bus data control functions. See Section 4.2.4.2 for further detail.

TABLE 4-2. BDIO0:5 VALUES FOR MICROPROCESSOR BUS FUNCTIONS

BDIO0:5		MODE & TIMING	FUNCTION MNEMONIC	FUNCTION NAME	CONTENTS OF BD0:7 BITS*								
OCT.	HEX.				BD7	BD6	BD5	BD4	BD3	BD2	BD1	BD0	
00	00	----- CLK23	NOP	No Operation									
01	01	Strobe CLK23	CINTCLR	Internal Clear									
02	02	Read CLK23	ECCLO	Load ECC Low	ECC23	ECC22	ECC21						
03	03	Read CLK23	ECCHI	Load ECC High	ECC31	ECC30	ECC29	ECC28	ECC27	ECC26	ECC25	ECC24	
04	04	R/W CLK23	XFERLO	Transfer Low Byte	**	**	**	**	**	**	**	**	**
05	05	R/W CLK23	XFERHI	Transfer High Byte	**	**	**	**	**	**	**	**	**
06	06	Read CLK23	DE	Data Enable	**	**	**	**	**	**	**	**	**
07	07	Strobe CLK23	RSTATN	Reset Attention									
10	08	Read CLK23	RBC	Read Bus Control	NEWFILE	INTREQ	EXTCLR	FILE23	FILE13	FUNC2	FUNC1	FUNC0	
11	09	Read CLK23	RRA	Read RAM Address	RAM7	RAM6	RAM5	RAM4	RAM3	RAM2	RAM1	RAM0	
12	0A	Read CLK23	EDS	Enable Disk Status	BUSY	WPROT	READY	ONCYL	SKER	FAULT	SECTOR	INDEX	
13	0B	Read CLK23	ESE	Enable Seek End and Drive Select	SKEND3	SKEND2	SKEND1	SKEND0	SEL3	SEL2	SEL1	SEL0	
14	0C	Read CLK23	RBD	Read Bus Data	D08	D09	D10	D11	D12	D13	D14	D15	
15	0D	Read CLK23	RBS	Read Bus Status	DMAGO	SELCHBZ	PARTIAL	OVERRUN	BITSR0	SECTOV	TIMEOUT	FMTENBL	

TABLE 4-2. BDI00:5 VALUES FOR MICROPROCESSOR BUS FUNCTIONS
(Continued)

BDI00:5		MODE & TIMING	FUNCTION MNEMONIC	FUNCTION NAME	CONTENTS OF BD0:7 BITS*							
OCT.	HEX.				BD7	BD6	BD5	BD4	BD3	BD2	BD1	BD0
16	0E	Read CLK23	ESTBRA	Establish Branch Address	Mask BUSY	Mask WPROT	Mask READY	Mask ONCYL	Mask SKER	Mask FAULT	***	
17	0F	Strobe CLK23	SSYN	Set Sync								
20	10	Write CLK3	LDPAGE	Load RAM Page Number					****	****	LP23	LP13
21	11	Write CLK3	LDDSK	Load Disk	RAM7	RAM6	RAM5	RAM4	RAM3	RAM2	RAM1	RAM0
22	12	Write CLK3	LDCB	Load Disk Data Bus	B07	B06	B05	B04	B03	B02	B01	B00
23	13	Write CLK3	LDCT	Load Disk Control Tag	SCT	SHT	CT	USEL Tag	(spare)	(spare)	B09	B08
24	14	Write CLK3	LDDMA	Load DMA					****	Write/ Read	DMA23	DMA13
25	15	Strobe CLK3	SATN	Set Attention								
26	16	Write CLK3	TBD	Transmitted Bus Data	GPD08	GPD09	GPD10	GPD11	GPD12	GPD13	GPD14	GPD15
27	17	Strobe CLK3	LON	Turn On Diagnostic								
30	18	Strobe CLK3	CON	Microcode Clear to Zero								
31	19	Write CLK3	INTDATA	Interrupt Data					CINT/ FINT	****	FA14	FA15
32	1A	Strobe CLK3	LOF	Clear Diagnostic								
33	1B	Strobe CLK3	DMASTRT	DMA Start								

TABLE 4-2. BDIO0:5 VALUES FOR MICROPROCESSOR BUS FUNCTIONS
(Continued)

BDIO0:5		MODE & TIMING	FUNCTION MNEMONIC	FUNCTION NAME	CONTENTS OF BD0:7 BITS*								
OCT.	HEX.				BD7	BD6	BD5	BD4	BD3	BD2	BD1	BD0	
34	1C	Strobe CLK3	SAVCRY0	Save Carry									
35	1D	Strobe CLK3	STPSLCH	Stop SELCH Strobe									
36	1E	Strobe CLK3	SETIDL	Set Idle									
37	1F	Strobe CLK3	RSTIDL	Reset Idle									
40	20	Read CLK23	DCL	Disk Status Clear and Enable	BUSY	WPROT	READY	ONCYL	SKER	FAULT	SECTOR	INDEX	
41	21	Strobe CLK23	OFF	ECC Off									
42	22	Strobe CLK23	ON	ECC On									
43	23	Strobe CLK23	SEC	Shift ECC									
44	24	Strobe CLK23	MEC	Enable ECC Shift									
45	25	Strobe CLK23	ME	Map PROM Enable									
46	26	Strobe CLK23	FOUND	Sector Found									
47	27	Write CLK23	SEL	Select Pulse							DRV23	DRV13	

* Blank entries indicate that the bit position is neither latched nor used.

** Register data I/O. See descriptions of corresponding mnemonics in Appendix A.

*** Bits BD7:2 associated with ESTBRA do not actually contain the specified mask data. However, the BD7:2 bits are ANDed with the specified mask mnemonics to enable status branches.

**** These entries indicate that the bit position is latched but not currently used.

4.2.1.3 Arithmetic Logic Unit (ALU) Address/Control Field

This field has nineteen bits. As shown in Figure 3-6, four outputs leave the top of the pipeline register and go to the microprocessor circuitry: A, B, CONT and I.

A-output represents four lines: A-register address bits (A0:3). A0:3 contain a binary value for selecting one of the ALU registers as the source A-register. Section 4.2.2 further discusses this selection.

B-output represents four lines: B-register address bits (B0:3). B0:3 contain a binary value for selecting one of the ALU registers as the source/destination B-register. Section 4.2.2 further discusses this selection.

CONT output represents two lines: Carry-in (CIN) and ALU output enable (POE). CIN is a microcode-generated carry input to the ALU. POE enables ALU output onto BD0:7. Section 4.2.2 further discusses these lines.

I output represents nine lines: ALU instruction bits (I0:8). I0:8 contain a 9-bit instruction for an ALU operation. The first three bits of this code, I0:2, denote the source of input data; the second three bits, I3:5, specify the particular ALU operation; and the third three bits, I6:8, denote the destination of results. See Tables 4-4 through 4-7 in Section 4.2.2 for detailed descriptions of I0:8.

4.2.1.4 Branch Address/Control Field

This field has ten bits: branch address bits (BRA0:9). BRA0:9 contain either a 10-bit branch address or a constant count value as input to the microprogram sequencer. These bits specify either the location of the next microinstruction to branch to or the count value for controlling microinstruction loop executions. Execution of a particular branch address depends on the microprogram sequencer field discussed below.

4.2.1.5 Microprogram Sequencer Field

This field has eight bits. As shown in Figure 3-6, two outputs leave the top of the pipeline register and go to the microprogram sequencer, via the condition code MUX and the MUX inverter. These outputs are: condition code MUX control (COND MUX CTL) and microprogram sequencer controls (CTL).

COND MUX CTL represents four lines: condition code MUX selection bits (MA:MC) and the CC MUX inverter bit (MI). MA:MC contain a 3-bit code that results in a condition code (CC) output, via the condition code MUX, to the microprogram sequencer. This CC output, along with BRA0:9, is used for a next address calculation. Table 4-3 gives the MA:MC possibilities; where necessary, see Appendix A for further description of the mnemonics. MI, the fourth bit of COND MUX CTL, inverts the CC output from the MUX inverter when required.

Sequencer instruction bits (SI0:3) contain a hexadecimal value for one of sixteen possible sequencer instructions to generate the next microinstruction address within PROM. Table 4-8 presents a detailed description of these bits.

TABLE 4-3. MA:MC VALUES FOR CC OUTPUT

MA:MC VALUE	CONDITION MNEMONIC	CONDITION NAME
0	CCMUXP	CC MUX Output
1	OFLOW	Overflow
2	SIGN	Sign Bit
3	CARRY7	Carry Bit 7
4	RSEL	Register Select
5	IPRY	Input Ready
6	SON	Latched Sync On
7	F=0	Function Equals Zero

* Condition Code (CC) output from the condition code multiplexer consists of one of the eight conditions selected by the octal value of the three bits, MA:MC. (MC is the most significant bit.) See Appendix A for further description of the selected conditions.

4.2.2 The 4-Bit Slice Microprocessors

Two identical 4-bit slice microprocessor chips are connected on the IDC board to form the 8-bit ALU circuitry. One chip handles the most significant four bits (MSBs) of each I/O byte, and the other handles the least significant four bits (LSBs). Figure 4-1 shows a functional block diagram of one 4-Bit slice microprocessor; for further information, see the block diagram of Figure 3-6. The following items discuss the functional blocks and I/O lines in Figure 4-1. Labeling in this figure is according to manufacturer's specification.

a. MicroRAM

This block, also referred to as local RAM, consists of sixteen 4-bit RAM locations. These are addressed by the A- and B-register address lines (A0:3 and B0:3). That is, A0:3 and B0:3 inputs determine which of the sixteen locations are read into the A- and B-Latches.

A0:3 and B0:3 inputs can specify the same address. Also, B0:3 specifies the RAM write location for data input via the RAM shift MUX.

b. A- and B-latches

These two latches hold output from the MicroRAM and serve as inputs to the R- and S-MUXs. Data is held in the A- and B-latches while CLK6 (see Section 4.2.4) is low, thereby avoiding any race condition.

c. R-MUX and S-MUX

These multiplexers are the two input ports to the ALU. As shown in Figure 4-1, the R-MUX passes input from either of two sources: latched bus data bits (LBD0:3 or LBD4:7, depending on whether the microprocessor is the less significant or more significant chip) or A-latch output. LBD0:7 input is also referred to as direct data. The S-MUX passes input from one of three sources: A-latch output, B-latch output, or Q-register output (Q0:3). In addition to the inputs just specified, the R- and S-MUXs can output a zero to the ALU.

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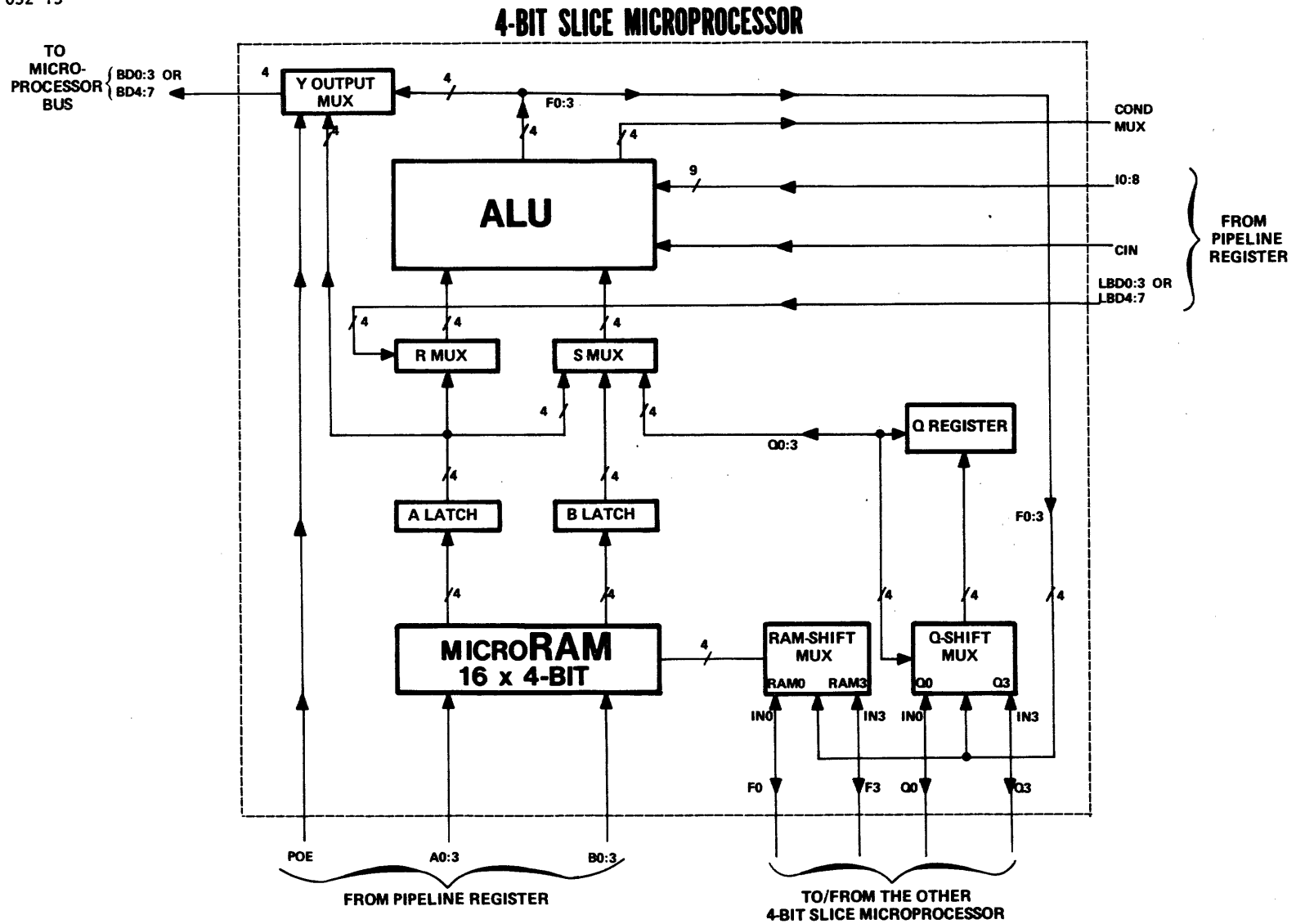


Figure 4-1 Block Diagram of the 4-Bit Slice Microprocessor

d. Q-register

The main purpose of the Q-register is to enable the double length shifts required by binary multiplication and division. Therefore, the Q-register receives, via the Q-shift MUX, both ALU output (F0:3) and its own output (Q0:3). Shifts are controlled by the ALU destination control bits I6:8; Table 4-7 specifies I6:8 values for up and down shifting.

The Q-register is also employed as a holding register or accumulator.

e. Q-shift MUX

This multiplexer receives F0:3 as input from the ALU and Q0:3 as input from the Q-register. Output to the Q-register can be shifted one bit in either direction, up or down or, not shifted at all.

The IN0/IN3 inputs and the Q0/Q3 outputs carry overflow bits resulting from an up or down shift operation. Table 4-7 presents further information on this operation.

f. RAM-shift MUX

This multiplexer receives F0:03 as input from the ALU. Output goes to the MicroRAM and, like the Q-shift MUX, this output can be shifted one bit in either direction, or not shifted at all.

The IN0/IN3 inputs and the F0/F3 outputs carry overflow bits resulting from an up or down shift operation. Table 4-7 presents further information on this operation.

g. Y-output MUX

This multiplexer receives input from either the ALU or the A-latch. When the ALU output Enable (POE) signal is active, low, the Y-output MUX outputs F0:3 or the A-register contents onto the microprocessor Bus (BD0:3 or BD4:7, depending on whether this microprocessor is the less significant or more significant chip).

Microprocessor output lines to BD0:7 are in the high-impedance state whenever POE is high.

h. ALU

Depending on the input of the ALU instruction bits (I0:I8), the ALU performs arithmetic or boolean functions. See Tables 4-4 through 4-7 for detailed information. The carry-in (CIN) input is generated by microcode to increase the number of possible functions. For the more significant ALU, CIN is the carry-out of the less significant ALU. Condition code (CC) output indicates the results of ALU instruction execution, i.e.; the execution of the I0:8 bits. It is a 4-bit condition code representing four lines: overflow (OFLOW), sign bit (SIGN), carry bit (CARRY7) and function equals zero (F=0). For further description of these four lines, see Appendix A.

4.2.2.1 Arithmetic Logic Unit Instructions From I0:8

ALU instructions are input to the ALU through nine lines: I0:8. (As previously discussed, an ALU instruction is part of the 56-bit microinstruction output from control store PROM; see Figure 3-6.) These nine bits determine data flow and control function. The first three bits, I0:2, select the input source to the ALU. The second three bits, I3:5, specify the ALU function to be performed. The third three bits, I6:8, select the destination for the results of the executed function. Tables 4-4 through 4-7 define the contents of I0:8, and Items 1 through 3 below discuss these bits.

1. ALU source selection with I0:2

See Figure 4-1. As illustrated there, input to the ALU is from the R-MUX and S-MUX. Furthermore, as discussed earlier:

- a. Input from the R-MUX to the ALU can be one of three sources: LBD0:3/LBD4:7, A-latch data or zero.
- b. Input from the S-MUX to the ALU can be one of four sources: A-latch data, B-latch data, Q0:3 or zero.

Consequently, the ALU has twelve possible input combinations, as shown below, where: A refers to A-latch, B refers to B-latch, D refers to direct data of LBD0:7, Q refers to Q-register and Z refers to zero.

R-MUX Input: AAAA DDDD ZZZZ
S-MUX Input: ABQZ ABQZ ABQZ

Since only three bits of the instruction code are available for specifying source input, only eight of the twelve combinations can be defined. However, since A and B can refer to the same MicroRAM location, the AA, AZ and DB combinations are redundant. Also, since zero/zero input is considered meaningless, ZZ is redundant. Consequently, I0:2 can specify all eight of the effective combinations. See Table 4-4.

TABLE 4-4. MICROINSTRUCTION BITS I0:2 FOR ALU SOURCE CONTROL

I0:2 VALUE			OCTAL CODE	ALU SOURCE INPUT		SOURCE MNEMONIC
I2	I1	I0		R-MUX*	S-MUX*	
0	0	0	0	A-Latch	Q-Register	AQ
0	0	1	1	A-Latch	B-Latch	AB
0	1	0	2	Zero	Q-Register	ZQ
0	1	1	3	Zero	B-Latch	ZB
1	0	0	4	Zero	A-Latch	ZA
1	0	1	5	LBD0:7	A-Latch	DA
1	1	0	6	LBD0:7	Q-Register	DQ
1	1	1	7	LBD0:7	Zero	DZ

* As represented in Figure 4-1, R-MUX and S-MUX are the two input ports to the ALU. Refer to Table 4-6 for I0:2 combinations with the I3:5 bits.

2. ALU Function Control with I3:5

Basically, I3:5 bits allow eight ALU functions to be specified three arithmetic and five boolean. See Table 4-5. However, since there are eight different ALU input combinations from I0:2, I3:5 actually allow more than just eight ALU functions. Also, the CIN bit permits additional operations. Table 4-6 shows all functions permitted with I3:5, I0:2 and CIN inputs.

TABLE 4-6. SOURCE-FUNCTION MATRIX FOR MICROINSTRUCTION BITS I0:5*

ALU FUNCTION BITS I3:5 (OCTAL VALUE)		ALU SOURCE INPUT BITS I0:2 (OCTAL VALUE)							
		AQ (0)	AB (1)	ZQ (2)	ZB (3)	ZA (4)	DA (5)	DQ (6)	DZ (7)
ADD (0)	R+S with CIN=0	A+Q	A+B	Q	B	A	D+A	D+Q	D
	R+S with CIN=1	A+Q+1	A+B+1	Q+1	B+1	A+1	D+A+1	D+Q+1	D+1
SUBR (1)	S-R with CIN=0	Q-A-1	B-A-1	Q-1	B-1	A-1	A-D-1	Q-D-1	-D-1
	S-R with CIN=1	Q-A	B-A	Q	B	A	A-D	Q-D	-D
SUBS (2)	R-S with CIN=0	A-Q-1	A-B-1	-Q-1	-B-1	-A-1	D-A-1	D-Q-1	D-1
	R-S with CIN=1	A-Q	A-B	-Q	-B	-A	D-A	D-Q	D
OR (3)	R OR S	A OR Q	A OR B	Q	B	A	D OR A	D OR Q	D
AND (4)	R AND S	A AND Q	A AND B	0	0	0	D AND A	D AND Q	0
NRS (5)	NOT R AND S	A AND Q	A AND B	Q	B	A	D AND A	D AND Q	0
XOR (6)	R XOR S	A XOR Q	A XOR B	Q	B	A	D XOR A	D XOR Q	D
XNOR (7)	R XNOR S	A XOR Q	A XOR B	Q	B	A	D XOR A	D XOR Q	D

* This table is a combination of Tables 4-4 and 4-5. If necessary, see these tables for further detail.

TABLE 4-7 MICROINSTRUCTION BITS I6:8 FOR ALU DESTINATION CONTROL*

I6:8 VALUE			OCTAL CODE	RAM SHIFTER IN/OUT		RAM FUNCTION		Q-SHIFTER IN/OUT		Q-REGISTER FUNCTION		COMMENTS
I8	I7	I6		RAM0	RAM3	SHIFT	LOAD	Q0	Q3	SHIFT	LOAD	
0	0	0	0	n/a	n/a	n/a	none	n/a	n/a	none	F to Q	Loads F0:3 to the Q-register.
0	0	1	1	n/a	n/a	n/a	none	n/a	n/a	n/a	none	Generates BD0:3/BD4:7 output only if POE control input is low.
0	1	0	2	n/a	n/a	none	F to B	n/a	n/a	n/a	none	Generates BD0:3/BD4:7 output directly from a MicrorAM A-register. F0:3 output is to a MicrorAM B-register.
0	1	1	3	n/a	n/a	none	F to B	n/a	n/a	n/a	none	F0:3 output is to a MicrorAM B-register.
1	0	0	4	F0	IN3	down	F/2 to B	Q0	IN3	down	Q/2 to Q	F0:3 output is down-shifted and input to a MicrorAM B-register: F0 output, resulting from the down-shift of the less significant MicrorAM, wraps around as IN3 input to the MSB of the more significant MicrorAM. Q-register output is down-shifted and again input to the Q-register: Q0 output, resulting from the down-shift of the less significant Q-register, wraps around as IN3 input to the more significant Q-register.
1	0	1	5	F0	IN3	down	F/2 to B	Q0	n/a	n/a	none	F0:3 output is down-shifted and input to a MicrorAM B-register as just discussed above.
1	1	0	6	IN0	F3	up	2xF to B	IN0	Q3	up	2xQ to Q	F0:3 output is up-shifted and input to a MicrorAM B-register: F3 output, resulting from the up-shift of the more significant MicrorAM, wraps around as IN0 input to the LSB of the less significant MicrorAM. Q-register output is up-shifted and again input to the Q-register: Q3 output, resulting from the up-shift of the more significant Q-register, wraps around as IN0 input to the less significant Q-register.
1	1	1	7	IN0	F3	up	2xF to B	n/a	Q3	n/a	none	F0:3 output is up-shifted and input to the MicrorAM B-register as just discussed above.

* Every I6:8 value generates a BD0:3/BD4:7 output, provided the POE input to the Y-output MUX is low. The letters n/a (non-applicable) denote a don't care combination where the associated output is in a high-impedance state. (Specifically, the shift pin is a TTL input internally connected to a 3-state output in the high-impedance state.) The terms up and down respectively refer to a shift up towards the MSB or a shift down towards the LSB.

4.2.3 Microprogram Sequencer

As its name implies, the microprogram sequencer controls the sequence of microinstruction execution. See the block diagram of Figure 3-6. To output the 10-bit address (PA0:8, SPA9) to PROM for the next microinstruction to be executed, the microprogram sequencer receives three inputs:

1. Branch Address Bits (BRA0:9)
2. Condition Code (CC)
3. Sequencer Instruction Bits (SI0:3)

From the pipeline register, BRA0:9 supplies a 10-bit branch address for the next microinstruction to be executed by IDC controller circuitry. BRA0:9 can address all of the 1024 56-bit locations within control store PROM. The actual branch address, if any, depends on the CC and SI0:3 inputs. Alternately, instead of a branch address, BRA0:9 can supply a count value for iterations (repetitive executions) of a microinstruction loop.

CC supplies one of eight condition code tests used by the microprogram sequencer for a next address calculation. Table 4-3 describes the MA:MC bits associated with the CC.

SI0:3 specify one of sixteen possible sequencer instructions. These are described later in Section 4.2.3.1. (To more easily understand the following discussions, you might want to refer there now and scan Table 4-8 to gain an overview of these instructions.)

Figure 4-2 on the next page shows a functional block diagram of the microprogram sequencer. The following items discuss the functional blocks and I/O lines shown in the figure.

a. Address/down-counter register and zero detector

This register functions either as an address register or a down counter. As an address register, it functions as a holding register to temporarily store a branch address from BRA0:9. As a down counter, it controls microinstruction loop iterations. Specifically, BRA0:9 loads the register with a count value of one less than the wanted number of iterations. Before each successive execution of a microinstruction loop, the zero detector examines the count for a zero value; if not equal to zero, the count is decremented and the loop executes. This operation continues until a zero is detected, terminating loop execution. [The decrement repeat loop (DRL), decrement repeat instruction (DRI), and three-way branch (TWB) sequencer instructions in Table 4-8 use the register as a down counter.]

The address/down-counter register is loaded with either of two sequencer instructions from Table 4-8: load counter (LDCT) or push conditional load (PCL). LDCT explicitly loads the down counter register with a count value from BRA0:9. PCL conditionally loads the address register with a branch address from BRA0:9.

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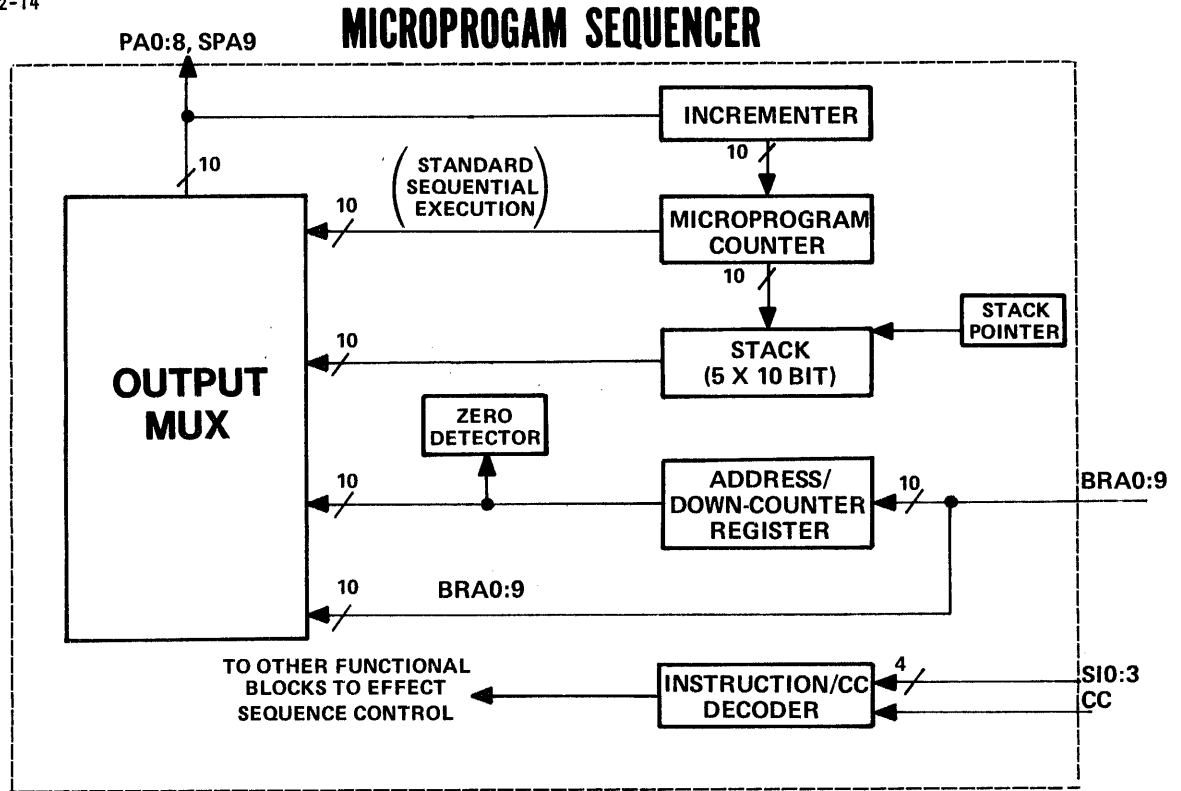


Figure 4-2 Block Diagram of the Microprogram Sequencer

b. Incrementer

The 10-bit address from the output MUX is always input to the incrementer which increments the address by a value of one before passing it to the microprogram counter.

c. Microprogram counter

Once incremented, the 10-bit address from the output MUX is stored in the microprogram counter. During standard sequential microinstruction execution, this functional block supplies the output MUX with the address of the next microinstruction to be executed by the IDC logic.

d. 5x10 bit stack with stack pointer

This functional block stores return addresses for subroutine calls. It is a 5-level first-in/first-out (FIFO) stack with a stack pointer pointing to the top address. Return address inputs and outputs of this stack are performed by push and pop operations from the sequencer instructions. A push operation increments the stack pointer and pushes an address from the microprogram counter to the top-of-stack. (Should the stack be full when an address is pushed in, the current address at top-of-stack is overwritten and lost.) A pop operation decrements the stack pointer and pops the formerly current return address from the top-of-stack. [Push operations are performed by the CC, push conditional load (PCL) and conditional call 2 places (CC2) sequencer instructions. Pop operations are performed by the DRL, conditional return (CR), conditional jump and pop (CJP), loop on fail (LOOP) and TWB sequencer instructions.]

e. Instruction/CC decoder

This functional block receives the sequence instruction bits (SI0:3) and CC input that control other-than-standard sequencing of microinstruction execution. Section 4.2.3.1 discusses the sixteen possible sequencer instruction input from SI0:3. For information pertaining to the CC bit, see Table 4-3.

With the SI0:3 and CC inputs, the instruction/CC decoder outputs the sequence control signals to numerous points throughout the microprogram sequencer to effect sequence control.

f. Output MUX

Depending on the sequencer instruction received via SI0:3, the output MUX selects an address from one of four sources:

1. BRA0:9 (direct data)
2. Address Register
3. Stack
4. Microprogram Counter

For specific source inputs, see the list of sequencer instructions in Table 4-8.

4.2.3.1 Sequencer Instructions from SI0:3

Sequencer instructions are input to the microprogram sequencer through four lines: SI0:3. (As discussed in Section 4.2.1.5, SI0:3 are part of the 56-bit microinstruction output from control store PROM.) These four lines specify a hexadecimal code for one of sixteen sequencer instructions.

Table 4-8 lists and describes these instructions. By briefly scanning the descriptions in this table, you can see that a conditional pass or fail test is used frequently to effect various operations. A pass condition occurs when the CC input is low; a fail condition occurs when CC input is high.

TABLE 4-8. SIO:3 INPUT TO MICROPROGRAM SEQUENCER

SIO:3 VALUE	INSTRUCTION NAME (MNEMONIC)	DESCRIPTION
0	Jump-to-Zero (JZ)	Used at power-up or initialization. As a result of this instruction, the address of the next microinstruction is zero, and the stack pointer resets to zero. The microprogram counter now holds an address value of 0.
1	Conditional Call (CC)	A conditional call to a subroutine, depending on whether a condition passes or fails. If the condition passes, contents of the microprogram counter are pushed onto the stack, and the microinstruction addressed by BRA0:9 is executed by the IDC logic. If the condition fails, the next sequential instruction from the microprogram counter is executed by the IDC logic.
2	Unconditional Jump (JT)	An unconditional jump to the start of a new microprogram. As a result of this instruction, the microinstruction addressed by BRA0:9 is executed, and the microprogram counter is loaded with the BRA0:9 address plus one.
3	Conditional Jump Microcode (CJ)	A conditional jump or branch in microinstruction execution, depending on whether a condition passes or fails. If the condition passes, the microinstruction addressed by BRA0:9 is executed. If the condition fails, the next sequential instruction from the microprogram counter is executed.
4	Push, Conditional Load (PCL)	Used primarily to set-up loop execution. It causes the contents of the microprogram counter to be pushed onto the stack. Then the condition is tested to determine if the down counter is to be loaded. If the condition passes, BRA0:9 contents are loaded into the down counter to become the count value. If the condition fails, the down counter is not loaded.
5	Conditional Call, 2 Places (CC2)	A conditional call to one of two subroutines, depending on whether a condition passes or fails. After the contents of the microprogram counter are pushed into the stack, the condition is tested. If it passes, the subroutine addressed by BRA0:9 is executed, i.e.; the output MUX selects the BRA0:9 address. If the condition fails, the subroutine addressed by the address register is executed, i.e.; the output MUX selects the output of the address register.
6	Conditional Jump Map (CMAP)	A conditional jump or branch based on the input of BRA0:7 from map PROM. The branch depends on a conditional test. If it passes, the next microinstruction addressed by BRA0:7 is executed. If it fails, the next sequential instruction from the microprogram counter is executed.
7	Conditional Jump, 2 Places (CJ2)	A conditional jump or branch to one of two locations, depending on the conditional test results. (This instruction is like CC2 described above, but without a stack push.) If the condition passes, the microinstruction addressed by BRA0:9 is executed. If it fails, the microinstruction at the address held by the address register is executed.
8	Decrement, Repeat Loop (DRL)	Repeats a microinstruction loop until down counter contents equal zero. Stack contains the starting address of the microinstruction loop. Before this instruction can execute, the down counter must have been loaded with a

TABLE 4-8. SIO:3 INPUT TO MICROPROGRAM SEQUENCER
(Continued)

SIO:3 VALUE	INSTRUCTION NAME (MNEMONIC)	DESCRIPTION
		value of one less than the wanted number of iterations. Before each loop, the down counter contents are examined: if contents do not equal zero, the down counter decrements and the address at top-of-stack executes; or, if contents equal zero, the stack pops and the next sequential instruction from the microprogram counter executes.
9	Decrement, Repeat Instruction (DRI)	Repeats execution of a microinstruction until the down counter contents equal zero. BRA0:9 contain the address of the microinstruction to be repeatedly executed. Before this instruction can execute, the down counter must have been loaded with a value of one less than the wanted number of iterations. Before each repetitive execution, down counter contents are examined: if contents do not equal zero, the down counter decrements and the BRA0:9 address executes; if contents equal zero, the next sequential instruction from the microprogram counter executes.
A	Conditional Return (CR)	A conditional return from a subroutine to the microinstruction following the call to that subroutine. The return depends on a pass or fail condition. If the condition passes, the microinstruction given by the stack Address is executed. If it fails, the next sequential instruction of the subroutine loop is executed, i.e.; the output MUX takes the microinstruction address from the microprogram counter.
B	Conditional Jump and Pop (CJP)	A conditional loop termination with stack maintenance, depending on conditional testing. If the test passes, the stack pops and the microinstruction addressed by BRA0:9 executes. If it fails, the next sequential microinstruction from the microprogram counter executes.
C	Load Counter (LDCT)	Loads the down counter with a count from BRA0:9 for subsequent loop iteration. It then executes the next sequential microinstruction from the microprogram counter.
D	Loop on Fail (LOOP)	Causes a loop to be executed for failure of a conditional test. That is, if the test fails, the microinstruction addressed by the contents of stack is executed. If the test passes, the stack pops and the microinstruction addressed by the microprogram counter executes.
E	No Operation (NOP)	A default instruction resulting in an increment of the microprogram counter contents and the execution of the next sequential microinstruction from the microprogram counter.
F	Three-Way Branch (TWB)	A conditional loop instruction that permits a branch to three possible microinstructions. Before TWB executes, the down counter is loaded with a count value, and the stack has a branch address pushed in. During TWB execution, the down counter value decrements by one and a conditional test occurs. If the test passes, the next sequential microinstruction addressed from the microprogram counter executes; the stack then pops. If the test fails, the down counter contents are examined: if contents do not equal zero, the microinstruction addressed by BRA0:9 executes and the stack pops.

4.2.4 Intelligent Disk Controller (IDC) Operational Cycle

The IDC is a sequential state machine with a 16MHz clock as the basic timing signal. All other timing signals are either divisions of the 16MHz clock or summations of divisions. See the IDC schematics (sheet 19, grid coordinates B and 2). This sheet shows the 16MHz oscillator of the IDC. Output from this oscillator is the OSC signal from which the other clock signals, also shown on sheet 19, are derived. For brief descriptions of the clock signals shown on this sheet, see the table of mnemonics in Appendix A.

An IDC operational cycle is 375ns, made up of six negative-going clock phases of 62.5ns. Figure 4-3 illustrates this basic system timing. The following sections describe the IDC operations occurring for the operational phases of the IDC cycle.

4.2.4.1 Intelligent Disk Controller (IDC) Instruction Decoding Phase (CLK1)

At the falling edge of CLK1, the microprocessor (the two 4-Bit slice microprocessors) and the microprogram sequencer clock-in their respective fields of the 56-bit microinstruction. More specifically, the microprocessor clocks-in the ALU instructions from I0:8, and the microprogram sequencer clocks-in the sequencer instructions from SI0:3. At the rising edge of CLK1, instruction decoding finishes. (Although there appears to be a conflict in the figure between the active CLK1 and the direct memory access (DMA) bus low phases, internal decoding times associated with these phases absorb the contention.)

4.2.4.2 Intelligent Disk Controller (IDC) Instruction Cycle

As shown in Figure 4-3, the IDC instruction cycle consists of three phases:

1. Internal IDC Operation
2. DMA Bus High
3. DMA Bus Low

The following Items discuss these phases of the instruction cycle.

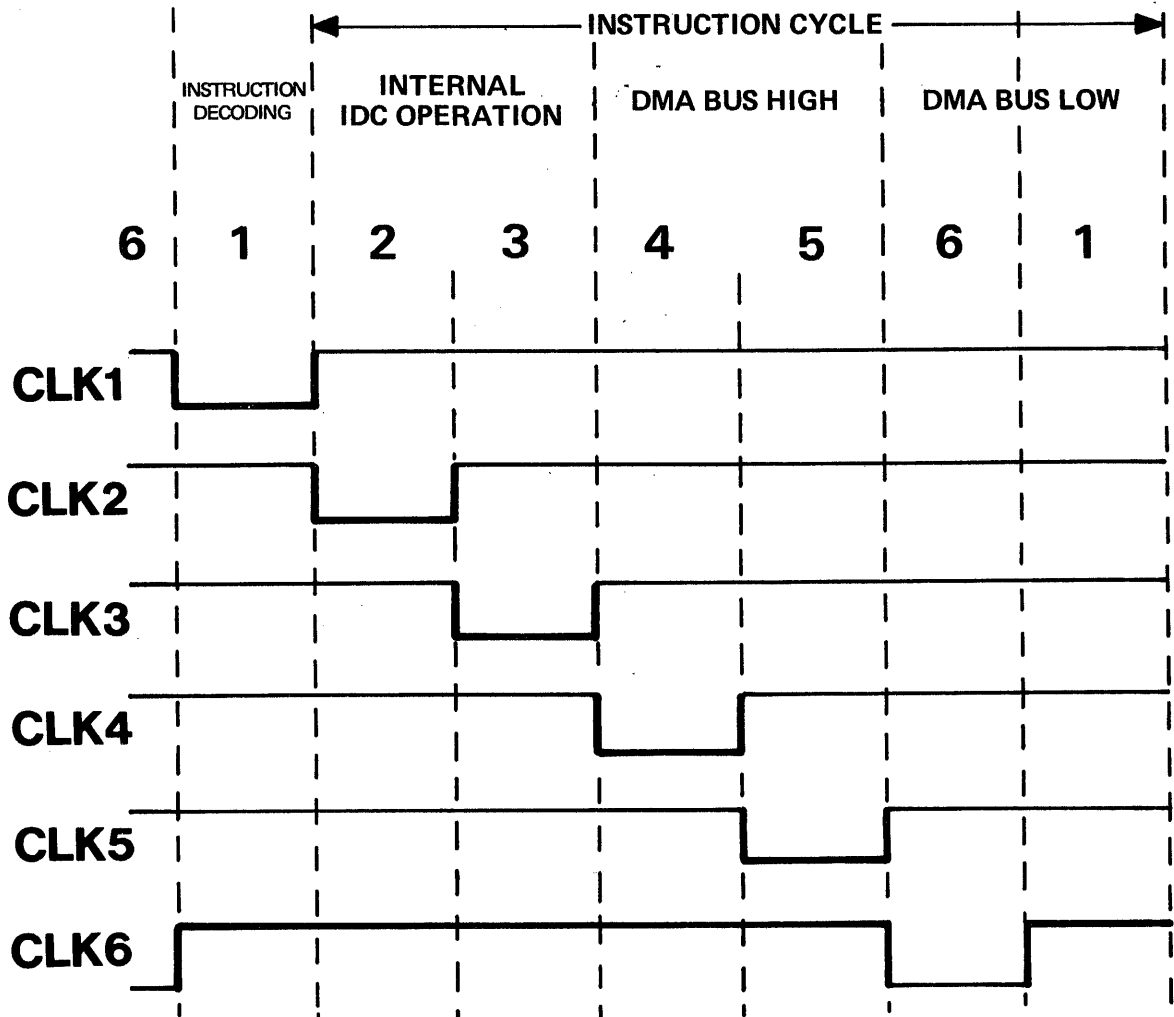


Figure 4-3 IDC Operational Cycle

1. Internal IDC Operation

This phase, occurring during CLK23 (summation of CLK2 and CLK3), encompasses IDC operations not directly related with a DMA transfer. During CLK23, the IDC RAM circuitry may be written or read with disk data. Also during CLK23, BDIO0:5 functions are active. These functions control the source and destination of BD0:7 data and provide numerous control signals.

NOTE

As shown in Table 4-2, under the MODE column, each bus function is a read, a write or a strobe. A read signifies a data source; a write, a destination; and a strobe, a control signal.

The BD0:7 bus source, as determined by BDIO0:5, can be the serial-to-parallel converter, the general-purpose data register, etc., as illustrated in Figure 3-6. During CLK23, the selected source data goes to the microprocessor/sequencer circuitry or to the RAM. The internal destinations and control strobes are active during CLK3. A destination can be the RAM address counter, the disk data bus, the disk control tag or DMA circuitry. If the BDIO0:5 function is a strobe, it performs one of the numerous control functions listed in Table 4-2.

2. DMA Bus High, and
3. DMA Bus Low

All DMA transfer is in halfword mode. Therefore, to transfer a halfword to/from the SELCH/MUX bus, two accesses with the IDC RAM circuitry are required: one access writes or reads the more significant (high) byte to or from RAM, and the other access writes or reads the less significant (low) byte to or from RAM.

If the DMA transfer is to the IDC, the IDC lines D00:15 receive a halfword from SELCH. IDC then stores this halfword into the DMA data register. (See Figure 3-6.) Thus, during CLK45 (sum of CLK4 and CLK5 phases), the high byte of data from the DMA data register is written to RAM. And, during CLK61 (sum of CLK6 and CLK1 phases), the low byte of data from the DMA data register is written to RAM.

If the DMA transfer is from the IDC, then the IDC lines D00:15 send a halfword of data to SELCH. As above, this data is first stored in the DMA data register. Thus, during CLK45 and CLK61 respectively, the high and low bytes of data are read to the DMA data register from RAM.

As evident from the preceding paragraphs, the IDC can simultaneously perform instruction execution and DMA transfer during one 375ns operational cycle. In addition, during the internal IDC operational phase, the IDC can write or read a byte of data to or from a disk file. Consequently a DMA transfer to or from a disk file, via the IDC controller logic, does not need IDC microprogram intervention until the transfer ends. Stated in broader terms, one sector of data can be written to or read from a

disk file while, at the same time, a sector of data is transferred to or from the SELCH. During these simultaneous transfers, the microprocessor controller logic checks for track boundaries and DMA statuses.

4.2.5 Microprocessor/Sequencer Operation

At the start of an IDC operational cycle, with CLK6 going high, the ALU instructions on I0:8 and the sequencer instructions on SI0:3 are latched, respectively, into the microprocessor and the microprogram sequencer. Concurrent with the latching of these inputs, the next 56-bit microinstruction is latched into the pipeline register.

The I0:8 and SI0:3 instructions decoded during the CLK1 phase are executed during the CLK23 phase. Also during CLK23, BDIO0:5 contain a value whenever a microinstruction requires bus data I/O. When a data transfer from the microprocessor onto BD0:7 is required, BDIO0:5 determines either a source or a destination, but not both. See Table 4-2. If BDIO0:5 determine a data source (read mode), the destination is the IDC RAM or the A/B registers of the ALU. If BDIO0:5 determine a destination (write mode), the source is RAM, the ALU or the map PROM. Instead of determining a source read or a destination write, BDIO0:5 can specify a control strobe.

The actual microinstruction latched into the Pipeline Register, as discussed in Section 4.2.3, depends on the CC and SI0:3 inputs and, depending on the particular sequencer instruction from SI0:3, the BRA0:9 input. These inputs alter the normal sequence of microinstruction execution. Normally, microinstructions are executed from sequential PROM locations unless the CC and SI0:3 inputs determine a branch address.

The following items present three examples of typical microprocessor/sequencer operation.

1. Example 1

Objective:

Illustrate ALU-RAM interaction by adding the contents of an IDC RAM location to the contents of a microprocessor B-register.

Initial Conditions:

- a. I0:8 contain a value of 502. From Tables 4-4 through 4-7 and Figure 4-1. A01:31 specifies register 4; B01:31 specifies register 4.
 - 5 denotes an R-MUX source of lBD0:7 and an S-MUX source of A-latch, which specifies MicroRAM register 4.
 - 0 denotes an ADD function of R-MUX input and S-MUX input.
 - 3 denotes an output over BD0:7 and a load of the same output to a MicroRAM B-register.
- b. RAM0:7 specify RAM address 87, the contents of which are to be added to B-register 4.
- c. SI0:3 contain a value of X'E' for NOP.
- d. BDIO0:5 contain a value of X'00' for NOP.
- e. BRA0:9 has no address.

Operational Sequence:

1. During CLK1, the microprocessor decodes I0:8.
2. During CLK23, these RAM controls are asserted: RAM page address bits (PAGE13,23) and RAM chip enable (CENB). These assertions result in the contents of RAM location 87 being read into BD0:7 as LBD0:7 input to the microprocessor.
3. During CLK23, according to the I0:8 value of 503, the microprocessor adds LBD0:7 input data to B-register 4.

2. Example 2

Objective:

Illustrate how the microprocessor/sequencer circuitry performs a branch within the microprogram.

Initial Conditions:

- a. I0:8 has a value of 001. From Tables 4-4 through 4-7 and Figure 4-1:

- 0 denotes an R-MUX source of A-latch and an S-MUX source of B-latch.
 - 0 denotes an ADD function of R-MUX input and S-MUX input.
 - 1 denotes only an output onto BD0:7 from the ALU should POE be active.
- b. POE input is inactive, inhibiting BD0:7 output from the ALU. Hence, the I0:8 instruction is effectively a NOP.
 - c. SI0:3 has a value of X'3' for a conditional jump (CJ).
 - d. BRA0:9 specify PROM address 34 as the branch address for the conditional jump.
 - e. CC is low to indicate a pass condition for RSEL.

Operational Sequence:

1. During CLK1, I0:8 and SI0:3 are decoded.
2. During the entire instruction cycle, RSEL is active (i.e.; CC is enabled with a low) and BRA0:9 specifies the address.
3. During CLK23, the microprogram sequencer sees an enabled CC input and executes the SI0:3 input. The resulting 10-bit address output from the microprogram sequencer causes a PROM microprogram branch to address 34.

3. Example 3

Objective:

Illustrate how BDIO0:5 lines put data onto the BD0:7 bus and into a MicroRAM B-register.

Initial Conditions:

- a. BDIO0:5 has a value of X'0A' for an EDS signal to enable disk status.
- b. I0:8 has a value of 543. From Tables 4-4 through 4-7 and Figure 4-1, A01:31 specifies register 3; B01:31 specifies register 3.

- 5 denotes an R-MUX source of LBD0:7 and an S-MUX source of A-latch, which specifies ALU register 3.
 - 4 denotes an AND function of R-MUX input and S-MUX input.
 - 3 denotes a load function of the resulting F0:F3 to a MicroRAM B-register.
- c. SI0:3 have a value of X'E' for a NOP.
- d. RAM0:7 have no address.
- e. BRA0:9 have no address.

Operational Sequence:

1. During CLK1, the microprocessor decodes ALU instruction 543.
2. During CLK23, the BDIO0:5 function of EDS causes the contents of the disk file status register to be output onto BD0:7 and to be input to the microprocessor through LBD0:7.
3. During CLK23, execution of the ALU instruction ANDs two values: the disk status input from LBD0:7 and the contents of A-register 3. The ANDed value is then stored into MicroRAM B-register 3.

4.3 SELECTOR CHANNEL (SELCH)/MULTIPLEXOR (MUX) BUS INTERFACE

This portion of the IDC board interfaces the SELCH/MUX bus of a Series-3200 Processor with the IDC controller logic. The bus interface works with the microprocessor/sequencer logic in generating the commands, data and control sequences necessary for disk file I/O. I/O through the SELCH/MUX bus is either programmed or DMA. Section 4.3.1 discusses programmed I/O, and Section 4.3.2 discusses DMA I/O. For supplemental information on signal flow and mnemonics within these two sections, refer to the IDC block diagram of Figure 3-6, the table of mnemonics of Appendix A, and the 23 IDC schematic sheets.

4.3.1 Programmed Input/Output (I/O)

The SELCH/MUX bus interface supports the standard addressing functions:

- IDC or disk file address (ADRS)
- Receive acknowledgment (RACK)

As illustrated in Figure 3-6, the IDC receives an ADRS0 signal into the control line receivers. The controller address/file address compare and select circuitry uses ADRS0 for the address comparison and selection. If the address input through D08:15 pertains to this IDC or to an attached file, either equals controller (=CONT) or equals file (=FILE) is output accordingly. This output goes to the function encoding circuits discussed later.

A received RACK0 signal, if applicable to this IDC, results in the bus interface gating the IDC address or a disk file address to the processor. That is, the controller address (CA8:15) or the file address (FA8:15) is input to the data MUX, where it is gated and output to the processor via the data transceivers. If this IDC has no interrupt pending, RACK0 is passed on out as TACK0.

In addition to the two addressing functions described above, the SELCH/MUX bus interface supports the four standard bus I/O functions:

- Status request (SR)
- Output command (OC)
- Data request (DR)
- Data available (DA)

As illustrated in Figure 3-6, the IDC receives an SR0, OC0, DR0 or DA0 signal into the control line receivers, where they are output to the control line latches. The latched signal is then output to the function encoding circuits, which also receive the =CONT or =FILE input from the controller address/file address compare and select circuitry. The encoding circuits AND the received inputs to generate an encoded (octal) signal over the IDC function lines (FUNC0:2). Table 4-9 lists the eight bus functions associated with FUNC0:2.

The assertion of one of the FUNC0:2 functions enables the register select (RSEL) signal from the function encoding circuits. During the microprocessor/sequencer idle loop, microcode monitors RSEL. On finding RSEL enabled, the microcode acts on the encoded function, along with any associated input data, and performs the necessary operations. Afterwards, microcode responds with a controller sync (CONTSYNC) or file sync (FILESYNC) to indicate successful completion of the received bus I/O function.

TABLE 4-9. FUNC0:2 VALUES FOR ENCODED MUX BUS FUNCTIONS*

FUNC0:2 VALUE	FUNCTION MNEMONIC	FUNCTION NAME
0	ILDR	Idle Controller Data Request
1	ILDA	Idle Controller Data Available
2	ILSR	Idle Controller Status Request
3	CLOC	Controller Latched Output Command
4	FLDR	File Data Request
5	FLDA	File Data Available
6	FLSR	File Status Request
7	FLOC	File Output Command

* FUNC0:2 output is an octal value corresponding to one of the eight functions. (FUNC2 is the most significant bit.) See Appendix A for further description of the specified mnemonics.

Three of the bus functions SR0, DR0 and RACK0 require the IDC to respond with output data to the processor. MUX control bits (MUX13,23) select the particular register whose contents are to be transferred through the data transceivers. (See Appendix A for a description of these bits.) The enable MUX Output (EBLOUT) signal goes active to transmit this data. However, to ensure sufficient time for the register contents to be propagated through the data MUX, EBLOUT goes active 50ns after MUX13,23.

4.3.2 Direct Memory Access (DMA) Input/Output (I/O)

Microprocessor/sequencer microcode initiates DMA I/O, a halfword transfer, by generating DMA start (DMASTRT). If the transfer is a read operation from IDC to SELCH, IDC RAM circuits are read in two sequences:

1. Load high byte (LDHIBYT) loads the more significant RAM byte into the DMA register (chip 6F, sheet 5).
2. Load low byte (LDLOBYT) loads the less significant RAM byte into the other DMA register (chip 5F, sheet 5).

Once the RAM halfword is at the DMA registers, SELCH transfer (SELCHXFR) starts the DMA transfer over the SELCH/MUX bus.

If the transfer is a write operation from SELCH to IDC, the SELCHXFR signal first causes the received halfword to be loaded into the DMA registers (Chips 7J and 5J, sheet 5). Then:

1. Read high byte (RDHIBYT) loads the more significant SELCH byte into RAM.
2. Read low byte (RDLOBYT) loads the less significant SELCH byte into RAM.

Proper synchronization between SELCH and IDC for I/O is established by two DMA transfer flip-flops (chip 17J, sheet 7). During the read operation from RAM to SELCH, these flip-flops ensure the sequential activation of the RAM and DMA transfer controls, as follows: RAMXFR, DMAXFR, RAMXFR, The less significant 17J flip-flop is initially set high by IDC read (READ) to establish this sequence. During the write operation from SELCH to RAM, the flip-flops ensure the sequential activation of the DMA and RAM transfer controls, as follows: DMAXFR, RAMXFR, DMAXFR, The less significant 17J flip-flop is initially set low by IDC write (WRITE) to establish this sequence.

Before any disk file read/write operation, the processor performs these operational steps to position the disk read/write heads to the proper track and to select a specified sector:

1. Writes the specified cylinder number to the selected disk file.
2. Issues a seek command to the selected disk file.
3. Writes the specific head number to the selected disk file.
4. Issues a set head command to the selected disk file.
5. Writes the starting sector number to the IDC.

See Section 4.4 for further discussion of the above operations.

Sections 4.3.2.1 and 4.3.2.2 further discuss the DMA read and write operations.

4.3.2.1 Direct Memory Access (DMA) Read Operation

Steps 1-10 below present the sequence of operations occurring with a DMA read, i.e.; a read of a data sector from a disk file via IDC to SELCH. Figure 4-4 shows the timing signals involved with a DMA read operation; see Appendix A for further description of the mnemonics there.

1. IDC receives a read command (a CMD0 function along with associated input data) from the processor. IDC then reads a previously specified sector into RAM page 1.
2. IDC receives a SELCH DR0 function.
3. Microprocessor/sequencer microcode then asserts DMA Start (DMASTRT).
4. DMASTRT assertion sets the DMA go (DMAGO) flip-flop and line, and resets the last word (LASTWRD) flip-flop. DMAGO starts the DMA transfer from RAM (i.e.; RAMXFR goes active).
5. The delayed DMA go (DDMAGO) line ensures that the two bytes read from RAM are stored in the DMA registers before being transferred to SELCH. During the RAMXFR operation, LDHIBYT loads the even RAM location of one byte to the DMA register; LDLOBYT loads the odd RAM location of one byte to the other DMA register.
6. To start the transfer to SELCH, provided a DR is asserted from SELCH, these signals go active: SELCHXFR, DMAXFR and XFERSYNCH. RAMXFR goes inactive.
7. A sync return (SYN) is output to SELCH after successful completion of the SELCH DR function.
8. SELCHXFR remains asserted after the SYN output to prevent another DMA operation, just yet, for another SELCH DR0 reception. XFERSYNCH, DMAXFR and SYN go inactive.
9. Transfer done (XFRDONE) is asserted once the IDC completes another RAM transfer, inactivating SELCHXFR.
10. RAM transfer repeats, starting at step 6 above, for each additional SELCH DR0 function received.

032-16

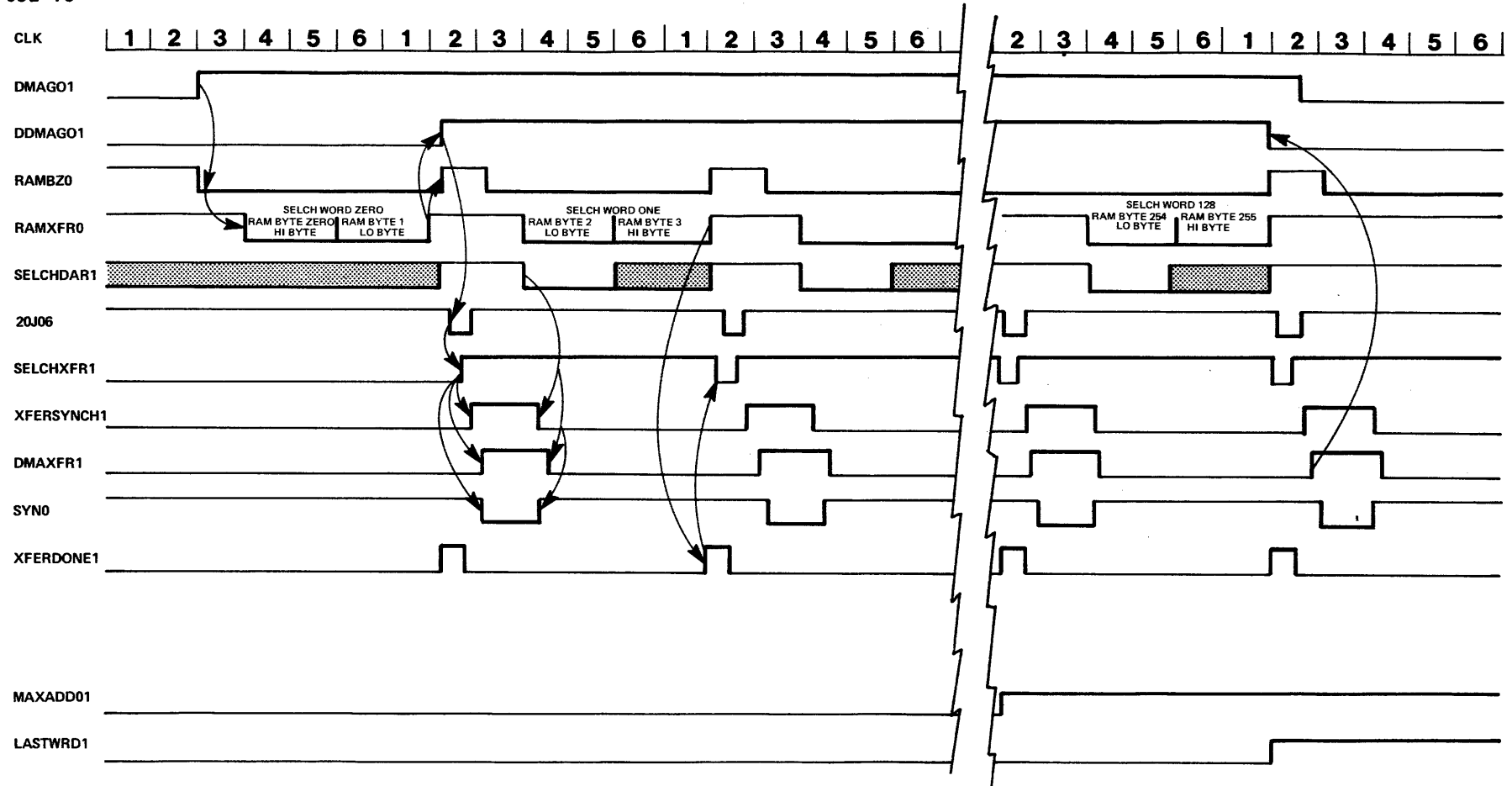


Figure 4-4 Timing Signals for a DMA Read Operation

Switching among RAM pages 1-3 during a DMA read operation is enabled with an active maximum sector count (MAXADD). MAXADD indicates that all 256 bytes of the current RAM page have been read. Once MAXADD is active, another RAMXFR operation occurs to transfer the last halfword from the current RAM page to the DMA registers. Then LASTWRD goes active, and a final DMAXFR occurs. Once this final halfword is transferred from the DMA registers, DMAGO resets. Additional pages read from the disk file are transferred in the identical manner as discussed above.

A DMA read operation ends normally by an active partial transfer (PARTIAL). PARTIAL indicates nonreception of a SELCH DR0 for 3 microseconds (μ s). More specifically, if the IDC receives no DR0 from SELCH for 3 μ s during a DMA read operation, PARTIAL is asserted. Its assertion indicates a termination of SELCH transfer.

4.3.2.2 Direct Memory Access (DMA) Write Operation

Steps 1-10 below present the sequence of operations occurring with a DMA write, i.e.; a write of a data sector to a disk file via IDC. Figure 4-5 shows the timing signals involved with a DMA write operation; see Appendix A for further description of the mnemonics.

1. IDC receives a write command (CMD0 function with associated data) from the processor.
2. IDC receives a SELCH DA0 function.
3. Microprocessor/sequencer microcode then asserts DMASTRT.
4. Step 3 sets DMAGO and resets LASTWRD. Activating DMAGO starts the DMA transfer from SELCH; i.e.; SELCHXFR, DMAXFR and XFRSYNCH go active.
5. Transfer sync (XFRSYNCH) clocks SELCH DMA data into the DMA registers.
6. A SYN is output to SELCH after successful completion of the SELCH DA function.
7. RAMXFR goes high: LDHIBYT loads the more significant byte of DMA data into the even RAM location; LDLOBYT loads the less significant byte of DMA data into the odd RAM location.
8. SELCHXFR remains asserted after the SYN output to prevent another DMA operation, just yet, for another SELCH DA0 reception. XFRSYNCH, DMAXFR and SYN go inactive.
9. XFRDONE activates, clearing SELCHXFR once both bytes are written into RAM.
10. DMA transfer repeats, starting from step 5, for each subsequently received SELCH DA0 function.

032-17

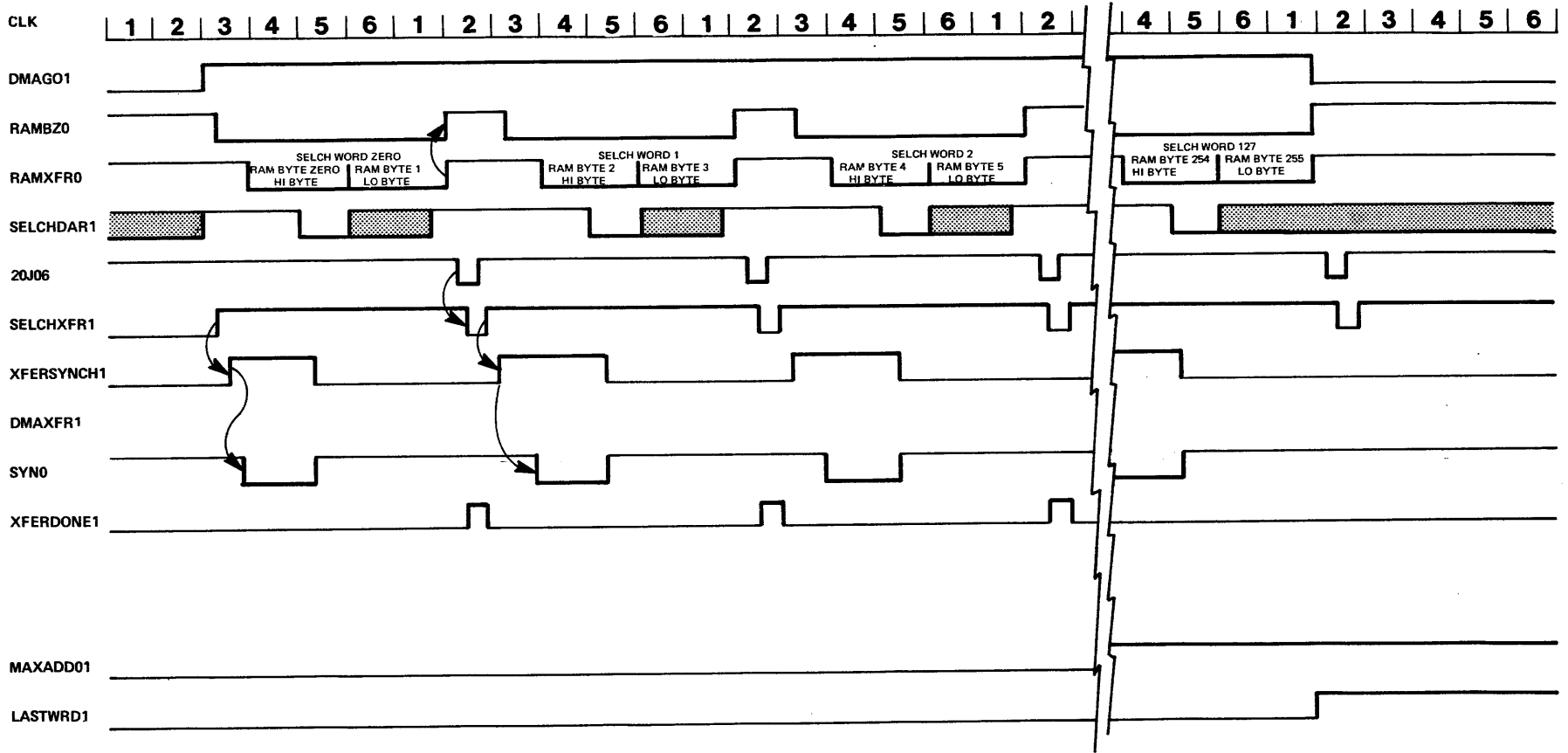


Figure 4-5 Timing Signals for a DMA Write Operation

Switching among RAM pages 1-3 during a DMA write operation is enabled with an active MAXADD, which indicates that 256 bytes have been written to the current RAM page. Once MAXADD is active, another RAMXFR operation occurs to transfer the last halfword from the DMA register to RAM. This final transfer activates LASTWRD to stop the DMA. LASTWRD gated with WRITE inactivates DMAGO. Additional pages read from the DMA registers are transferred in an identical manner.

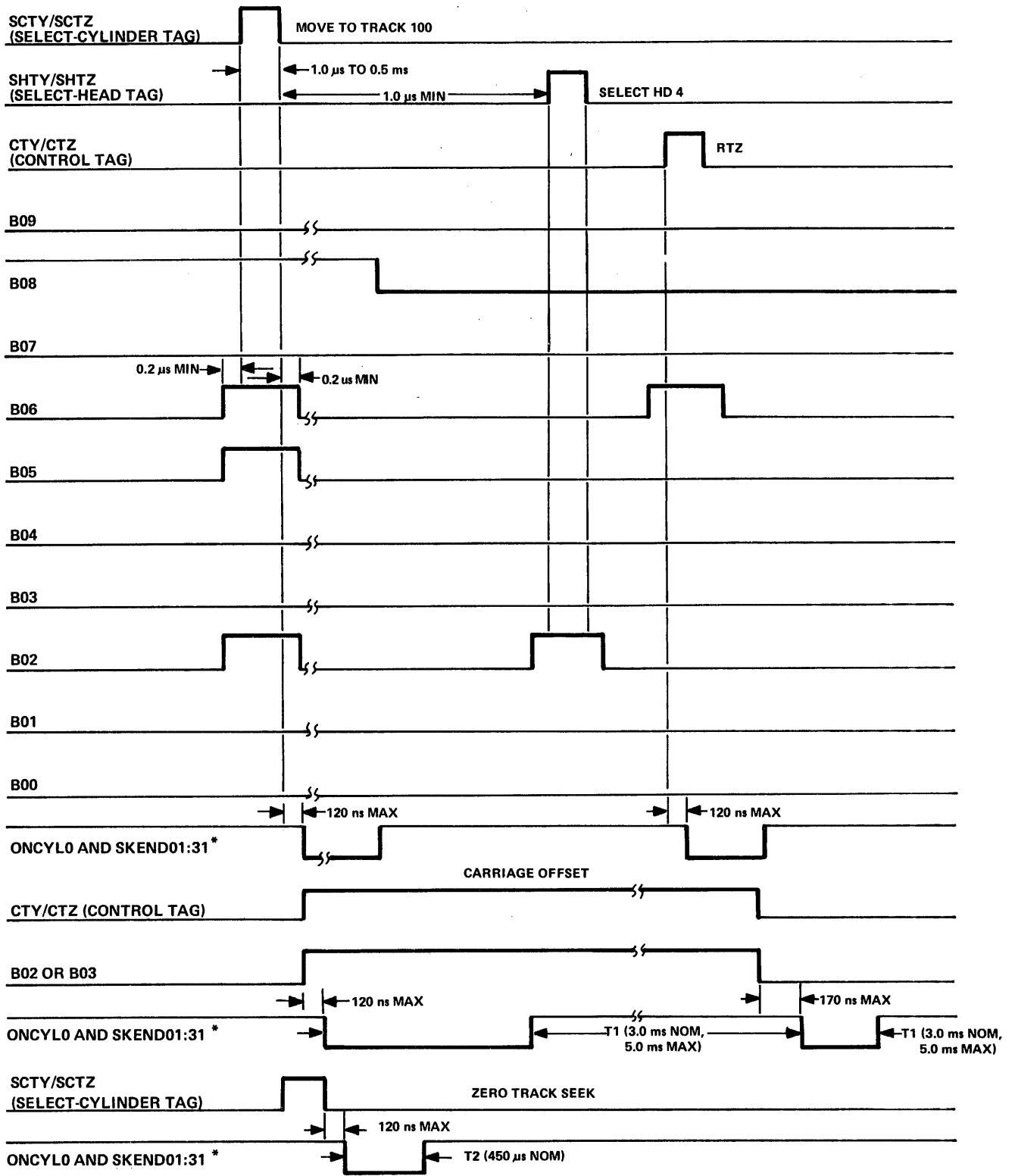
A DMA write operation ends normally by an active PARTIAL, which indicates nonreception of a SELCH DA0 for 3 μ s. That is, if the IDC receives no DA0 from SELCH for 3 μ s during a DMA write operation, PARTIAL is asserted. Its assertion indicates a termination of SELCH transfer.

4.4 DISK FILE INTERFACE

This portion of the IDC board interfaces disk files with the IDC controller logic. Specifically, it works with the microprocessor/sequencer logic to generate necessary control sequences, data and error correction code (ECC). Sections 4.4.1 through 4.4.6 discuss the major operational areas required for disk file I/O. Figure 4-6 presents timing signals for the various control and address lines discussed in these sections. For supplemental descriptions, see Appendix A.

4.4.1 Unit Selection

The first operation the interface must perform is disk file selection. To do this, the microcode places the unit select number (from RAM page 0) onto BD0:7. From BD0:7, the microcode-generated select pulse (SEL) loads the unit select number into the disk file number flip-flop (chip 23, sheet 17). The dual line driver (chip 18A, sheet 17) puts the disk file number onto the A-cable unit select lines (USEL0,USEL1). Next the microcode generates a unit select tag (USTAG). To do this, the microcode generates BDIO0:5 output specifying a load control tag (LDCT) function; see Table 4-2. To ensure proper disk file selection, the microcode issues a BDIO0:5 specifying an enable drive select (ESE) function. This ESE latches the unit selected tag (USEL0:3) and enables it as disk file selected (SEL0:3) onto BD0:7. Finally, the microcode compares SEL0:3 with the actual driver select bits 13 and 23 (DRV13,23) value. They should match to indicate proper selection.



* SIGNALS ARE IDENTICAL UNLESS SKER1 OCCURS.

Figure 4-6 Tag and Bus Timing

4.4.2 Selecting Disk File Cylinder and Head

The next operation in any read or write operation is to correctly position the disk file heads to the correct head and cylinder address. To position the heads, the microcode issues two BDIO0:5 outputs: the first specifies a load disk data bus (LDCB); the second specifies an LDCT. The LDCB loads the head address, latched in the load disk bus register (chip 15E, sheet 14), to BD0:7 and transmits it over the A-cable. The LDCT sends a select-head tag (SHT), latched in the load disk control tag register (chip 16E, sheet 15), to BD0:7 and transmits it over the A-cable.

Likewise, to select the particular cylinder, microcode issues a BDIO0:5 specifying an LDCB and another BDIO0:5 specifying an LDCT for the select cylinder tag (SCT). See Table 4-2. Since cylinder selection may take up to 65ms, the IDC goes idle once the SCT is issued. The IDC is then free to perform another command if the processor should issue one. While in the idle state, the ALU checks for a seek end (SKEND) from any disk file with the SHT in progress. To do this, the microcode issues a BDIO0:5 enable seek end (ESE) and loads SKEND onto BD0:7 via the selected seek-end register (chip 16C, sheet 15).

4.4.3 Disk File Status Check

When the processor requests a disk file status check, the IDC first ensures the particular disk file is currently selected. If that file is not selected, IDC selects it. The status of the disk file is latched by BDIO0:5 enable disk status (EDS) and put onto BD0:7 via the enable disk status register (chip 15C, sheet 14). The IDC then maps these status bits into the corresponding status bits for the Series-3200 Processor.

4.4.4 Decoding Index and Sector Pulses

During various read/write operations, the IDC must decode index (INX) and sector (SECT) pulses. INX pulses received from the B-cable are multiplexed into the disk drive index pulse (INDEX) via the selected index MUX (chip 12A, sheet 16), depending on the selected disk file. The SECT pulses from the B-cable are multiplexed into the Sector pulse (SECTOR) via the selected sector MUX (chip 12A, sheet 17), according to the selected drive. INDEX and SECTOR are output onto BD0:7 under microprogram control via the enabled disk status register (chip 15C, sheet 14) and disk status clear and enable (DCL).

4.4.5 Disk File Read Data Path

Once disk file heads are positioned over the data field of the sector to be read, microcode activates the read gate (RGATE). Then, read data (RDAT) and read clock (RCLK) from the selected disk file are received through the B-cable. Data read from the disk is selected by the 8-to-1 MUX (chip 9A, sheet 16), emerging as read/write clock (RWCLK).

SDATA is clocked into the serial-to-parallel converter (chips 14K and 15K, sheet 18) by RWCLK. When a sync word is detected here, SYNC goes active to enable the byte synchronizer (chip 22R, sheet 7) to generate data register ready (IPRDY). IPRDY indicates the serial-to-parallel converter contains two bytes of data to be written to IDC RAM. Microcode, which monitors IPRDY, then generates XFERHI and XFERLO to enable the less significant and more significant byte of read data to be transferred over BD0:7 to the IDC RAM. This halfword transfer occurs repeatedly until a full sector of 256 bytes are read. The same serial data is also fed to the ECC circuitry (sheet 11) as read serial disk Data (RSRO) for accumulation and comparison.

4.4.6 Disk File Write Data Path

When the heads are positioned over the data field of the sector to be written, microcode turns on the write gate (WGATE). At this time, the microcode will have filled the parallel-to-serial converter (chips 14J and 15J, sheet 18) with the first two bytes of RAM data to be written to the sector. To fill the parallel-to-serial converter with a halfword, microcode issues a BDIO0:5 transfer low byte (XFERLO) and transfer high byte (XFRHI). The less significant byte is loaded into the write shift register (chip 14F, sheet 18) from BD0:7. The more significant byte is loaded into the other half of the write shift register (chip 15F, sheet 18) from BD0:7.

The byte synchronizer (chip 22R, sheet 7) generates bit 151 inverted (09R08) to control the loading and shifting of the parallel-to-serial converter. When 09R08 is low and RWCLK jumps to high, data from chips 14F and 15F are loaded into the converter. When 09R08 is high and RWCLK jumps to high, data from the converter is serially shifted. Thus, the serial-to-parallel register is loaded by RWCLK and shifted for fifteen RWCLK periods.

Data emerges from the registers as write serial data (WSR) and goes to the data 8-to-1 MUX (chip 9A, sheet 16). The asserted WGATE signal causes this data to emerge as serial read data (SDATA). SDATA is fed into the shift register (chip 14K, sheet 18) and is shifted with RWCLK to produce RSRO. RSRO now goes to the data/ECC selector (gate 18R01, sheet 7), where it emerges as WDATA to be sent to the selected disk file over the B-cable. WDATA is also fed to the ECC Input (gate 16R04, sheet 11), where it is used to form the ECC.

The parallel-to-serial halfword transfer repeats until 256 bytes of data are written to the sector. Microcode then enables ECC feedback bit 31 (ECC31), the output of the ECC registers, onto the WDATA line. Consequently, the 32-bit ECC is appended to the sector of write data.

4.5 ERROR CORRECTION CODE (ECC) CIRCUITRY

This circuitry, although part of the IDC controller logic of Figure 3-6, is discussed here, after the disk file interface, because of its logical association.

The ECC circuitry shown on Sheet 11 of the IDC schematic, uses this formula to generate a 32-bit ECC:

$$X^{32} + X^{23} + X^{21} + X^{11} + X^2 + 1$$

During a write operation, the ECC circuitry appends the generated ECC to the sector written to a selected disk file. During a read operation, the ECC circuitry compares the generated ECC with the ECC appended to the sector read from the selected disk. Whenever a mismatch occurs during this comparison, the ECC error detection bit (BITSR) becomes active (low).

The following operations occur for ECC generation during a disk file write:

1. The ECC registers (sheet 11) are initialized by a shift of 32 0-bits from the phase lock oscillator (PLO) field of the formatted disk media.
2. Microcode sets the accumulate ECC (ACCECC) signal.
3. Serial data (RSRO) to be written to a disk sector is fed through the ECC registers. The first 1-bit input sets ECC contents according to the above generation formula; i.e.; the first 1-bit sets the 32nd, 23rd, 21st, 11th and 2nd flip-flops.
4. Each additional bit causes mixing, or accumulation.
5. Once the ECC registers accumulate the last bit of the sector to be written, microcode asserts ECC Off (OFF) to place the registers into the shift mode. Consequently, the ECC is appended to the written sector.

The following operations occur for ECC generation/comparison during a disk file read:

1. The ECC registers (sheet 11) are initialized by a shift of 32 0-bits from the PLO field of the formatted disk media.
2. Microcode sets the accumulate ECC (ACCECC) signal.
3. Serial data (RSRO) read from a disk sector is fed through the ECC registers. ECC accumulation begins with the first 1-bit after the sector sync word. This bit sets ECC contents according to the above generation formula.
4. Each additional bit causes mixing, or accumulation.
5. Once the ECC register accumulates the last bit of the read sector, the ECC appended to that sector is compared to the newly accumulated ECC. The comparison is accomplished by shifting the 32-bit ECC into the ECC registers.
6. If the two ECCs match, BITSR remains inactive (high) and the ECC registers contain only zeros. The current sector, just loaded into IDC RAM, is enabled for DMA transfer.
7. If the two ECCs mismatch, indicating an ECC error, BITSR goes active (low) and the ECC register contents are nonzero.
8. Microcode automatically rereads the same sector. If the error persists, microcode implements ECC operation as discussed below.
9. To internally correct an ECC error of 11 bits or less, the microcode:
 - a. Generates BDIO0:5 load ECC low (ECCL0), which results in ECC21:23 being read onto BD5:7 of the BD0:7 bus. (See Table 4-2, BDIO0:5 value X'02'.) These three syndrome bits, needed to perform the correction, are stored in RAM.
 - b. Generates BDIO0:5 load ECC high (ECCHI), which results in ECC24:31 being read on to BD0:7. (See Table 4-2, BDIO0:5 value X'03'.) These eight syndrome bits, needed to perform the correction, are also stored in RAM.
 - c. Shifts the ECC register, still containing the syndrome bits, 40,907 times to initialize it to the first bit position of the read sector, which is now in the current RAM page.
 - d. Shifts the ECC register one bit at a time up to 2,048 bit shifts. After each shift, microcode examines BITSR for a low (error) setting:

If BITSR is low, the microcode ORs the ECC21:31 syndrome bits with eleven bits in RAM, starting at the same bit position. This operation implements the correction. Execution now repeats from step (5).

If BITSR is not found as low throughout the 2,048 shifts, an additional 32 bit shifts are examined to see if the error occurred in the 32-bit ECC itself. If BITSR equals low here, the error occurred in the ECC, thus the data was read correctly; execution repeats from step 5. However, if BITSR is still not found as low, an uncorrectable ECC error exists. The IDC controller status will be set to X'0B'. See the IDC Programming Manual for further description of this status.

TABLE 4-5. MICROINSTRUCTION BITS I3:5 FOR ALU FUNCTIONS

I3:5 VALUE			OCTAL CODE	ALU FUNCTION*	FUNCTION MNEMONIC
I5	I4	I3			
0	0	0	0	R+S (R plus S)	ADD
0	0	1	1	S-R (S minus R)	SUBR
0	1	0	2	R-S (R minus S)	SUBS
0	1	1	3	R OR S	OR
1	0	0	4	R AND S	AND
1	0	1	5	R AND S (not R and S)	NRS
1	1	0	6	R XOR S (R exclusive or S)	XOR
1	1	1	7	R XOR S (R exclusive nor S)	XNOR

* R and S respectively refer to the two input ports, R-MUX and S-MUX, represented in Figure 4-1. Refer to Table 4-6 for I3:5 combinations with the I0:2 bits.

3. ALU Destination Selection with I6:8

I6:8 bits select the destination of the F0:3 output resulting from ALU execution of bits I0:5. As illustrated in Figure 4-1, ALU output goes to one or more destinations: the MicroRAM circuitry, the Q-register circuitry and the Y-output MUX. And depending on the value of I6:8, this output can be up- or down-shifted. Table 4-7 shows the destination control associated with I6:8. With any value of I6:8, and with an active (low) POE input, the Y-output MUX outputs the F0:3 results over the microprocessor bus BD0:7.

APPENDIX A

TABLE OF IDC MNEMONICS

The following pages contain the mnemonics found in the intelligent disk controller (IDC) schematics of Appendix B and discussed throughout Chapters 1 through 4 of this manual. The SOURCE column in this table specifies the sheet number and grid coordinates of the location for each mnemonic.

MNEMONIC	SOURCE	NAME	COMMENT
ACCECC1	7C4	Accumulate ECC	Allows ECC generation.
ADRS01	3B8	IDC or Disk File Address	Input from the processor to select a device (IDC or disk file) for an I/O operation. Data bits D080:150 contain this address.
ADRS1	3D8	Received ADRS0	Indicates an active ADRS0 signal.
ADRSYN0	3N9	Address Sync	A sync return for address selection.
AE/OE1	8L4	RAM Address Enable	Gates the address lines to the RAM. That is, it selects the RAM address source: a high selects RAM0:7 from the pipeline register, or a low selects RAM0:7 from the RAM address counter.
ANYCRY1	13M1	Carry into ALU	The carry generated from the previous ALU cycle or the microcode.
AR01:31	9H2	ALU A-Register Selection Bits 0-3	A01:31 before the pipeline register.
ASERVO00:30	17D5	Disk Drive Write Clocks 0-3	Output to disk files.
ATN01	3M3	Attention	Output to the processor to signal an interrupt pending.
A01:31	9M2	A-Register Address Bits 0-3	A 4-bit binary value for selecting one of the ALU registers as the source A-register.
BAOE1	13C9	Inverted RAM Address Enable	AE/OE1 inverted.
BD01:71	12C6	8-Bit Microprocessor Data Bus	The main data path among the functional blocks of the IDC. It buses various data and control bytes.
BDIO01:51	8M9	Bus Data I/O and Control Bits 0-5	A 6-bit code that controls the source and destination for BD0:7 and provides numerous control signals. See Table 4-2 for detailed description.
BITON0	6B1	Masked CC Bit	Masked condition-code bit of the disk file status.
BIT151	7F3	Carry Bit 15	Carry bit from the serial-to-parallel converter for synchronizing microprocessor data with serial disk data.

MNEMONIC	SOURCE	NAME	COMMENT
BITSR01	11L2	ECC Error Detection Bit	A zero indicates a data read error.
BL	6K8	Reset SELCH Transfer	Terminates DMA transfer to/from SELCH.
BRA01:91	10L6	Branch Address Bits 0-9	A 10-bit branch address to the microprogram sequencer. When output from the pipeline register, BRA0:9 specify the location of the next microinstruction to branch to. BRA0:9 also load the microprogram sequencer with a count value for loop iteration. When output from the map PROM, BRA0:7 provide constant data or a branch address for a map jump.
BUSAOE0	13D9	LDR Counter RAM Address	Selects the LDR counter as the RAM address.
BUSSW0	6G3	Bus Switch	Output to SELCH to indicate IDC support for the new high-speed SELCH protocol, with an I/O Bus Switch. Pins W1 and W3 on the IDC board should be strapped for this support.
BUSYA1,B1	14A6	Differential Dual-Port Busy	Informs this IDC that a disk file has been acquired by another IDC. (Applicable only to dual-port operation.)
BUSY1	14D6	Busy Signal	Received from disk file.
B00Y1,B00Z1 thru B10Y1,B10Z1	14M-, 15M-	Differential Data Bus Bits 0-10	Output to disk files for control and address data. B10Y1,B10Z1 is a spare. These lines are alternately referred to as B00:10. See Tables 3-1 and 3-2 for further description.
B01:31	9M5	B-Register Address Bits 0-3	A 4-bit binary value for selecting one of the ALU registers as the source/destination B-register.
CARRY31	12C3	Carry Bit 3	Carry-out associated with the last operation of the less significant ALU slice.
CARRY71	12E3	Carry Bit 7	Carry-out associated with the last operation of the more significant ALU slice.
CA081:151	3C2-	Controller Address Bits 8-15	IDC address (of this controller) to be sent as MD08:15 input to the data transceivers or to the processor along with the SYN0 signal.

MNEMONIC	SOURCE	NAME	COMMENT
CBIT0	14J2	Data Bit 0	With CTAG3, it indicates an ongoing write operation to a disk file, i.e.; when both CTAG3 and CBIT are high, a write is in progress.
CBIT1	14J2	Data Bit 1	With CTAG3, it indicates an ongoing read operation to disk file, i.e.; when both CTAG3 and CBIT are high, a read is in progress.
CCLK0	19D3	Gated 10MHz Clock	Used to generate timing signals within the IDC.
CCMUXP1	6D2	CC MUX Output	The multiplexed condition code resulting from the disk file status.
CCO	12H1	Condition Code	Indicates a pass or fail for one of eight conditions. The microprogram sequencer uses CC for a next address calculation, like a conditional branch or return. See MA:MC.
CENB0	12L8	RAM Chip Enable	Enables RAM output onto BD0:7.
CINTCLR0	10J3	Internal Clear	Resets SECTOV, the watchdog timer, and various statuses of the IDC.
CINT1	4L6	Controller Interrupt	Indicates the controller portion of the IDC is generating an interrupt to the processor.
CIN1	9M9	Carry-In	Microcode-generated carry input to the ALU.
CLK10:60	19J2	Clock Phases 1-6	One of six 62.5ns phases of the 375ns IDC cycle.
CLK12D0	19K3	Delayed Clock Phase 1/2	Delayed summation of CLK10 and CLK20.
CLK12345D1	19G1	Delayed Clock Phase 1-5	The clock phase feedback to the input stage of the clock generator to regenerate the other clock signals.
CLK150,151	19M2	Clock Phase 1/5	Summation of CLK10 and CLK50.
CLK230,231	19M3	Clock Phase 2/3	Summation of CLK20 and CLK30.
CLK34D0	19K3	Delayed Clock Phase 3/4	Delayed summation of CLK30 and CLK40.
CLK450,451	19M3	Clock Phase 4/5	Summation of CLK40 and CLK50.

MNEMONIC	SOURCE	NAME	COMMENT
CLK641	19K2	Clock Phase 6/4	Summation of CLK60 and CLK40.
CLOC0	3L6	Controller Latched Output Command	Indicates a received CMD0 signal from the processor, e.g.; read, write or format sector.
CL0701	3B9	Early Power Failure	Input from the processor to signal an imminent power failure.
CMD01	3J4	Command	Input from the processor to signal the presence of a command on data bits D080:150.
CNT1	8L6	RAM Page Counter Enable	When high, it enables the RAM page counter to increment to the next page.
=CONT	3E6	Equals Controller	Indicates that the received controller address matches the address of this IDC. Also, it indicates that the FUNC0:2 bits apply to this selected IDC.
CONTACK0	4N5	Controller Acknowledge	An acknowledgment from the processor for the controller address of this IDC.
CONTSEL1	3H6	Controller Selected	Indicates the processor has selected the controller address of this IDC.
CONTSYNC0	3E8	Controller Sync Return	Indicates the IDC has properly accepted and responded to a control line signal.
CON0	5M5	Microcode Clear to Zero	Internally resets the IDC and causes the microcode to go to zero.
CRST0	19F7	Controller Reset	Either an EXTCLR or an OCRST.
CTAG31	15J8	Control Tag 3	Causes execution of the disk file function associated with the contents of B00:B09. See Table 3-1.
CTLOPTCL1	3F5	Controller in Optional Protocol	See OPTPTCL1.
CTY1,Z1	15M-	Differential Control Tag	Output to disk files to indicate that bus lines B00:09 are supplying a driver command.

MNEMONIC	SOURCE	NAME	COMMENT
DAR1	7H7	Data Available or Requested	Indicates a DAO or a DRO received from the SELCH during a DMA.
DATA001:071	5G2-	Data Bits 0-7	More significant byte of DMA data to be sent to SELCH.
DATA081:151	5G5-	Data Bits 8-15	Less significant byte of DMA data to be sent to SELCH.
DA01	3J2	Data Available	Input from processor or SELCH to inform the IDC of a write operation to the selected IDC or disk file. Data is available on data bits D000:150.
DA1	3K2	DA0 Received	Output resulting from a DA0 input.
DCL0	5M7	Disk Status Clear and Enable	Clears various counters and registers associated with the disk file interface.
DDMAGO0,1	6C7	Delayed DMA Go	A delayed DMAGO signal -- a one-buffer delay on a read operation.
DE0	5K3	Data Enable	Reads the map PROM register to BD0:7.
DLYSUS1	6L9	Delay 3 Microseconds	Sets partial flip-flop if SELCHDAR1 is not received within 3 μ s and if the partial counter is not enabled.
DLYSYNC0	6M2	Delayed Sync Return	Either the DMA sync signal to the SELCH (resulting from SELCHSYN) or the interrupt-acknowledgment signal (resulting from OURACK0) to the processor.
DMAGO0,1	6J6	DMA Go	Indicates that the IDC is performing a DMA transfer to the SELCH.
DMASR0	6H1	DMA Status Request	A status request from the SELCH to this idle IDC.
DMASTR0	5M5	DMA Start	Microcode bit to start DMA operation. It sets the DMAGO flip-flop and resets the LASTWRD flip-flop.
DMAXFR1	6S5	DMA Transfer	Indicates an ongoing DMA transfer.
DMA130,230	12K8	DMA Bits 13 and 23	DMA RAM-page bits, encoded.

MNEMONIC	SOURCE	NAME	COMMENT
DRV131:231	17K4	Drive Select Bits 13 and 23	Two binary bits to select one of four disk files.
DR01	3J2	Data Request	Input from processor or SELCH to inform the IDC of a read operation from the selected IDC or disk file. Data is requested from D000:150.
DR1	3K1	DR0 Received	Output resulting from DR0 input.
DSBCRY0	13J1	Disable Carry	Clears CARRY7.
D000:150	4E-	Data Bits 0-15	I/O consisting of data, an address, a command or a status.
D001:151	4E-	Received-Data Bits 0-15	Output corresponding to D000:150 for received data from the SELCH/MUX bus.
EBLD01:41	5J7	Enable-Decoder Bits 0-4	Select one of the five BDIO decoders (the 3-8 decoders).
EBLOUT0	4G3	Enable MUX Output	Enables MUX bus data output, i.e.; sets the transceiver mode to transmit or receive.
EBLPRTL1	6H9	Enable Partial	Enables the partial counter to determine if a partial DMA has occurred.
EBLTCLK0	14D9	Enable Clock	Can be used in an IDC developmental system to disable the 16MHz clock and to enable TSTCLK.
ECCCLK1	7M3	ECC Clock	Clock to ECC circuitry for generating correction code.
ECCHI0	5K3	Load ECC High	Indicates the more significant byte of the ECC syndrome is loaded onto BD0:7. Specifically, it reads ECC24:31 to BD0:7.
ECCL00	5K3	Load ECC Low	Indicates the less significant byte of the ECC syndrome is loaded onto BD0:7. Specifically, it reads ECC21:23 to BD5:7.
ECC001:311	11-	ECC Output Bits 0-21	The 32 bits of the ECC generator.
ECC311	11A6	ECC Feedback Bit 31	The 32nd bit of ECC fed back into ECC circuitry.

MNEMONIC	SOURCE	NAME	COMMENT
EDS0	5K5	Enable Disk Status	Indicates that the disk file status register is loaded onto BD0:7.
EOXFRL	6R4	End of Transfer	Inverted PARTIAL0 input.
ESE0	5K5	Enable Seek End and Drive Select	Indicates that the seek-end/drive-select register is loaded onto BD0:7.
ESTBRA0	5K6	Establish Branch Address	Enables disk status into the condition code MUX.
EXTCLK1	19C4	External Clock	A test clock signal associated with TSTCLK0.
EXTCLR0	3H7	External Clear	An externally generated IDC reset resulting from the ORing of three signals: TESTCLR0, SCLR0 and CL070.
FAULTA1,B1	14A1	Differential Fault	Input indicating a fault condition at a disk file.
FAULT1	14D2	Disk Drive Fault	Indicates that the selected disk file is experiencing a fault condition.
FA081:151	3G1	File Address Bits 8-15	File address to be sent as MD081:151 input to the Data Transceivers, or to be sent to the processor along with the sync signal SYN0.
FILEACK0	4N6	File Address Acknowledge	An acknowledgment from the processor for one of the disk file addresses of this IDC.
FILESEL1	3J7	File Selected	Indicates the processor has selected one of the disk file addresses of this IDC.
FILESYNCO	3L9	File Sync Return	Indicates that an attached disk file has properly accepted and responded to a control line signal.
=FILE1	3F6	Equals File	Indicates that the received file address matches the address of a disk file at the IDC. It also indicates that the FUNC0:2 bits apply to a selected disk file.
FILE130,131 and FILE230,231	3H8-	File Address Bits 13 and 23	Two binary bits with one of the four disk file addresses (0-3).

MNEMONIC	SOURCE	NAME	COMMENT
FINT1	4L6	File Interrupt	Indicates a disk file is generating an interrupt to the processor.
FLDA0	3L7	File Data Available	Indicates a disk file received a DA0 signal from the processor. The data available is the cylinder or head address of the currently selected disk file.
FLDRO	3L7	File Data Request	Indicates a disk file received a DRO signal from the processor. Consequently, the disk file returns an RPS or an X'FE' to the processor.
FLOC0	3L8	File Output Command	Indicates a disk file received a CMD0 signal from the processor, e.g.; seek, set head or RTZ.
FLSRO	3L7	File Status Request	Indicates a disk file received an SRO signal from the processor. As a result, the IDC returns the status of the currently selected disk file.
FMTENBL1	3G6	Format Enabled	Indicates that toggle 8 of the file 0 Address Switch is pushed down to the 1-position to enable IDC formatting.
FOUND0	5M8	Sector Found	Test point to indicate whether or not the IDC has found the sector to be written to or read from.
FUNC00:20	3N6	IDC Function Lines 0-2	One of eight encoded functions output to BD0:7. See Table 4-9.
F=0	12F2	Function Equals Zero	Indicates ALU computation equals zero.
GME0	12K1	Gated Map PROM Enable	Enables the map PROM outputs onto BRA0:7.
GOTO00	19M6	Go to Address Zero	Forces microcode to address zero.
GPD081:151	5F9	General-Purpose Data Bits 8-15	Control data to be sent as MD081:151 input to the data transceivers.
HOLD0/PICK0	17K2	Power Sequence Hold/Pick	Two lines with which the processor picks and holds the power sequencing capability for disk files in the remote mode. When the processor is turned on, IDC logic applies a ground to these lines to sequentially power-up the attached disk files.

MNEMONIC	SOURCE	NAME	COMMENT
HWO	6F2	Halfword Mode	Output to SELCH indicating that this IDC is a halfword-oriented device.
IDLE0,1	6D9	Controller Idle	Indicates IDC not performing any operation.
ILDA0	3L5	Idle Controller Data Available	Indicates a received DA0 signal from the processor while the IDC was idle. Specifically, it indicates the processor has data (sector number) to be written to the IDC.
ILDRO	3L5	Idle Controller Data Request	Indicates a received DR0 signal from the processor while the IDC was idle. Serves no function; just results in zero being returned to the processor.
ILSR0	3L6	Idle Controller Status Request	Indicates a received SR0 signal from the processor while the IDC was idle. It directs the IDC to return the current IDC status to the processor.
INDEX1	16M2	Disk-Drive Index Pulse	Indicates that the index pulse is being received from the selected disk file.
INGPG1	13C8	Enable Page Counter Increment	Enables the page counter to be incremented while sectors are read from a disk file.
INTCLK1	19C3	Internal Clock	A 16MHz signal associated with OSC0.
INTCLR0	10M3	Internal Clear	Internally generated IDC reset signal.
INTDATA0	5M5	Interrupt Data	Loads interrupt register with data.
INTREQ1	4K3	Interrupt Request	Indicates that this IDC is requesting an interrupt from the processor.
INX0A1,0B1 thru INX3A1,3B1	16H1-	Differential Index	Input from a disk file to mark the leading edge of sector zero for every disk revolution.
IprDY1	7F4	Data Register Ready	For a read it indicates the serial-to-parallel converter contains the two bytes of data written to the IDC RAM. For write, it indicates the parallel-to-serial converter is empty.

MNEMONIC	SOURCE	NAME	COMMENT
IPRY0,1	3M4	Input Ready	Indicates the write shift register (WSR) is filled or that the read shift register (RSR) is emptied.
I01:81	9N6	ALU Instruction Bits 0-8	The nine instruction bits required by the ALU to perform an operation. See Tables 4-4 thru 4-7 for further description.
LASTDA0	6J5	Last Data Available	Indicates the last DA0 signal received from SELCH during a DMA transfer.
LASTWRD1	6K7	DMA Last Halfword	Indicates the last halfword of a sector is being DMAed via SELCH.
LBD01:71	12K1	Latched Bus Data Bits 0-7	Latched data from BD0:7 for ALU input. Or, as input to the map PROM, LBD01:71 causes output of either constant data or a microroutine address.
LDAL	3N2	Latched Data Available	Latch signal corresponding to DA input.
LDCB0	5N3	Load Disk Data Bus	Loads disk Data Bus Bits, B00:07. See Table 4-2.
LDCT0	5N3	Load Disk Control Tag	Loads control tags and B08:09. See Table 4-2.
LDDMA0,1	5N3	Load DMA	Loads RAM page and mode (read or write) into DMA.
LDDSK0	5N3	Load Disk	Loads the bus RAM-address counter for disk I/O.
LDHIBYT1/ LDLOBYT1	6C6	Load High/Low Byte	Loads the halfword data registers for MUX bus I/O from BD0:7.
LDPAGE0	5N3	Load RAM Page Number	Causes the RAM page number to be loaded from BD0:7.
LDRL	3M1	Latched Data Request	Latch signal corresponding to DR input.
LME1	12L4	Latched ME0	Latch signal corresponding to ME0.
LOC1	3N3	Latched Output Command	Latch signal corresponding to the OC input.
LOf0	5N5	Clear Diagnostic	Causes the diagnostic flip-flop to reset and the error LED to go off.

MNEMONIC	SOURCE	NAME	COMMENT
LON0	5N4	Turn On Diagnostic	Causes the diagnostic flip-flop to set and the error LED to light.
LP131:231	12H8	Page Counter Bits	Binary value to identify RAM pages 1-3 of the disk file during a read. (Page 0 is reserved for constants, statuses, etc.)
LSR	3N2	Latched Status Request	Latch signal corresponding to the SRL input.
MAXADD01	6H8	Maximum Sector Count	Indicates that 256 bytes of data have been DMAed via the SELCH.
MAXADD11	13D2	Maximum Address Counter 1	Indicates that the maximum DMA count is reached with the less significant DMA counter.
MAXADD21	13D4	Maximum Address Counter 2	Indicates that the maximum DMA count is reached with the more significant DMA counter.
MA1:MC1	8M7	Condition Code MUX Selection Bits A-C	Three bits to select one of eight condition codes for the next address calculation. See Table 4-3.
MCE1	8L5	RAM Chip Enable	Enables the RAM for a read or write operation.
MD081:151	4C-	Multiplexed Data Bits	One of four multiplexed data sources to be sent to the SELCH or processor.
MEC0	5M7	Enable ECC Shift	Enables the ECC register to shift continually.
ME0	5M8	Map PROM Enable	Reads the map PROM location to BRA0:7 and to the map register.
MI1	9M9	CC MUX Inverter Bit	Fourth bit of the COND MUX CTL line; see Figure 3-6. If MI is not set, condition code (CC) output is inverted.
MOUT1	12G1	Condition Code MUX Output	Output consisting of one of the eight condition code inputs.

MNEMONIC	SOURCE	NAME	COMMENT
MUX131,231	4H2	MUX Control Bits 13 and 23	Two binary bits for selecting one of four registers to be output to the MUX bus: general-purpose data register, file address register, controller address register or DMA data register.
MWE1	8L5	RAM Write Enable	Enables RAM to be written to.
NEWFILE1	3M8	New File	Indicates a new disk file has been addressed by the processor.
NOPO	5K2	No Operation	(Not connected or used.)
NOWRDS0	6M5	No Words	Indicates no words have yet been transferred in this DMA sequence.
NXCIN1	13L1	Latched ALU Carry Bit	CARRY71 latched.
OBCADY1,Z1	17K3	Differential Open Cable Detect	Output to disk files to indicate an open A-cable or a loss of IDC power.
OCRST0	4L9	Output Command Reset	A reset command from the processor to the IDC.
OC1	3K4	CMD0 Received	Output resulting from CMD0 input.
OFF0	5N7	ECC Off	Terminates ECC generation on read. On write, it causes ECC to be written.
OFLOW1	12E2	Overflow	Indicates the ALU operation produced an overflow.
ONCYLA1,B1	14A3	Differential On-Cylinder Detection	Input status from a disk file to indicate positioned heads.
ONCYL0	14D3	Not On Cylinder	Indicates the disk drive head is not on cylinder.
ON0	5N7	ECC On	Starts ECC generation on read. On write, it causes WSR data to be written
OPTPTCL1	3F6	Optional Protocol	Indicates that toggle 7 of the file 0 address Switch is pushed down to the 1-position to employ the new high-speed SELCH protocol.

MNEMONIC	SOURCE	NAME	COMMENT
OSCO	19B3	Oscillator	The 16-MHz oscillator of the IDC.
OURACK0	4M4	Our RACK0	Indicates a received RACK0 is for this IDC, which has an interrupt pending.
OVERRUN0,1	6M6	Data Overrun	Indicates a data overrun during a DMA operation with SELCH.
PAD1	4J9	Program Controller Reset	Indicates that the processor has sent an OCRST to the IDC.
PAGE131:231	12M8	RAM Page Address Bits 13 and 23	Two bits to select one of three RAM pages (1, 2 or 3) for either DMA or disk file I/O.
PARTIAL0	6M7	Partial Transfer	A partial sector transfer occurred.
PA0SPA90	10K2	SPA91 Inverted	See comment for SPA91.
PA01:81	10A1	PROM Address Bits 0-8	The nine least significant bits of the PROM address.
PA90,91	10M2	PROM Bank Address Bit 9	PA90 selects the second PROM bank of 512 words. PA91 selects the first PROM bank of 512 words.
PICK0	17K1	Power Sequence Pick	See HOLD0/PICK0 in this table.
POE0,1	9M9	ALU Output Enable	Indicates that the ALU output goes to BD0:7.
PROMEN1	10J1	PROM Enable	When low it enables access to the PROM banks.
PZ0	8L4	RAM Page Zero	Indicates selection of RAM page 0.
P11:31	Global	Pull-Up Resistor	5-volt pull-ups for guaranteed highs as inputs to IDC logic.
QSHFT21	12A2	Right-Shift of Q-Register	Right-shifts the contents of the Q-register (a barrel shifter) of the ALU.
RACK01	4J6	Receive Acknowledgment	Input from the processor to signal an interrupt acknowledgment.
RAE/OE1	8C5	PROM's RAM Enable or Output Enable	AE/OE1 before it enters the pipeline register.

MNEMONIC	SOURCE	NAME	COMMENT
RAMBZ0	7G9	RAM Busy	Indicates the RAM is busy with a read or write.
RAMXFERO,1	7G7	RAM Transfer	Indicates the IDC is performing a data transfer to the RAM.
RAM01:71	8M1	RAM Address Lines 0-7	Eight bits that select one of 256 RAM locations in a page.
RBC0	5K5	Read Bus Control	Various IDC statuses gated onto BD0:7.
RBDIO01:51	8C5-	FROM's BDIO Bits 0-5	Bus data I/O and controls before the pipeline register.
RBD0	5K5	Read Bus Data	Indicates DATA08:15 are gated onto BD0:7.
RBRA01:91	8H7, 10D6-	PROM's Branch Address Bits 0-9	BRA01:91 before they enter the pipeline register.
RBS0	5K6	Read Bus Status	Reads bus status to BD0:7.
RB01:31	9D4	PROM's ALU B-Register Selection Bits 0-3	B01:31 before they enter the pipeline register.
RCLK0A1,0B1 thru RCLK3A1,3B1	16A6-	Differential Read Clock	Input from a disk file to synchronize data read from it.
RCLK01:31	16D5-	Read Clock	Read clocks from a disk file to IDC.
RCNT1	8H6	PROM's RAM Page Counter Enable	CNT1 before it enters the pipeline register.
RCN1	9D8	PROM's Carry Bit	CIN1 before it enters the pipeline register.
RDATA01:31	16D1-	Read Data	Data read from a disk file to the IDC.
RDATA0A1,0B1 thru RDAT3A1,3B1	16A1-	Differential Read Data	Input data read from the disk file.
RDHIBYT0, RDLOBYT0	6D5-	Read High, Low Byte	Reads the high- or low-order data byte to BD0:7.
READY0	14D4	Selected Disk File Ready	Indicates the selected disk file is ready for I/O.

MNEMONIC	SOURCE	NAME	COMMENT
READ1	12D8	IDC Read	Indicates the IDC is currently executing a read operation.
REGSYNO	6J4	Register Sync	Indicates that the IDC received one of the four control functions SR0, CMD0, DR0 or DA0.
RGATE0, RGATE1	18J9, 16D9	Read Gate	Read Gate of the selected disk file.
RI01:81	9D4	PROM's ALU Instruction Bits 0-8	I01:81 before they enter the pipeline register.
RMAL:RMC1	8H8	PROM's Condition Code MUX Selection Bits	MAL:MC1 before they enter the pipeline register.
RMCE1	8C5	PROM's RAM Chip Enable	MCE1 before it enters the pipeline register.
RM11	9D9	PROM's MUX Inverter Bit	M11 before it enters the pipeline register.
RMWE1	8H5	PROM's RAM Write Enable	MWE1 before it enters the pipeline register.
RPOE1	9D8	PROM's ALU Output Enable	POE1 before it enters the pipeline register.
RPZ0	8D5	PROM's RAM Page Zero	PZ0 before it enters the pipeline register.
RRA0	5K5	Read RAM Address	Microcode signal to read the RAM address counter Bus (RADD CTR BUS).
RRA01:71	8D2	PROM's RAM Address	RAM address before it enters the pipeline register.
RSEL1	3N6	Register Select	Indicates that the encoded FUNC0:2 bits are now active. An I/O operation is now active for the IDC or a disk file.
RSFT21	12A2	RAM Shift 2nd ALU Slice	Shifts the RAM either up or down according to the ALU operation.
rSI01:31	9D2	PROM's Sequence Instruction Bits 0-3	SI01:31 before they enter the pipeline register.
RSR001	18H1	Read/Write Serial Disk Data	Serial data shifted into the ECC circuitry during a read/write operation.

MNEMONIC	SOURCE	NAME	COMMENT
RSR00:15	18J-	Read Shift Register Bits 0-15	Accumulated bits associated with a disk file read operation.
RSTATNO	5K4	Reset Attention	Microcode signal to reset ATNO.
RSTIDL0	5N6	Reset Idle	Indicates the idle flip-flop is reset and the idle LED is off.
RWCLK1	16F7	Read/Write Clock	Read/write clock from the selected disk file.
RWGATE0,1	16G9	Read/Write Gate	Indicates the read gate or the write gate of the disk file is on.
SATNO	5M3	Set Attention	Sets the INTREQ flip-flop, thus activating ATNO output.
SAVCRY0	13G1	Save Carry	Enables the save carry flip-flop.
SBSY01	6A4	SELCH Busy	Input from SELCH indicating SELCH is currently busy with a block data transfer.
SCHK01	6F2	Status Check	Output to SELCH to indicate a bad IDC status. (Applicable only to the new SELCH protocol.)
SCLK0A1,0B1 thru SCLK3A1,3B1	17A5-	Differential Servo Clock	Input from a disk file for the write clock (WCLK0A1,0B1 thru WCLK3A1,3B1).
SCLR01	3B9	System Clear	Input from the processor to initialize IDC logic.
SCTY1,Z1	15M-	Differential Select-Cylinder Tag	Output to a disk file to indicate that bus lines B00:09 are supplying a cylinder address.
SDATA1	16F3	Serial Read Data	Serial data, including ECC, read from a disk file.
SECTOR0,1	17M6	Sector Pulse	Sector pulses from selected disk file.
SECTOV0,1	19C6	Sector Overflow	Error condition indicating the read or write gate is up when the sector pulse is active.
SECT0A1,0B1 thru SECT3A1,3B1	17H6-	Differential Sector	Input pulse to mark the beginning of each physical sector.

MNEMONIC	SOURCE	NAME	COMMENT
SECO	5M7	Shift ECC	Shifts the ECC register once.
SELCHBZ1	6C4	SELCH Busy	Indicates that the SELCH is currently busy with a block data transfer.
SELCHDAR1	7M7	SELCH Data Available or Requested	Indicates a received DA0 or DR0 via the SELCH.
SELCHDR0	7M6	SELCH Data Request	Indicates a data request from the SELCH.
SELCHXFR0,1	7M9	SELCH Transfer	Indicates SELCH is transferring data.
SEL01:31	15D2-	Disk File Selected	Indicates that the disk file is now selected.
SEL1	5M8	Select Pulse	Loads the disk file number (0-3) onto USEL0,USEL1.
SETIDLO	5M6	Set Idle Flip-Flop	Sets the idle flip-flop and turns on the idle LED.
SHTY1,21	15M-	Differential Select-Head Tag	Output to disk files to indicate that the bus lines are supplying head-select or volume-select data.
SIGN1	12E3	Sign Bit	Represents the most significant bit of the high-order slice from an ALU operation.
SI01:31	9M1	Sequencer Instruction Bits 0-3	Sequencer instruction bits input to the microprogram sequencer. See Table 4-8.
SKED0A1,0B1 thru SKED3A1,3B1	16H6-	Differential Seek End	Input from a disk file to indicate the end of a seek operation.
SKEND01:31	16L6	Seek End	Indicates the end of a seek operation at a disk file.
SKERAL,B1	14A2-	Seek Error	Indicates a seek error on a selected disk file.
SKER1	14D2	Seek Error	Indicates a seek error on a selected disk file.
SNS	6F3	Set New Sequence	Output to SELCH to indicate IDC support for the new high-speed SELCH protocol.

MNEMONIC	SOURCE	NAME	COMMENT
SNS0	6G3	Set New Sequence without Bus Switch	Output to SELCH to indicate IDC support for the new high-speed SELCH protocol, without an I/O Bus Switch. Jumping pins W1 and W2 on the IDC board for this support is not recommended.
SON1	3M3	Latched Sync On	Indicates a latched sync word received from a disk file, i.e.; a sync mark is now in the read shift register (RSR).
SPA91	10E2	Most-Significant PROM Bit 9	Most significant bit of the 10-bit PROM address which also includes PA01:81.
SR01	3J3	Status Request	Input from the processor requesting the current status (onto D080:150) of IDC or a disk file.
SRL	3K3	SR0 Received	Output resulting from SR0 input.
SSYN0	5J6	Set Sync	Microcode-generated sync return.
STCHK1	6E3	Status Check	See comment with SCHK01.
STOPDMA0	6G5	Stop DMA	Stops DMA when a partial DMA transfer occurs.
SYNCON1	7A4	Sync On	Indicates a received sync word from a disk file.
STPSLCH0	5M6	Stop SELCH Strobe	Generates SCHK0. (Applicable only to the new high-speed SELCH protocol.)
SYNCO,1	18M1, 7C2	Sync Word Detect	Indicates a sync word was detected while IDC was reading disk file data.
SYNO,1	6M4	Sync Return	Output to the processor or SELCH indicating that this IDC or an attached disk file has properly accepted and responded to a control line signal.
TACK0	4M3	Transmit Acknowledge	Output to the next IDC board to signal an interrupt acknowledgment from the processor.
TBD0	5M4	Transmitted Bus Data	Latches bus data to GPD8:15.

MNEMONIC	SOURCE	NAME	COMMENT
TESTCLR0	3B9	Test Clear	A ground signal manually placed here clears IDC logic.
TIMEOUT0,1	10M4	IDC Timeout	IDC timed out during an operation.
TSTCLK0	14F8	Test Clock	System clock for an IDC developmental system.
UNRDYLA1,B1	14A4-	Differential Unit Ready	Input from a disk file indicating its readiness for I/O.
UPWEL	12K9	Clocked RAM Write Enable	MWEL gated with CLK341. See comment for MWEL.
UP130:230	12K8	Page Counter Bits	Binary value to identify RAM pages 0-3 of the disk file during a read.
USELOA1,0B1 thru USEL3A1,3B1	15A2	Differential Unit-Selected Tag	Input from a disk file indicating its selection.
USELOY1,0Z1 and USEL1Y1,1Z1	17M4-	Differential Unit Select	Output to disk files consisting of the address number (0-3) of the disk file to be selected.
USTAGY1,Z1	15M-	Differential Unit-Select Tag	Output to disk files informing them that the unit select lines (see above) are supplying a file address.
WCLK0A1,0B1 thru WCLK3A1,3B1	17F5-	Differential Write Clock	Output to a disk file to synchronize data written to the disk file.
WDATA1	7M5	Serial Write Data	Serial data, including ECC, written to a disk file.
WDAT0A1,0B1 thru WDAT3A1,3B1	17F1-	Differential Write Data	Output data written to a disk file.
WECC0	7H5	Write ECC	Enables the ECC circuitry.
WENB0	12M9	Read/Write Enable to RAM	Selects a read/write operation over BD0:7.

MNEMONIC	SOURCE	NAME	COMMENT
WGATE1	16D9	Write Gate to Disk File	Indicates a write operation is being performed to the selected disk file.
WPROT1	14D5	Write Protected	Indicates a write-protected disk file.
WRITE1	12D8	IDC Write	Indicates this IDC is performing a write to a disk file.
WRRAM1	12K9	Write RAM Enable	Enables the IDC RAM to be written with DMA data.
WSR0:15	18E-	Write Shift Register Bits 0-15	Loaded into the WSR from BD0:7. They are written to the selected disk file.
WSR1	18F7	Write Serial Data	Serial data written to a disk file.
WTPTAL,B1	14A5-	Differential Write Protect	Input from a disk file to indicate it is in the write-protected mode.
XFERHI0	5K3	Transfer High Byte	Reads RSR08:15 to BD0:7; writes BD0:7 to WSR08:15.
XFERLO0	5K3	Transfer Low Byte	Reads RSR00:07 to BD0:7; writes BD0:7 to WSR00:07.
XFRDONE1	7J9	Transfer Done	A particular DMA transfer is complete.
XFRGPD0	3N5	Transfer General-Purpose Data	Selects the general-purpose register to be output onto the SELCH/MUX bus.
XFRREQ1	7C8	Transfer Required	DMA transfer is required.
XFRSYNCH0,1	7M8	Transfer Sync	Transfers SYN0 to the SELCH. It also clocks SELCH DMA data into the IDC.
09R08	7G3	Bit 151 Inverted	Loads data from the serial-to-parallel converter into the BD0:7 register.
09R10	7G1	DCL0 Inverted	Resets ECC clock generation.

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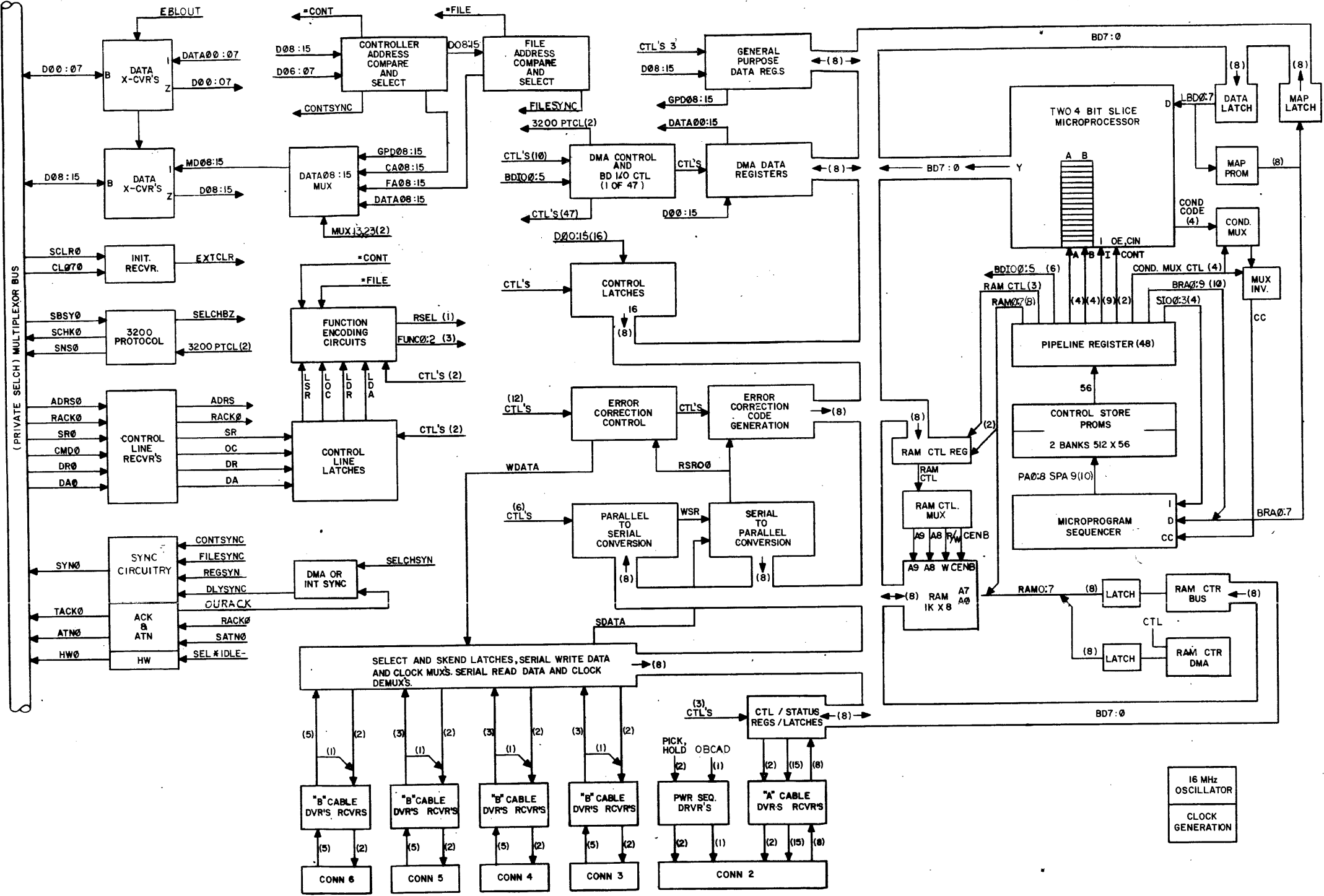
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REVISIONS



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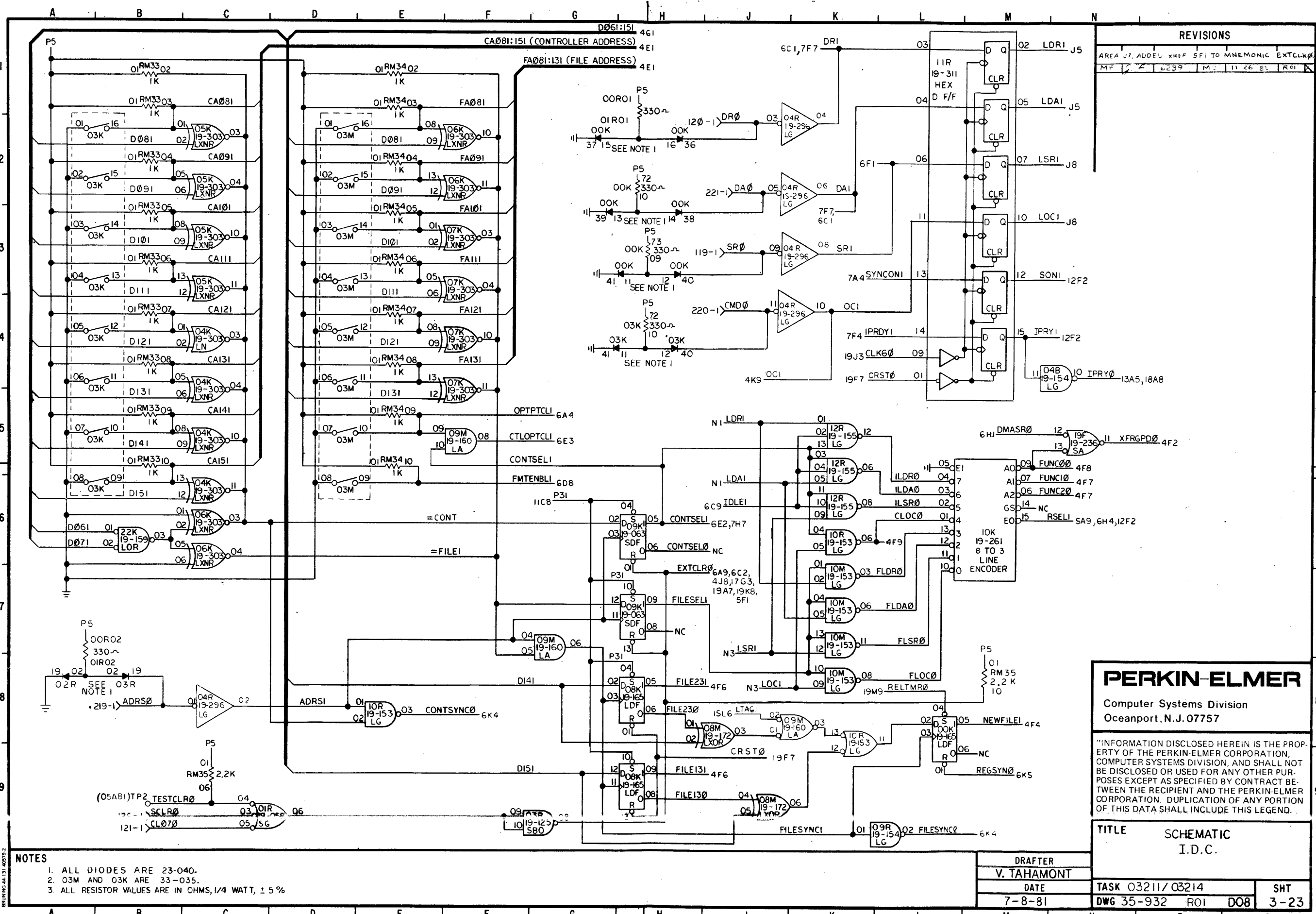
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TITLE SCHEMATIC
 I. D. C.

DRAFTER	VINCE TAHAMONT
DATE	8-5-81
TASK 03211/03214	SHT 2-23
DWG 35-932	D08

NOTES

44-131-40972-2



REVISIONS	
AREA J7, ADDEL XREF SF1 TO MNEMONIC EXTCLR0	
MF 2 6239	M: 11 26 81

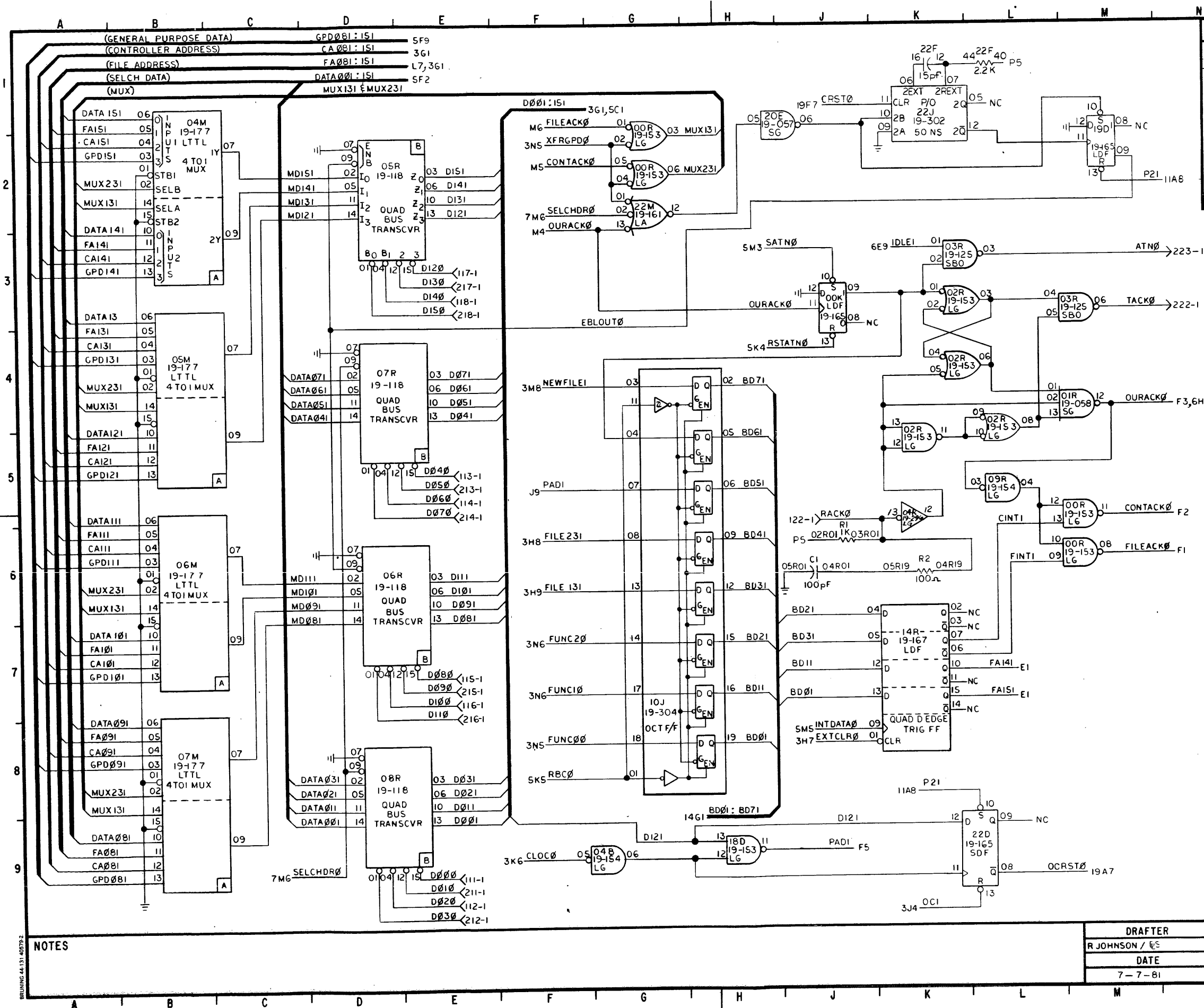
- NOTES**
- ALL DIODES ARE 23-040.
 - 03M AND 03K ARE 33-035.
 - ALL RESISTOR VALUES ARE IN OHMS, 1/4 WATT, ± 5 %

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TITLE	SCHEMATIC I.D.C.	
DRAFTER	V. TAHAMONT	
DATE	7-8-81	SHT
TASK	03211/03214	DWG
DWG	35-932	RO1
DO8		3-23

BRUNING 44-131-40279-2



REVISIONS			
AREA J3, 00R-10 WAS CONNECTED TO 03R-01			
MF 11-26-85	MS	11-26-85	ROI

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 Oceanport, N.J. 07757

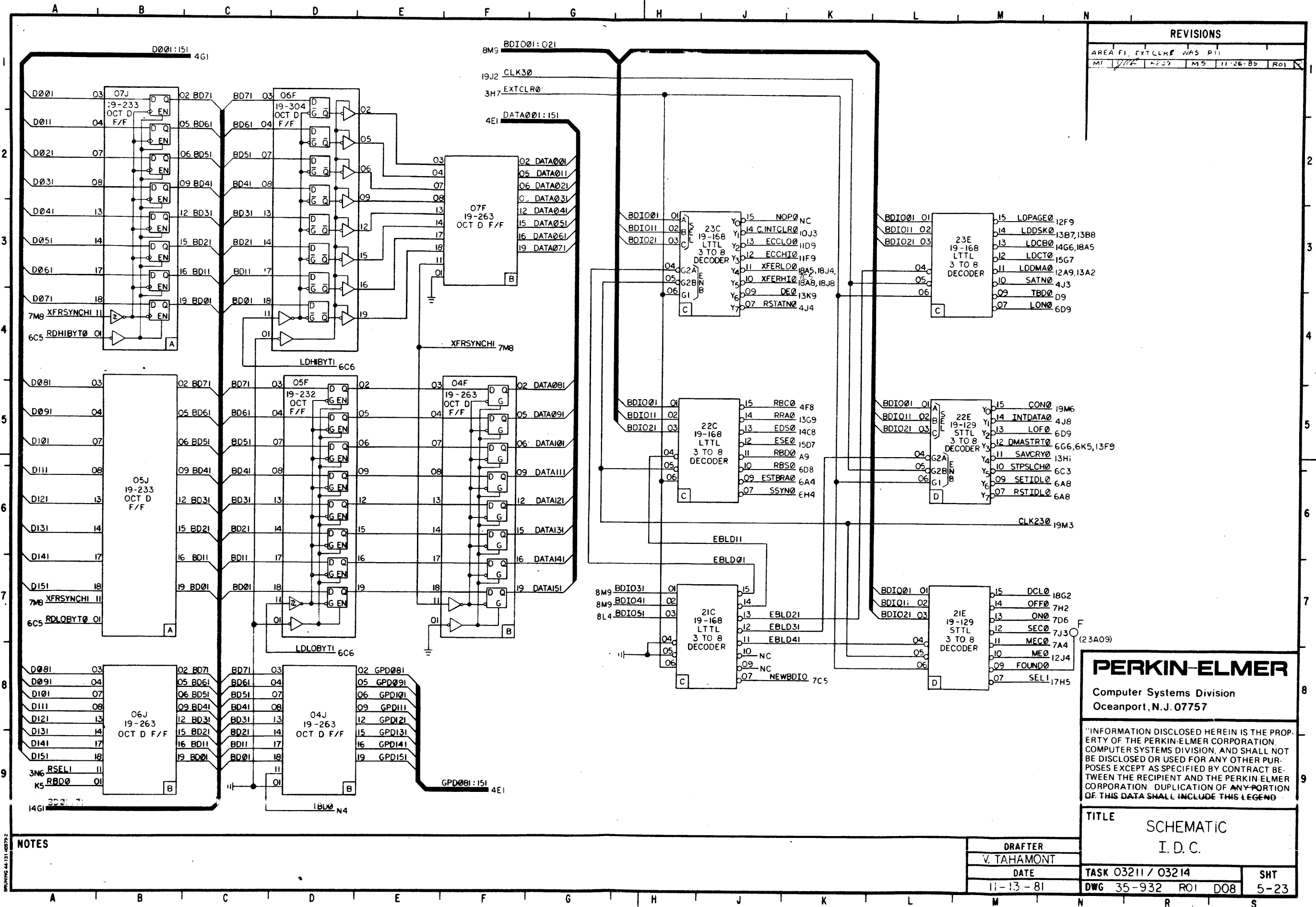
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TITLE SCHEMATIC
 IDC

DRAFTER	R JOHNSON / W/S
DATE	7-7-81
TASK	03211/03214
DWG	35-932 ROI DOB
SHT	4-23

NOTES

BRUNING 44-131-405792



REVISIONS				
AREA	FI	EXT	CLK	WAS P11
MT	1/16	2/29	MS	11-26-85
			ROI	

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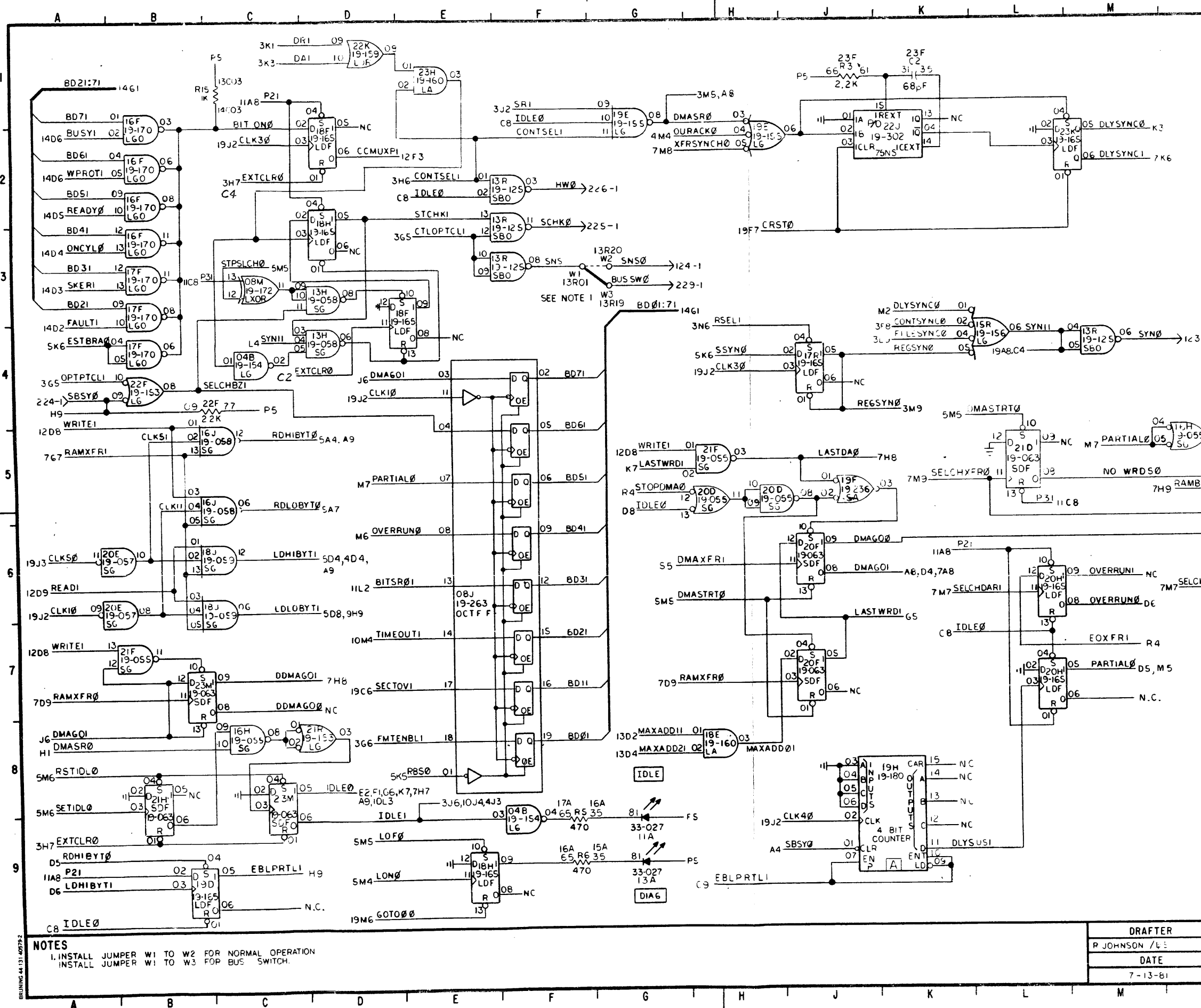
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TITLE
 SCHEMATIC
 I. D. C.

DRAFTER	V. TAHAMONT	DATE	11-13-81	SHT	5-23
TASK	TASK 03211 / 03214		DWG	35-932 ROI DOB	

NOTES

DRAWING 44-131-00792



REVISIONS	
AREA M, MNEMONIC DLYSYN1 XRF WAS N.C.	
AREA E7 ADD: XRF 4J3 T: IDLE1.	
MF 6239	MC 11 26 85
MOI	X

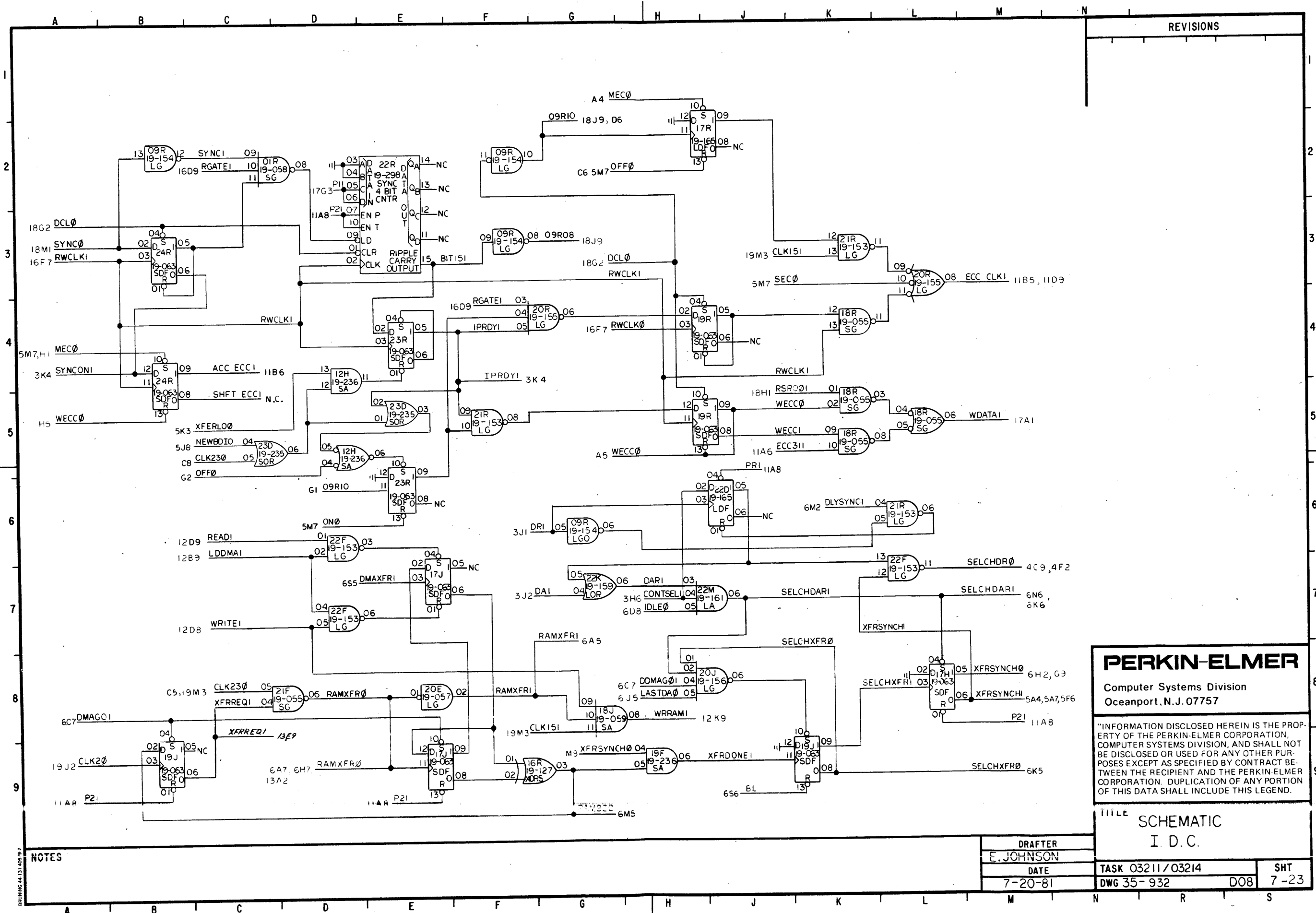
NOTES
 1. INSTALL JUMPER W1 TO W2 FOR NORMAL OPERATION
 2. INSTALL JUMPER W1 TO W3 FOR BUS SWITCH.

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TITLE SCHEMATIC
 IDC

DRAFTER	R JOHNSON / L E
DATE	7-13-81
TASK	O3211 / O3214
DWG	35-932 RO1 DO8 6-23



REVISIONS

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Computer Systems Division
Oceanport, N.J. 07757

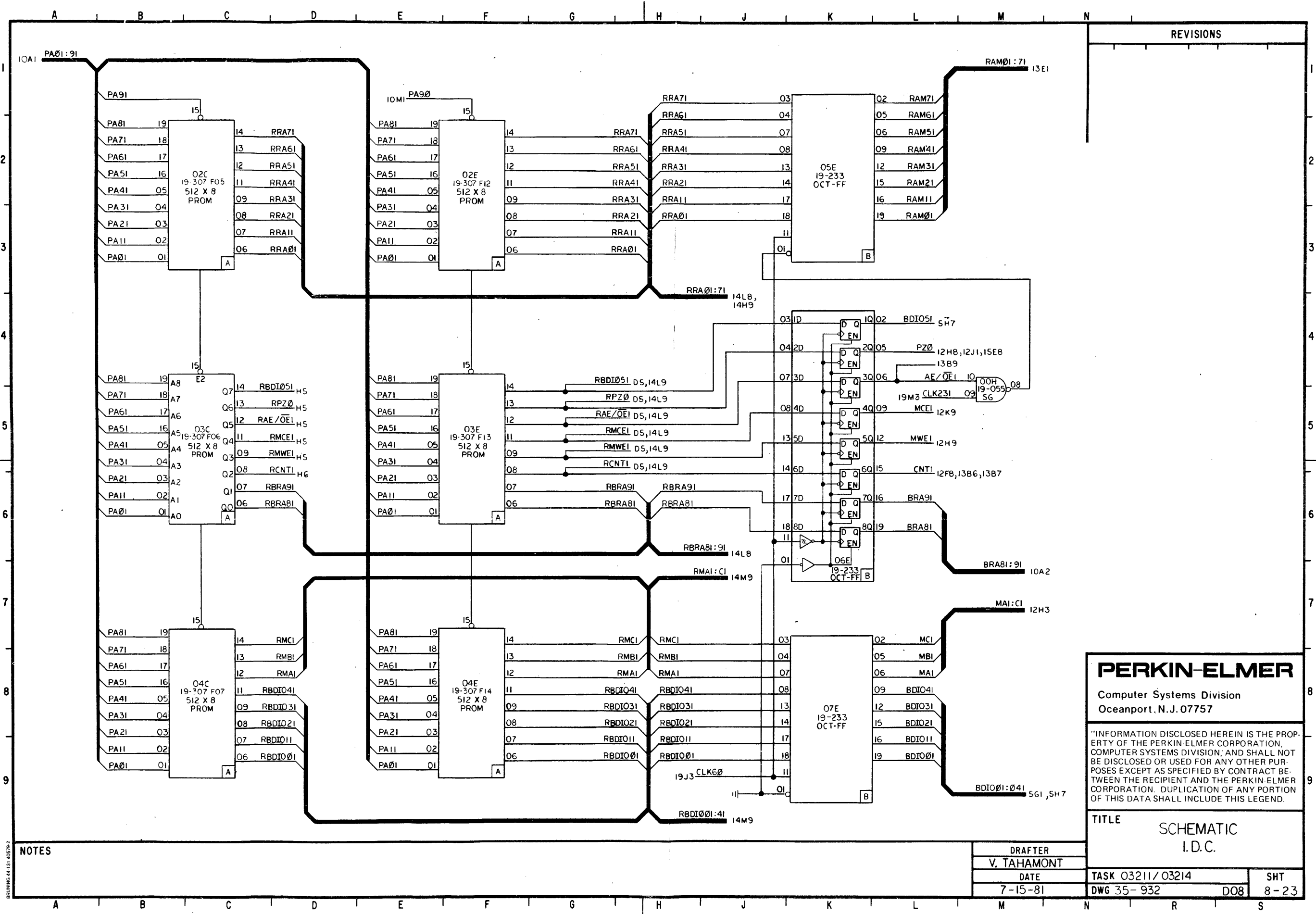
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TITLE SCHEMATIC
I. D. C.

DRAFTER	E. JOHNSON
DATE	7-20-81
TASK	O3211/O3214
DWG	35-932
SHT	7-23

NOTES

DRAWING 44-131-0079-2



REVISIONS	

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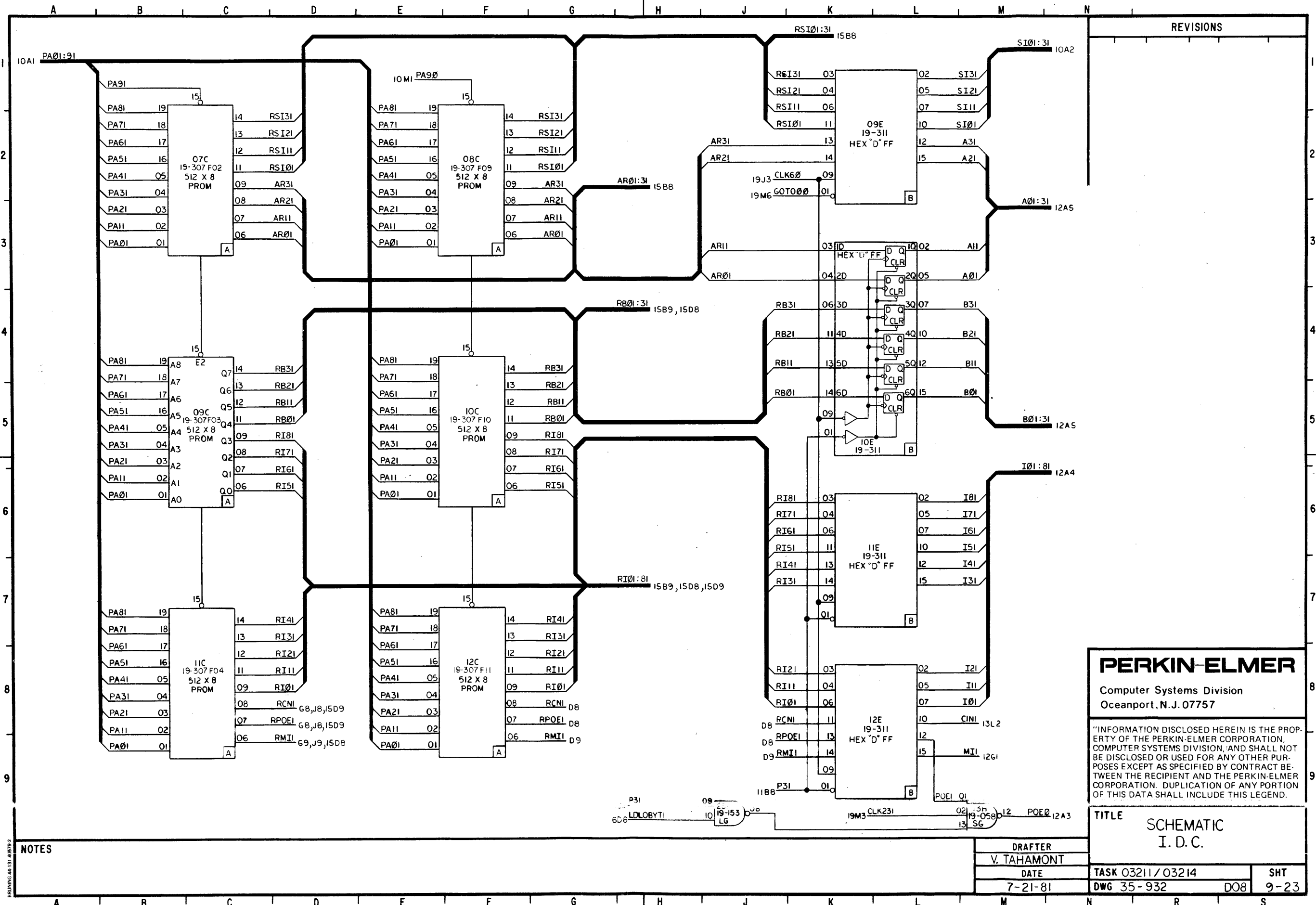
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TITLE: SCHEMATIC I.D.C.

DRAFTER	V. TAHAMONT	TASK	O3211/03214	SHT	8-23
DATE	7-15-81	DWG	35-932	DO8	

NOTES

BRUNING 44-131-00279-2



REVISIONS

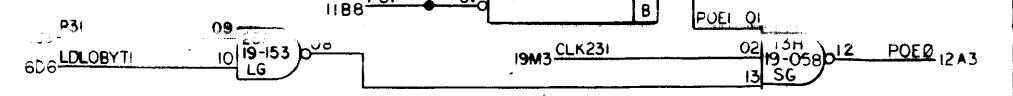
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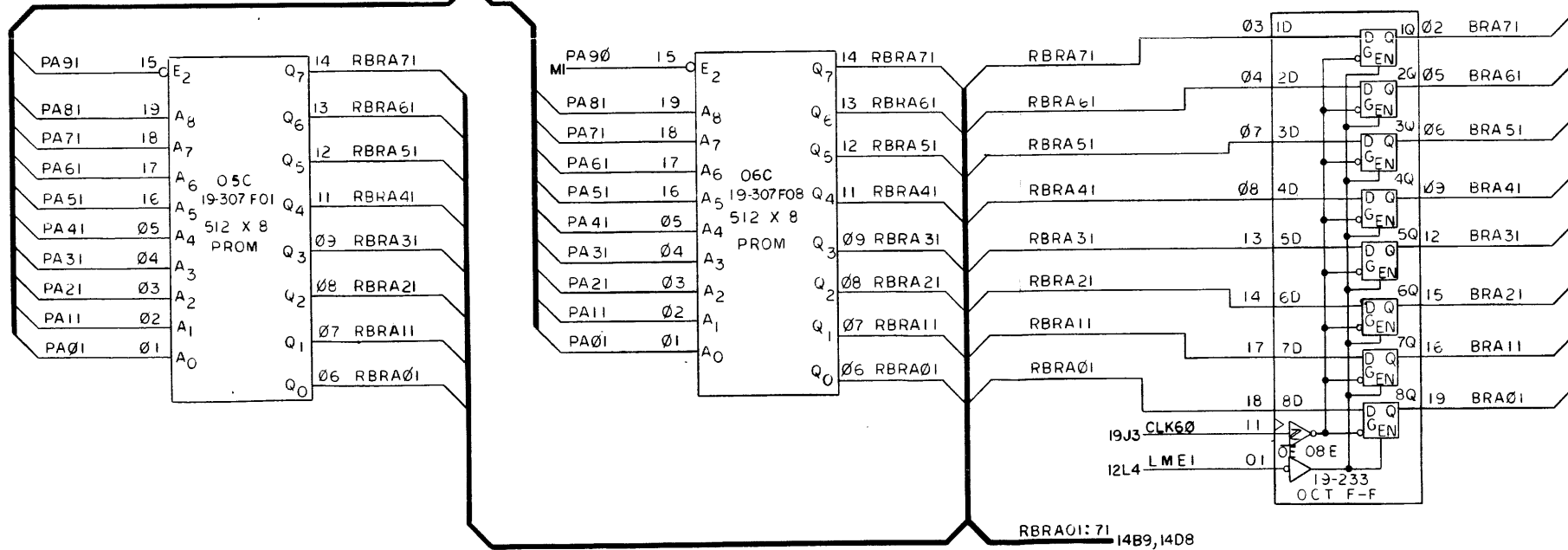
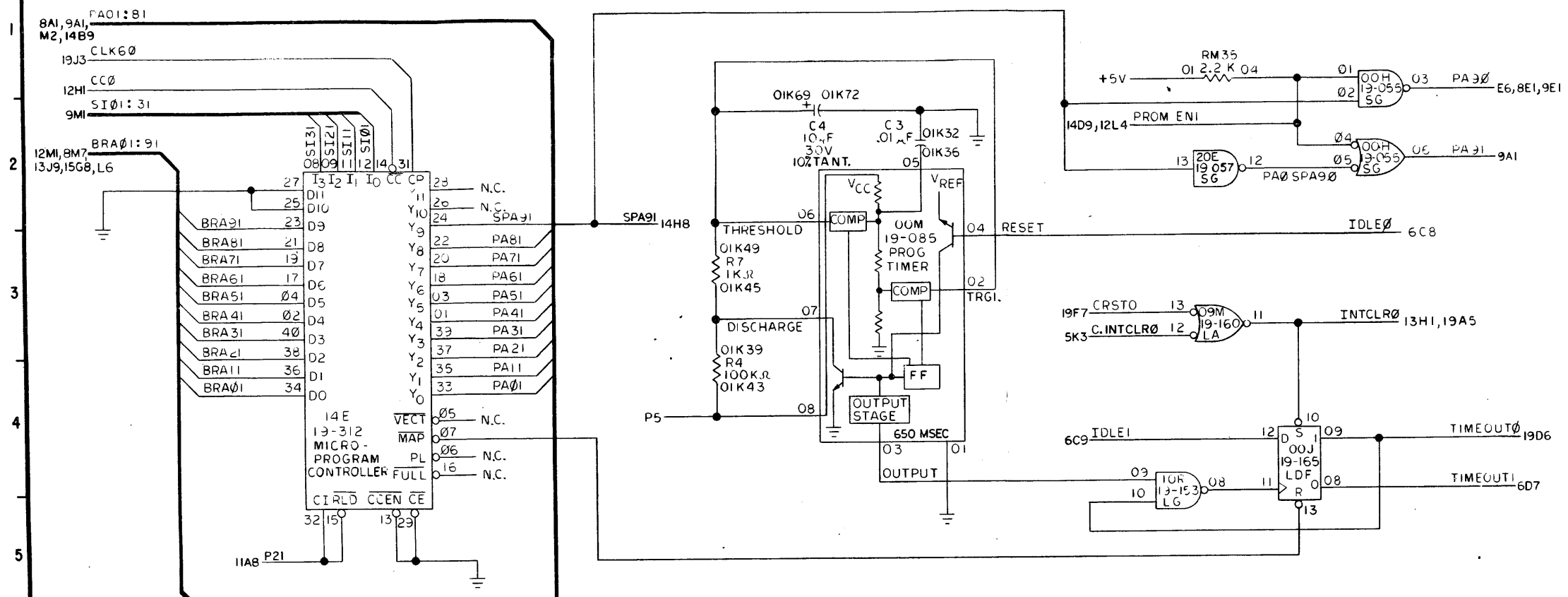
TITLE		SCHEMATIC I. D. C.	
DRAFTER	V. TAHAMONT	TASK 03211/03214	SHT
DATE	7-21-81	DWG 35-932	DO8 9-23

NOTES

REVIEWS 44-131-40792-2



REVISIONS



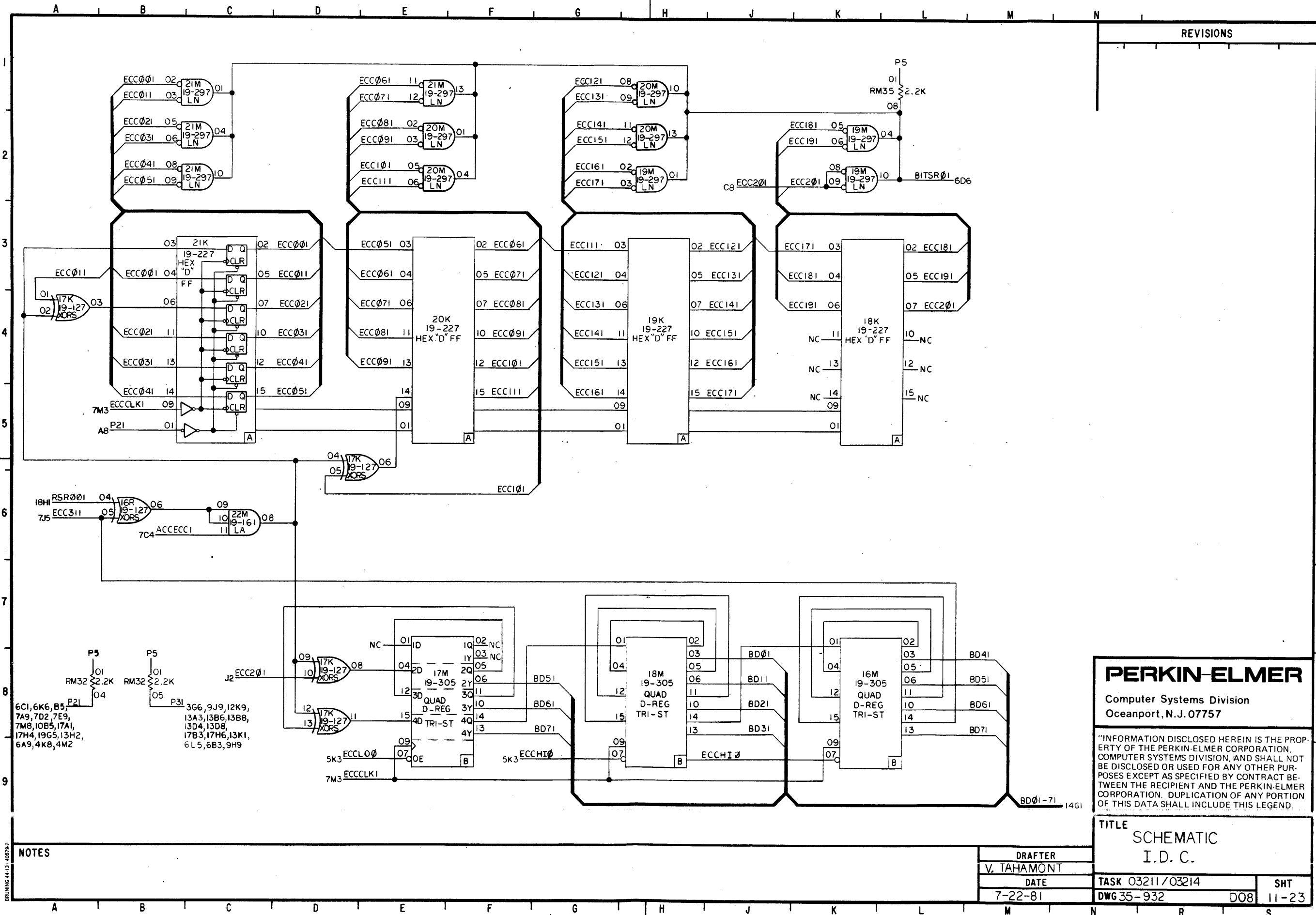
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TITLE		SCHEMATIC IDC	
DRAFTER	P. MARCUS	TASK 03211 / 03214	SHT
DATE	7-21-81	DWG 35-932	D08 10-23

NOTES

BRUNING 44 131 40272 2



REVISIONS	

NOTES

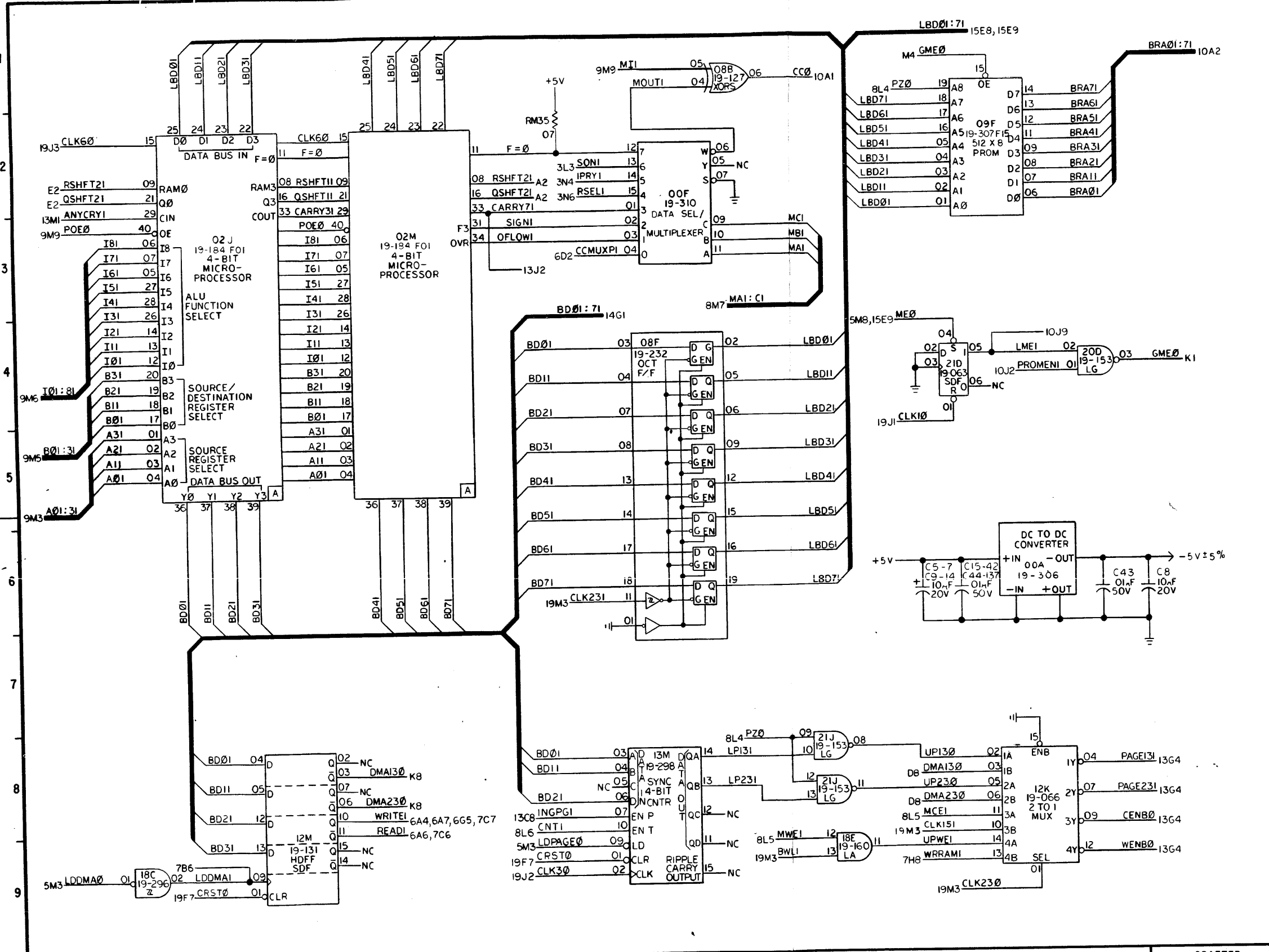
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TITLE	
SCHEMATIC	
I.D. C.	
DRAFTER	V. TAHAMONT
DATE	7-22-81
TASK	03211/03214
DWG	35-932
SHT	11-23

BRUNING 44 131 405752

REVISIONS



NOTES

BRUNING 44-131-4079.2

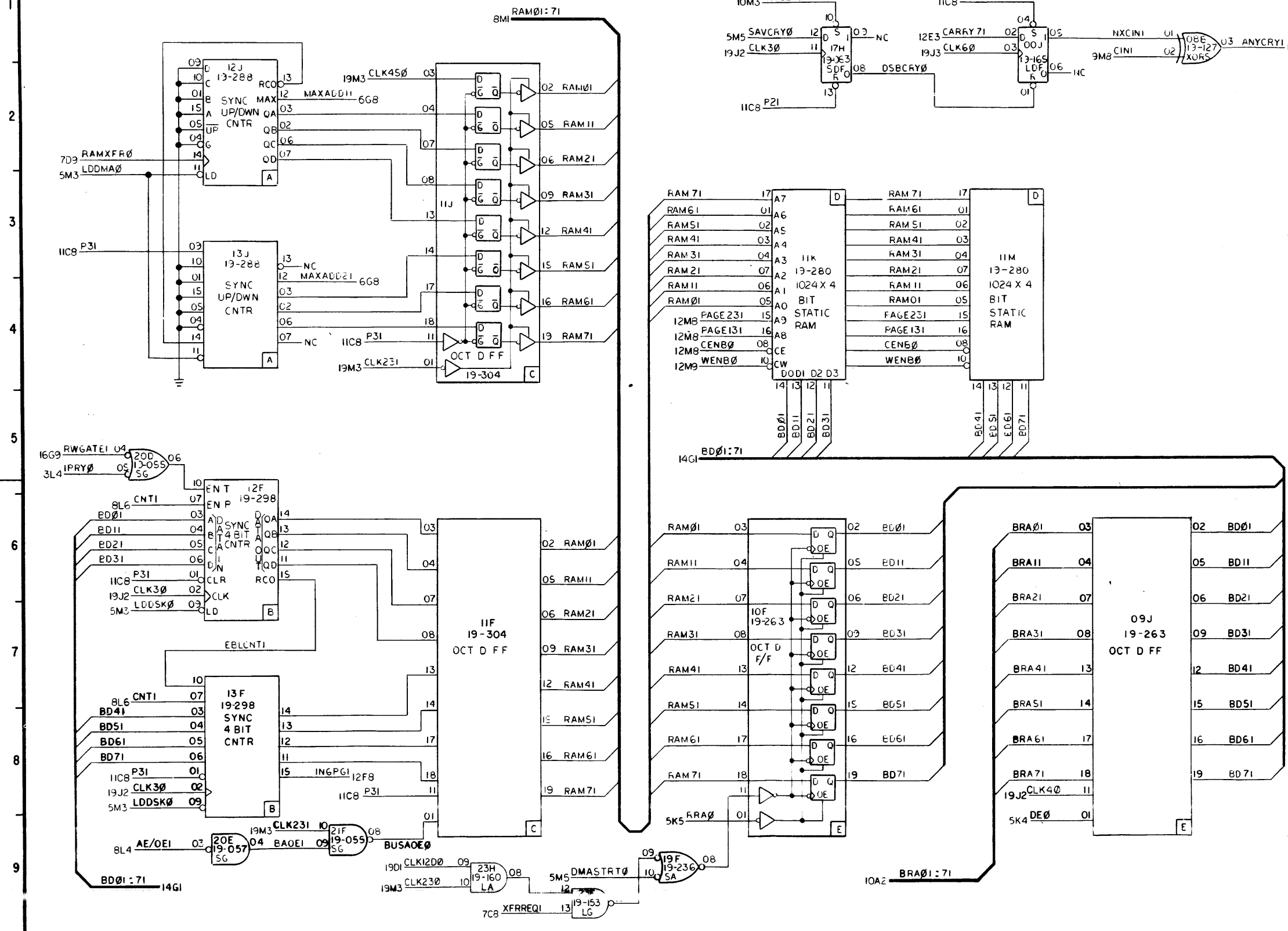
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TITLE		SCHEMATIC I. D. C.	
DRAFTER	V TAHAMONT	TASK 03211/03214	SHT
DATE	7-24-81	DWG 35-932	D08 12-23

A B C D E F G H J K L M N

REVISIONS



DRAWING 44-131-40792

NOTES

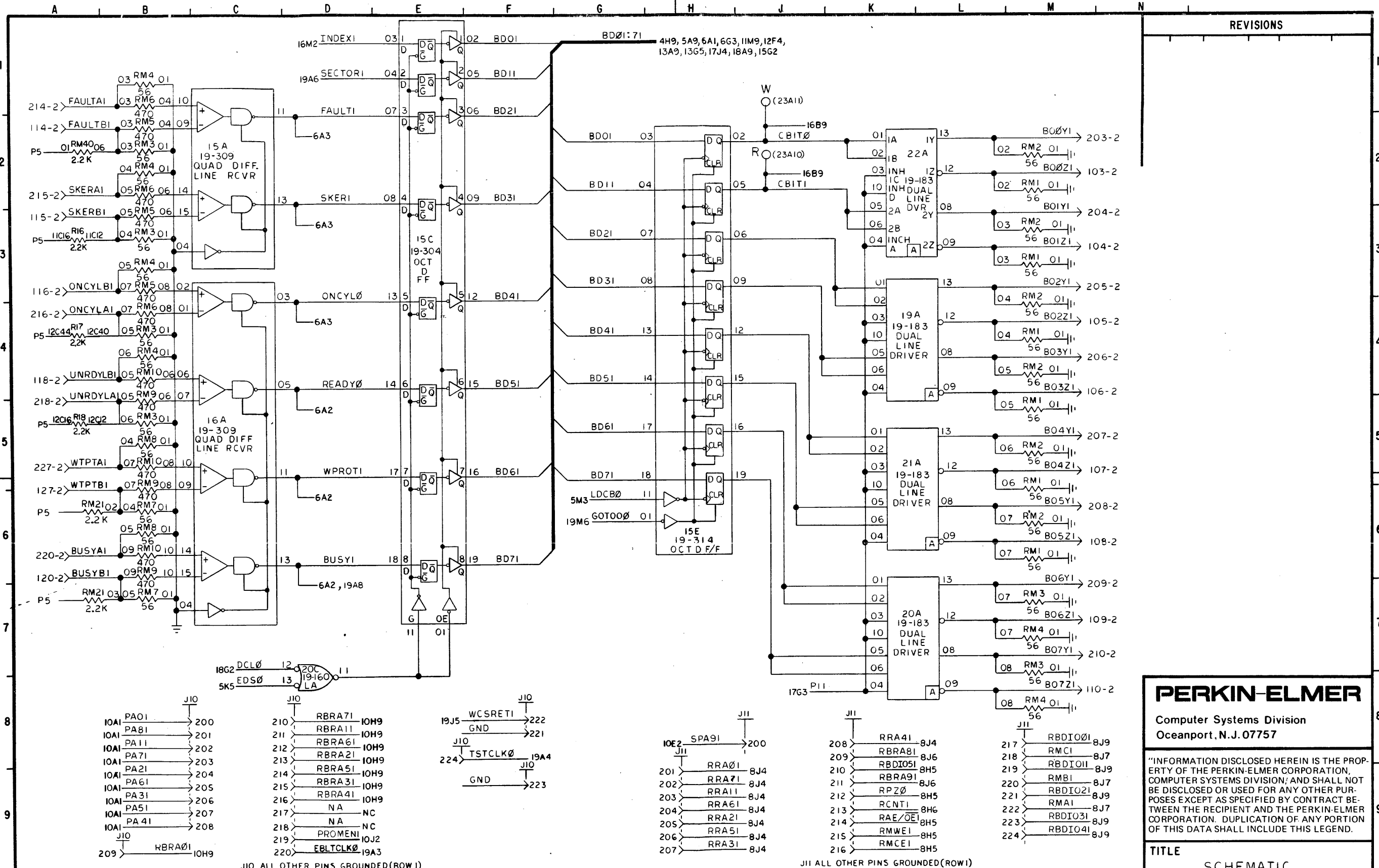
DRAFTER Q5		TASK 03211 / 03214 DWG 35- 932	SHT 13 - 23
DATE 4-21-81			

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TITLE SCHEMATIC
IDC

A B C D E F G H J K L M N R S



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TITLE
 SCHEMATIC
 I.D.C.

DRAFTER P MARCUS	TASK 03211 / 03214	SHT 14 -23
DATE 7-23-81	DWG 35-932	DOB

NOTES

- J10
- IOAI PA01 → 200
 - IOAI PA81 → 201
 - IOAI PA11 → 202
 - IOAI PA71 → 203
 - IOAI PA21 → 204
 - IOAI PA61 → 205
 - IOAI PA31 → 206
 - IOAI PA51 → 207
 - IOAI PA41 → 208
 - IOAI HBRA01 → 209

- J10
- 210 RBRA71 IOH9
 - 211 RBRA11 IOH9
 - 212 RBRA61 IOH9
 - 213 RBRA21 IOH9
 - 214 RBRA51 IOH9
 - 215 RBRA31 IOH9
 - 216 RBRA41 IOH9
 - 217 NA NC
 - 218 NA NC
 - 219 PROMEN1 IOJ2
 - 220 EBLTCLK0 19A3

- J10
- 19J5 WCSRET1 → 222
 - GND → 221
 - J10 TSTCLK0 → 19A4
 - GND → 223

- J11
- IOE2 SPA91 → 200
 - 201 RRA01 8J4
 - 202 RRA71 8J4
 - 203 RRA11 8J4
 - 204 RRA61 8J4
 - 205 RRA21 8J4
 - 206 RRA51 8J4
 - 207 RRA31 8J4

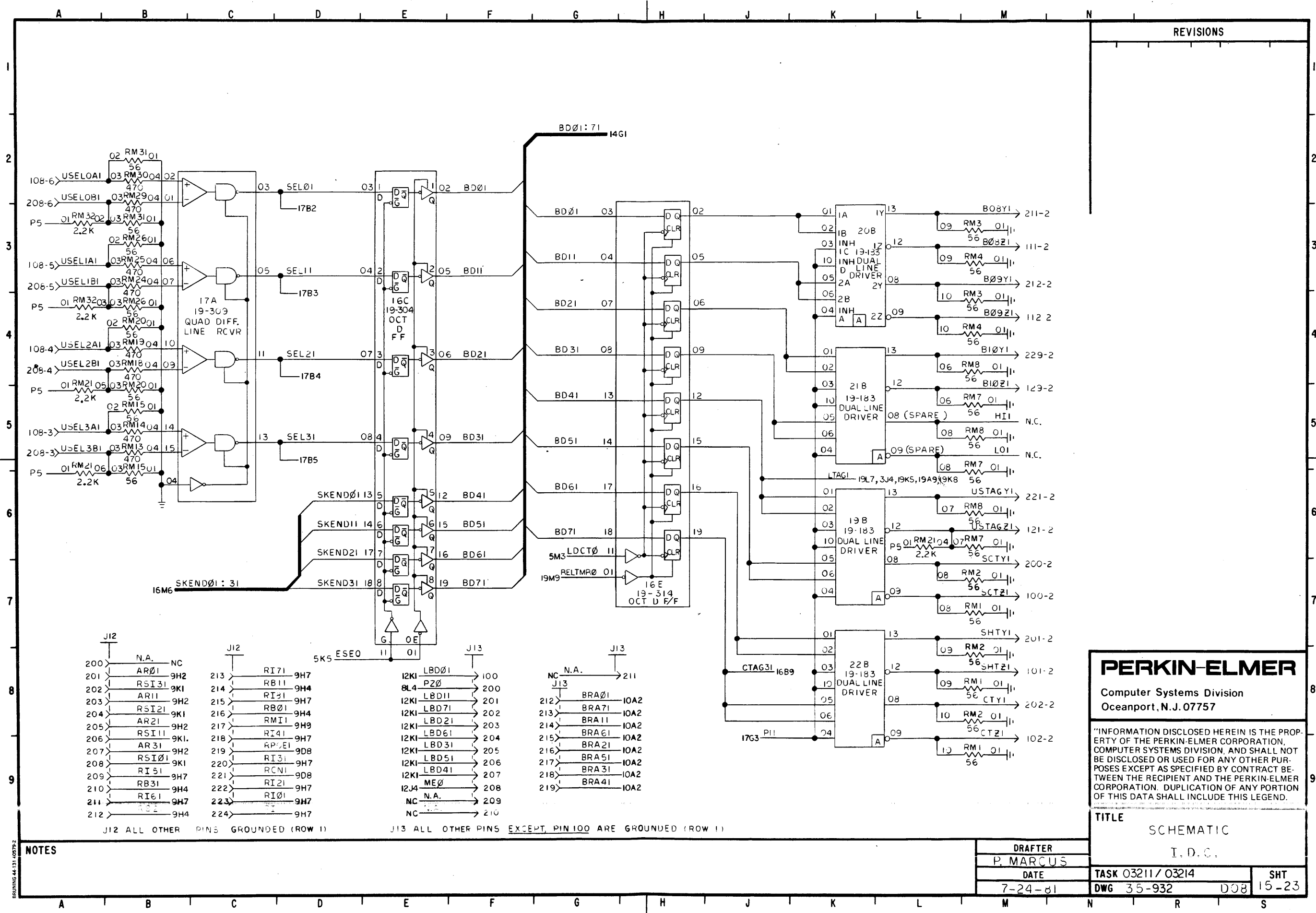
- J11
- 208 RRA41 8J4
 - 209 RBRA81 8J6
 - 210 RBDIO51 8H5
 - 211 RBRA91 8J6
 - 212 RPZ0 8H5
 - 213 RCNT1 8H6
 - 214 RAE/OE1 8H5
 - 215 RMWE1 8H5
 - 216 RMCE1 8H5

- J11
- 217 RBDIO01 8J9
 - 218 RMC1 8J7
 - 219 RBDIO11 8J9
 - 220 RMB1 8J7
 - 221 RBDIO21 8J9
 - 222 RMA1 8J7
 - 223 RBDIO31 8J9
 - 224 RBDIO41 8J9

J10 ALL OTHER PINS GROUND(ROW I)

J11 ALL OTHER PINS GROUND(ROW I)

DRAWING 44-131-408752



REVISIONS

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TITLE SCHEMATIC
 I. D. C.
 TASK 03211/03214 SHT
 DWG 35-932 DOB 15-23

NOTES

J12 ALL OTHER PINS GROUNDED (ROW 1)
 J13 ALL OTHER PINS EXCEPT PIN 100 ARE GROUNDED (ROW 1)

200	N.A.	NC
201	AR01	9H2
202	RSI31	9K1
203	ARI1	9H2
204	RSI21	9K1
205	AR21	9H2
206	RSI11	9K1
207	AR31	9H2
208	RSI01	9K1
209	RI51	9H7
210	RB31	9H4
211	RI61	9H7
212		9H4

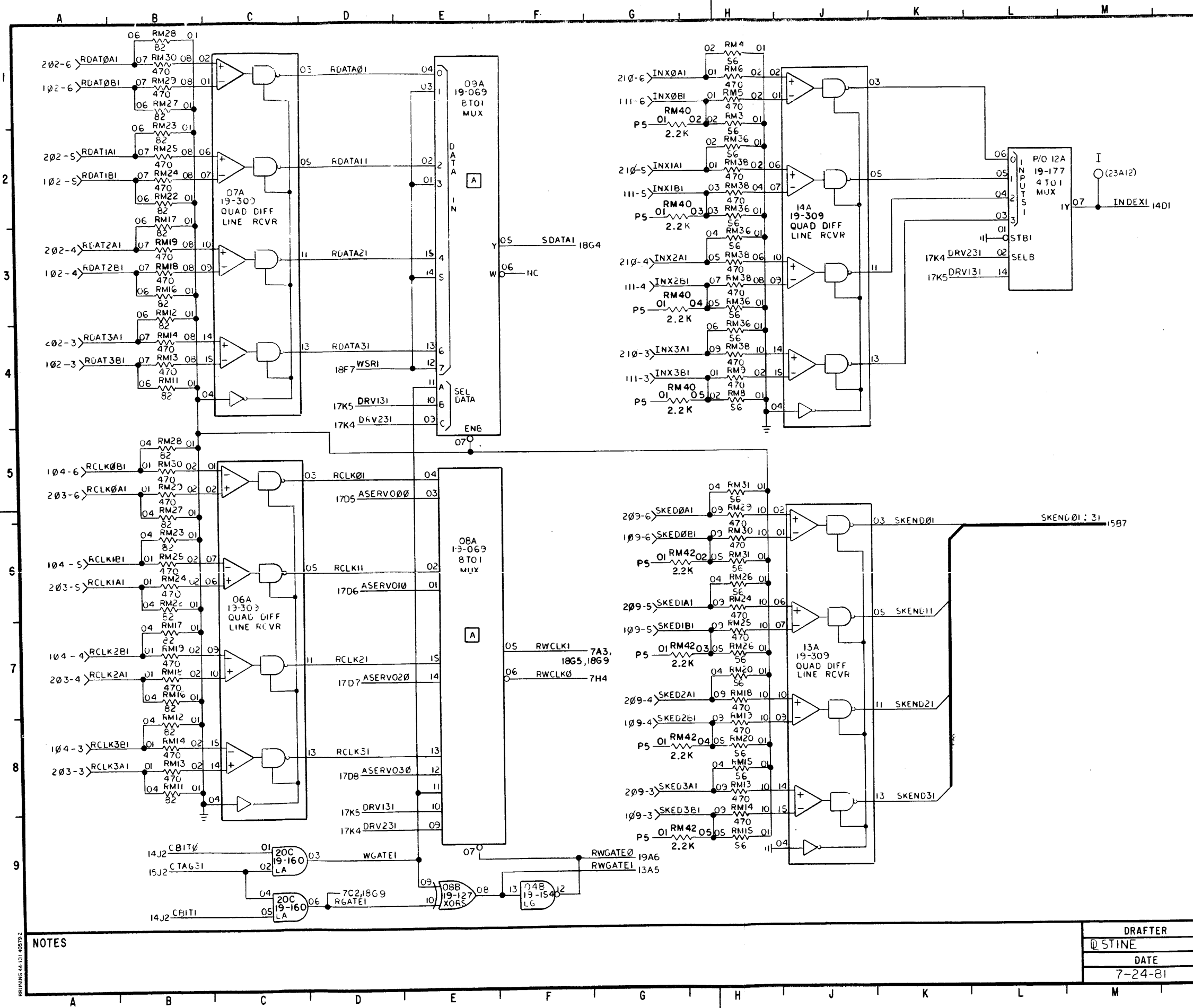
213	RI71	9H7
214	RB11	9H4
215	RI31	9H7
216	RB01	9H4
217	RMI1	9H9
218	RI41	9H7
219	RP1E1	9D8
220	RI31	9H7
221	RCN1	9D8
222	RI21	9H7
223	RI01	9H7
224		9H7

12K1	LBD01	100
8L4	PZ0	200
12K1	LBD11	201
12K1	LBD71	202
12K1	LBD21	203
12K1	LBD61	204
12K1	LBD31	205
12K1	LBD51	206
12K1	LBD41	207
12J4	ME0	208
NC	N.A.	209
NC		210

NC	N.A.	211
212	BRA01	10A2
213	BRA71	10A2
214	BRA11	10A2
215	BRA61	10A2
216	BRA21	10A2
217	BRA51	10A2
218	BRA31	10A2
219	BRA41	10A2

DRAFTER	P. MARCUS
DATE	7-24-81

DRAWING 44-131-10792



REVISIONS

NO.	DESCRIPTION
1	
2	
3	
4	
5	
6	
7	
8	
9	

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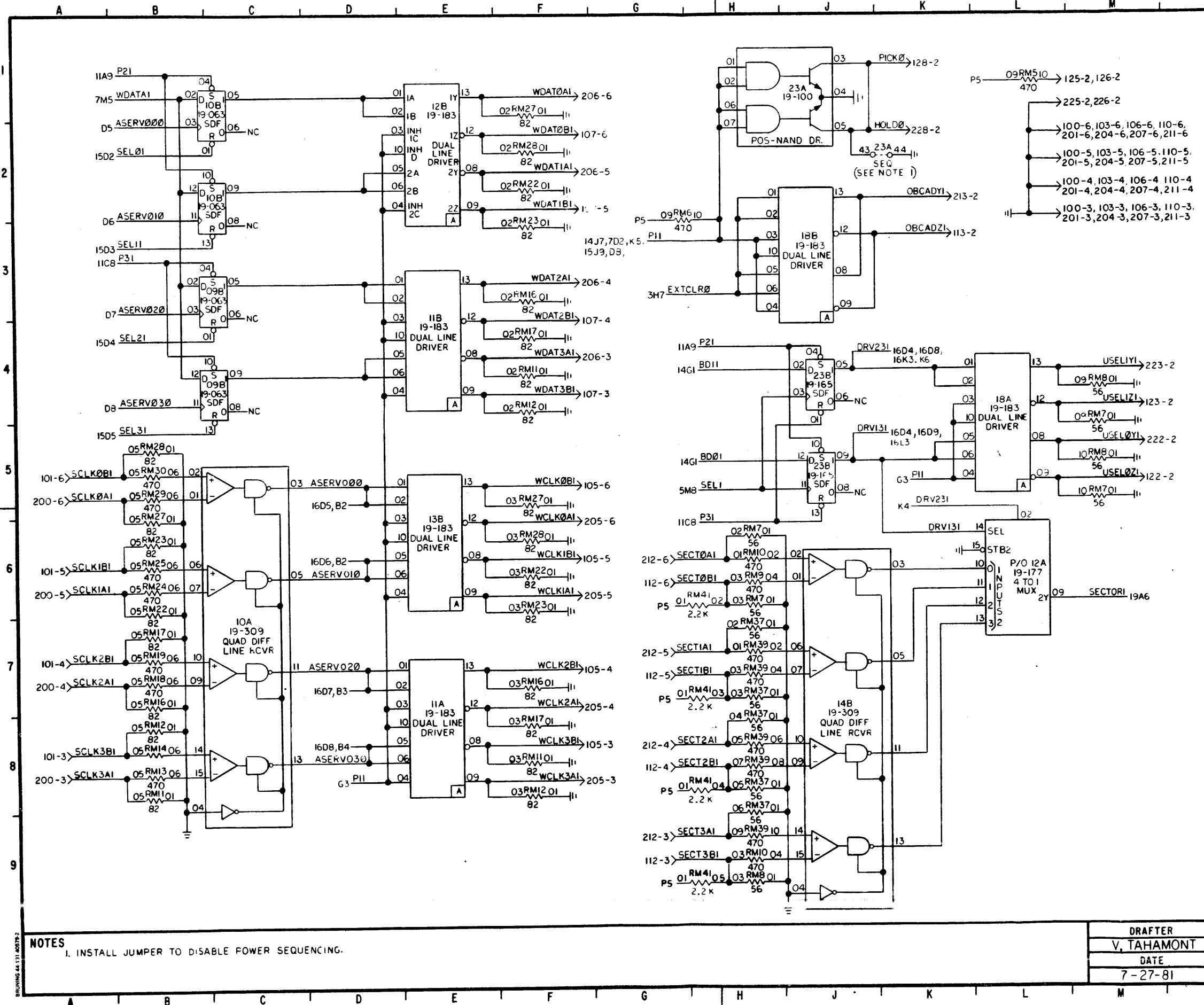
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TITLE SCHEMATIC
 IDC

NOTES

DRAFTER	Q STINE
DATE	7-24-81
TASK	O3211 / O3214
DWG	35-932
SHT	D08 16 -23

REV. 10/81 44-131-00752



REVISIONS			
AREA	12	REV	1
DATE	7/27/78	BY	ROI

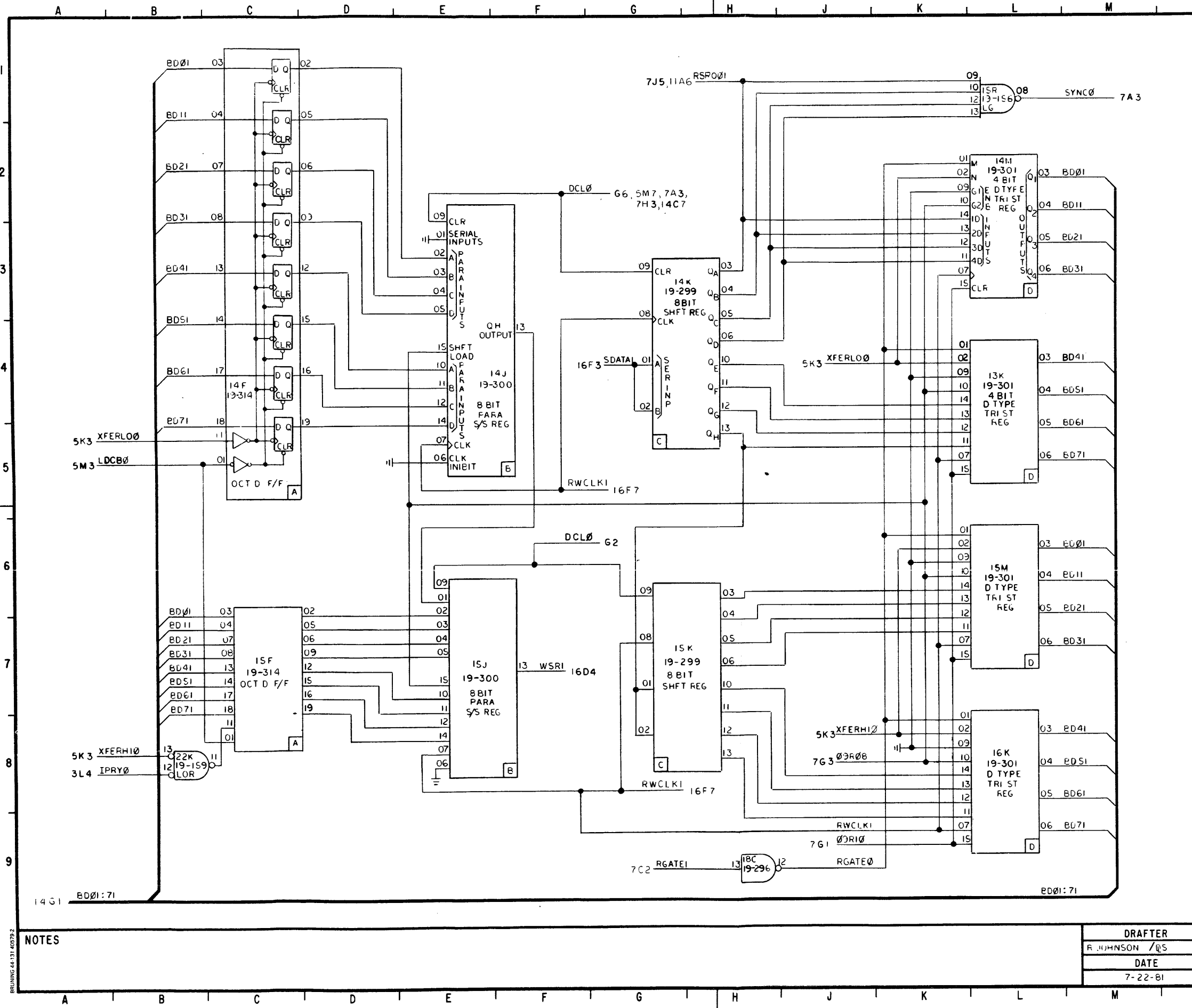
NOTES
 1. INSTALL JUMPER TO DISABLE POWER SEQUENCING.

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TITLE: SCHEMATIC
 I.D.C.

DRAFTER V. TAHAMONT	TASK 03211 / 03214	SHT
DATE 7-27-81	DWG 35-932 ROI DOB	17-23



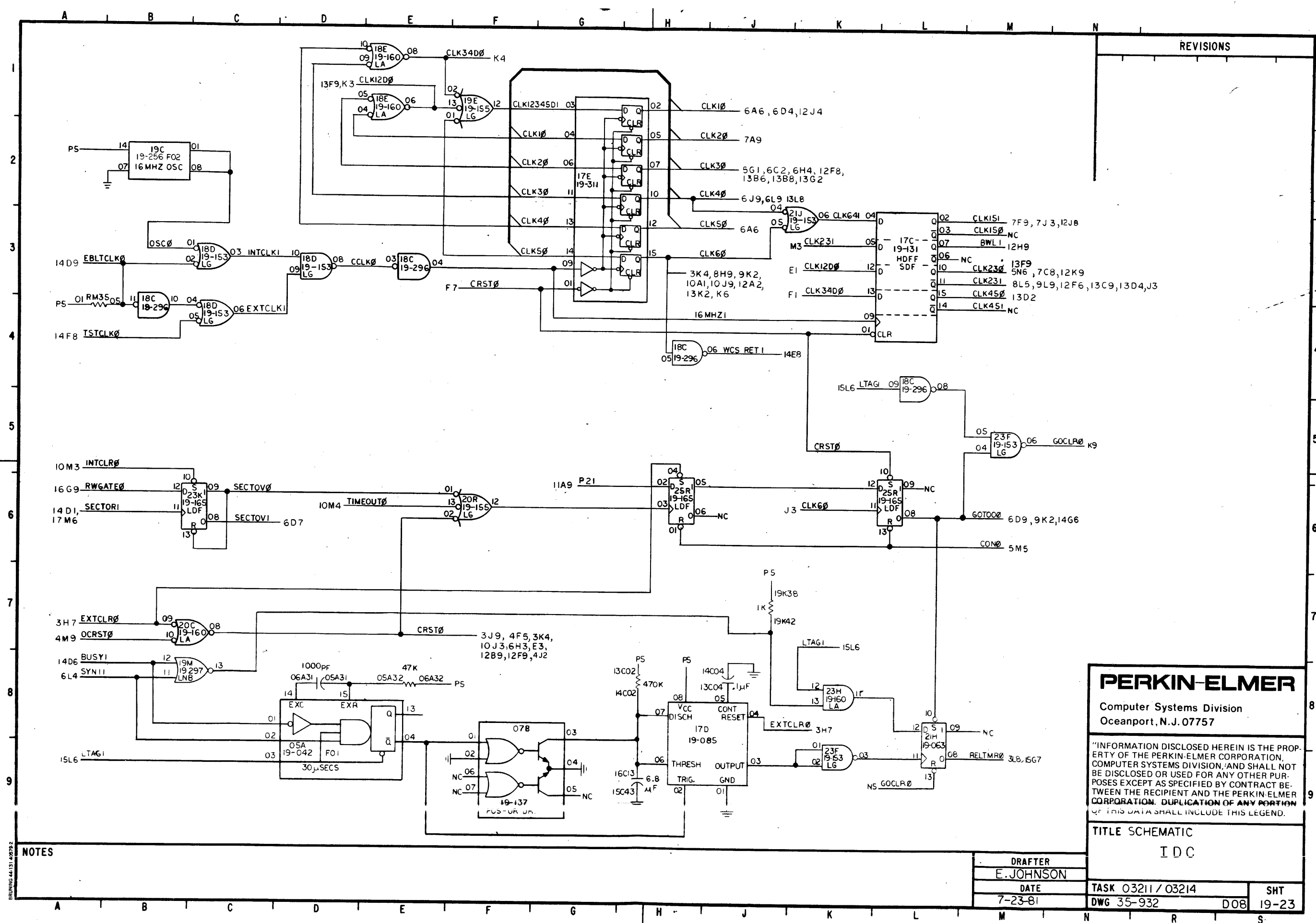
REVISIONS		

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TITLE SCHEMATIC	
IDC	
DRAFTER R. JOHNSON / RS	DATE 7-22-81
TASK 03211 / 03214	SHT 18-23
DWG 35-932	D08

NOTES

14 G1 BD01:71

DRAFTER	R. JOHNSON / RS
DATE	7-22-81
TASK	03211 / 03214
DWG	35-932
SHT	18-23



REVISIONS	

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TITLE SCHEMATIC
 IDC

DRAWN	E. JOHNSON
DATE	7-23-81
TASK	03211 / 03214
DWG	35-932
SHT	19-23

NOTES

DRAWING 44131 40782

IDC RESISTOR MODULE CONVERSION CHART											REVISIONS							
RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	
1 RM1	01	8	1	44	GND	RM 7	01	8	1	24	GND	RM15	01	6	1	06	GND	
	02			43	B00Z1		02			23	SECT0A1		02			05	USEL3A1	
	03			42	B01Z1		03			22	SECT0B1		03			04	USEL3B1	
	04			41	B02Z1		04			21	WTP1B1		04			03	SKED3A1	
	05			40	B03Z1		05			20	BUSYB1		05			02	SKED3B1	
	06			39	B04Z1		06			19	B10Z1		RM15	06	8	1	01	
	07			38	B05Z1		07			18	USTAGZ1							
	08			37	SCTZ1		08			17	LO							
	09			36	SHTZ1		09			16	USELIZ1							
	10			35	CTZ1		10			15	USELOZ1							
2 RM2	01	8	2	44	GND	RM 8	01	8	2	24	GND	RM16	01	9	1	47	GND	
	02			43	B00Y1		02			23	INX3B1		02			46	WDAT2A1	
	03			42	B01Y1		03			22	SECT3B1		03			45	WCLK2B1	
	04			41	B02Y1		04			21	WTP1A1		04			44		
	05			40	B03Y1		05			20	BUSYAI		05			43	SCLK2A1	
	06			39	B04Y1		06			19	B10Y1		RM16	06	9	1	42	
	07			38	B05Y1		07			18	USTAGY1							
	08			37	SCTY1		08			17	H1							
	09			36	SHTY1		09			16	USELIY1							
	10			35	CTY1		10			15	USELOY1							
3 RM3	01	8	1	34	GND	RM 9	01	7	2	24	INX3B1	RM16	01	9	3	47		
	02			33	INX0B1		02			23	I4A15		02			46		
	03			32	FAULTB1		03			22	SECT0B1		03			45	USEL2B1	
	04			31	SKERB1		04			21	I4B01		04			44	17A09	
	05			30	ONCYLA1		05			20	UNRDYLA1		05			43	SCLK2A1	
	06			29	UNRDYLA1		06			19	I6A07		06			42	IOA09	
	07			28	B06Y1		07			18	WTP1B1		07			41		
	08			27	B07Y1		08			17	I6A09		08			40	SKED2A1	
	09			26	B08Y1		09			16	BUSYB1		09			39	I3A10	
	10			25	B09Y1		10			15	I6A15		10			38		
4 RM3	01	8	1	34	GND	RM 9	01	7	2	24	SECT0IA	RM18	01	9	3	47		
	02			33	INX0A1		02			23	I4B02		02			46		
	03			32	FAULTA1		03			22	SECT3B1		03			45	USEL2A1	
	04			31	SKERA1		04			21	I4B15		04			44	17A10	
	05			30	ONCYLB1		05			20	UNRDYLB1		05			43	SCLK2B1	
	06			29	UNRDYLB1		06			19	I6A06		06			42	IOA10	
	07			28	B06Z1		07			18	WTP1A1		07			41		
	08			27	B07Z1		08			17	I6A10		08			40	SKED2B1	
	09			26	B08Z1		09			16	BUSYAI		09			39	I3A09	
	10			25	B09Z1		10			15	I6A14		10			38		
5 RM4	01	8	2	34	GND	RM 10	01	7	1	24	SECT0IA	RM19	01	9	4	47		
	02			33	INX0A1		02			23	I4B02		02			46		
	03			32	FAULTA1		03			22	SECT3B1		03			45	USEL2A1	
	04			31	SKERA1		04			21	I4B15		04			44	17A10	
	05			30	ONCYLB1		05			20	UNRDYLB1		05			43	SCLK2B1	
	06			29	UNRDYLB1		06			19	I6A06		06			42	IOA10	
	07			28	B06Z1		07			18	WTP1A1		07			41		
	08			27	B07Z1		08			17	I6A10		08			40	SKED2B1	
	09			26	B08Z1		09			16	BUSYAI		09			39	I3A09	
	10			25	B09Z1		10			15	I6A14		10			38		
6 RM5	01	7	2	34	INX0B1	RM 11	01	8	1	12	GND	RM20	01	9	1	41	GND	
	02			33	I4A01		02			11	WDAT3A1		02			40	USEL2A1	
	03			32	FAULTB1		03			10	WCLK3B1		03			39	USEL2B1	
	04			31	15A09		04			09	SCLK3A1		04			38	SKED2A1	
	05			30	SKERB1		05			08			05			37	SKED2B1	
	06			29	15A15		06			07			06			36		
	07			28	ONCYLB1		RM11	06	8	1	08							
	08			27	I6A02													
	09			26	P5													
	10			25	I25-2													
7 RM6	01	7	1	34	INX0A1	RM 12	01	8	2	12	GND	RM21	01	9	2	41	P5	
	02			33	I4A02		02			11	WDAT3B1		02			40	WTP1B1	
	03			32	FAULTA1		03			10	WCLK3A1		03			39	BUSYB1	
	04			31	15A10		04			09			04			38	USTAGZ1	
	05			30	SKERA1		05			08	SCLK3B1		05			37	USEL2B1	
	06			29	15A14		06			07			06			36	USEL3B1	
	07			28	ONCYLA1		RM12	06	8	2	08							
	08			27	I6A01													
	09			26	P5													
	10			25	I8B03													
8 RM6	01	7	1	34	INX0A1	RM 13	01	7	2	12	GND	RM22	01	9	1	31	GND	
	02			33	I4A02		02			11			02			30	WDAT1A1	
	03			32	FAULTA1		03			10	USEL3B1		03			29	WCLK1B1	
	04			31	15A10		04			09	17A15		04			28		
	05			30	SKERA1		05			08	SCLK3A1		05			27	SCLK1A1	
	06			29	15A14		06			07	IOA15		06			26		
	07			28	ONCYLA1		RM13	06	7	2	08							
	08			27	I6A01													
	09			26	P5													
	10			25	I8B03													
9 RM6	01	7	1	34	INX0A1	RM 13	01	7	2	12	GND	RM23	01	9	2	31	GND	
	02			33	I4A02		02			11			02			30	WDAT1B1	
	03			32	FAULTA1		03			10	USEL3A1		03			29	WCLK1A1	
	04			31	15A10		04			09	17A14		04			28		
	05			30	SKERA1		05			08	SCLK3B1		05			27		
	06			29	15A14		06			07	IOA14		06			26		
	07			28	ONCYLA1		RM13	06	7	2	08							
	08			27	I6A01													
	09			26	P5													
	10			25	I8B03													

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Computer Systems Division
Oceanport, N.J. 07757

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NOTES	DRAFTER	TITLE
EXAMPLE: RM5 PIN 1 = 72 x 34 CONNECTOR ROW PIN NO	E. JOHNSON	SCHMATIC
RM25 PIN 6 = 94 x 26 CONNECTOR ROW PIN NO	DATE	INTELLIGENT DISC CONTROLLER
	11-4-81	TASK 03211 / 03214
		DWG35-932 DOB SHT
		20-23

IDC RESISTOR MODULE CONVERSION CHART													REVISIONS							
RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC			
1	RM25	01	9	4	31		RM 38	01	9	3	61	INX1AI								
		02			30	02		60			I4A06									
		03			29	03		59			INX1BI									
		04			28	04		58			I4AC7									
		05			27	05		57			INX2AI									
		06			26	06		56			I4A10									
		07			25	07		55			INX2BI									
		08			24	08		54			I4A09									
		09			23	09		53			INX3AI									
		10			22	10		52			I4A14									
2	RM26	01	9	1	25	GND	RM 39	01	9	4	61	SECT1AI								
		02			24	02		60			I4B06									
		03			23	03		59			SECT1BI									
		04			22	04		58			I4B07									
		05			21	05		57			SECT2AI									
		06			20	06		56			I4B10									
3	RM27	01	9	1	13	GND	RM 39	01	9	4	55	SECT2BI								
		02			12	02		54			I4B09									
		03			11	03		53			SECT3AI									
		04			10	04		52			I4B14									
		05			09	05		51			SECT3BI									
		06			08	06		50			I4B14									
4	RM28	01	9	2	13	GND	RM 40	01	8	2	06	P5								
		02			12	02		05			INX0BI									
		03			11	03		04			INX1BI									
		04			10	04		03			INX2BI									
		05			09	05		02			INX3BI									
		06			08	06		01			FAULTBI									
5	RM29	01	9	3	13		RM 41	01	9	2	55	P5								
		02			12	02		54			SECT0BI									
		03			11	03		53			SECT1BI									
		04			10	04		52			SECT2BI									
		05			09	05		51			SECT3BI									
		06			08	06		50												
6	RM30	01	9	4	13		RM 42	01	9	1	55	P5								
		02			12	02		54			SKED0BI									
		03			11	03		53			SKED1BI									
		04			10	04		52			SKED2BI									
		05			09	05		51			SKED3BI									
		06			08	06		50												
7	RM31	01	9	1	07	GND	RM 42	01	9	1	55	P5								
		02			06	02		54			SKED0BI									
		03			05	03		53			SKED1BI									
		04			04	04		52			SKED2BI									
		05			03	05		51			SKED3BI									
		06			02	06		50												
8	RM32	01	9	2	07	P5	RM 42	01	9	1	55	P5								
		02			06	02		54			SKED0BI									
		03			05	03		53			SKED1BI									
		04			04	04		52			SKED2BI									
		05			03	05		51			SKED3BI									
		06			02	06		50												
9	RM36	01	9	1	51		RM 38	01	9	3	61	INX1AI								
		02			60	02		59			INX1BI									
		03			59	03		58			INX2AI									
		04			58	04		57			INX2BI									
		05			57	05		56			INX3AI									
		06			56	06														
9	RM37	01	9	2	61	GND	RM 39	01	9	4	61	SECT1AI								
		02			60	02		59			SECT1BI									
		03			59	03		58			SECT2AI									
		04			58	04		57			SECT2BI									
		05			57	05		56			SECT3AI									
		06			56	06														

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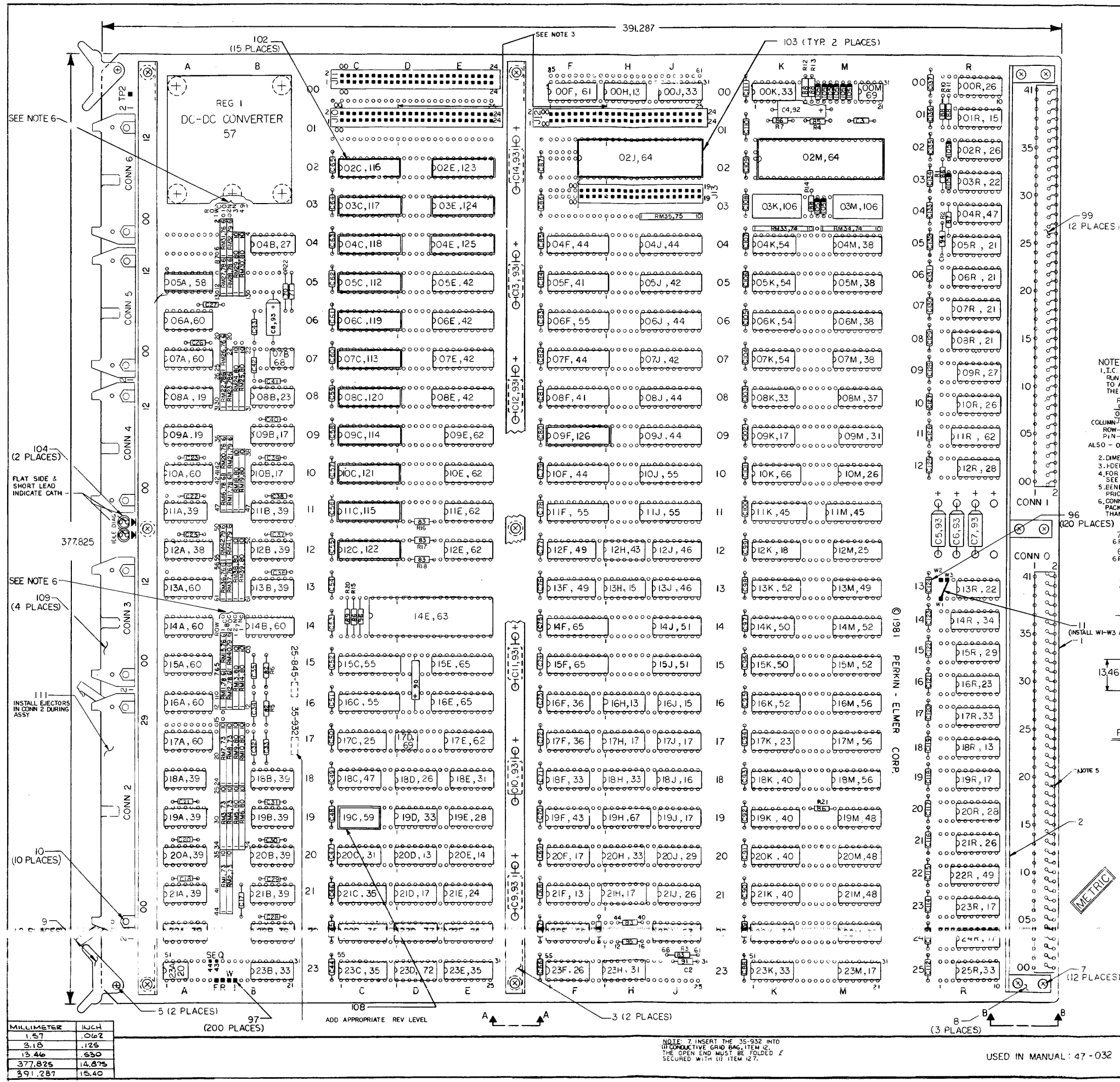
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TITLE SCHEMATIC
INTELLIGENT DISC CONTROLLER

NOTES

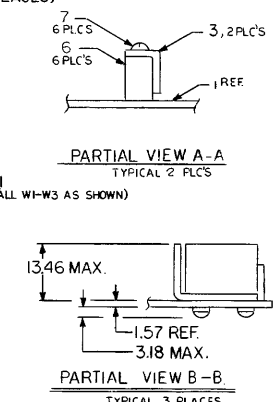
DRAFTER E. JOHNSON		TASK 03211 / 03214		SHT
DATE 11-11-81		DWG 35-932		D08 21-23

BRUNING 44131 40279 2



REVISIONS		
PRE PRODUCTION APPROVAL	INIT DATE	DATE
DEV PROD	9/29/85	9/30/85
RELEASED FOR PRODUCTION		
MFG. ENG.	DATE	
REVISED PER APPROVAL PRINTS.		
JH	2-11-86	ROI

NOTES
 1. I.C. PACK LOCATIONS ARE GIVEN ON THE WIRE RUN LIST AS ROW A, C, F, OR R ONLY. TRANSLATE TO ACTUAL POSITIONS ON THIS ASSY BY USING THE FOLLOWING EXAMPLE:
 RUN LIST LOCATION = SCHEMATIC ASSY LOCATION
 02C 11 = 02G 41
 ALSO - 05J 01 = 05F 16
 2. DIMENSIONS ARE IN MILLIMETERS.
 3. DIMENSIONS PH1 IN COLUMNS DEN.
 4. FOR MOUNTING OF STANDARD HARDWARE SEE 16-642 D12.
 5. END PINS CLOSEST TO EDGE OF BOARD INWARD PRIOR TO SOLDERING.
 6. CONNECTOR AREAS WHERE THE RESISTOR SIP PACKAGES ARE INSTALLED BEGIN WITH 01 RATHER THAN 00.



UNLESS OTHERWISE SPECIFIED		
SCALE:	TOLERANCE:	
2/1	XX ±.13	X ±.8
(SEE NOTE 3)	X ±.5	ANGLES ±1°
NAME	TITLE	DATE
K. REED	K. REED	DES/DFT 7-23-85
R. CERO	SUPV	
A. HANSEL	CHK	
A. HANSEL	ENG	7/9/85
R. BARKER	MGR	7/11/85
	QC	

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TITLE	ASSEMBLY INTELLIGENT DISC CONTROLLER (IDC) HIGH SPEED
TASK	03211 / 03214
DWG	35-932 RO1 E03 1-1

CAUTION
 PRINTED CIRCUIT PATHS AND PADS ARE SHOWN FOR PERKIN-ELMER'S INTERNAL REFERENCE INFORMATION ONLY.

MILLIMETER	INCH
1.57	.062
3.18	.125
13.46	.530
377.825	14.875
391.287	15.40

NOTE 7: INSERT THE 35-932 INTO CONDUCTIVE GRID BAG, ITEM 12. THE OPEN END MUST BE FOLDED & SECURED WITH (1) ITEM 127.

USED IN MANUAL: 47-032

CONNECTOR 10 (J10)						CONNECTOR 11 (J11)					
ROW 2			ROW 1			ROW 2			ROW 1		
PIN NO.	BRD. LOC.	MNEMONIC	PIN NO.	BRD. LOC.	MNEMONIC	PIN NO.	BRD. LOC.	MNEMONIC	PIN NO.	BRD. LOC.	MNEMONIC
24	OIC61	TSTCLK0	24	OIC31	GND	24	OOC61	RBDI041	24	OOC51	GND
23	OIC62	GND	23	OIC32		23	OOC62	RBDI031	23	OOC52	
22	OIC63	WCSRETI	22	OIC33		22	OOC63	RMAI	22	OOC53	
21	OIC64	GND	21	OIC34		21	OOC64	RBDI021	21	OOC54	
20	OIC65	FBLTCLK0	20	OIC35		20	OOC65	RMBI	20	OOC55	
19	OIC66	PROMENI	19	OIC36		19	OOC66	RBDI011	19	OOC56	
18	OIC67		18	OIC37		18	OOC67	RMCI	18	OOC57	
17	OIC68		17	OIC38		17	OOC68	RBDI001	17	OOC58	
16	OIC69	RBRA41	16	OIC39		16	OOC69	RMCEI	16	OOC59	
15	OIC70	RBRA31	15	OIC40		15	OOC70	RMWEI	15	OOC60	
14	OIC71	RBRA51	14	OIC41		14	OOC71	RAE/OEI	14	OOC61	
13	OIC72	RBRA21	13	OIC42		13	OOC72	RCNTI	13	OOC62	
12	OIC73	RBRA61	12	OIC43		12	OOC73	RPZ0	12	OOC63	
11	OIC74	RBRA11	11	OIC44		11	OOC74	RBRA91	11	OOC64	
10	OIC75	RBRA71	10	OIC45		10	OOC75	RBDI051	10	OOC65	
09	OIC76	RBRA01	09	OIC46		09	OOC76	RBRA81	09	OOC66	
08	OIC77	PA41	08	OIC47		08	OOC77	RRA41	08	OOC67	
07	OIC78	PA51	07	OIC48		07	OOC78	RRA31	07	OOC68	
06	OIC79	PA31	06	OIC49		06	OOC79	RRA51	06	OOC69	
05	OIC80	PA61	05	OIC50		05	OOC80	RRA21	05	OOC70	
04	OIC81	PA21	04	OIC51		04	OOC81	RRA61	04	OOC71	
03	OIC82	PA71	03	OIC52		03	OOC82	RRA11	03	OOC72	
02	OIC83	PA11	02	OIC53		02	OOC83	RRA71	02	OOC73	
01	OIC84	PA81	01	OIC54		01	OOC84	RRA01	01	OOC74	
00	OIC85	PA01	00	OIC55	GND	00	OOC85	SPA91	00	OOC75	GND

CONNECTOR 12 (J12)						CONNECTOR 13 (J13)					
ROW 2			ROW 1			ROW 2			ROW 1		
PIN NO.	BRD. LOC.	MNEMONIC	PIN NO.	BRD. LOC.	MNEMONIC	PIN NO.	BRD. LOC.	MNEMONIC	PIN NO.	BRD. LOC.	MNEMONIC
24	OIF61	RI11	24	OIF31	GND	19	O3F61	BRA41	19	O3F31	GND
23	OIF62	RI01	23	OIF32		18	O3F62	BRA31	18	O3F32	
22	OIF63	RI21	22	OIF33		17	O3F63	BRA51	17	O3F33	
21	OIF64	RCN1	21	OIF34		16	O3F64	BRA21	16	O3F34	
20	OIF65	RI31	20	OIF35		15	O3F65	BRA61	15	O3F35	
19	OIF66	RPOE1	19	OIF36		14	O3F66	BRA11	14	O3F36	
18	OIF67	RI41	18	OIF37		13	O3F67	BRA71	13	O3F37	
17	OIF68	RM11	17	OIF38		12	O3F68	BRA01	12	O3F38	
16	OIF69	RB01	16	OIF39		11	O3F69		11	O3F39	
15	OIF70	RI81	15	OIF40		10	O3F70		10	O3F40	
14	OIF71	RB11	14	OIF41		09	O3F71		09	O3F41	
13	OIF72	RI71	13	OIF42		08	O3F72	ME0	08	O3F42	
12	OIF73	RB21	12	OIF43		07	O3F73	LBD41	07	O3F43	
11	OIF74	RI61	11	OIF44		06	O3F74	LBD51	06	O3F44	
10	OIF75	RB31	10	OIF45		05	O3F75	LBD31	05	O3F45	
09	OIF76	RI51	09	OIF46		04	O3F76	LBD61	04	O3F46	
08	OIF77	RSI01	08	OIF47		03	O3F77	LBD21	03	O3F47	
07	OIF78	AR31	07	OIF48		02	O3F78	LBD71	02	O3F48	
06	OIF79	RSI11	06	OIF49		01	O3F79	LBD11	01	O3F49	GND
05	OIF80	AR21	05	OIF50		00	O3F80	PZ0	00	O3F50	LBD01
04	OIF81	RSI21	04	OIF51							
03	OIF82	ARI1	03	OIF52							
02	OIF83	RSI31	02	OIF53							
01	OIF84	AR01	01	OIF54							
00	OIF85		00	OIF55	GND						

C. NO.	CABLE CONNECTOR MAP		BACK PANEL MAP		TERM. NO.
	ROW 2	ROW 1	ROW 1	ROW 2	
6	12 SECT0A1	SECT0B1			41
	11 GND	INX0B1			40
	10 INX0A1	GND			39
	09 SKED0A1	SKED0B1			38
	08 USEL0B1	USEL0A1			37
	07 GND	WDAT0B1			36
	06 WDAT0A1	GND			35
	05 WCLK0A1	WCLK0B1			34
	04 GND	RCLK0B1			33
	03 RCLK0A1	GND			32
	02 RDAT0A1	RDAT0B1			31
	01 GND	SCLK0B1		BUS SW0	30
	00 SCLK0A1	GND			29
					28
					27
			SCLR0	HW0	26
				SCHK0	25
			SNS0	SBST0	24
			SYND	ATND	23
			RACK0	TACK0	22
			CL070	DA0	21
			DR0	CM00	20
			SR0	ADR50	19
			D140	D150	18
			D120	D130	17
			D100	D110	16
			D080	D090	15
			D060	D070	14
			D040	D050	13
			D020	D030	12
			D000	D010	11
					10
					09
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REVISIONS

RELEASED FOR PRODUCTION

MFG. ENG. MTD BK DATE 9/2/82

REVISION COLUMN CLEARED FOR PREVIOUS REVS SEE ROA MICRO FILM COPY IN SPAKE'S LIST. DELETED INFO FOR 19-058 IC 16J OUTPUTS 6 & 12. ADDED INFO FOR 20J & 22M. REV'D SHTS 1,3,4,6,7,10,12,13 & 17.

AH 411 5250 R 1-28-83 AD9 X

SPARE GATE LIST: ADD 13H PIN 12 (19-058), REMOVED 08M PIN 14-04B PIN 02 (19-154), AREA M9, 35-807 WAS R09. REV'D SHTS 1,6,7,11,14,21 & 23.

KR 411 5311 MS 4-7-83 R0 X

AREA M9, 35-807 WAS R12. REVISED SHTS 1 & 3.

DE J11 5397 MS 7-5-83 R11 X

AREA M9, 35-807 WAS R11. REVISED SHTS 15, 17.

DB 5541 MS 11-16-83 R12 X

SPARE GATE LIST: ADDED NEW IC 19-153, 23F PINS 03, 06 & 11. AREA M9, 35-807 WAS R12. ADDED GATE 00H PIN 11 (19-055). DELETED GATE 13H PIN 12 (19-058). REVISED SHTS 1,6,9,11,14 & 23.

DB KR 5549 MS 12-20-83 R13 X

SPARE GATE LIST: DELETED 23H 08 & 23F 11. REVISED SHTS 1,7,13,14 & 23.

HH 411 5668 MS 4-12-84 R14 X

SPARE GATES LIST: DELETED: 23F 03/06 (19-153), 21H 08-09 (19-063), 19C 08 (19-290), 19M 18 (19-297), 23H 11 (19-160). REVISED SHTS: 1,3,6,14,15,19 & 23.

MF 411 5747 MS 9-25-84 R15 X

SPARE GATES LIST: ADDED 19-042 F01, 05A PINS 05/12 & 19-137, 07B PIN 05. REVISED SHTS 1,3,6,14,15,19 & 23.

MF 411 5853 MS 2-27-85 R16 X

REVISED SHEETS 1,3,6 & 19.

BG 411 6191 MS 9-20-85 R17 X

UNLESS OTHERWISE SPECIFIED

SCALE: NONE TOLERANCE:

DIMENSIONS ARE IN .XXX ± .005 X ± .03 INCHES .XX ± .02 ANGLES ± 1°

NAME	TITLE	DATE
BLUSK	BLUSK	DES/DFT 6-23-81
R. CERO	SUPV	4-30-82
E. GREENSTEIN	TEST	4-30-82
R. REAGO	ENG	4-30-82
W. RICE	MGR	4-30-82
R. BARKER	QC	4-30-82

PERKIN-ELMER

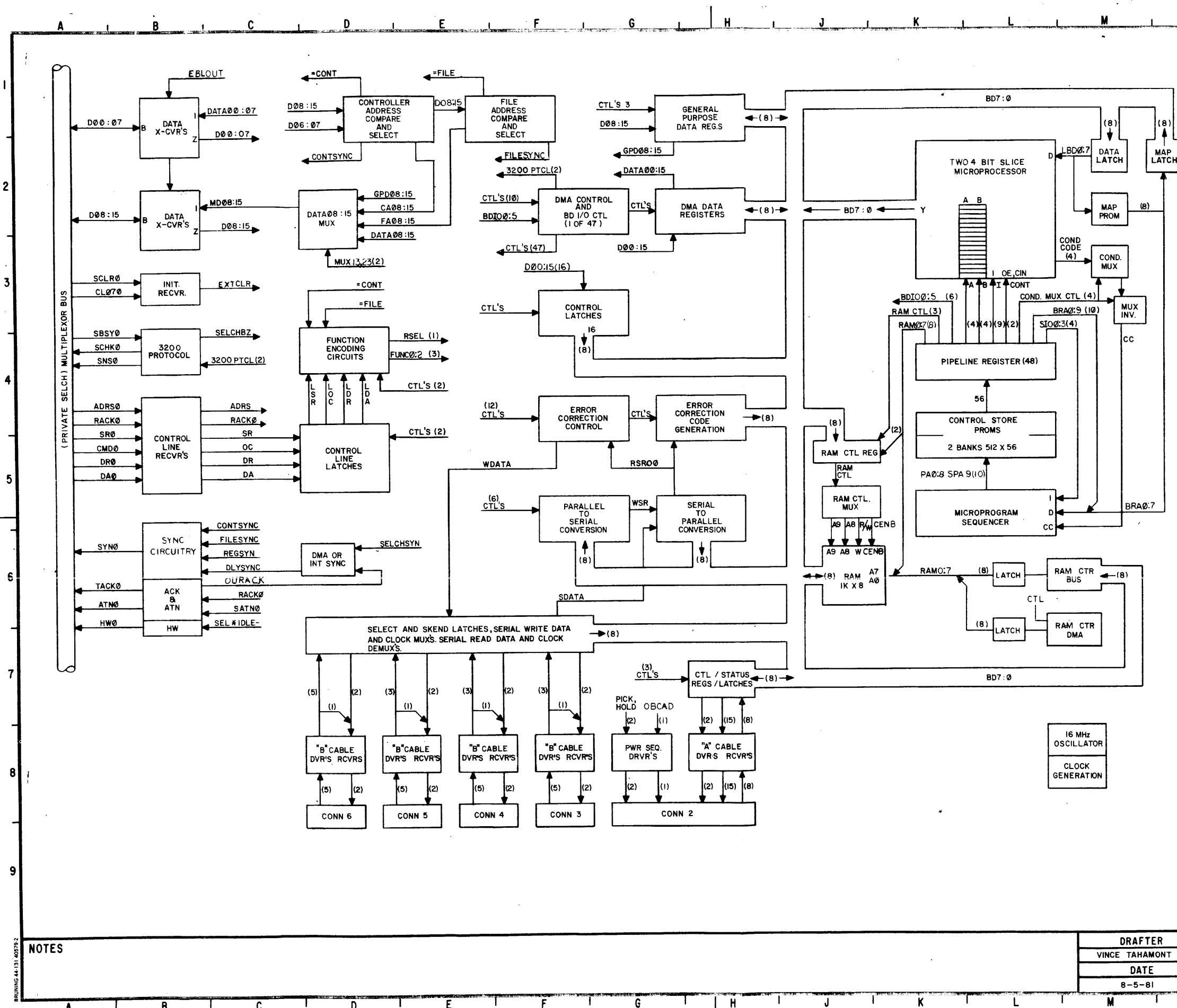
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TITLE SCHEMATIC INTELLIGENT DISC CONTROLLER

TASK 03983 SHT 1-23

DWG 35-807R17 D08



REVISIONS			
PROTO	REL AT	ROI.	
E.C.J.	016	11-18-81	RO1
2ND PROTO REL AT RO2			
E.C.J.		12-30-81	RO2
EXTENSIVE CHANGES			
DS	4986	2-5-82	RO3
EXTENSIVE CHANGES TO CORRECT NUMEROUS DOCUMENT ERRORS. SEE RO3 MICROFILM FOR PREVIOUS REV LEVEL.			
JLV	5127	7-27-82	RO4

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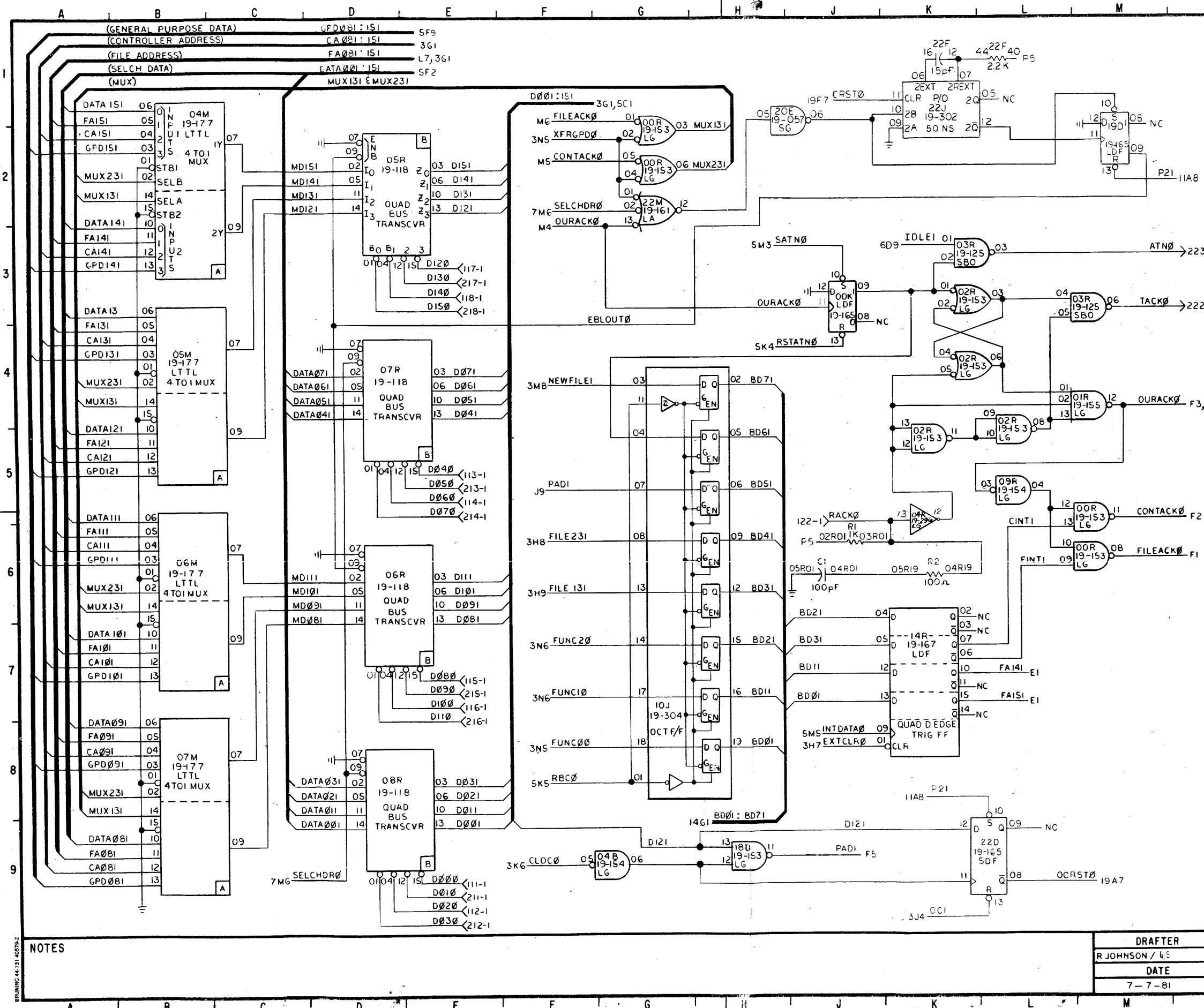
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TITLE SCHEMATIC
 I. D. C.

DRAFTER	VINCE TAHAMONT
DATE	8-5-81
TASK	03983
DWG	35-807 R04
SHT	2-23

NOTES

BRUNING 44-131 40979-2



REVISIONS				
PRCTC	REL AT	ROI.		
ECJ	11-18-81	ROI		
2ND PRCTC REL AT RO2				
ECJ	12-30-81	RO2		
AREA K3 ADD-L 22D (19-023)				
ENVL	4986	2-5-82	203	X
19D12 AT M2 WAS PS. I.C. 22D AT AT L9 WAS 19-063				
ECJ	5012	M	3-2-82	RO4
AREA M2 I.C. 19D WAS 19-063 SDF. AREA K6 I.C. 07H WAS 19-154 LG.				
JAH	5250	K	1-28-83	RO5
AREA K3 03R-01 WAS CONNECTED TO 00K-10 (SAT10)				
EG	6191	MS	9-20-85	RO6

PERKIN-ELMER

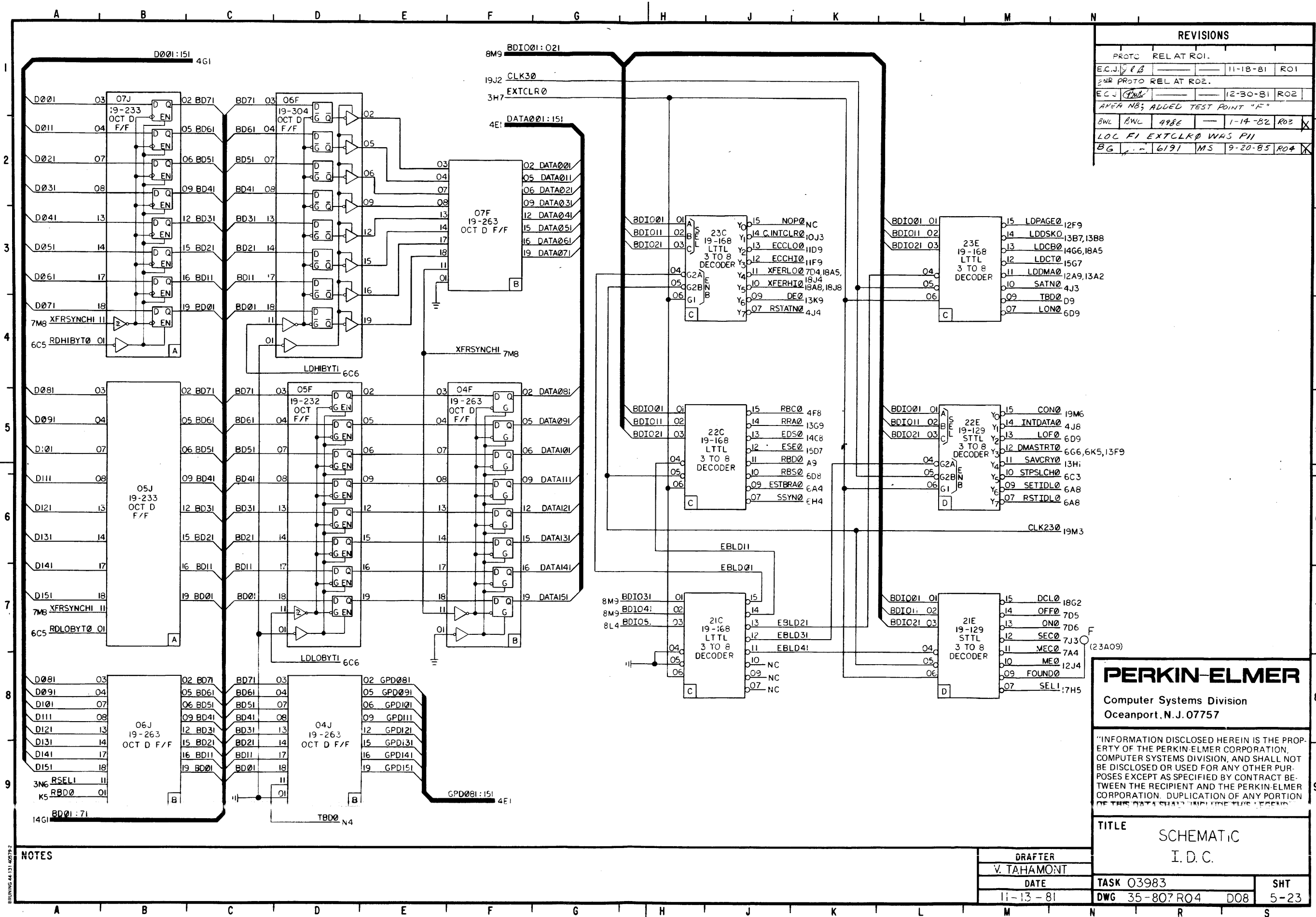
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TITLE SCHEMATIC	
IDC	
DRAFTER	R JOHNSON / WJS
DATE	7-7-81
TASK	03983
DWG	35-807R06
SHT	4-23

NOTES

BRUNING 44-131-40292



REVISIONS				
PROTC	REL AT	ROI.		
ECJ	11-18-81	ROI		
2ND PRTO REL AT R02.				
ECJ	12-30-81	R02		
AREA N8; ADDED TEST POINT "F"				
BWL	BWL	4986	1-14-82	R03
LOC FI EXTCLK0 WAS P11				
BG	6191	MS	9-20-85	R04

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 Oceanport, N.J. 07757

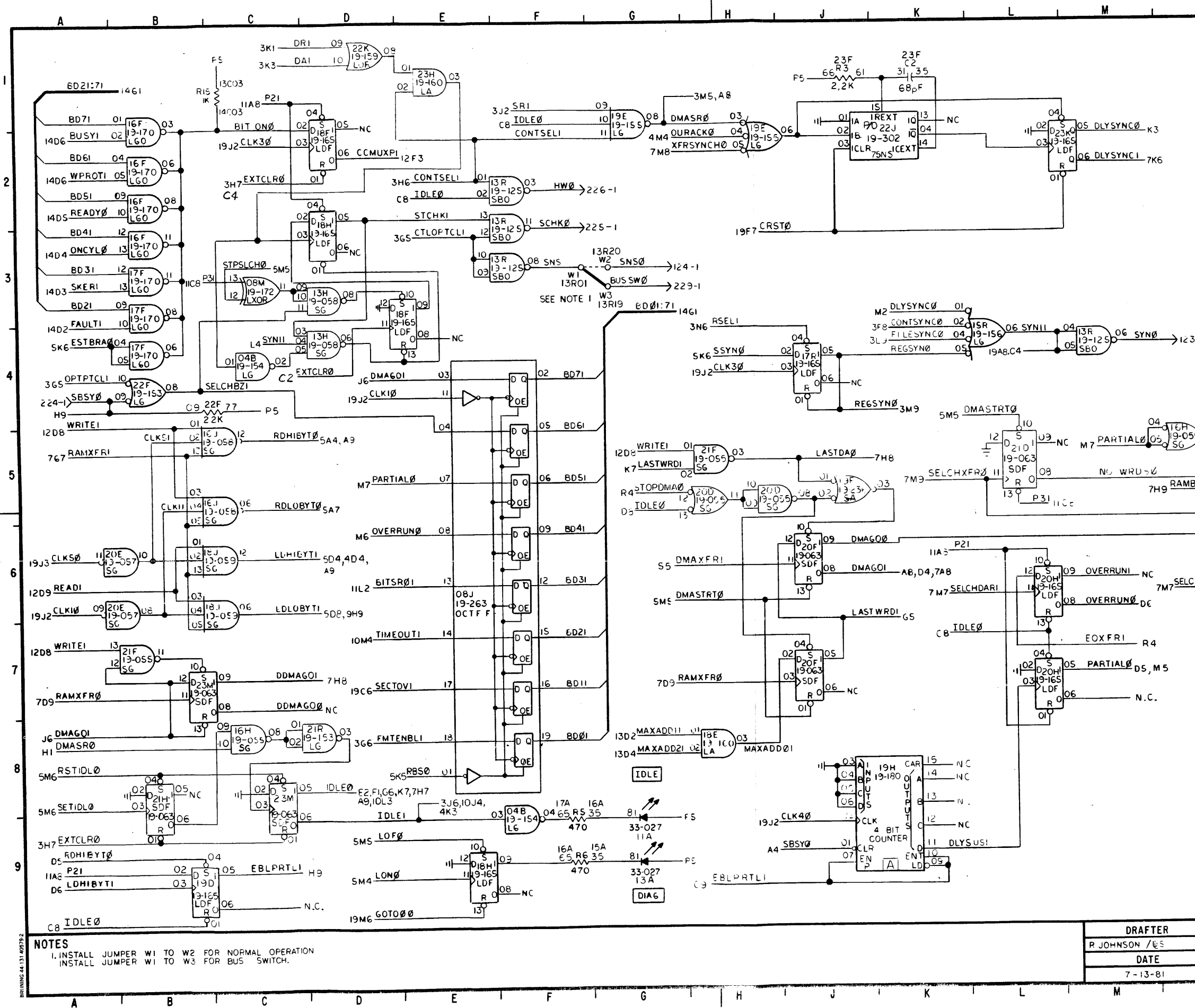
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TITLE
 SCHEMATIC
 I. D. C.

DRAFTER	V. TAHAMONT	TASK	O3983	SHT	
DATE	11-13-81	DWG	35-807 R04	D08	5-23

NOTES

BRUNING 44-131-6079-2



REVISIONS			
FOR PREVIOUS REV HISTORY SEE ROT MICROFILM.			
AREA C1, RESISTOR R15 WAS RM35, 2.2K. AREA D6, ADDED CROSS REF "9H9" TO MINEMONK LDLOBYTI.			
DB	KE	5549	MS 12-16-83 ROB
AREA L4, CHANGED 15H 02, 04, 05. CONNECTIONS WERE: 15R02 TO MORSYN0, 3ND. 15R04 F15 TO 17K05, 01. 15R05 ADDED CROSS REF 19M7.			
MF	772	6747	MS 9-25-84 ROB
AREA L4, X-REF 19A8 WAS 19M7 ON 13R05.			
MF	772	5853	MS 2-21-85 R10
LOC M2 DLYSYN01 WAS NC			
BG	772	6191	MS 9-20-85 R11

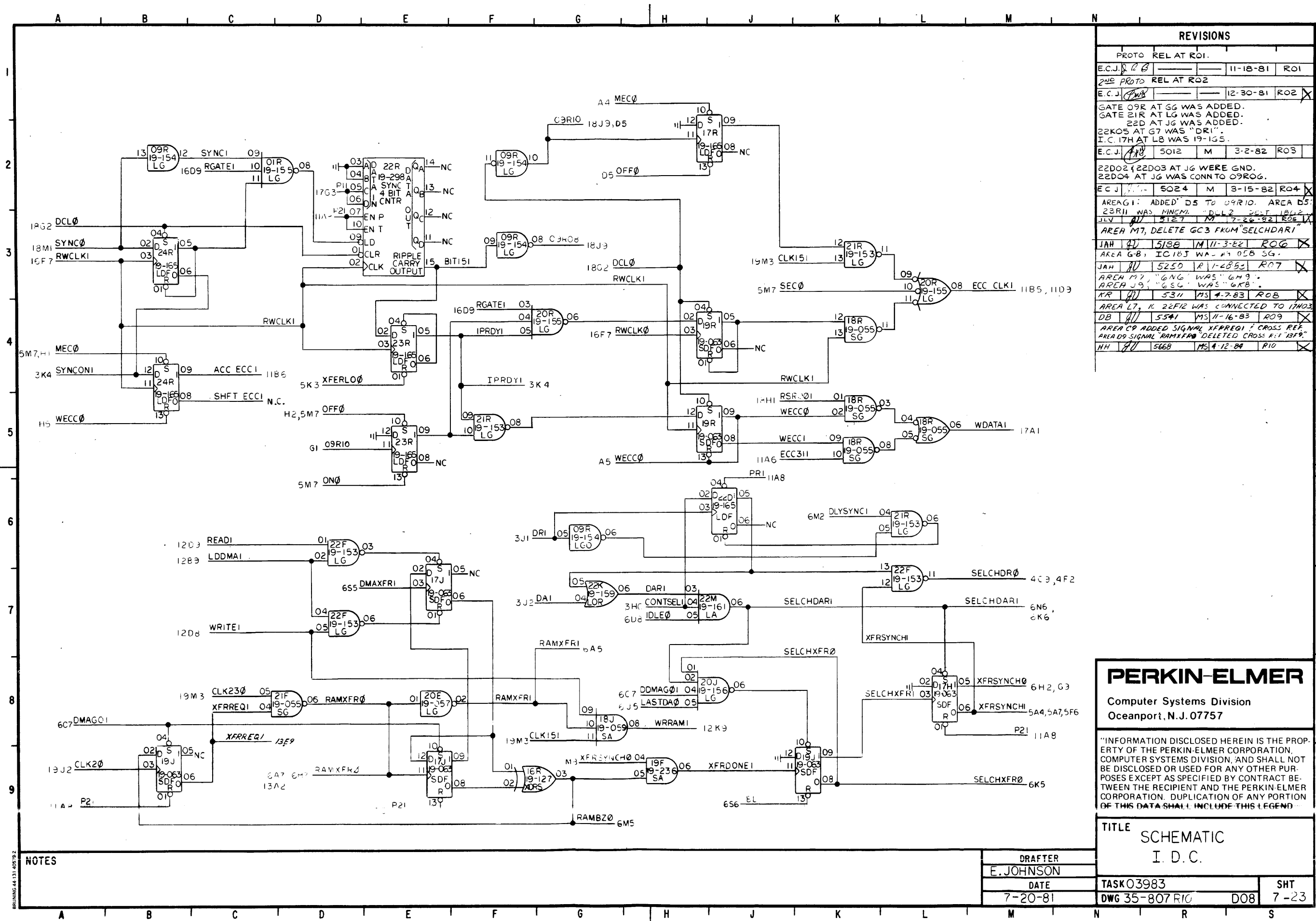
NOTES
 1. INSTALL JUMPER W1 TO W2 FOR NORMAL OPERATION
 2. INSTALL JUMPER W1 TO W3 FOR BUS SWITCH.

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TITLE SCHEMATIC
 IDC

DRAFTER	R JOHNSON /ES
DATE	7-13-81
TASK 03983	SHT
DWG 35-807 R11	D08 6-23

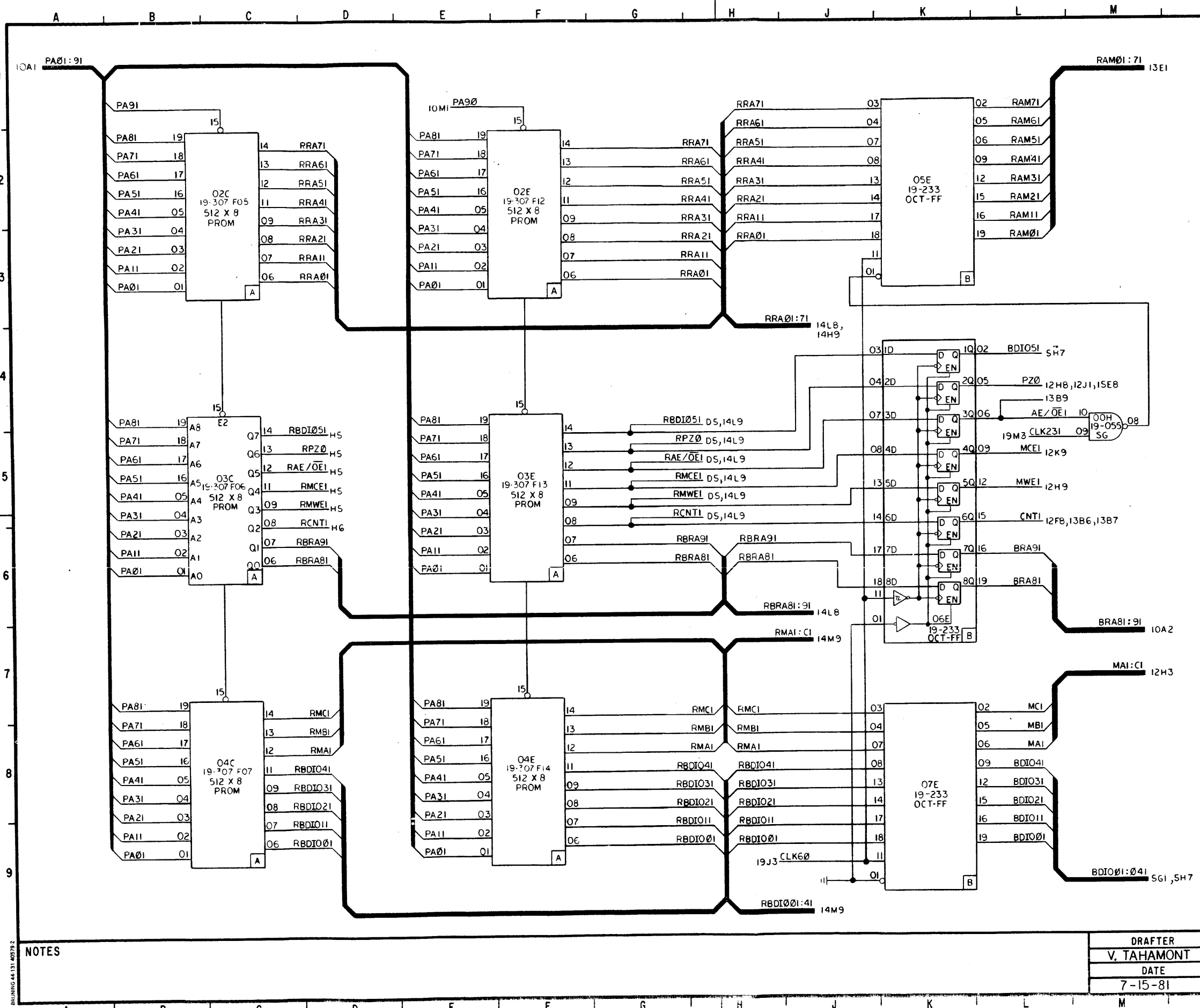


REVISIONS				
PROTO	REL AT	ROI	DATE	BY
E.C.J.	11-18-81	RO1		
2ND PRTO REL AT R02				
E.C.J.	12-30-81	RO2		
GATE 09R AT GG WAS ADDED. GATE 21R AT LG WAS ADDED. 22D AT JG WAS ADDED. 22K05 AT G7 WAS "DRI". I.C. 17H AT L8 WAS 19-1G5.				
E.C.J.	5012	M	3-2-82	RO3
22D02, 22D03 AT JG WERE GND. 22D04 AT JG WAS CONN TO 09R0G.				
E.C.J.	5024	M	3-15-82	RO4
AREA G1: ADDED D5 TO 09R10. AREA D5: 23R11 WAS MNEI. D5L2, D5L1, 18L2 JLV 11 5127 M 7-26-82 R05 X				
AREA M7, DELETE GC3 FROM SELCHDARI				
JAH	5158	M	11-3-82	RO6
AREA G8, IC18J WA- 19 05B SG.				
JAH	5250	R	1-6-83	RO7
AREA M7, "6NG" WAS "6M9". AREA J9, "6SL" WAS "6KB".				
KR	5311	MS	4-7-83	RO8
AREA L7, IC 22F2 WAS CONNECTED TO 17H03				
DB	5541	MS	11-16-83	RO9
AREA C9 ADDED SIGNAL XFRREQI / CROSS REF. AREA D9 SIGNAL RAMXFØ DELETED CROSS REF. 18F9.				
HH	5668	MS	4-12-84	R10

NOTES

DRAFTER		TITLE	
E. JOHNSON		SCHEMATIC	
DATE		I. D. C.	
7-20-81		TASK03983	SHT
		DWG 35-807 R10	7-23
		D08	

BRUNING 44131-005/82



REVISIONS			
PROTO	REL AT	RO1	
E.C.J.		11-19-81	RO1
2ND PROTO REL AT RO2			
E.C.J.		12-30-81	RO2 X
ADDED FUNCTION VARIATION DESIGNATION TO ALL 19-307 IC (6 PLCS)			
JLV	9/1	5127	M 7-26-82 RO3 X

NOTES

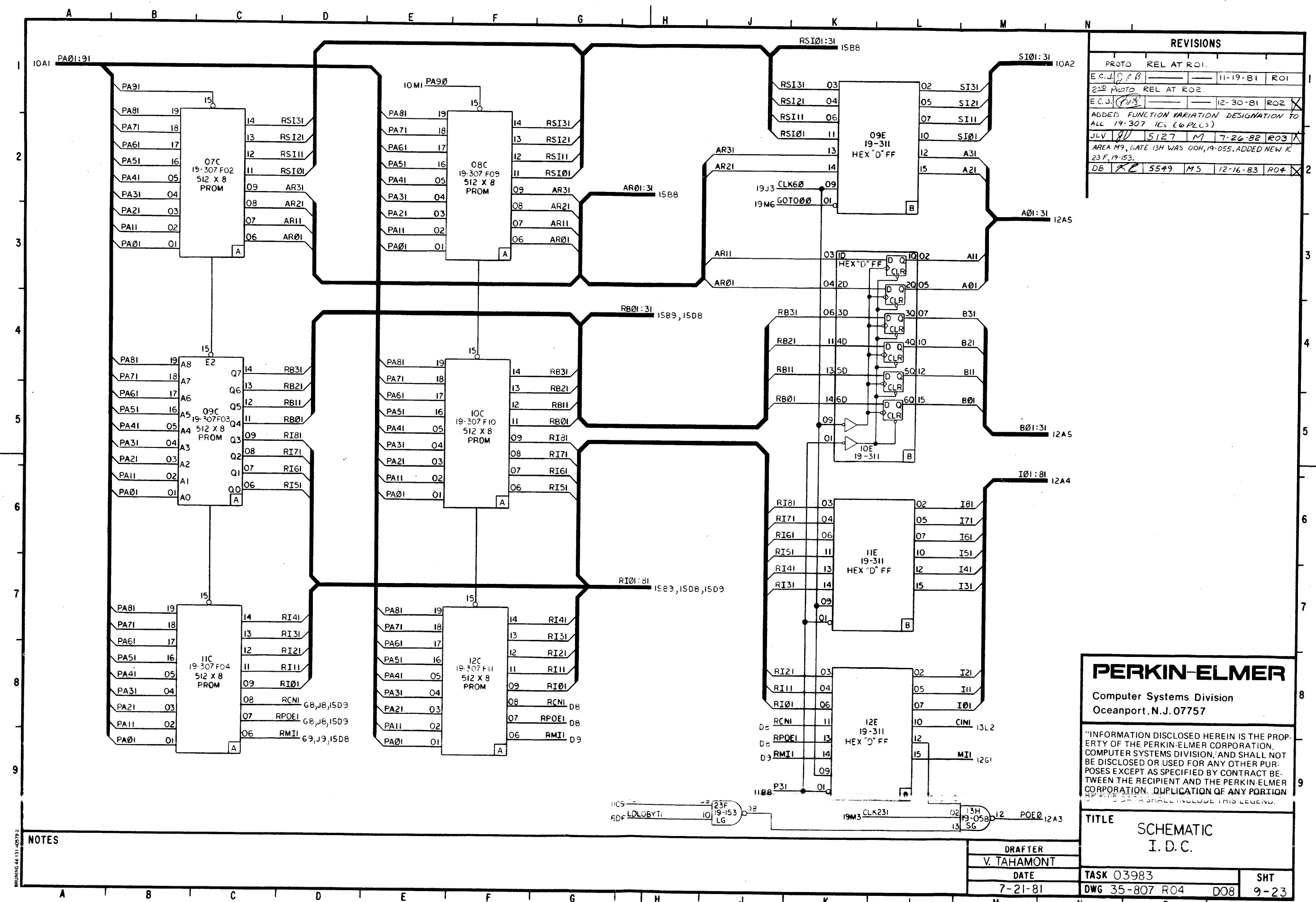
REVISIONS 44-131-402702

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TITLE
 SCHEMATIC
 I.D.C.

DRAFTER	V. TAHAMONT	TASK 03983	SHT
DATE	7-15-81	DWG 35-807R03	DO8
			8-23



REVISIONS			
PROTO	REL AT	ROI	
E.C.J.	11-19-81	ROI	
2 ND PHOTO REL AT RO2.			
E.C.J.	12-30-81	RO2	X
ADDED FUNCTION VARIATION DESIGNATION TO ALL 19-307 ICs (6 PLS)			
JLV	5127 M	7-26-82	RO3 X
AREA M9, GATE 13H WAS 00H, 19-055. ADDED NEW IC 23F, 19-153.			
DB	5549 MS	12-16-83	RO4 X

NOTES

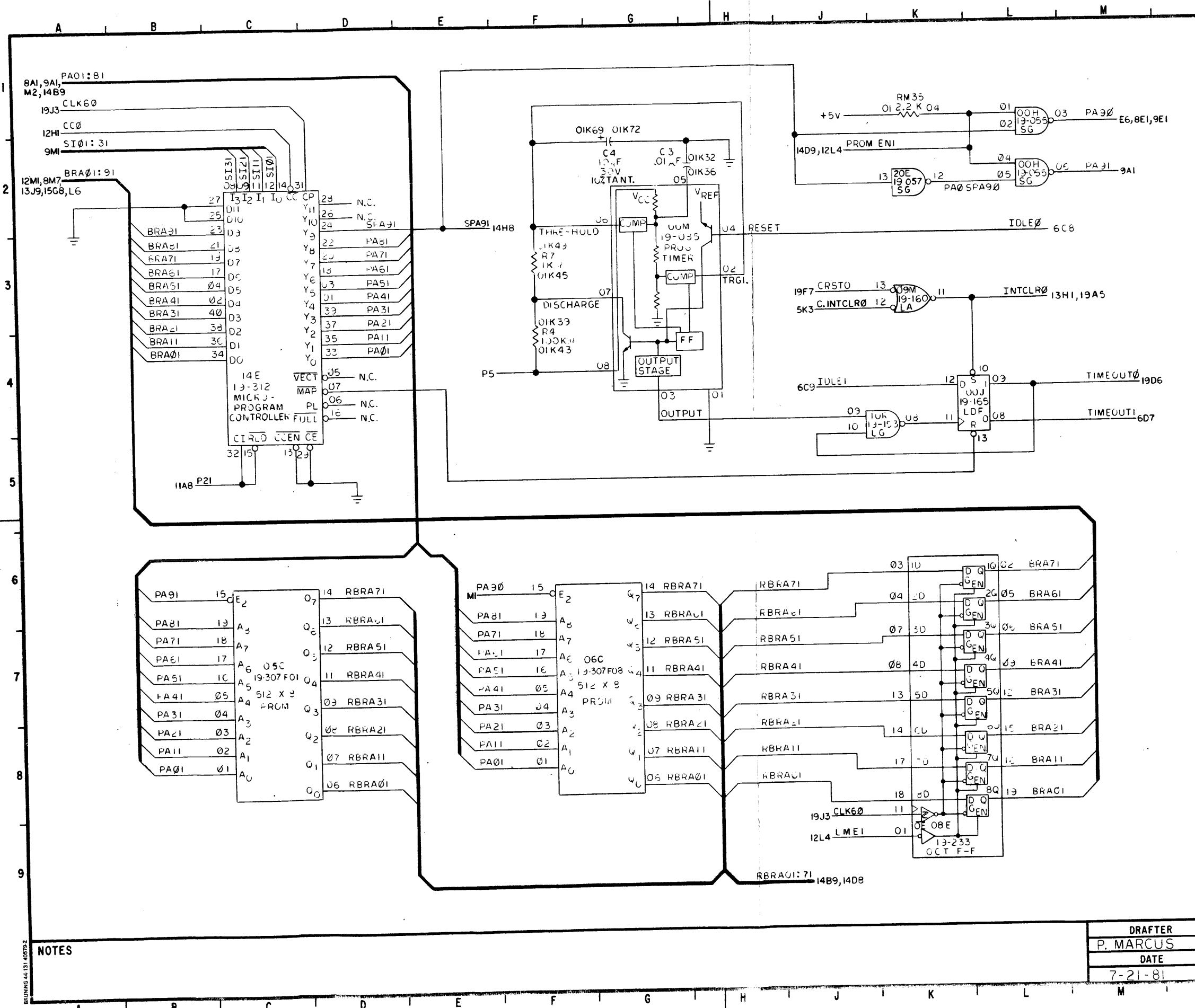
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TITLE: SCHEMATIC I. D. C.

DRAFTER	V. TAHAMONT
DATE	7-21-81
TASK	O3983
DWG	35-807 R04
SHT	9-23

BRUNING 44 131 4078 Z



REVISIONS				
PROTO REL AT R01				
ECJ	B		11-19-81	R01
2ND PROTO REL AT R02				
ECJ			12-30-81	R02
ADDED FUNCT VARIATION DESIGNATION TO 19-307, ICs 05C & 06C				
JLV	Q1	S127	M	7-26-82 R03
AREA K-2, IC-20E, PAET # WAS 19-154				
JAH	RU	5250	R	1-28-82 R04

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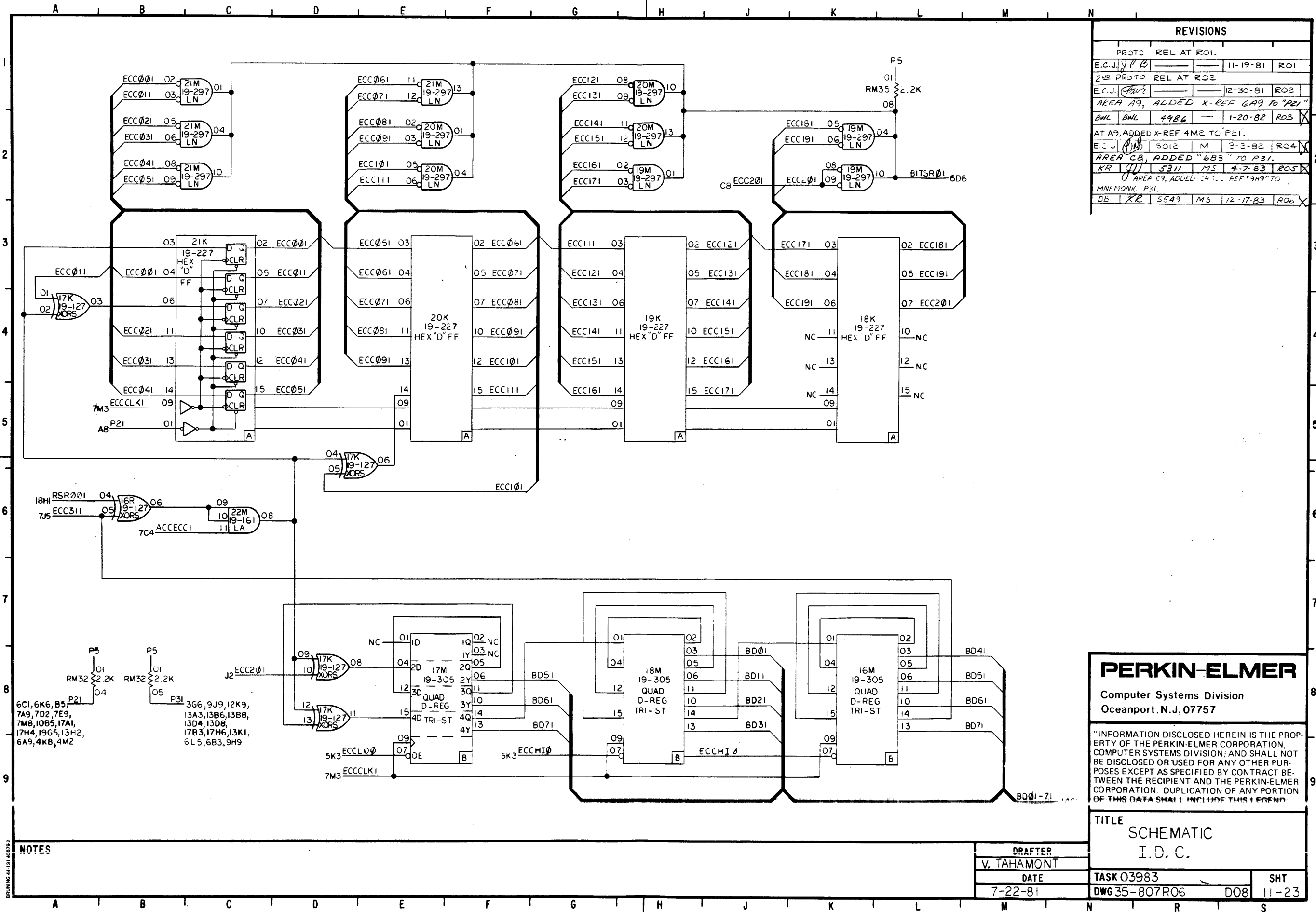
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TITLE
 SCHEMATIC
 IDC

DRAFTER P. MARCUS	TASK 03983	SHT
DATE 7-21-81	DWG 35-807R04	10-23

NOTES

BRUNING 44-131-409792



REVISIONS					
PRTO REL AT RO1.					
E.C.J.	11-19-81	RO1			
2ND PRTO REL AT RO2					
E.C.J.	12-30-81	RO2			
AREA A9, ADDED X-REF 6A9 TO "P21"					
BWL	4986	1-20-82	RO3		
AT A9, ADDED X-REF 4M2 TO "P21"					
E.C.J.	5012	M	3-2-82	RO4	
AREA C9, ADDED "6B3" TO P31.					
KR	5311	MS	4-7-83	RO5	
AREA C9, ADDED "4" - REF "949" TO MNEMONIC P31.					
DB	KR	5549	MS	12-17-83	RO6

NOTES

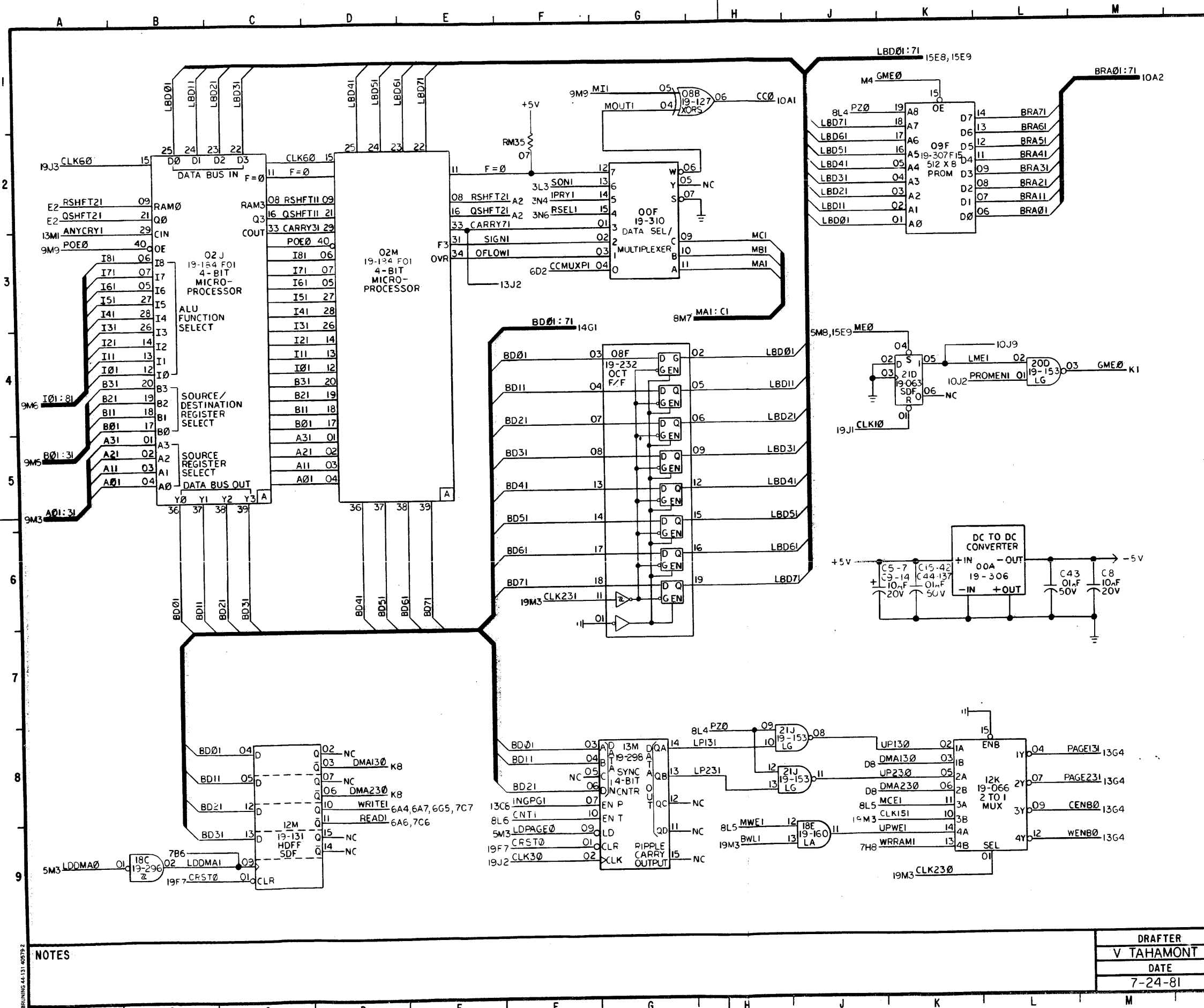
- 6C1, 6K6, 85, 7A9, 7D2, 7E9, 7M8, 10B5, 17A1, 17H4, 19G5, 13H2, 6A9, 4K8, 4M2
- 3G6, 9J9, 12K9, 13A3, 13B6, 13B8, 13D4, 13D8, 17B3, 17H6, 13K1, 6L5, 6B3, 9H9

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TITLE
 SCHEMATIC
 I.D.C.

DRAFTER	V. TAHAMONT
DATE	7-22-81
TASK	03983
DWG	35-807RO6
SHT	11-23
	DO8

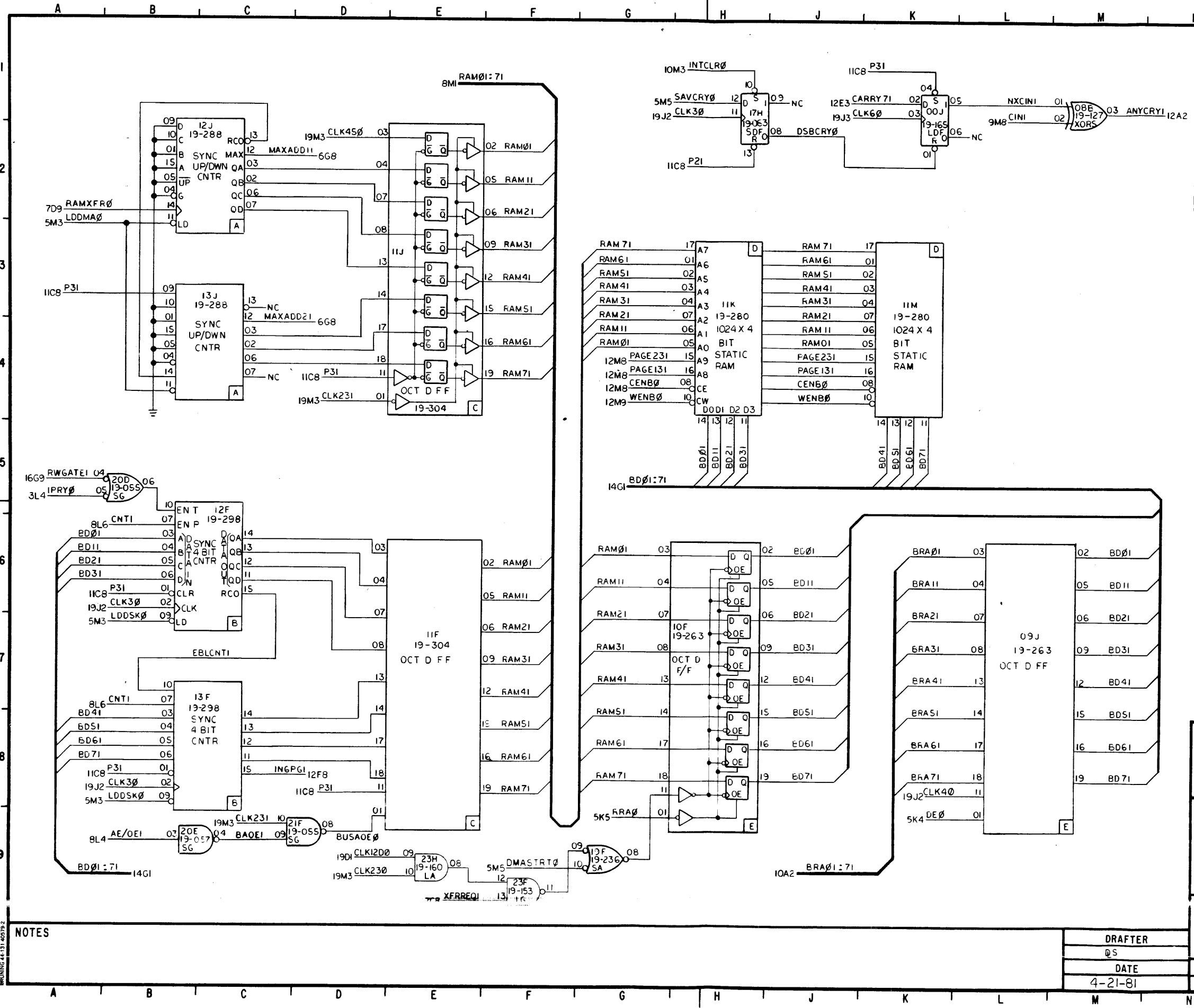


REVISIONS			
PROTO REL AT RO1.			
ECJ	11-19-81	RO1	
REL AT RO2			
ECJ	12-31-81	RO2	X
18E13 AT H9 WAS CLK20 WITH X-REF 19J2			
ECJ	5024 M	3-15-82	RO3 X
AREAS C3 & D3 O2J & O2M WERE 19-313.			
JLV	4921 R	4-16-82	RO4 X
AREA K9: 12K10 WAS MNEIM P31 DEST 11CB. ADDED F15 TO 1C M/F (AREA K2)			
JLV	5127 M	7-26-82	RO5 X
AREA K6: ADDED LD LOGIC TO DC TO DC CONVERTER (O2A).			
JLV	5250 K	1-28-83	RO6 X

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TITLE SCHEMATIC I. D. C.	
DRAFTER V TAHAMONT	TASK O3983
DATE 7-24-81	DWG 35-807RO6
	SHT 12-23

NOTES

BRUNING 44-131 409782



REVISIONS				
PROTO REL AT R01.				
E.C.J.	P.R.		11-19-81	R01
E.C.J. PROTO REL AT R02.				
E.C.J.	W.B.		12-31-81	R02
AT H1, 17H WAS 19-165.				
E.C.J.	W.B.	5012	M	3-2-82
AREA B9, IC 20E, 19H, 17H WAS 19-159.				
JAH	R.U.	5250	R	1-23-83
AREA E9 ADDED IC'S 23H, 23F, AREA G9 IC 19F PIN 09 WAS SIGNAL RAMXFR, CROSS REF 709.				
NH	A.U.	5660	MS	4-12-84
				R05

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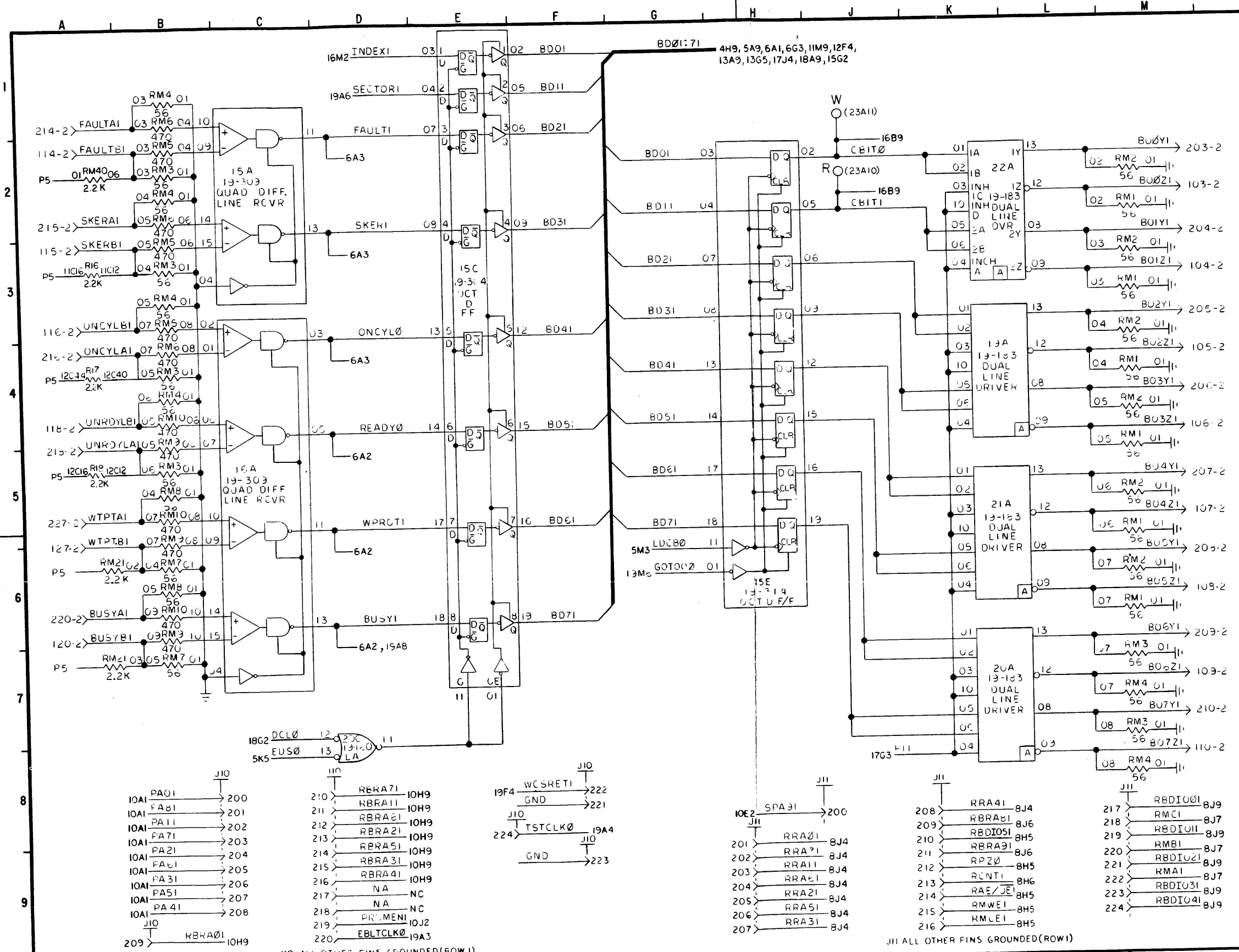
TITLE SCHEMATIC
IDC

DRAFTER	DS
DATE	4-21-81
TASK	TASK 03983
DWG	DWG 35-807R05
SHT	D08 13 -23

NOTES

DRAWING 44131-00519-2

REVISIONS				
PRG	REL AT	ROI		
E.C.J.	11-19-81	RO1		
REL AT RO2.				
E.C.J.	12-31-81	RO2		
ADDED TESTPOINTS W&R				
BWL	ENL	4986	1-14-82	RO3
AREA A2, ADDED RESISTOR RM40.				
KR	5311	MS	3-31-83	RO4
AREA A3-A5, ADDED RESISTORS R16, R17 & R18.				
DB	KR	5549	MS	12-17-83
AREA A4, 15E, CLR, WAS DE (OFF S).				
AREA D6 ADDED, XIN & XOUT TO MESSAGES BUSY1.				
MF	5747	MS	5-25-84	RO6
AREA D6 X-REF 19A3 WAS 19H7 ON BUSY1.				
MF	5853	MS	2-21-85	RO7



J10	J10
IOA1 PA01	200
IOA1 FA01	201
IOA1 PA11	202
IOA1 FA71	203
IOA1 PA21	204
IOA1 FA01	205
IOA1 PA31	206
IOA1 PA51	207
IOA1 PA41	208
J10	
209	HBRA01 10H9

J10	J10
210	RBRA71 10H9
211	RBRA11 10H9
212	RBRA01 10H9
213	RBRA21 10H9
214	RBRA51 10H9
215	RBRA31 10H9
216	RBRA41 10H9
217	NA NC
218	NA NC
219	PRY.MEN1 10J2
220	EBLTCLK0 19A3

J10	J10
19F4	WCSRET1 222
	GND 221
J10	
224	TSTCLK0 19A4
	GND 223

J11	J11
IOE2	SPA31 200
J11	
201	RRA01 8J4
202	RRA11 8J4
203	RRA01 8J4
204	RRA01 8J4
205	RRA21 8J4
206	RRA51 8J4
207	RRA31 8J4

J11	J11
208	RRA41 8J4
209	RBRA01 8J6
210	RBRA01 8H5
211	RPZ01 8J6
212	RBRA01 8H5
213	RCNT1 8H6
214	RAE/01 8H5
215	RMWE1 8H5
216	RMCE1 8H5

J11	J11
217	RBDA01 8J9
218	RMCE1 8J7
219	RBDA01 8J9
220	RMB1 8J7
221	RBDA01 8J9
222	RMA1 8J7
223	RBDA01 8J9
224	RBDA01 8J9

J10 ALL OTHER PINS GROUNDED (ROW 1)

J11 ALL OTHER PINS GROUNDED (ROW 1)

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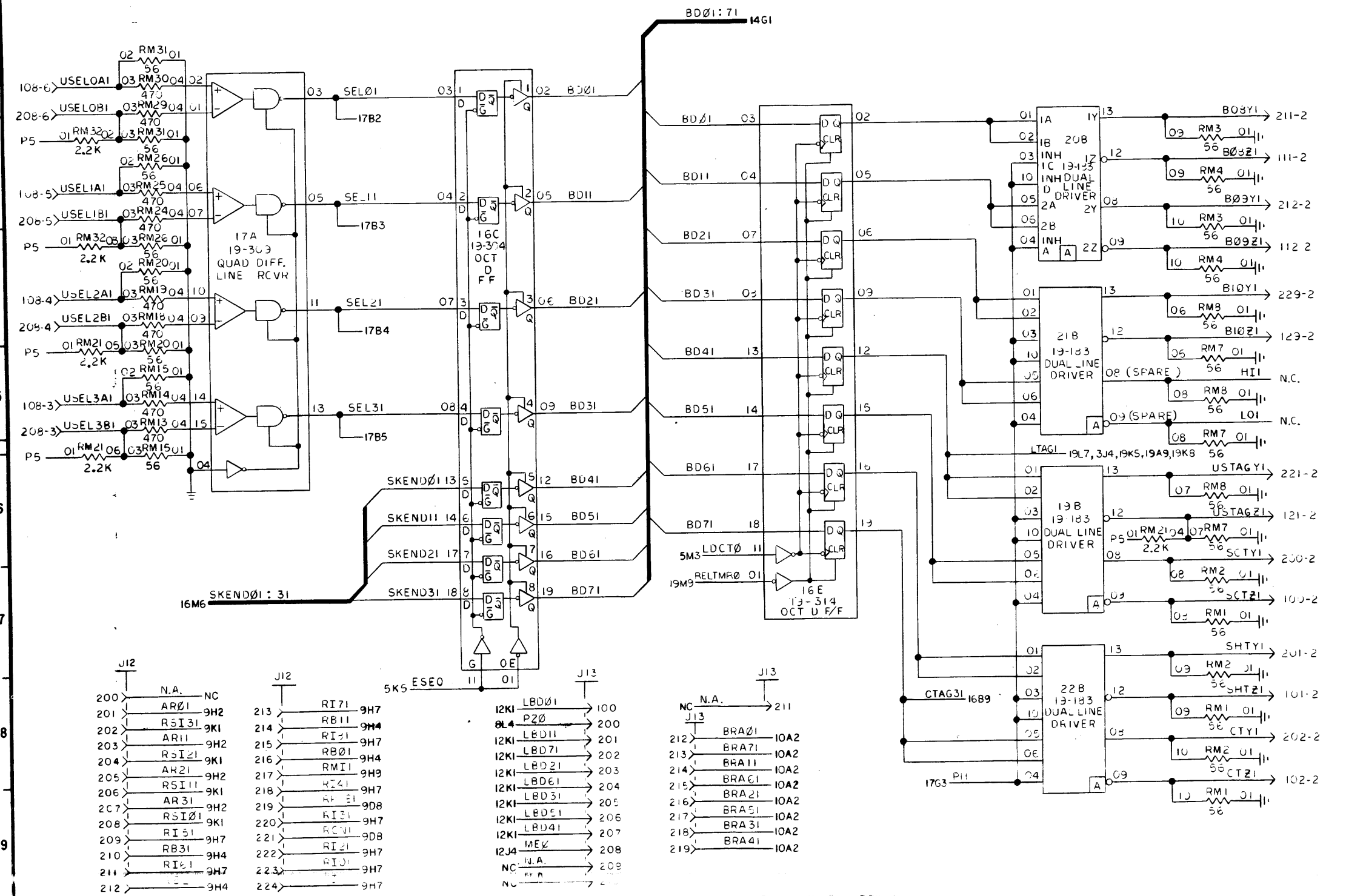
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DRAFTER	P. MARCUS	TASK	03983
DATE	7-23-81	DWG	35-807R07
SHT	14-23	DO3	

NOTES

BRUNING 44-131-405782

A B C D E F G H J K L M N

1
2
3
4
5
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7
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9



J12

200	N.A.	NC
201	AR01	9H2
202	RSI31	9K1
203	ARI1	9H2
204	RSI21	9K1
205	AR21	9H2
206	RSI11	9K1
207	AR31	9H2
208	RSI01	9K1
209	RI51	9H7
210	RB31	9H4
211	RI61	9H7
212	N.A.	9H4

J12 ALL OTHER PINS UNCONNECTED (ROW 1)

J13

12K1	LBD01	100
12K1	PZ0	200
12K1	LBD11	201
12K1	LBD71	202
12K1	LBD21	203
12K1	LBD61	204
12K1	LBD31	205
12K1	LBD51	206
12K1	LBD41	207
12J4	MEK	208
NC	N.A.	209
NC	N.A.	210

J13 ALL OTHER PINS EXCEPT PIN 100 ARE UNCONNECTED (ROW 1)

J13

NC	N.A.	211
212	BRA01	10A2
213	BRA71	10A2
214	BRA11	10A2
215	BRA61	10A2
216	BRA21	10A2
217	BRA51	10A2
218	BRA31	10A2
219	BRA41	10A2

REVISIONS

PROTO REL AT R01.			
E.C.J.	11-19-81	R01	
2ND PROTO REL AT R02.			
E.C.J.	12-31-81	R02	
SIG5 USTAGY1 & USTAGZ1 OF AREA M6 WERE USTAGY1 & USTAGZ1 RESPECTIVELY.			
DS	4986	12-5-82	R03
AREA M3 'CLK' WMS 'DE (PFL)'. AREA J5 ADDED X-REF LTAG1. AREA G7 X-REF 19M3 WAS 19M4 (CROSS).			
MF	5141	3-20-84	R04
AREA L6 ADDED X-REF 19A9 & 19K8 TO LTAG1			
MF	5853	2-21-85	R05

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Computer Systems Division
Oceanport, N.J. 07757

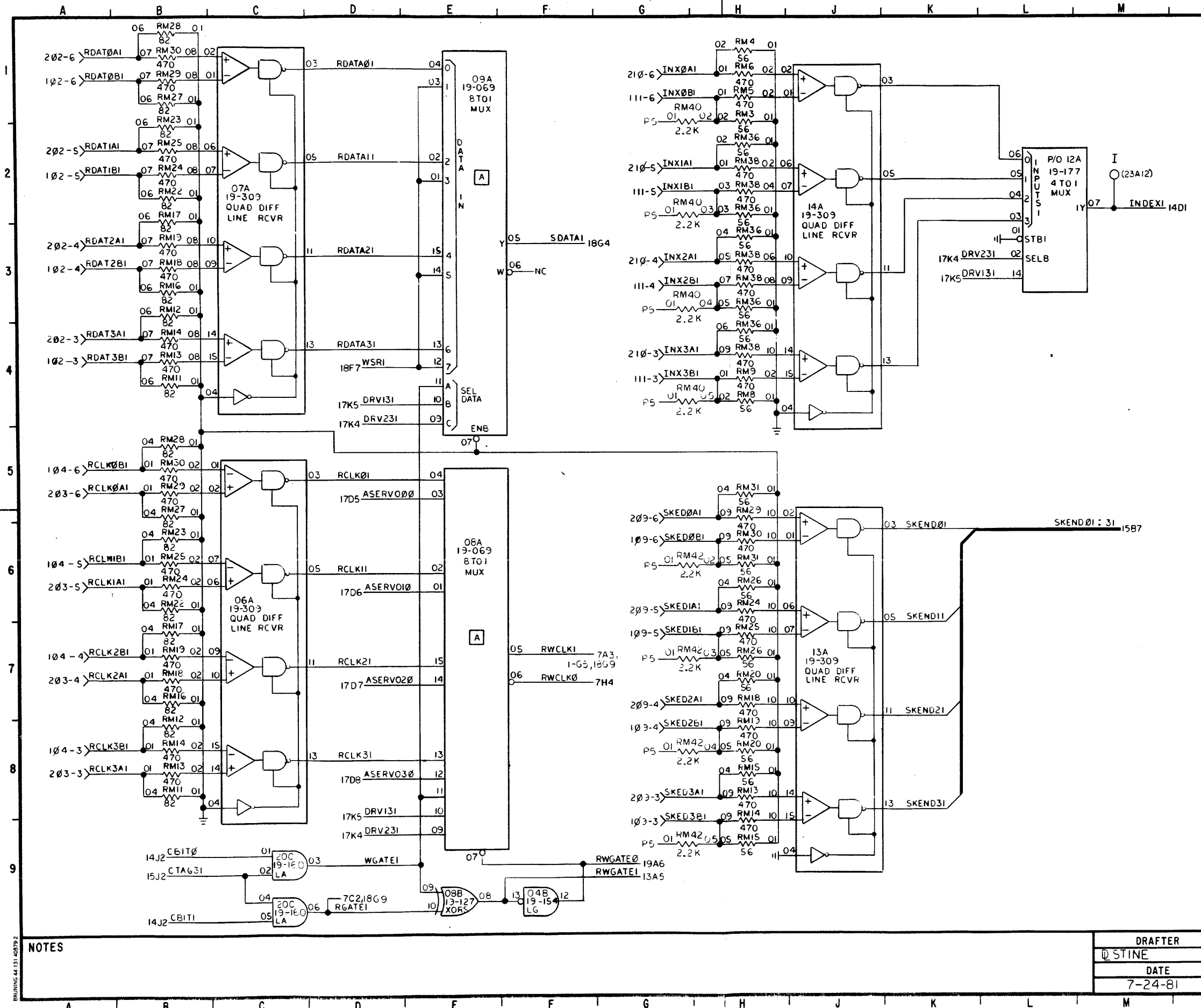
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TITLE	
SCHEMATIC	
I.D.C.	
DRAFTER	SHT
P. MARCUS	15-23
DATE	TASK 03983
7-24-81	DWG 35-807R05 D08

NOTES

FORMING 44-131-42732-2

A B C D E F G H J K L M N R S



REVISIONS			
PROTO REL AT R01			
E.C.J.	11-19-81	R01	
2 ND PROTO REL AT R02			
E.C.J.	12-31-81	R02	
AREAS M2 & M3, ADDED TEST POINT "I"			
BWL	BWL	4986	1-14-82 R03

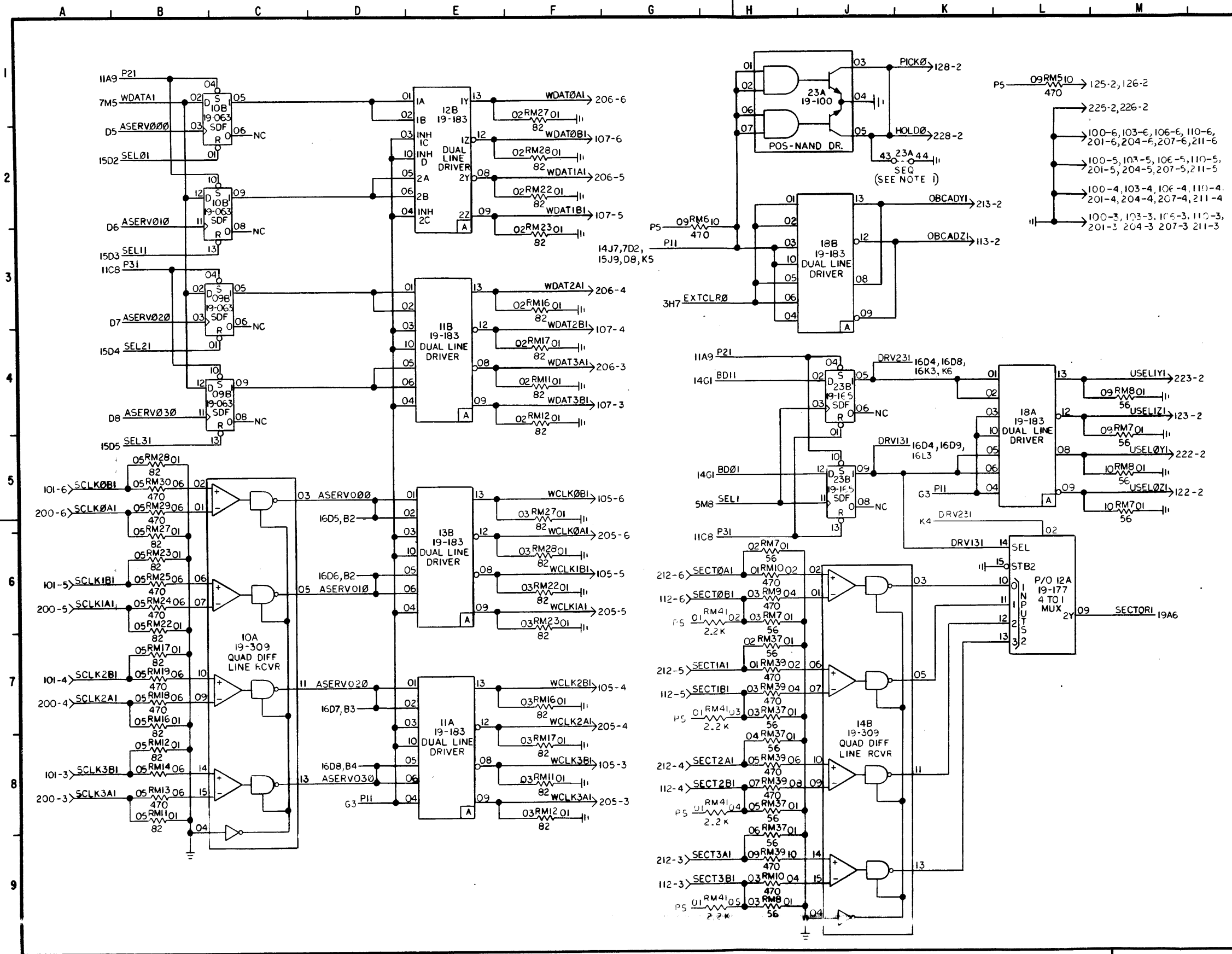
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TITLE SCHEMATIC	
IDC	
DRAFTER	Q STINE
DATE	TASK 03983
7-24-81	DWG 35-807 R03
SHT	DOB 16 -23

NOTES

BRUNING 44-131-409792



REVISIONS			
PROTO	REL AT RO1.		
E.C.J.		11-19-81	RO1
2ND PRTO REL AT RO2.			
BWL	BWL	12-31-81	RO2
AREA J1 23A04 WAS NC. NOTE 1 WAS 'ENABLE POWER SEQUENCING'			
JLV	5127	M 7-26-82	RO3
AREA H- VALU OF RM6 WAS 450 IN ERROR.			
JAH	5250	R 1-28-83	RO4
AREA G3, DEL. XREF SFI FROM MNEMONIC P11.			
MF	6191	MS 10-18-85	RO5

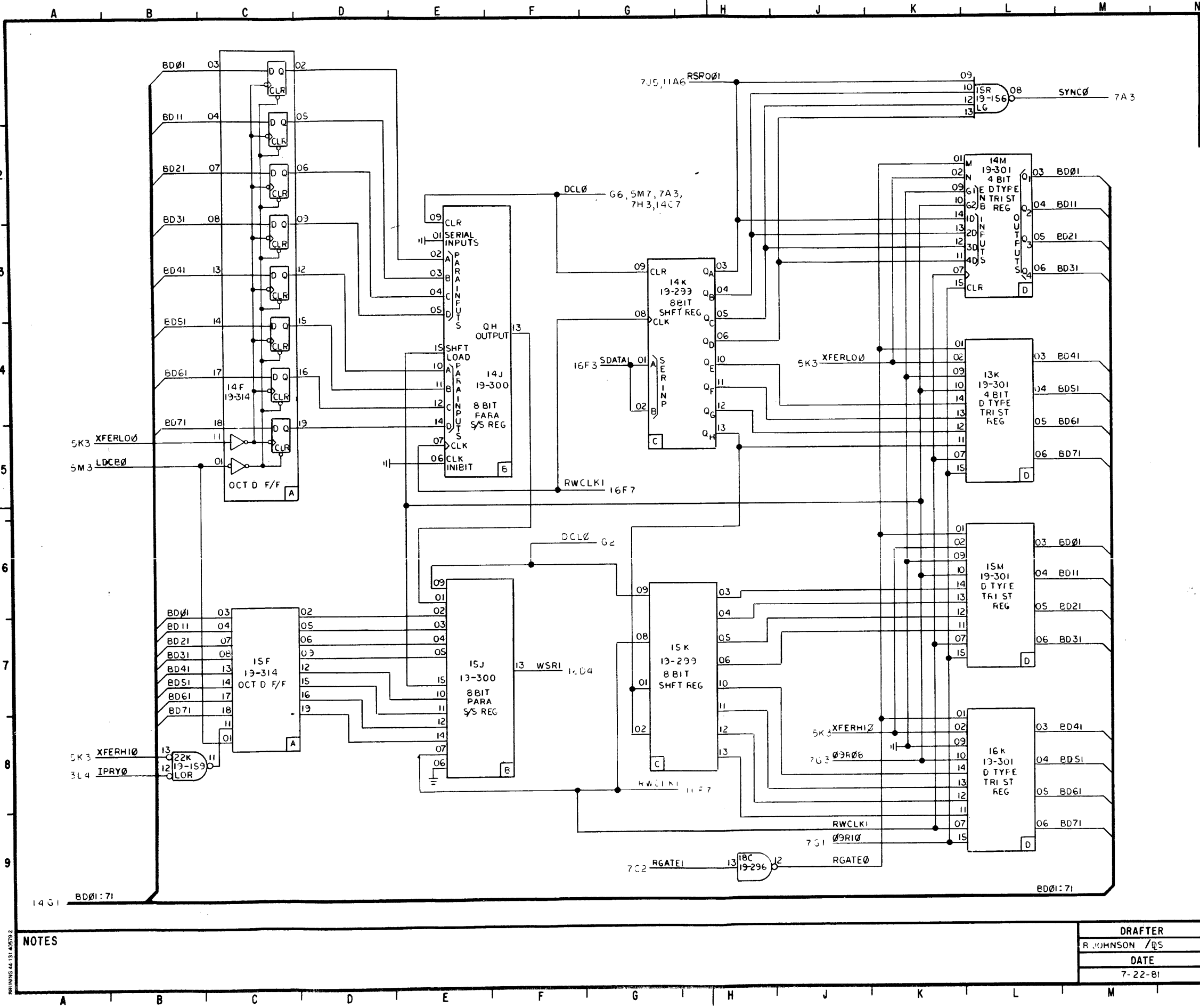
NOTES
1. INSTALL JUMPER TO DISABLE POWER SEQUENCING.

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TITLE	SCHEMATIC	
	I.D.C.	
DRAFTER	V. TAHAMONT	
DATE	7-27-81	TASK 03983
	DWG 35-807R05	SHT 17-23

BRUNING 44131 409792



REVISIONS			
PROTO REL AT RO1.			
ECJ		11-19-81	RO1
2ND PROTO REL AT RO2.			
ECJ		12-31-81	RO2
AKIA 32 DELETED 7LS FROM DCL0			
JLV	37	5127 M	7-27-82 RO3

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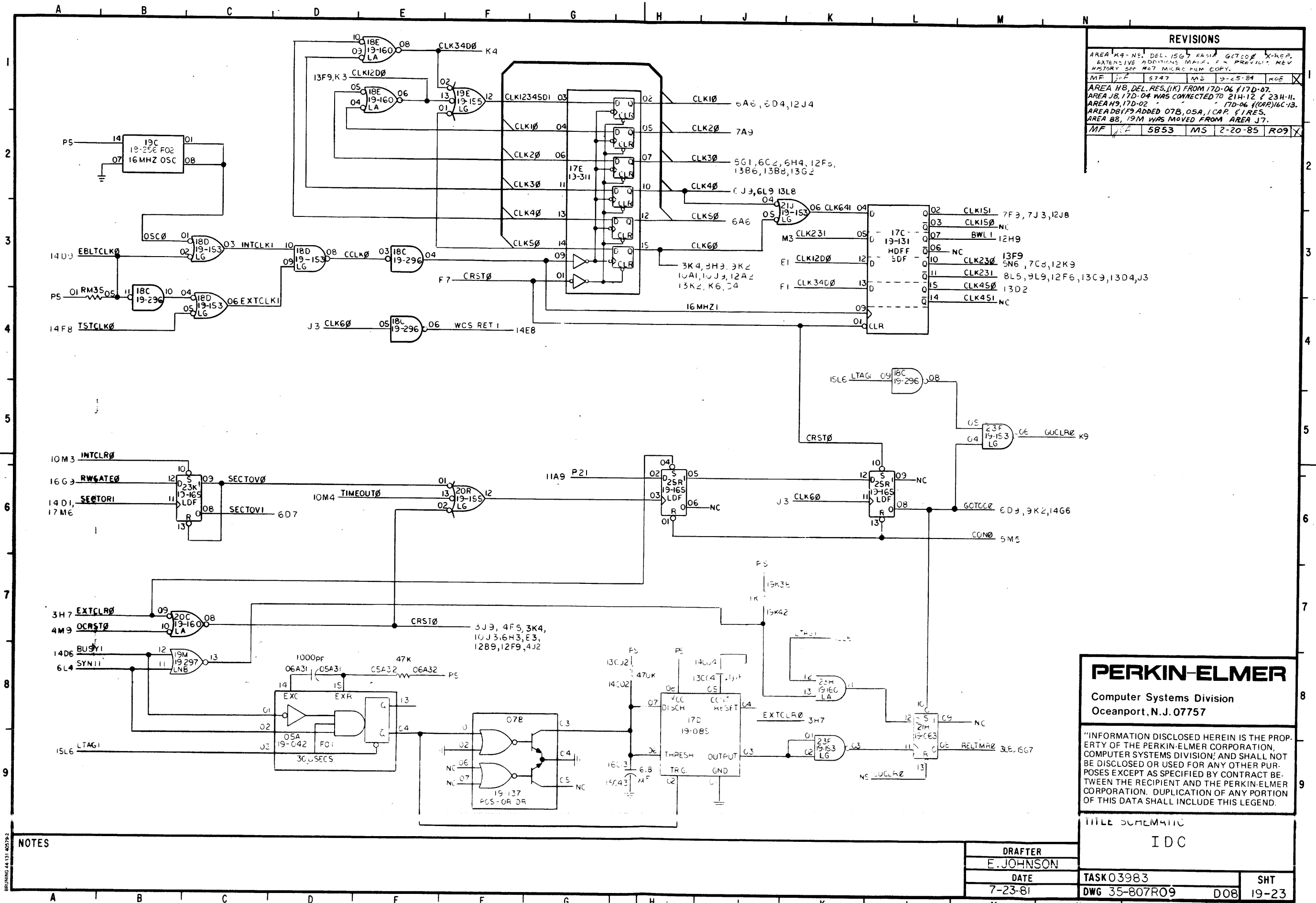
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TITLE SCHEMATIC
 IDC

DRAFTER	R. JOHNSON / QS
DATE	7-22-81
TASK	03983
DWG	35-807 RO3
SHT	18-23

NOTES

DRAWING 44-131-42752



REVISIONS			
AREA KA-NE, DEL. 15G7, FRM1, GIT208, X-REF, EXTENSIVE ADDITIONS MADE. F-2 PREVIOUS REV HISTORY SEE #07 MICRO FILM COPY.			
MF	5747	MS	9-25-84 R05
AREA HB, DEL. RES. (K) FROM 17D-06 #17D-07.			
AREA JB, 17D-04 WAS CONNECTED TO 21H-12 #23H-11.			
AREA H9, 17D-02 " " " " " " " " 17D-06 #16C-13.			
AREA D8/F9 ADDED 07B, 05A, 1 CAP, F RES.			
AREA B8, 19M WAS MOVED FROM AREA J7.			
MF	5853	MS	2-20-85 R09

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TITLE SCHEMATIC	
IDC	
DRAFTER E. JOHNSON	
DATE 7-23-81	TASK 03983 DWG 35-807R09
SHT 19-23	D08

NOTES
 DRAWING #4131 607942

IDC RESISTOR MODULE CONVERSION CHART																REVISIONS						
RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	RESISTOR MODULE	PIN NO.	CONN. NO.	ROW	PIN NO.	MNEMONIC	PRGTO	REL AT	ROI.		
1	RM25	01	9	4	31		RM 38	01	9	3	61											
		02			30			02				60	INX1A1									
		03			29	USEL1A1		03				59	INX1B1									
		04			28	17A06		04				58	14A07									
		05			27	SCLK1B1		05				57	INX2A1									
		06			26	10A06		06				56	14A10									
		07			25			07				55	INX2B1									
		08			24			08				54	14A09									
		09			23	SKED1B1		09				53	INX3A1									
		10			22	13A07		10				52	14A14									
2	RM26	01	9	1	25	GND	RM 39	01	9	4	61											
		02			24	USEL1A1		02				60	SECT1A1									
		03			23	USEL1B1		03				59	14B06									
		04			22	USEL1B1		04				58	SECT1B1									
		05			21	SKED1A1		05				57	14B07									
		06			20	SKED1B1		06				56	SECT2A1									
3	RM27	01	9	1	13	GND	RM 39	01	9	4	52											
		02			12	WDAT0A1		02				51	14B10									
		03			11	WCLK0B1		03				50	SECT2B1									
		04			10			04				49	14B09									
		05			09	SCLK0A1		05				48	SECT3A1									
		06			08			06				47	14B14									
4	RM28	01	9	2	13	GND	RM 40	01	8	2	06											
		02			12	WDAT0B1		02				05	P5									
		03			11	WCLK0A1		03				04	INX0B1									
		04			10			04				03	INX1B1									
		05			09	SCLK0B1		05				02	INX2B1									
		06			08			06				01	INX3B1									
5	RM29	01	9	3	13	GND	RM 41	01	9	2	55											
		02			12	USEL0B1		02				54	P5									
		03			11	17A01		03				53	SKED0B1									
		04			10	SCLK0A1		04				52	SKED1B1									
		05			09	10A01		05				51	SKED2B1									
		06			08			06				50	SKED3B1									
6	RM30	01	9	4	13	GND	RM 42	01	9	1	55											
		02			12	USEL0A1		02				54	SKED0B1									
		03			11	17A02		03				53	SKED1B1									
		04			10	SCLK0B1		04				52	SKED2B1									
		05			09	10A02		05				51	SKED3B1									
		06			08			06				50										
7	RM31	01	9	1	07	GND																
		02			06	USEL0A1																
		03			05	USEL0B1																
		04			04	SKED0A1																
		05			03	SKED0B1																
		06			02																	
8	RM32	01	9	2	07	P5																
		02			06	USEL0B1																
		03			05	USEL1B1																
		04			04	P21																
		05			03	P31																
		06			02																	
9	RM36	01	9	1	55	INX1A1																
		02			54	INX1B1																
		03			53	INX2A																
		04			52	INX2B																
		05			51	INX3A1																
		06			50																	
9	RM37	01	9	2	50	GND																
		02			49	SECT1A1																
		03			48	SECT1B1																
		04			47	SECT2A1																
		05			46	SECT2B1																
		06			45	SECT3A1																

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 Computer Systems Division
 Oceanport, N.J. 07757

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TITLE
 SCHEMATIC
 INTELLIGENT DISC CONTROLLER

DRAFTER
 E. JOHNSON

DATE
 11-11-81

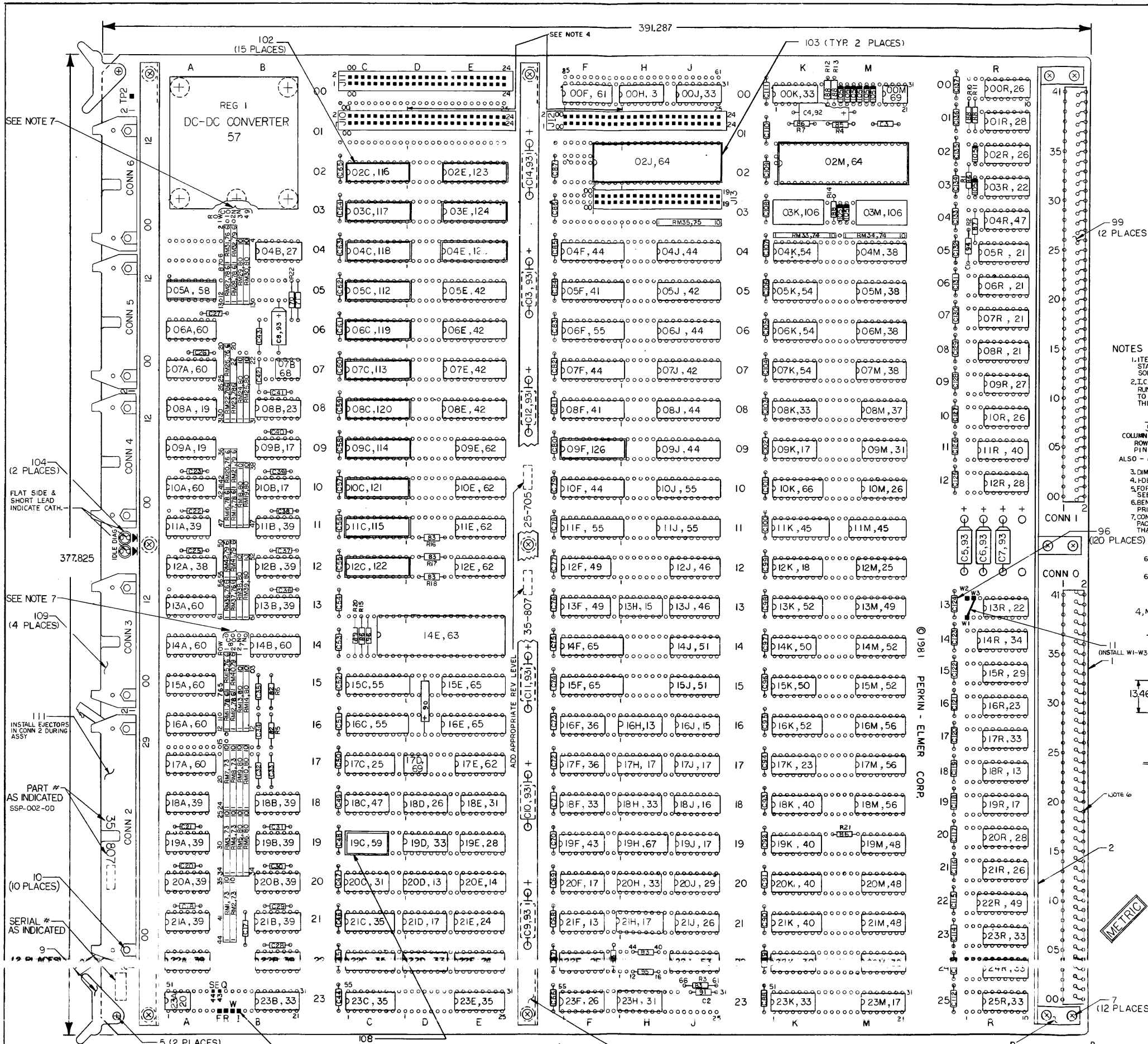
TASK 03983
 DWG 35-807 R03

SHT
 D08 21-23

NOTES

BRUNING 44-131-0079 Z

	A			B			C			D			E			F			G			H			J			K			L			M			N		
	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT	NET	MNEMONIC	SHT			
	0001	A11	09	0071	B0921	15	0130	CLK50	19	0187	DATA091	05	0244	EXTCLK1	19	0303	INX0A1	16	0359	HRC	12	0415	13J06	13	0471	18M05	11												
	0002	A21	09	0072	B10Y1	15	0131	CLK60	19	0188	DATA101	05	0245	EXTCLRC	03	0304	INX0B1	16	0360	HRC0	07	0416	12J13	13	0472	18R11	11												
	0003	A31	09	0073	B10Z1	15	0133	CLO70	03	0189	DATA111	05	0247	FA081	04	0305	INX1A1	16	0361	MI1	09	0417	14F05	18	0473	18R14	11												
	0004	ACCCECC1	07	0074	BIT151	07	0134	CLOCO	03	0190	DATA121	05	0248	FA091	04	0306	INX1B1	16	0362	MOU11	12	0418	14F06	18	0474	16R02	11												
	0005	ADRS1	03	0075	BITONO	06	0135	CMCO	03	0191	DATA131	05	0249	FA101	04	0307	INX2A1	16	0363	HUX131	04	0419	14F09	18	0475	16P05	11												
	0006	ADRS0	03	0076	BITSRO1	11	0136	CMT1	08	0192	DATA141	05	0250	FA111	04	0308	INX2B1	16	0364	MUF231	04	0420	14F12	18	0476	16R11	11												
	0007	AE/OE1	08	0078	BRA01	10	0137	CONC	19	0193	DATA151	05	0251	FA121	04	0309	INX3A1	16	0365	HWF1	08	0421	14F15	18	0477	15C11	14												
	0008	ANTCRY1	13	0079	BPA11	10	0138	CONTRACKO	04	0194	DCLO	18	0252	FA131	04	0310	INX3B1	16	0366	NFVIFL1	03	0422	14F16	18	0478	15E06	14												
	0009	AR01	09	0080	BPA21	10	0139	CONTSSEL1	03	0196	DEO	05	0253	FA141	04	0311	INDEX1	15	0367	22F03	03	0423	14F19	18	0479	15E09	14												
	0010	AR11	09	0081	BPA31	10	0140	CONTSYNCO	03	0197	DL13U51	06	0254	FA151	04	0312	INTCLK1	19	0368	21R06	03	0424	15F02	18	0480	15E12	14												
	0011	AR21	09	0082	BPA41	10	0141	CTAG31	15	0198	DL13U51	06	0255	FAULT1	14	0313	INTCLPO	10	0369	08M03	03	0425	15F05	18	0481	15E15	14												
	0012	AR31	09	0083	BPA51	10	0142	CTLOPTCL1	03	0199	DMA130	12	0256	FAULTA1	14	0314	INTDATA0	05	0370	08M06	03	0426	15F06	18	0482	15E16	14												
	0013	ASERY000	17	0084	BPA61	10	0143	DOC1	04	0200	DMA230	12	0257	FAULTB1	14	0315	DDX09	04	0371	10R11	03	0427	15F09	18	0483	15E19	14												
	0014	ASERV010	17	0085	BPA71	10	0144	D011	04	0201	DMA301	06	0258	FILE131	03	0316	IPRDY1	07	0372	02R11	04	0428	15F12	18	0484	16E02	15												
	0015	ASERV020	17	0086	BPA81	10	0145	D021	04	0202	DMA3PTC	05	0259	FILE130	03	0317	IPRY1	03	0373	02R0R	04	0429	15F15	18	0485	16F05	15												
	0016	ASERV030	17	0087	BPA91	10	0146	D031	04	0203	DR1	07	0260	FILE231	03	0318	LASTDA0	06	0374	02R06	04	0430	15F16	18	0486	16F06	15												
	0017	ATNO	04	0088	BUSAOEC	13	0147	D041	04	0204	DRY131	17	0261	FILE230	03	0319	LASTWRD1	06	0375	02R03	04	0431	15F19	18	0487	16F09	15												
	0018	B01	09	0089	BUSYA1	14	0148	D051	04	0205	DRV231	17	0262	FILEACK0	04	0320	LRD01	12	0376	06F02	05	0432	09R08	07	0488	17G1	15												
	0019	B11	09	0090	BUSYB1	14	0149	D061	04	0206	DPO	03	0263	FILESEL1	03	0321	LRD11	12	0377	06F05	05	0433	14K04	18	0489	16F15	15												
	0020	B21	09	0091	BUSY1	14	0150	D071	04	0207	EBLCWT1	13	0264	FILESYNCO1	03	0322	LRD21	12	0378	06F06	05	0434	14K05	18	0490	16E16	15												
	0021	B31	09	0092	=CONT	03	0151	D081	04	0208	EBLOUT0	04	0265	FILESYNCO	03	0323	LRD31	12	0379	06F09	05	0435	14K06	18	0491	10B05	17												
	0022	BA0E1	13	0094	CA081	03	0152	D091	04	0209	19F06	06	0266	FINT1	04	0324	LRD41	12	0380	06F12	05	0436	14K10	18	0492	10R09	17												
	0023	BD01	18	0095	CA091	03	0153	D101	04	0210	ECC001	11	0267	=FILE1	03	0325	LRD51	12	0381	06F15	05	0437	14K11	18	0493	09B05	17												
	0024	BD11	18	0096	CA101	03	0154	D111	04	0211	ECC011	11	0268	FLDA0	03	0326	LRD61	12	0382	06F16	05	0438	14K12	18	0494	09R09	17												
	0025	BD21	18	0097	CA111	03	0155	D121	04	0212	ECC021	11	0269	FLDRO	03	0327	LRD71	12	0383	06F19	05	0439	14K13	18	0495	20D06	13												
	0026	BD31	18	0098	CA121	03	0156	D131	04	0213	ECC031	11	0270	FLOCO	03	0328	LDA1	03	0384	05F02	05	0440	15K03	18	0496	OUTPUT	10												
	0027	BD41	18	0099	CA131	03	0157	D141	04	0214	ECC041	11	0271	FLSRO	03	0329	LD51	03	0385	05F05	05	0441	15K04	18	0497	10P08	10												
	0028	BD51	18	0100	CA141	03	0158	D151	04	0215	ECC051	11	0272	FMTENB1	03	0330	LDCTO	05	0386	05F06	05	0442	15F05	18	0498	00H0E	08												
	0029	BD61	18	0101	CA151	03	0159	D000	04	0216	ECC061	11	0274	FUNCOO	03	0331	LDCCO	05	0387	05F09	05	0443	15F06	18	0500	20R12	19												
	0030	BD71	18	0102	CARRY31	12	0160	D010	04	0217	ECC071	11	0275	FUNCO1	03	0332	LDDMA1	12	0388	05F12	05	0444	15K10	18	0501	25R05	19												
	0031	A01	09	0103	CARRY71	12	0161	D020	04	0218	ECC081	11	0276	FUMCO20	03	0333	LDDMA0	05	0389	05F15	05	0445	15K11	18	0502	14J13	18												
	0046	BDI001	08	0104	CB170	14	0162	D030	04	0219	ECC091	11	0277	F=0	12	0334	LDSSKG	05	0390	05F16	05	0446	15K12	18	0503	14F02	18												
	0047	BDI011	08	0105	CB171	14	0163	D040	04	0220	ECC101	11	0278	GOT000	19	0335	LDIRIT1	06	0391	05F19	05	0447	15K13	18	0504	18C10	19												
	0048	BDI021	08	0106	CCO	12	0164	D050	04	0221	ECC111	11	0279	GPDO81	05	0336	LDOBY71	06	0392	19F03	06	0448	09R10	07	0505	22K11	18												
	0049	BDI031	08	0107	CCLO	19	0165	D060	04	0222	ECC121	11	0280	GPDO91	05	0337	LDPAGEC	05	0393	22F03	07	0449	24R05	07	0506	14R03	16												
	0050	BDI041	08	0108	CCMXP1	06	0166	D070	04	0223	ECC131	11	0281	GPD101	05	0338	LOC1	03	0394	22F06	07	0450	01R08	07	0507	14R05	16												
	0051	BDI051	08	0109	CENBO	12	0167	D080	04	0224	ECC141	11	0282	GPD111	05	0339	LOF0	05	0395	17J06	07	0451	23R06	07	0508	14R11	16												
	0052	B001	14	0110	DDWAG01	06	0168	D090	04	0225	ECC151	11	0283	SPD121	05	0340	LON0	05	0396	17J09	07	0452	23R09	07	0509	14R13	16												
	0053	B00Z1	14	0111			0169	D100	04	0226	ECC161	11	0284	GPD131	05	0341	LF131	12	0397	17J08	07	0453	21R08	07	0510	14B03	17												
	0054	B01Y1	14	0112	C1MT1	04	0170	D110	04	0227	ECC171	11	0285	SPD141	05	0342	LPZ31	12	0398	21F11	06	0454	20R06	07	0511	14B05	17												
	0055	B01Z1	14	0113	CLMTCLO	05	0171	D120	04	0228	ECC181	11	0286	SPD151	05	0343	LSF1	03	0399	22J04	06	0455	17R09	07	0512	14B11	17												
	0056	B02Y1	14	0114	C1M1	09	0172	D130	04	0229	ECC191	11	0287	HWO	06	0344	NA1	08	0400	18F09	06	0456	21R11	07	0513	14B13	17												
	0057	B02Z1	14	0115	CLK641	19	0173	D140	04	0230	ECC201	11	0288	IG1	09	0345	MAXADD01	06	0401	12F14	13	0457	18R11	07	0514	RM6-02	16												
	0058	B03Y1	14	0116	CLK450	19	0174	D150	04	0231	ECC311	11	0289	I11	04	0346	MAXADD11	13	0402	12F13	13	0458	19R05	07	0515	RM5-02	16												
	0059	B03Z1	14	0118	CLK231	19	0175	DA1	03																														

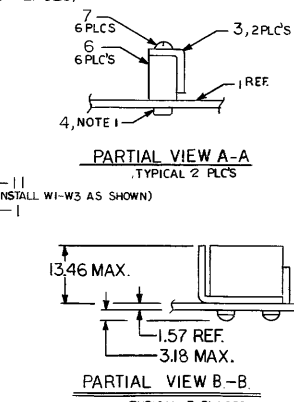


REVISIONS		
PRE PRODUCTION APPROVAL	DEV RVP	INIT DATE 2/19/82
	PROD MAB	DATE 4/18/82
RELEASED FOR PRODUCTION		
MFG. ENG. mab DATE 4/18/82		
FOR PREVIOUS REVISION HISTORY SEE R14 MICROFILM COPY.		
ADDED IC 05A, 19-042 FOI. ADDED IC 07B, 19-137. ADDED RESISTOR R22, 27-001 P12, AT LOC. 05A32. ADDED CAPACITOR C42-014, AT LOC. 06A31. REMOVED RESISTOR 21-001 F09 FROM LOC. PC01 (ITEM 86).		
TRF TTB	SBSS	MS 12-16-85 R15

NOTES

- ITEM 4 (PHN SCREW) TO BE MOUNTED TO CENTER STANDOFF OF FRONT & MIDDLE STIFFENERS ON SOLDER SIDE ONLY.
- I.C. PACK LOCATIONS ARE GIVEN ON THE WIRE RUN LIST AS ROW A CFK OR R ONLY. TRANSLATE TO ACTUAL POSITIONS ON THIS ASSY BY USING THE FOLLOWING EXAMPLE:

RUN LIST LOCATION	SCHEMATIC ASSY LOCATION
02C11	02C41
- DIMENSIONS ARE IN MILLIMETERS.
- 4-DENOTES PIN 1 IN COLUMNS D & H.
- FOR MOUNTING OF STANDARD HARDWARE SEE 16-042 D12.
- BEND PINS CLOSEST TO EDGE OF BOARD INWARD PRIOR TO SOLDERING.
- CONNECTOR AREAS WHERE THE RESISTOR SIP PACKAGES ARE INSTALLED BEGIN WITH 01 RATHER THAN 00.



UNLESS OTHERWISE SPECIFIED			
SCALE: 2/1	TOLERANCE:		
DIMENSIONS (SEE NOTE 3)	.XX ± .13	X ± .8	ANGLES ± 1°
NAME	TITLE	DATE	
BLUSK	BLUSK	DES/DFT	6-22-81
R. CERO	SUPP	4-30-82	
R. REAGO	ENG	4-30-82	
W. RICE	MGR	4-30-82	
R. BARKER	QC	4-30-82	

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TITLE ASSEMBLY INTELLIGENT DISC CONTROLLER (IDC)

TASK 03983 SHT - 1
DWG 35-807 R15 E03

MILLIMETER	INCH
1.57	.062
3.18	.125
13.46	.530
37.825	1.4875
39.1281	1.540

NOTE: 8. INSERT THE 35-807 INTO CONDUCTIVE GRID BAG, ITEM 12. THE OPEN END MUST BE FOLDED & SECURED WITH ITEM 127.

USED IN MANUAL: 47-032

CAUTION
PRINTED CIRCUIT PATHS AND PADS ARE SHOWN FOR PERKIN-ELMER'S INTERNAL REFERENCE INFORMATION ONLY.



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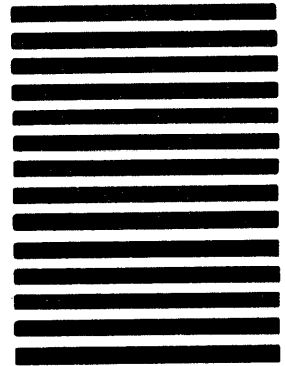
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